32-Bit

Microcontroller

TC270 / TC275 / TC277

32-Bit Single-Chip Micocontroller
DC-Step

32-Bit Single-Chip Micocontroller

Data Sheet

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1 Summary of Features

The TC27x product family has the following features:

- High Performance Microcontroller with three CPU cores
- Two 32-bit super-scalar TriCore CPUs (TC1.6P), each having the following features:
  - Superior real-time performance
  - Strong bit handling
  - Fully integrated DSP capabilities
  - Multiply-accumulate unit able to sustain 2 MAC operations per cycle
  - Fully pipelined Floating point unit (FPU)
  - up to 200 MHz operation at full temperature range
  - up to 120 Kbyte Data Scratch-Pad RAM (DSPR)
  - up to 32 Kbyte Instruction Scratch-Pad RAM (PSPR)
  - 16 Kbyte Instruction Cache (ICACHE)
  - 8 Kbyte Data Cache (DCACHE)
- Power Efficient scalar TriCore CPU (TC1.6E), having the following features:
  - Binary code compatibility with TC1.6P
  - up to 200 MHz operation at full temperature range
  - up to 112 Kbyte Data Scratch-Pad RAM (DSPR)
  - up to 24 Kbyte Instruction Scratch-Pad RAM (PSPR)
  - 8 Kbyte Instruction Cache (ICACHE)
  - 0.125Kbyte Data Read Buffer (DRB)
- Lockstepped shadow cores for one TC1.6P and for TC1.6E
- Multiple on-chip memories
  - All embedded NVM and SRAM are ECC protected
  - up to 4 Mbyte Program Flash Memory (PFLASH)
  - up to 384 Kbyte Data Flash Memory (DFLASH) usable for EEPROM emulation
  - 32 Kbyte Memory (LMU)
  - BootROM (BROM)
- 64-Channel DMA Controller with safe data transfer
- Sophisticated interrupt system (ECC protected)
- High performance on-chip bus structure
  - 64-bit Cross Bar Interconnect (SRI) giving fast parallel access between bus masters, CPUs and memories
  - 32-bit System Peripheral Bus (SPB) for on-chip peripheral and functional units
  - One bus bridge (SFI Bridge)
- Optional Hardware Security Module (HSM) on some variants
- Safety Management Unit (SMU) handling safety monitor alarms
- Memory Test Unit with ECC, Memory Initialization and MBIST functions (MTU)
- Hardware I/O Monitor (IOM) for checking of digital I/O
- Versatile On-chip Peripheral Units
  - Four Asynchronous/Synchronous Serial Channels (ASCLIN) with hardware LIN support (V1.3, V2.0, V2.1 and J2602) up to 50 MBaud

  - Four Queued SPI Interface Channels (QSPI) with master and slave capability up to 50 Mbit/s
  - High Speed Serial Link (HSSL) for serial inter-processor communication up to 320 Mbit/s
  - Two serial Micro Second Bus interfaces (MSC) for serial port expansion to external power devices
  - One MultiCAN+ Module with 4 CAN nodes and 256 free assignable message objects for high efficiency data handling via FIFO buffering and gateway data transfer
  - 10 Single Edge Nibble Transmission (SENT) channels for connection to sensors
  - One FlexRay™ module with 2 channels (E-Ray) supporting V2.1
  - One Generic Timer Module (GTM) providing a powerful set of digital signal filtering and timer functionality to realize autonomous and complex Input/Output management
  - One Capture / Compare 6 module (Two kernels CCU60 and CCU61)
  - One General Purpose 12 Timer Unit (GPT120)
  - Three channel Peripheral Sensor Interface conforming to V1.3 (PSI5)
  - Peripheral Sensor Interface with Serial PHY (PSI5-S)
  - Optional Inter-Integrated Circuit Bus Interface (I2C) conforming to V2.1
  - Optional IEEE802.3 Ethernet MAC with RMII and MII interfaces (ETH)
- Versatile Successive Approximation ADC (VADC)
  - Cluster of 8 independent ADC kernels
  - Input voltage range from 0 V to 5.5V (ADC supply)
- Delta-Sigma ADC (DSADC)
  - Six channels
- Digital programmable I/O ports
- On-chip debug support for OCDS Level 1 (CPUs, DMA, On Chip Buses)
- multi-core debugging, real time tracing, and calibration
- four/five wire JTAG (IEEE 1149.1) or DAP (Device Access Port) interface
- Power Management System and on-chip regulators
- Clock Generation Unit with System PLL and Flexray PLL
- Embedded Voltage Regulator

Ordering Information

The ordering code for Infineon microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- The package and the type of delivery.

For the available ordering codes for the TC270 / TC275 / TC277 please refer to the **"AURIX™ TC2xx Data Sheet Addendum"**, which summarizes all available variants.

Table 1-1 Overview of TC27x Functions

Feature		
CPU Core	Type	TC1.6P / TC1.6E
	P Cores / Checker Cores / E Cores / Checker Cores	2 / 1 / 1 / 1
	Max. Freq.	200 MHz
	FPU	yes
Program Flash	Size	4 Mbyte
Data Flash	Size	384 Kbyte
Cache	Instruction (P / E)	16 Kbyte / 8 Kbyte
	Data (P / E)	8 Kbyte / -
SRAM	Size TC1.6P (DSPR/PSPR)	120 Kbyte / 32 Kbyte [2]
	Size TC1.6E (DSPR/PSPR)	112 Kbyte / 24 Kbyte [1] [2]
	Size LMU	32 Kbyte
DMA	Channels	64
ADC	Channels	48 + 12
	Converter	8
DSADC	Channels	6
GTM	TIM	4
	TOM	3
	ATOM / MCS	5 / 4
	CMU / ICM	1 / 1
	PSM	1
	TBU	1
	SPE	2
	CMP / MON	1 / 1
	BRC / DPLL	1 / 1
Timer	GPT12	2
	CCU6	2
STM	Modules	3
FlexRay	Modules	1
	Channels	2

Table 1-1 Overview of TC27x Functions (cont'd)

Feature		
CAN	Nodes	4
	Message Objects	256
QSPI	Channels	4
ASCLIN	Interfaces	4
I2C	Interfaces	1
SENT	Channels	10
PSI5	Modules	3
PSI5-S	Modules	1
HSSL	Channels	1
MSC	Channels	2
Ethernet	Channels	1
ASIL	Level	up to ASIL-D
FCE	Modules	1
Safety support	SMU	1
	IOM	1
Security	HSM	1
Embedded Voltage Regulator	DCDC from 5 V / 3.3 V to 1.3 V	Yes
Embedded Voltage Regulator	LDO from 5 V / 3.3 V to 1.3 V	Yes
Embedded Voltage Regulator	LDO from 5 V to 3.3 V	Yes
Low Power Feature	Standby RAM	Yes
Packages	Type	PG-LQFP-176-22 / LF-BGA-292-6 / LF-BGA-292-10
I/O	Type	5 V CMOS / 3.3 V CMOS / LVDS
$T_{ambient}$	Range	−40 … +125°C

1) Address range starts at lowest address defined in the User's Manual. For reference see the Memory Maps chapter of the User's Manual.

2) To ensure the processor cores are provided with a constant stream of instructions the Instruction Fetch Units will speculatively fetch instructions from the up to 64 bytes ahead of the current PC.
If the current PC is within 64 bytes of the top of an instruction memory the Instruction Fetch Unit may attempt to speculatively fetch instruction from beyond the physical range. This may then lead to error conditions and alarms being triggered by the bus and memory systems.
It is therefore recommended that the upper 64 bytes of any memory be unused for instruction storage.

2 Package and Pinning Definitions

This chapter gives a pinning of the different packages of the TC270 / TC275 / TC277.

2.1 TC275x Pin Definition and Functions: LQFP176

Figure 2-1 is showing the TC275x Logic Symbol for the package variant: QFP176.

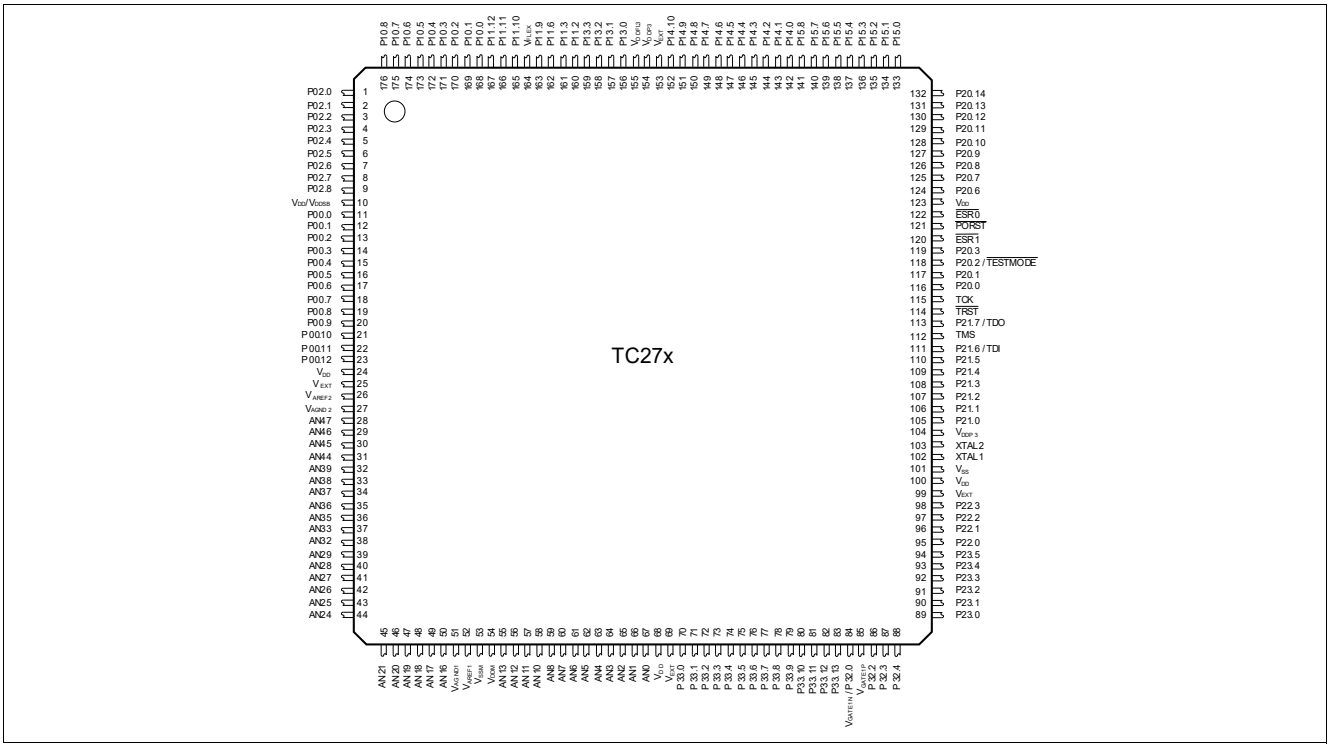


Figure 2-1 TC275x Logic Symbol for the package variant LQFP176.

2.1.1 TC275x LQFP176 Package Variant Pin Configuration'

Table 2-1 Port 00 Functions

Pin	Symbol	Ctrl	Type	Function
11	P00.0	I	**MP / PU1 / VEXT**	General-purpose input
	TIN9			GTM input
	$\overline{\text{CTRAPA}}$			CCU61 input
	T12HRE			CCU60 input
	INJ00			MSC0 input
	CIFD9			CIF input
	P00.0	O0		General-purpose output
	TOUT9	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	ATX3	O3		ASCLIN3 output
	–	O4		Reserved
	TXDCAN1	O5		CAN node 1 output
	–	O6		Reserved
	COUT63	O7		CCU60 output
	ETHMDIOA	HWOUT		ETH input/output
12	P00.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN10			GTM input
	ARX3E			ASCLIN3 input
	RXDCAN1D			CAN node 1 input
	PSIRX0A			PSI5 input
	SENT0B			SENT input
	CC60INB			CCU60 input
	CC60INA			CCU61 input
	DSCIN5A			DSADC channel 5 input A
	DS5NA			DSADC negative analog input of channel 5, pin A
	VADCG7.5			VADC analog input channel 5 of group 7
	CIFD10			CIF input
	P00.1	O0		General-purpose output
	TOUT10	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT5	O4		DSADC channel 5 output
	–	O5		Reserved
	SPC0	O6		SENT output
	CC60	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
13	P00.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN11			GTM input
	SENT1B			SENT input
	DSDIN5A			DSADC channel 5 input A
	DS5PA			DSADC positive analog input of channel 5, pin A
	VADCG7.4			VADC analog input channel 4 of group 7
	CIFD11			CIF input
	P00.2	O0		General-purpose output
	TOUT11	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	PSITX0	O4		PSI5 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	COUT60	O7		CCU61 output
14	P00.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN12			GTM input
	RXDCAN3A			CAN node 3 input
	PSIRX1A			PSI5 input
	PSISRXA			PSI5-S input
	SENT2B			SENT input
	CC61INB			CCU60 input
	CC61INA			CCU61 input
	DSCIN3A			DSADC channel 3 input A
	VADCG7.3			VADC analog input channel 3 of group 7
	DSITR5F			DSADC channel 5 input F
	CIFD12			CIF input
	P00.3	O0		General-purpose output
	TOUT12	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT3	O4		DSADC channel 3 output
	–	O5		Reserved
	SPC2	O6		SENT output
	CC61	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
15	P00.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN13			GTM input
	REQ7			SCU input
	SENT3B			SENT input
	DSDIN3A			DSADC channel 3 input A
	DSSGNA			DSADC input
	VADCG7.2			VADC analog input channel 2 of group 7 (MD)
	CIFD13			CIF input
	P00.4	O0		General-purpose output
	TOUT13	O1		GTM output
	PSISTX	O2		PSI5-S output
	–	O3		Reserved
	PSITX1	O4		PSI5 output
	VADCG4BFL0	O5		VADC output
	SPC3	O6		SENT output
	COUT61	O7		CCU61 output
16	P00.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN14			GTM input
	PSIRX2A			PSI5 input
	SENT4B			SENT input
	CC62INB			CCU60 input
	CC62INA			CCU61 input
	DSCIN2A			DSADC channel 2 input A
	VADCG7.1			VADC analog input channel 1 of group 7 (MD)
	CIFD14			CIF input
	P00.5	O0		General-purpose output
	TOUT14	O1		GTM output
	DSCGPWMN	O2		DSADC output
	–	O3		Reserved
	DSCOUT2	O4		DSADC channel 2 output
	VADCG4BFL1	O5		VADC output
	SPC4	O6		SENT output
	CC62	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
17	P00.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN15			GTM input
	SENT5B			SENT input
	DSDIN2A			DSADC channel 2 input A
	VADCG7.0			VADC analog input channel 0 of group 7
	DSITR4F			DSADC channel 4 input F
	CIFD15			CIF input
	P00.6	O0		General-purpose output
	TOUT15	O1		GTM output
	DSCGPWMP	O2		DSADC output
	VADCG4BFL2	O3		VADC output
	PSITX2	O4		PSI5 output
	VADCEMUX10	O5		VADC output
	SPC5	O6		SENT output
	COUT62	O7		CCU61 output
18	P00.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN16			GTM input
	SENT6B			SENT input
	CC60INC			CCU61 input
	CCPOS0A			CCU61 input
	T12HRB			CCU60 input
	T2INA			GPT120 input
	DSCIN4A			DSADC channel 4 input A
	DS4NA			DSADC negative analog input of channel 4, pin A
	VADCG6.5			VADC analog input channel 5 of group 6
	CIFCLK			CIF input
	P00.7	O0		General-purpose output
	TOUT16	O1		GTM output
	–	O2		Reserved
	VADCG4BFL3	O3		VADC output
	DSCOUT4	O4		DSADC channel 4 output
	VADCEMUX11	O5		VADC output
	SPC6	O6		SENT output
	CC60	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
19	P00.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN17			GTM input
	SENT7B			SENT input
	CC61INC			CCU61 input
	CCPOS1A			CCU61 input
	T13HRB			CCU60 input
	T2EUDA			GPT120 input
	DSDIN4A			DSADC channel 4 input A
	DS4PA			DSADC channel 4 input A
	VADCG6.4			VADC analog input channel 4 of group 6
	CIFVSNC			CIF input
	P00.8	O0		General-purpose output
	TOUT17	O1		GTM output
	SLSO36	O2		QSPI3 output
	–	O3		Reserved
	–	O4		Reserved
	VADCEMUX12	O5		VADC output
	SPC7	O6		SENT output
	CC61	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
20	P00.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN18			GTM input
	SENT8B			SENT input
	CC62INC			CCU61 input
	CCPOS2A			CCU61 input
	T13HRC			CCU60 input
	T12HRC			CCU60 input
	T4EUDA			GPT120 input
	DSCIN1A			DSADC channel 1 input A
	VADCG6.3			VADC analog input channel 3 of group 6
	DSITR3F			DSADC channel 3 input F
	CIFHSNC			CIF input
	P00.9	O0		General-purpose output
	TOUT18	O1		GTM output
	SLSO37	O2		QSPI3 output
	ARTS3	O3		ASCLIN3 output
	DSCOUT1	O4		DSADC channel 1 output
	–	O5		Reserved
	SPC8	O6		SENT output
	CC62	O7		CCU61 output
21	P00.10	I	**LP / PU1 / VEXT**	General-purpose input
	TIN19			GTM input
	SENT9B			SENT input
	DSDIN1A			DSADC channel 1 input A
	VADCG6.2			VADC analog input channel 2 of group 6 (MD)
	P00.10	O0		General-purpose output
	TOUT19	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	SPC9	O6		SENT output
	COUT63	O7		CCU61 output

Table 2-1 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
22	P00.11	I	**LP / PU1 / VEXT**	General-purpose input
	TIN20			GTM input
	CTRAPA			CCU60 input
	T12HRE			CCU61 input
	DSCIN0A			DSADC channel 0 input A
	VADCG6.1			VADC analog input channel 1 of group 6 (MD)
	P00.11	O0		General-purpose output
	TOUT20	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	DSCOUT0	O4		DSADC channel 0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
23	P00.12	I	**LP / PU1 / VEXT**	General-purpose input
	TIN21			GTM input
	ACTS3A			ASCLIN3 input
	DSDIN0A			DSADC channel 0 input A
	VADCG6.0			VADC analog input channel 0 of group 6
	P00.12	O0		General-purpose output
	TOUT21	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT63	O7		CCU61 output

Table 2-2 Port 02 Functions

Pin	Symbol	Ctrl	Type	Function
1	P02.0	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN0			GTM input
	ARX2G			ASCLIN2 input
	REQ6			SCU input
	CC60INA			CCU60 input
	CC60INB			CCU61 input
	CIFD0			CIF input
	P02.0	O0		General-purpose output
	TOUT0	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO31	O3		QSPI3 output
	DSCGPWMN	O4		DSADC output
	TXDCAN0	O5		CAN node 0 output
	TXDA	O6		ERAY output
	CC60	O7		CCU60 output
2	P02.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN1			GTM input
	REQ14			SCU input
	ARX2B			ASCLIN2 input
	RXDCAN0A			CAN node 0 input
	RXDA2			ERAY input
	CIFD1			CIF input
	P02.1	O0		General-purpose output
	TOUT1	O1		GTM output
	–	O2		Reserved
	SLSO32	O3		QSPI3 output
	DSCGPWMP	O4		DSADC output
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-2 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
3	P02.2	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN2			GTM input
	CC61INA			CCU60 input
	CC61INB			CCU61 input
	CIFD2			CIF input
	P02.2	O0		General-purpose output
	TOUT2	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO33	O3		QSPI3 output
	PSITX0	O4		PSI5 output
	TXDCAN2	O5		CAN node 2 output
	TXDB	O6		ERAY output
	CC61	O7		CCU60 output
4	P02.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN3			GTM input
	ARX1G			ASCLIN1 input
	RXDCAN2B			CAN node 2 input
	RXDB2			ERAY input
	PSIRX0B			PSI5 input
	DSCIN5B			DSADC channel 5 input B
	SDI11			MSC1 input
	CIFD3			CIF input
	P02.3	O0		General-purpose output
	TOUT3	O1		GTM output
	ASLSO2	O2		ASCLIN2 output
	SLSO34	O3		QSPI3 output
	DSCOUT5	O4		DSADC channel 5 output
	–	O5		Reserved
	–	O6		Reserved
	COUT61	O7		CCU60 output

Table 2-2 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
5	P02.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN4			GTM input
	SLSI3A			QSPI3 input
	ECTT1			TTCAN input
	RXDCAN0D			CAN node 0 input
	CC62INA			CCU60 input
	CC62INB			CCU61 input
	DSDIN5B			DSADC channel 5 input B
	SDA0A			I2C0 input
	CIFD4			CIF input
	P02.4	O0		General-purpose output
	TOUT4	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	SLSO30	O3		QSPI3 output
	PSISCLK	O4		PSI5-S output
	SDA0	O5		I2C0 output
	TXENA	O6		ERAY output
	CC62	O7		CCU60 output
6	P02.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN5			GTM input
	MRST3A			QSPI3 input
	ECTT2			TTCAN input
	PSIRX1B			PSI5 input
	PSISRXB			PSI5-S input
	SENT3C			SENT input
	DSCIN4B			DSADC channel 4 input B
	SCL0A			I2C0 input
	CIFD5			CIF input
	P02.5	O0		General-purpose output
	TOUT5	O1		GTM output
	TXDCAN0	O2		CAN node 0 output
	MRST3	O3		QSPI3 output
	DSCOUT4	O4		DSADC channel 4 output
	SCL0	O5		I2C0 output
	TXENB	O6		ERAY output
	COUT62	O7		CCU60 output

Table 2-2 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
7	P02.6	I	**MP / PU1 / VEXT**	General-purpose input
	TIN6			GTM input
	MTSR3A			QSPI3 input
	SENT2C			SENT input
	CC60INC			CCU60 input
	CCPOS0A			CCU60 input
	T12HRB			CCU61 input
	T3INA			GPT120 input
	CIFD6			CIF input
	DSDIN4B			DSADC channel 4 input B
	DSITR5E			DSADC channel 5 input E
	P02.6	O0		General-purpose output
	TOUT6	O1		GTM output
	PSISTX	O2		PSI5-S output
	MTSR3	O3		QSPI3 output
	PSITX1	O4		PSI5 output
	VADCEMUX00	O5		VADC output
	–	O6		Reserved
	CC60	O7		CCU60 output

Table 2-2 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
8	P02.7	I	**MP / PU1 / VEXT**	General-purpose input
	TIN7			GTM input
	SCLK3A			QSPI3 input
	PSIRX2B			PSI5 input
	SENT1C			SENT input
	CC61INC			CCU60 input
	CCPOS1A			CCU60 input
	T13HRB			CCU61 input
	T3EUDA			GPT120 input
	CIFD7			CIF input
	DSCIN3B			DSADC channel 3 input B
	DSITR4E			DSADC channel 4 input E
	P02.7	O0		General-purpose output
	TOUT7	O1		GTM output
	–	O2		Reserved
	SCLK3	O3		QSPI3 output
	DSCOUT3	O4		DSADC channel 3 output
	VADCEMUX01	O5		VADC output
	SPC1	O6		SENT output
	CC61	O7		CCU60 output

Table 2-2 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
9	P02.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN8			GTM input
	SENT0C			SENT input
	CC62INC			CCU60 input
	CCPOS2A			CCU60 input
	T12HRC			CCU61 input
	T13HRC			CCU61 input
	T4INA			GPT120 input
	CIFD8			CIF input
	DSDIN3B			DSADC channel 3 input B
	DSITR3E			DSADC channel 3 input E
	P02.8	O0		General-purpose output
	TOUT8	O1		GTM output
	SLSO35	O2		QSPI3 output
	–	O3		Reserved
	PSITX2	O4		PSI5 output
	VADCEMUX02	O5		VADC output
	ETHMDC	O6		ETH output
	CC62	O7		CCU60 output

Table 2-3 Port 10 Functions

Pin	Symbol	Ctrl	Type	Function
168	P10.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN102			GTM input
	T6EUDB			GPT120 input
	P10.0	O0		General-purpose output
	TOUT102	O1		GTM output
	–	O2		Reserved
	SLSO110	O3		QSPI1 output
	–	O4		Reserved
	VADCG6BFL0	O5		VADC output
	–	O6		Reserved
	–	O7		Reserved

Table 2-3 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
169	P10.1	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN103			GTM input
	MRST1A			QSPI1 input
	T5EUDB			GPT120 input
	P10.1	O0		General-purpose output
	TOUT103	O1		GTM output
	MTSR1	O2		QSPI1 output
	MRST1	O3		QSPI1 output
	EN01	O4		MSC0 output
	VADCG6BFL1	O5		VADC output
	END03	O6		MSC0 output
	–	O7		Reserved
170	P10.2	I	**MP / PU1 / VEXT**	General-purpose input
	TIN104			GTM input
	SCLK1A			QSPI1 input
	T6INB			GPT120 input
	REQ2			SCU input
	RXDCAN2E			CAN node 2 input
	SDI01			MSC0 input
	P10.2	O0		General-purpose output
	TOUT104	O1		GTM output
	–	O2		Reserved
	SCLK1	O3		QSPI1 output
	EN00	O4		MSC0 output
	VADCG6BFL2	O5		VADC output
	END02	O6		MSC0 output
	–	O7		Reserved

Table 2-3 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
171	P10.3	I	**MP / PU1 / VEXT**	General-purpose input
	TIN105			GTM input
	MTSR1A			QSPI1 input
	REQ3			SCU input
	T5INB			GPT120 input
	P10.3	O0		General-purpose output
	TOUT105	O1		GTM output
	VADCG6BFL3	O2		VADC output
	MTSR1	O3		QSPI1 output
	EN00	O4		MSC0 output
	END02	O5		MSC0 output
	TXDCAN2	O6		CAN node 2 output
	–	O7		Reserved
172	P10.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN106			GTM input
	MTSR1C			QSPI1 input
	CCPOS0C			CCU60 input
	T3INB			GPT120 input
	P10.4	O0		General-purpose output
	TOUT106	O1		GTM output
	–	O2		Reserved
	SLSO18	O3		QSPI1 output
	MTSR1	O4		QSPI1 output
	EN00	O5		MSC0 output
	END02	O6		MSC0 output
	–	O7		Reserved
173	P10.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN107			GTM input
	HWCFG4			SCU input
	INJ01			MSC0 input
	P10.5	O0		General-purpose output
	TOUT107	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO38	O3		QSPI3 output
	SLSO19	O4		QSPI1 output
	T6OUT	O5		GPT120 output
	ASLSO2	O6		ASCLIN2 output
	-	O7		Reserved

Table 2-3 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
174	P10.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN108			GTM input
	ARX2D			ASCLIN2 input
	MTSR3B			QSPI3 input
	HWCFG5			SCU input
	P10.6	O0		General-purpose output
	TOUT108	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	MTSR3	O3		QSPI3 output
	T3OUT	O4		GPT120 output
	-	O5		Reserved
	MRST1	O6		QSPI1 output
	VADCG7BFL0	O7		VADC output
175	P10.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN109			GTM input
	ACTS2A			ASCLIN2 input
	MRST3B			QSPI3 input
	REQ4			SCU input
	CCPOS1C			CCU60 input
	T3EUDB			GPT120 input
	P10.7	O0		General-purpose output
	TOUT109	O1		GTM output
	–	O2		Reserved
	MRST3	O3		QSPI3 output
	VADCG7BFL1	O4		VADC output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-3 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
176	P10.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN110			GTM input
	SCLK3B			QSPI3 input
	REQ5			SCU input
	CCPOS2C			CCU60 input
	T4INB			GPT120 input
	P10.8	O0		General-purpose output
	TOUT110	O1		GTM output
	ARTS2	O2		ASCLIN2 output
	SCLK3	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-4 Port 11 Functions

Pin	Symbol	Ctrl	Type	Function
160	P11.2	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN95			GTM input
	P11.2	O0		General-purpose output
	TOUT95	O1		GTM output
	END03	O2		MSC0 output
	SLSO05	O3		QSPI0 output
	SLSO15	O4		QSPI1 output
	EN01	O5		MSC0 output
	ETHTXD1	O6		ETH output
	COUT63	O7		CCU60 output

Table 2-4 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
161	P11.3	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN96			GTM input
	MRST1B			QSPI1 input
	SDI03			MSC0 input
	P11.3	O0		General-purpose output
	TOUT96	O1		GTM output
	–	O2		Reserved
	MRST1	O3		QSPI1 output
	TXDA	O4		ERAY output
	–	O5		Reserved
	ETHTXD0	O6		ETH output
	COUT62	O7		CCU60 output
162	P11.6	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN97			GTM input
	SCLK1B			QSPI1 input
	P11.6	O0		General-purpose output
	TOUT97	O1		GTM output
	$\overline{\text{TXENB}}$	O2		ERAY output
	SCLK1	O3		QSPI1 output
	$\overline{\text{TXENA}}$	O4		ERAY output
	FCLP0	O5		MSC0 output
	ETHTXEN	O6		ETH output
	COUT61	O7		CCU60 output
163	P11.9	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN98			GTM input
	MTSR1B			QSPI1 input
	RXDA1			ERAY input
	ETHRXD1			ETH input
	P11.9	O0		General-purpose output
	TOUT98	O1		GTM output
	–	O2		Reserved
	MTSR1	O3		QSPI1 output
	–	O4		Reserved
	SOP0	O5		MSC0 output
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-4 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
165	P11.10	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN99			GTM input
	REQ12			SCU input
	ARX1E			ASCLIN1 input
	$\overline{\text{SLSI1A}}$			QSPI1 input
	RXDCAN3D			CAN node 3 input
	RXDB1			ERAY input
	ETHRXD0			ETH input
	SDI00			MSC0 input
	P11.10	O0		General-purpose output
	TOUT99	O1		GTM output
	–	O2		Reserved
	SLSO03	O3		QSPI0 output
	SLSO13	O4		QSPI1 output
	–	O5		Reserved
	–	O6		Reserved
	CC62	O7		CCU60 output
166	P11.11	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN100			GTM input
	ETHCRSDVA			ETH input
	ETHRXDVA			ETH input
	ETHCRSB			ETH input
	P11.11	O0		General-purpose output
	TOUT100	O1		GTM output
	END02	O2		MSC0 output
	SLSO04	O3		QSPI0 output
	SLSO14	O4		QSPI1 output
	EN00	O5		MSC0 output
	$\overline{\text{TXENB}}$	O6		ERAY output
	CC61	O7		CCU60 output

Table 2-4 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
167	P11.12	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN101			GTM input
	ETHREFCLK			ETH input
	ETHTXCLKB			ETH input (Not for productive purposes)
	ETHRXCLKA			ETH input (Not for productive purposes)
	P11.12	O0		General-purpose output
	TOUT101	O1		GTM output
	ATX1	O2		ASCLIN1 output
	GTMCLK2	O3		GTM output
	TXDB	O4		ERAY output
	TXDCAN3	O5		CAN node 3 output
	EXTCLK1	O6		SCU output
	CC60	O7		CCU60 output

Table 2-5 Port 13 Functions

Pin	Symbol	Ctrl	Type	Function
156	P13.0	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN91			GTM input
	P13.0	O0		General-purpose output
	TOUT91	O1		GTM output
	END03	O2		MSC0 output
	SCLK2N	O3		QSPI2 output (LVDS)
	EN01	O4		MSC0 output
	FCLN0	O5		MSC0 output (LVDS)
	FCLND0	O6		MSC0 output (LVDS)
	–	O7		Reserved
157	P13.1	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN92			GTM input
	SCL0B			I2C0 input
	P13.1	O0		General-purpose output
	TOUT92	O1		GTM output
	–	O2		Reserved
	SCLK2P	O3		QSPI2 output (LVDS)
	–	O4		Reserved
	FCLP0	O5		MSC0 output (LVDS)
	SCL0	O6		I2C0 output
	–	O7		Reserved

Table 2-5 Port 13 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
158	P13.2	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN93			GTM input
	CAPINA			GPT120 input
	SDA0B			I2C0 input
	P13.2	O0		General-purpose output
	TOUT93	O1		GTM output
	–	O2		Reserved
	MTSR2N	O3		QSPI2 output (LVDS)
	FCLP0	O4		MSC0 output
	SON0	O5		MSC0 output (LVDS)
	SDA0	O6		I2C0 output
	SOND0	O7		MSC0 output (LVDS)
159	P13.3	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN94			GTM input
	P13.3	O0		General-purpose output
	TOUT94	O1		GTM output
	–	O2		Reserved
	MTSR2P	O3		QSPI2 output (LVDS)
	–	O4		Reserved
	SOP0	O5		MSC0 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved

Table 2-6 Port 14 Functions

Pin	Symbol	Ctrl	Type	Function
142	P14.0	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN80			GTM input
	P14.0	O0		General-purpose output
	TOUT80	O1		GTM output
	ATX0	O2		ASCLIN0 output Recommended as Boot loader pin.
	TXDA	O3		ERAY output
	TXDB	O4		ERAY output
	TXDCAN1	O5		CAN node 1 output Used for single pin DAP (SPD) function.
	ASCLK0	O6		ASCLIN0 output
	COUT62	O7		CCU60 output

Table 2-6 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
143	P14.1	I	**MP / PU1 / VEXT**	General-purpose input
	TIN81			GTM input
	REQ15			SCU input
	ARX0A			ASCLIN0 input Recommended as Boot loader pin.
	RXDCAN1B			CAN node 1 input Used for single pin DAP (SPD) function.
	RXDA3			ERAY input
	RXDB3			ERAY input
	EVRWUPA			SCU input
	P14.1	O0		General-purpose output
	TOUT81	O1		GTM output
	ATX0	O2		ASCLIN0 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT63	O7		CCU60 output
144	P14.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN82			GTM input
	HWCFG2 EVR13			SCU input Latched at cold power on reset to decide EVR13 activation.
	P14.2	O0		General-purpose output
	TOUT82	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO21	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	ASCLK2	O6		ASCLIN2 output
	–	O7		Reserved

Table 2-6 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
145	P14.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN83			GTM input
	ARX2A			ASCLIN2 input
	REQ10			SCU input
	HWCFG3_BMI			SCU input
	SDI02			MSC0 input
	P14.3	O0		General-purpose output
	TOUT83	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO23	O3		QSPI2 output
	ASLSO1	O4		ASCLIN1 output
	ASLSO3	O5		ASCLIN3 output
	–	O6		Reserved
	–	O7		Reserved
146	P14.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN84			GTM input
	HWCFG6			SCU input Latched at cold power on reset to decide default pad reset state (PU or HighZ).
	P14.4	O0		General-purpose output
	TOUT84	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-6 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
147	P14.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN85			GTM input
	HWCFG1 EVR33			SCU input Latched at cold power on reset to decide EVR33 activation.
	P14.5	O0		General-purpose output
	TOUT85	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	TXDB	O6		ERAY output
	–	O7		Reserved
148	P14.6	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN86			GTM input
	HWCFG0 DCLDO			SCU input If EVR13 active, latched at cold power on reset to decide between LDO and SMPS mode.
	P14.6	O0		General-purpose output
	TOUT86	O1		GTM output
	–	O2		Reserved
	SLSO22	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	$\overline{\text{TXENB}}$	O6		ERAY output
	–	O7		Reserved
149	P14.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN87			GTM input
	RXDB0			ERAY input
	P14.7	O0		General-purpose output
	TOUT87	O1		GTM output
	ARTS0	O2		ASCLIN0 output
	SLSO24	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-6 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
150	P14.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN88			GTM input
	ARX1D			ASCLIN1 input
	RXDCAN2D			CAN node 2 input
	RXDA0			ERAY input
	P14.8	O0		General-purpose output
	TOUT88	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
151	P14.9	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN89			GTM input
	ACTS0A			ASCLIN0 input
	P14.9	O0		General-purpose output
	TOUT89	O1		GTM output
	END03	O2		MSC0 output
	EN01	O3		MSC0 output
	–	O4		Reserved
	$\overline{\text{TXENB}}$	O5		ERAY output
	$\overline{\text{TXENA}}$	O6		ERAY output
	–	O7		Reserved
152	P14.10	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN90			GTM input
	P14.10	O0		General-purpose output
	TOUT90	O1		GTM output
	END02	O2		MSC0 output
	EN00	O3		MSC0 output
	ATX1	O4		ASCLIN1 output
	TXDCAN2	O5		CAN node 2 output
	TXDA	O6		ERAY output
	–	O7		Reserved

Table 2-7 Port 15 Functions

Pin	Symbol	Ctrl	Type	Function
133	P15.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN71			GTM input
	P15.0	O0		General-purpose output
	TOUT71	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO013	O3		QSPI0 output
	–	O4		Reserved
	TXDCAN2	O5		CAN node 2 output
	ASCLK1	O6		ASCLIN1 output
	–	O7		Reserved
134	P15.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN72			GTM input
	REQ16			SCU input
	ARX1A			ASCLIN1 input
	RXDCAN2A			CAN node 2 input
	$\overline{\text{SLSI2B}}$			QSPI2 input
	EVRWUPB			SCU input
	P15.1	O0		General-purpose output
	TOUT72	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO25	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
135	P15.2	I	**MP / PU1 / VEXT**	General-purpose input
	TIN73			GTM input
	$\overline{\text{SLSI2A}}$			QSPI2 input
	MRST2E			QSPI2 input
	P15.2	O0		General-purpose output
	TOUT73	O1		GTM output
	ATX0	O2		ASCLIN0 output
	SLSO20	O3		QSPI2 output
	–	O4		Reserved
	TXDCAN1	O5		CAN node 1 output
	ASCLK0	O6		ASCLIN0 output
	–	O7		Reserved

Table 2-7 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
136	P15.3	I	**MP / PU1 / VEXT**	General-purpose input
	TIN74			GTM input
	ARX0B			ASCLIN0 input
	SCLK2A			QSPI2 input
	RXDCAN1A			CAN node 1 input
	P15.3	O0		General-purpose output
	TOUT74	O1		GTM output
	ATX0	O2		ASCLIN0 output
	SCLK2	O3		QSPI2 output
	END03	O4		MSC0 output
	EN01	O5		MSC0 output
	–	O6		Reserved
	–	O7		Reserved
137	P15.4	I	**MP / PU1 / VEXT**	General-purpose input
	TIN75			GTM input
	MRST2A			QSPI2 input
	REQ0			SCU input
	SCL0C			I2C0 input
	P15.4	O0		General-purpose output
	TOUT75	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MRST2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	SCL0	O6		I2C0 output
	CC62	O7		CCU60 output

Table 2-7 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
138	P15.5	I	**MP / PU1 / VEXT**	General-purpose input
	TIN76			GTM input
	ARX1B			ASCLIN1 input
	MTSR2A			QSPI2 input
	REQ13			SCU input
	SDA0C			I2C0 input
	P15.5	O0		General-purpose output
	TOUT76	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MTSR2	O3		QSPI2 output
	END02	O4		MSC0 output
	EN00	O5		MSC0 output
	SDA0	O6		I2C0 output
	CC61	O7		CCU60 output
139	P15.6	I	**MP / PU1 / VEXT**	General-purpose input
	TIN77			GTM input
	MTSR2B			QSPI2 input
	P15.6	O0		General-purpose output
	TOUT77	O1		GTM output
	ATX3	O2		ASCLIN3 output
	MTSR2	O3		QSPI2 output
	–	O4		Reserved
	SCLK2	O5		QSPI2 output
	ASCLK3	O6		ASCLIN3 output
	CC60	O7		CCU60 output
140	P15.7	I	**MP / PU1 / VEXT**	General-purpose input
	TIN78			GTM input
	ARX3A			ASCLIN3 input
	MRST2B			QSPI2 input
	P15.7	O0		General-purpose output
	TOUT78	O1		GTM output
	ATX3	O2		ASCLIN3 output
	MRST2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-7 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
141	P15.8	I	**MP / PU1 / VEXT**	General-purpose input
	TIN79			GTM input
	SCLK2B			QSPI2 input
	REQ1			SCU input
	P15.8	O0		General-purpose output
	TOUT79	O1		GTM output
	–	O2		Reserved
	SCLK2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	ASCLK3	O6		ASCLIN3 output
	COUT61	O7		CCU60 output

Table 2-8 Port 20 Functions

Pin	Symbol	Ctrl	Type	Function
116	P20.0	I	**MP / PU1 / VEXT**	General-purpose input
	TIN59			GTM input
	RXDCAN3C			CAN node 3 input
	T6EUDA			GPT120 input
	REQ9			SCU input
	SYSCLK			HSCT input
	$\overline{\text{TGI0}}$			OCDS input
	P20.0	O0		General-purpose output
	TOUT59	O1		GTM output
	ATX3	O2		ASCLIN3 output
	ASCLK3	O3		ASCLIN3 output
	–	O4		Reserved
	SYSCLK	O5		HSCT output
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO0}}$	HWOUT		OCDS; ENx

Table 2-8 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
117	P20.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN60			GTM input
	$\overline{\text{TGI1}}$			OCDS input
	P20.1	O0		General-purpose output
	TOUT60	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO1}}$	HWOUT		OCDS; ENx
118	P20.2	I	**LP / PU / VEXT**	General-purpose input This pin is latched at power on reset release to enter test mode.
	$\overline{\text{TESTMODE}}$			OCDS input
	P20.2	O0		Output function not available
	–	O1		Output function not available
	–	O2		Output function not available
	–	O3		Output function not available
	–	O4		Output function not available
	–	O5		Output function not available
	–	O6		Output function not available
	–	O7		Output function not available
119	P20.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN61			GTM input
	T6INA			GPT120 input
	ARX3C			ASCLIN3 input
	P20.3	O0		General-purpose output
	TOUT61	O1		GTM output
	ATX3	O2		ASCLIN3 output
	SLSO09	O3		QSPI0 output
	SLSO29	O4		QSPI2 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-8 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
124	P20.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN62			GTM input
	P20.6	O0		General-purpose output
	TOUT62	O1		GTM output
	ARTS1	O2		ASCLIN1 output
	SLSO08	O3		QSPI0 output
	SLSO28	O4		QSPI2 output
	–	O5		Reserved
	WDT2LCK	O6		SCU output
	–	O7		Reserved
125	P20.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN63			GTM input
	ACTS1A			ASCLIN1 input
	RXDCAN0B			CAN node 0 input
	P20.7	O0		General-purpose output
	TOUT63	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	WDT1LCK	O6		SCU output
	COUT63	O7		CCU61 output
126	P20.8	I	**MP / PU1 / VEXT**	General-purpose input
	TIN64			GTM input
	P20.8	O0		General-purpose output
	TOUT64	O1		GTM output
	ASLSO1	O2		ASCLIN1 output
	SLSO00	O3		QSPI0 output
	SLSO10	O4		QSPI1 output
	TXDCAN0	O5		CAN node 0 output
	WDT0LCK	O6		SCU output
	CC60	O7		CCU61 output

Table 2-8 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
127	P20.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN65			GTM input
	ARX1C			ASCLIN1 input
	RXDCAN3E			CAN node 3 input
	REQ11			SCU input
	$\overline{\text{SLSI0B}}$			QSPI0 input
	P20.9	O0		General-purpose output
	TOUT65	O1		GTM output
	–	O2		Reserved
	SLSO01	O3		QSPI0 output
	SLSO11	O4		QSPI1 output
	–	O5		Reserved
	WDTSLCK	O6		SCU output
	CC61	O7		CCU61 output
128	P20.10	I	**MP / PU1 / VEXT**	General-purpose input
	TIN66			GTM input
	P20.10	O0		General-purpose output
	TOUT66	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO06	O3		QSPI0 output
	SLSO27	O4		QSPI2 output
	TXDCAN3	O5		CAN node 3 output
	ASCLK1	O6		ASCLIN1 output
	CC62	O7		CCU61 output
129	P20.11	I	**MP / PU1 / VEXT**	General-purpose input
	TIN67			GTM input
	SCLK0A			QSPI0 input
	P20.11	O0		General-purpose output
	TOUT67	O1		GTM output
	–	O2		Reserved
	SCLK0	O3		QSPI0 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU61 output

Table 2-8 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
130	P20.12	I	**MP / PU1 / VEXT**	General-purpose input
	TIN68			GTM input
	MRST0A			QSPI0 input
	P20.12	O0		General-purpose output
	TOUT68	O1		GTM output
	–	O2		Reserved
	MRST0	O3		QSPI0 output
	MTSR0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	COUT61	O7		CCU61 output
131	P20.13	I	**MP / PU1 / VEXT**	General-purpose input
	TIN69			GTM input
	$\overline{\text{SLSI0A}}$			QSPI0 input
	P20.13	O0		General-purpose output
	TOUT69	O1		GTM output
	–	O2		Reserved
	SLSO02	O3		QSPI0 output
	SLSO12	O4		QSPI1 output
	SCLK0	O5		QSPI0 output
	–	O6		Reserved
	COUT62	O7		CCU61 output
132	P20.14	I	**MP / PU1 / VEXT**	General-purpose input
	TIN70			GTM input
	MTSR0A			QSPI0 input
	P20.14	O0		General-purpose output
	TOUT70	O1		GTM output
	–	O2		Reserved
	MTSR0	O3		QSPI0 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-9 Port 21 Functions

Pin	Symbol	Ctrl	Type	Function
105	P21.0	I	**A2 / PU1 / VDDP3**	General-purpose input
	TIN51			GTM input
	P21.0	O0		General-purpose output
	TOUT51	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHMDC	O6		ETH output
	–	O7		Reserved
	HSM1	HWOUT		HSM output 1
106	P21.1	I	**A2 / PU1 / VDDP3**	General-purpose input
	TIN52			GTM input
	ETHMDIOB			ETH input (Not for production purposes)
	P21.1	O0		General-purpose output
	TOUT52	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHMDIO	O6		ETH output (Not for production purposes)
	–	O7		Reserved
	HSM2	HWOUT		HSM output 2

Table 2-9 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
107	P21.2	I	**LVDSH_N/ PU1 / VDDP3**	General-purpose input
	TIN53			GTM input
	MRST2CN			QSPI2 input (LVDS)
	MRST3FN			QSPI3 input (LVDS)
	ARX3GN			ASCLIN3 input (LVDS)
	EMGSTOPB			SCU input
	RXDN			HSCT input (LVDS)
	P21.2	O0		General-purpose output
	TOUT53	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	ETHMDC	O5		ETH output
	–	O6		Reserved
	–	O7		Reserved
108	P21.3	I	**LVDSH_P/ PU1 / VDDP3**	General-purpose input
	TIN54			GTM input
	MRST2CP			QSPI2 input (LVDS)
	MRST3FP			QSPI3 input (LVDS)
	ARX3GP			ASCLIN3 input (LVDS)
	RXDP			HSCT input (LVDS)
	P21.3	O0		General-purpose output
	TOUT54	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	ETHMDIOD	HWOUT		ETH input/output

Table 2-9 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
109	P21.4	I	**LVDSH_N/ PU1 / VDDP3**	General-purpose input
	TIN55			GTM input
	P21.4	O0		General-purpose output
	TOUT55	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	TXDN	HSCT		HSCT output (LVDS)
110	P21.5	I	**LVDSH_P/ PU1 / VDDP3**	General-purpose input
	TIN56			GTM input
	P21.5	O0		General-purpose output
	TOUT56	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	TXDP	HSCT		HSCT output (LVDS)
111[1)]	P21.6	I	**A2 / PU / VDDP3**	General-purpose input
	TIN57			GTM input
	ARX3F			ASCLIN3 input
	$\overline{\text{TGI2}}$			OCDS input
	TDI			OCDS (JTAG) input
	T5EUDA			GPT120 input
	P21.6	O0		General-purpose output
	TOUT57	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	SYSCLK	O5		HSCT output
	–	O6		Reserved
	T3OUT	O7		GPT120 output
	$\overline{\text{TGO2}}$	HWOUT		OCDS; ENx

Table 2-9 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
113	P21.7	I	**A2 / PU / VDDP3**	General-purpose input
	TIN58			GTM input
	DAP2			OCDS input
	$\overline{\text{TGI3}}$			OCDS input
	TDO			OCDS (JTAG) input The JTAG TDO function is overlayed with P21.7 via a double bond. In JTAG mode this pin is used as TDO, after power-on reset it is HighZ. In DAP mode this pin is used as P21.7 and controlled by the related port control logic
	ETHRXERB			ETH input
	T5INA			GPT120 input
	P21.7	O0		General-purpose output
	TOUT58	O1		GTM output
	ATX3	O2		ASCLIN3 output
	ASCLK3	O3		ASCLIN3 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	T6OUT	O7		GPT120 output
	$\overline{\text{TGO3}}$	HWOUT		OCDS; ENx
	TDO			OCDS (JTAG); ENx The JTAG TDO function is overlayed with P21.7 via a double bond. In JTAG mode this pin is used as TDO, after power-on reset it is HighZ. In DAP mode this pin is used as P21.7 and controlled by the related port control logic

1) For an Emulation Device in a non Fusion Quad package this pin is used as VDDPSB (3.3V)

Table 2-10 Port 22 Functions

Pin	Symbol	Ctrl	Type	Function
95	P22.0	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN47			GTM input
	MTSR3E			QSPI3 input
	P22.0	O0		General-purpose output
	TOUT47	O1		GTM output
	ATX3N	O2		ASCLIN3 output (LVDS)
	MTSR3	O3		QSPI3 output
	SCLK3N	O4		QSPI3 output (LVDS)
	FCLN1	O5		MSC1 output (LVDS)
	FCLND1	O6		MSC1 output (LVDS)
	–	O7		Reserved
96	P22.1	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN48			GTM input
	MRST3E			QSPI3 input
	P22.1	O0		General-purpose output
	TOUT48	O1		GTM output
	ATX3P	O2		ASCLIN3 output (LVDS)
	MRST3	O3		QSPI3 output
	SCLK3P	O4		QSPI3 output (LVDS)
	FCLP1	O5		MSC1 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved
97	P22.2	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN49			GTM input
	$\overline{\text{SLSI3D}}$			QSPI3 input
	P22.2	O0		General-purpose output
	TOUT49	O1		GTM output
	–	O2		Reserved
	SLSO312	O3		QSPI3 output
	MTSR3N	O4		QSPI3 output (LVDS)
	SON1	O5		MSC1 output (LVDS)
	SOND1	O6		MSC1 output (LVDS)
	–	O7		Reserved

Table 2-10 Port 22 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
98	P22.3	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN50			GTM input
	SCLK3E			QSPI3 input
	P22.3	O0		General-purpose output
	TOUT50	O1		GTM output
	–	O2		Reserved
	SCLK3	O3		QSPI3 output
	MTSR3P	O4		QSPI3 output (LVDS)
	SOP1	O5		MSC1 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved

Table 2-11 Port 23 Functions

Pin	Symbol	Ctrl	Type	Function
89	P23.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN41			GTM input
	P23.0	O0		General-purpose output
	TOUT41	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
90	P23.1	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN42			GTM input
	SDI10			MSC1 input
	P23.1	O0		General-purpose output
	TOUT42	O1		GTM output
	ARTS1	O2		ASCLIN1 output
	SLSO313	O3		QSPI3 output
	GTMCLK0	O4		GTM output
	–	O5		Reserved
	EXTCLK0	O6		SCU output
	–	O7		Reserved

Table 2-11 Port 23 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
91	P23.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN43			GTM input
	P23.2	O0		General-purpose output
	TOUT43	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
92	P23.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN44			GTM input
	INJ10			MSC1 input
	P23.3	O0		General-purpose output
	TOUT44	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
93	P23.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN45			GTM input
	P23.4	O0		General-purpose output
	TOUT45	O1		GTM output
	–	O2		Reserved
	SLSO35	O3		QSPI3 output
	END12	O4		MSC1 output
	EN10	O5		MSC1 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-11 Port 23 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
94	P23.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN46			GTM input
	P23.5	O0		General-purpose output
	TOUT46	O1		GTM output
	–	O2		Reserved
	SLSO34	O3		QSPI3 output
	END13	O4		MSC1 output
	EN11	O5		MSC1 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-12 Port 32 Functions

Pin	Symbol	Ctrl	Type	Function
84	P32.0	I	**LP / EVR13 SMPS -> PD, GPIO - > PU / VEXT**	General-purpose input
	TIN36			GTM input
	FDEST			PMU input
	VGATE1N			SMPS mode: analog output. External Pass Device gate control for EVR13
	P32.0	O0		General-purpose output
	TOUT36	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
86	P32.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN38			GTM input
	ARX3D			ASCLIN3 input
	RXDCAN3B			CAN node 3 input
	P32.2	O0		General-purpose output
	TOUT38	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	DCDCSYNC	O6		SCU output
	–	O7		Reserved

Table 2-12 Port 32 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
87	P32.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN39			GTM input
	P32.3	O0		General-purpose output
	TOUT39	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	ASCLK3	O4		ASCLIN3 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	–	O7		Reserved
88	P32.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN40			GTM input
	ACTS1B			ASCLIN1 input
	SDI12			MSC1 input
	P32.4	O0		General-purpose output
	TOUT40	O1		GTM output
	–	O2		Reserved
	END12	O3		MSC1 output
	GTMCLK1	O4		GTM output
	EN10	O5		MSC1 output
	EXTCLK1	O6		SCU output
	COUT63	O7		CCU60 output

Table 2-13 Port 33 Functions

Pin	Symbol	Ctrl	Type	Function
70	P33.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN22			GTM input
	DSITR0E			DSADC channel 0 input E
	P33.0	O0		General-purpose output
	TOUT22	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	VADCG2BFL0	O6		VADC output
	–	O7		Reserved

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
71	P33.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN23			GTM input
	PSIRX0C			PSI5 input
	SENT9C			SENT input
	DSCIN2B			DSADC channel 2 input B
	DSITR1E			DSADC channel 1 input E
	P33.1	O0		General-purpose output
	TOUT23	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT2	O4		DSADC channel 2 output
	VADCEMUX02	O5		VADC output
	VADCG2BFL1	O6		VADC output
	–	O7		Reserved
72	P33.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN24			GTM input
	SENT8C			SENT input
	DSDIN2B			DSADC channel 2 input B
	DSITR2E			DSADC channel 2 input E
	P33.2	O0		General-purpose output
	TOUT24	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	PSITX0	O4		PSI5 output
	VADCEMUX01	O5		VADC output
	VADCG2BFL2	O6		VADC output
	–	O7		Reserved

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
73	P33.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN25			GTM input
	PSIRX1C			PSI5 input
	SENT7C			SENT input
	DSCIN1B			DSADC channel 1 input B
	P33.3	O0		General-purpose output
	TOUT25	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	DSCOUT1	O4		DSADC channel 1 output
	VADCEMUX00	O5		VADC output
	VADCG2BFL3	O6		VADC output
	–	O7		Reserved
74	P33.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN26			GTM input
	SENT6C			SENT input
	$\overline{\text{CTRAPC}}$			CCU61 input
	DSDIN1B			DSADC channel 1 input B
	DSITR0F			DSADC channel 0 input F
	P33.4	O0		General-purpose output
	TOUT26	O1		GTM output
	ARTS2	O2		ASCLIN2 output
	–	O3		Reserved
	PSITX1	O4		PSI5 output
	VADCEMUX12	O5		VADC output
	VADCG0BFL0	O6		VADC output
	–	O7		Reserved

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
75	P33.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN27			GTM input
	ACTS2B			ASCLIN2 input
	PSIRX2C			PSI5 input
	PSISRXC			PSI5-S input
	SENT5C			SENT input
	CCPOS2C			CCU61 input
	T4EUDB			GPT120 input
	DSCIN0B			DSADC channel 0 input B
	DSITR1F			DSADC channel 1 input F
	P33.5	O0		General-purpose output
	TOUT27	O1		GTM output
	SLSO07	O2		QSPI0 output
	SLSO17	O3		QSPI1 output
	DSCOUT0	O4		DSADC channel 0 output
	VADCEMUX11	O5		VADC output
	VADCG0BFL1	O6		VADC output
	–	O7		Reserved
76	P33.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN28			GTM input
	SENT4C			SENT input
	CCPOS1C			CCU61 input
	T2EUDB			GPT120 input
	DSDIN0B			DSADC channel 0 input B
	DSITR2F			DSADC channel 2 input F
	P33.6	O0		General-purpose output
	TOUT28	O1		GTM output
	ASLSO2	O2		ASCLIN2 output
	-	O3		Reserved
	PSITX2	O4		PSI5 output
	VADCEMUX10	O5		VADC output
	VADCG1BFL0	O6		VADC output
	PSISTX	O7		PSI5-S output

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
77	P33.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN29			GTM input
	RXDCAN0E			CAN node 0 input
	REQ8			SCU input
	CCPOS0C			CCU61 input
	T2INB			GPT120 input
	P33.7	O0		General-purpose output
	TOUT29	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	SLSO37	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	VADCG1BFL1	O6		VADC output
	–	O7		Reserved
78	P33.8	I	**MP / HighZ/ VEXT**	General-purpose input
	TIN30			GTM input
	ARX2E			ASCLIN2 input
	EMGSTOPA			SCU input
	P33.8	O0		General-purpose output
	TOUT30	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO32	O3		QSPI3 output
	–	O4		Reserved
	TXDCAN0	O5		CAN node 0 output
	–	O6		Reserved
	COUT62	O7		CCU61 output
	SMUFSP	HWOUT		SMU
79	P33.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN31			GTM input
	P33.9	O0		General-purpose output
	TOUT31	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO31	O3		QSPI3 output
	ASCLK2	O4		ASCLIN2 output
	–	O5		Reserved
	–	O6		Reserved
	CC62	O7		CCU61 output

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
80	P33.10	I	**MP / PU1 / VEXT**	General-purpose input
	TIN32			GTM input
	SLSI3C			QSPI3 input
	P33.10	O0		General-purpose output
	TOUT32	O1		GTM output
	SLSO16	O2		QSPI1 output
	SLSO311	O3		QSPI3 output
	ASLSO1	O4		ASCLIN1 output
	PSISCLK	O5		PSI5-S output
	–	O6		Reserved
	COUT61	O7		CCU61 output
81	P33.11	I	**MP / PU1 / VEXT**	General-purpose input
	TIN33			GTM input
	SCLK3D			QSPI3 input
	P33.11	O0		General-purpose output
	TOUT33	O1		GTM output
	ASCLK1	O2		ASCLIN1 output
	SCLK3	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	DSCGPWMN	O6		DSADC output
	CC61	O7		CCU61 output
82	P33.12	I	**MP / PU1 / VEXT**	General-purpose input
	TIN34			GTM input
	MTSR3D			QSPI3 input
	P33.12	O0		General-purpose output
	TOUT34	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MTSR3	O3		QSPI3 output
	ASCLK1	O4		ASCLIN1 output
	–	O5		Reserved
	DSCGPWMP	O6		DSADC output
	COUT60	O7		CCU61 output

Table 2-13 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
83	P33.13	I	**MP / PU1 / VEXT**	General-purpose input
	TIN35			GTM input
	ARX1F			ASCLIN1 input
	MRST3D			QSPI3 input
	DSSGNB			DSADC input
	INJ11			MSC1 input
	P33.13	O0		General-purpose output
	TOUT35	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MRST3	O3		QSPI3 output
	SLSO26	O4		QSPI2 output
	–	O5		Reserved
	DCDCSYNC	O6		SCU output
	CC60	O7		CCU61 output

Table 2-14 Port 40 Functions

Pin	Symbol	Ctrl	Type	Function
44	P40.0	I	**S / HighZ / VDDM**	General-purpose input
	VADCG3.0			VADC analog input channel 0 of group 3
	DS2PB			DSADC: positive analog input channe of DSADC 2, pin B
	CCPOS0D			CCU60 input
	SENT0A			SENT input
43	P40.1	I	**S / HighZ / VDDM**	General-purpose inpu.t
	VADCG3.1			VADC analog input channel 1 of group 3 (MD)
	DS2NB			DSADC: negative analog of input channel 2, pin B
	CCPOS1B			CCU60 input
	SENT1A			SENT input
42	P40.2	I	**S / HighZ / VDDM**	General-purpose inpu.t
	VADCG3.2			VADC analog input channel 2 of group 3 (MD)
	CCPOS1D			CCU60 input
	SENT2A			SENT input
41	P40.3	I	**S / HighZ / VDDM**	General-purpose input
	VADCG3.3			VADC analog input channel 3 of group 3
	CCPOS2B			CCU60 input
	SENT3A			SENT input

Table 2-14 Port 40 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
38	P40.4	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.0			VADC analog input channel 0 of group 4
	CCPOS2D			CCU60 input
	SENT4A			SENT input
37	P40.5	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.1			VADC analog input channel 1 of group 4 (MD)
	CCPOS0D			CCU61 input
	SENT5A			SENT input
35	P40.6	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.4			VADC analog input channel 4 of group 4
	DS3PA			DSADC: positive analog input of channel 3, pin A
	CCPOS1B			CCU61 input
	SENT6A			SENT input
34	P40.7	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.5			VADC analog input channel 5 of group 4
	DS3NA			DSADC: negative analog input of channel 3, pin A
	CCPOS1D			CCU61 input
	SENT7A			SENT input
33	P40.8	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.6			VADC analog input channel 6 of group 4
	DS3PB			DSADC: positive analog input of channel 3, pin B
	CCPOS2B			CCU61 input
	SENT8A			SENT input
32	P40.9	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.7			VADC analog input channel 7 of group 4
	DS3NB			DSADC: negative analog input of channel 3, pin B
	CCPOS2D			CCU61 input
	SENT9A			SENT input

Table 2-15 Analog Inputs

Pin	Symbol	Ctrl	Type	Function
67	AN0	I	**D / HighZ / VDDM**	Analog input 0
	VADCG0.0			VADC analog input channel 0 of group 0
	DS1PA			DSADC: positive analog of input channel 1, pin A
66	AN1	I	**D / HighZ / VDDM**	Analog input 1
	VADCG0.1			VADC analog input channel 1 of group 0 (MD)
	DS1NA			DSADC: negative analog input of channel 1, pin A

Table 2-15 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
65	AN2	I	**D / HighZ / VDDM**	Analog input 2
	VADCG0.2			VADC analog input channel 2 of group 0 (MD)
	DS0PA			DSADC: positive analog input of channel 0, pin A
64	AN3	I	**D / HighZ / VDDM**	Analog input 3
	VADCG0.3			VADC analog input channel 3 of group 0
	DS0NA			DSADC: negative analog input of channel 0, pin A
63	AN4	I	**D / HighZ / VDDM**	Analog input 4
	VADCG0.4			VADC analog input channel 4 of group 0
62	AN5	I	**D / HighZ / VDDM**	Analog input 5
	VADCG0.5			VADC analog input channel 5 of group 0
61	AN6	I	**D / HighZ / VDDM**	Analog input 6
	VADCG0.6			VADC analog input channel 6 of group 0
60	AN7	I	**D / HighZ / VDDM**	Analog input 7
	VADCG0.7			VADC analog input channel 7 of group 0 (with pull down diagnostics)
59	AN8	I	**D / HighZ / VDDM**	Analog input 8
	VADCG1.0			VADC analog input channel 0 of group 1
58	AN10	I	**D / HighZ / VDDM**	Analog input 10
	VADCG1.2			VADC analog input channel 2 of group 1 (MD)
57	AN11	I	**D / HighZ / VDDM**	Analog input 11
	VADCG1.3			VADC analog input channel 3 of group 1 (with pull down diagnostics)
56	AN12	I	**D / HighZ / VDDM**	Analog input 12
	VADCG1.4			VADC analog input channel 4 of group 1
55	AN13	I	**D / HighZ / VDDM**	Analog input 13
	VADCG1.5			VADC analog input channel 5 of group 1
50	AN16	I	**D / HighZ / VDDM**	Analog input 16
	VADCG2.0			VADC analog input channel 0 of group 2
49	AN17	I	**D / HighZ / VDDM**	Analog input 17
	VADCG2.1			VADC analog input channel 1 of group 2 (MD)
48	AN18	I	**D / HighZ / VDDM**	Analog input 18
	VADCG2.2			VADC analog input channel 2 of group 2 (MD)

Table 2-15 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
47	AN19	I	**D / HighZ / VDDM**	Analog input 19
	VADCG2.3			VADC analog input channel 3 of group 2 (with pull down diagnostics)
46	AN20	I	**D / HighZ / VDDM**	Analog input 20
	VADCG2.4	I		VADC analog input channel 4 of group 2
	DS2PA	I		DSADC: positive analog input of channel 2, pin A
45	AN21	I	**D / HighZ / VDDM**	Analog input 21
	VADCG2.5	I		VADC analog input channel 5 of group 2
	DS2NA	I		DSADC: negative analog input of channel of DSADC 2, pin A
44	AN24	I	**S / HighZ / VDDM**	Analog input 24
	VADCG3.0			VADC analog input channel 0 of group 3
	DS2PB			DSADC: positive analog input of channel 2, pin B
	SENT0A			SENT input channel 0, pin A
43	AN25	I	**S / HighZ / VDDM**	Analog input 24
	VADCG3.1			VADC analog input channel 1 of group 3 (MD)
	DS2NB			DSADC: negative analog input of channel 2, pin B
	SENT1A			SENT input channel 1, pin A
42	AN26	I	**S / HighZ / VDDM**	Analog input 26
	VADCG3.2			VADC analog input channel 2 of group 3 (MD)
	SENT2A			SENT input channel 2, pin A
41	AN27	I	**S / HighZ / VDDM**	Analog input 27
	VADCG3.3			VADC analog input channel 3 of group 3 (with pull down diagnostics)
	SENT3A			SENT input channel 3, pin A
40	AN28	I	**D / HighZ / VDDM**	Analog input 28
	VADCG3.4			VADC analog input channel 4 of group 3
39	AN29	I	**D / HighZ / VDDM**	Analog input 29
	VADCG3.5			VADC analog input channel 5 of group 3
38	AN32	I	**S / HighZ / VDDM**	Analog input 32
	VADCG4.0			VADC analog input channel 0 of group 4
	SENT4A			SENT input channel 4, pin A
37	AN33	I	**S / HighZ / VDDM**	Analog input 33
	VADCG4.1			VADC analog input channel 1 of group 4 (MD)
	SENT5A			SENT input channel 5, pin A
36	AN35	I	**D / HighZ / VDDM**	Analog input 35
	VADCG4.3			VADC analog input channel 3 of group 4 (with pull down diagnostics)

Table 2-15 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
35	AN36	I	**S / HighZ / VDDM**	Analog input 34
	VADCG4.4			VADC analog input channel 4 of group 4
	DS3PA			DSADC: positive analog input of channel of DSADC 3, pin A
	SENT6A			SENT input channel 6, pin A
34	AN37	I	**S / HighZ / VDDM**	Analog input 37
	VADCG4.5			VADC analog input channel 5 of group 4
	DS3NA			DSADC: negative analog input of channel of DSADC 3, pin A
	SENT7A			SENT input channel 7, pin A
33	AN38	I	**S / HighZ / VDDM**	Analog input 38
	VADCG4.6			VADC analog input channel 6 of group 4
	DS3PB			DSADC: positive analog input of channel of DSADC 3, pin B
	SENT8A			SENT input channel 8, pin A
32	AN39	I	**S / HighZ / VDDM**	Analog input 39
	VADCG4.7			VADC analog input channel 7 of group 4
	DS3NB			DSADC: negative analog input of channel of DSADC 3, pin B
	SENT9A			SENT input channel 9, pin A
31	AN44	I	**D / HighZ / VDDM**	Analog input 44
	VADCG5.4			VADC analog input channel 4 of group 5
	DS3PC			DSADC: positive analog input of channel of DSADC 3, pin C
30	AN45	I	**D / HighZ / VDDM**	Analog input 45
	VADCG5.5			VADC analog input channel 5 of group 5
	DS3NC			DSADC: negative analog input of channel of DSADC 3, pin C
29	AN46	I	**D / HighZ / VDDM**	Analog input 46
	VADCG5.6			VADC analog input channel 6 of group 5
	DS3PD			DSADC: positive analog input of channel of DSADC 3, pin D
28	AN47	I	**D / HighZ / VDDM**	Analog input 47
	VADCG5.7			VADC analog input channel 7 of group 5
	DS3ND			DSADC: negative analog input of channel of DSADC 3, pin D

Table 2-16 System I/O

Pin	Symbol	Ctrl	Type	Function
121	$\overline{\text{PORST}}$	I	**I / PD / VEXT**	Power On Reset Input Additional strong PD in case of power fail.
122	$\overline{\text{ESR0}}$	I/O	**MP / OD / VEXT**	External System Request Reset 0 Default configuration during and after reset is open-drain driver. The driver drives low during power-on reset. This is valid additionally after deactivation of $\overline{\text{PORST}}$ until the internal reset phase has finished. See also SCU chapter for details. Default after power-on can be different. See also SCU chapter ´Reset Control Unit´ and SCU_IOCR register description.
	EVRWUP	I		EVR Wakeup Pin
120	$\overline{\text{ESR1}}$	I/O	**MP / PU1 / VEXT**	External System Request Reset 1 Default NMI function. See also SCU chapter ´Reset Control Unit´ and SCU_IOCR register description.
	EVRWUP	I		EVR Wakeup Pin
85	VGATE1P	O	**VGATE1P / - / VEXT**	External Pass Device gate control for EVR13
112	TMS	I	**A2 / PD / VDDP3**	JTAG Module State Machine Control Input
	DAP1	I/O		Device Access Port Line 1
114	$\overline{\text{TRST}}$	I	**A2 / PD / VDDP3**	JTAG Module Reset/Enable Input
115	TCK	I	**A2 / PD / VDDP3**	JTAG Module Clock Input
	DAP0	I		Device Access Port Line 0
102	XTAL1	I	**XTAL1 / - / VDDP3**	Main Oscillator/PLL/Clock Generator Input
103	XTAL2	O	**XTAL2 / - / VDDP3**	Main Oscillator/PLL/Clock Generator Output

Table 2-17 Supply

Pin	Symbol	Ctrl	Type	Function
52	VAREF1	I	**Vx**	Positive Analog Reference Voltage 1
51	VAGND1	I	**Vx**	Negative Analog Reference Voltage 1

Table 2-17 Supply (cont'd)

Pin	Symbol	Ctrl	Type	Function
26	VAREF2	I	**Vx**	Positive Analog Reference Voltage 2
27	VAGND2	I	**Vx**	Negative Analog Reference Voltage 2
54	VDDM	I	**Vx**	ADC Analog Power Supply (3.3V / 5V)
101	VSS	I	**Vx**	Digital Ground
10	VDD / VDDSB	I	**Vx**	Emulation Device: Emulation SRAM Standby Power Supply (1.3V) (Emulation Device only). Production Device: VDD (1.3V).
123, 68, 24	VDD	I	**Vx**	Digital Core Power Supply (1.3V)
100	VDD	I	**Vx**	Digital Core Power Supply (1.3V). The supply pin inturn supplies the main XTAL Oscillator/PLL (1.3V) . A higher decoupling capacitor is therefore recommended to the VSS pin for better noise immunity.
153, 99, 69, 25	VEXT	I	**Vx**	External Power Supply (5V / 3.3V)
154	VDDP3	I	**Vx**	Digital Power Supply for Flash (3.3V). Can be also used as external 3.3V Power Supply for VFLEX.
104	VDDP3	I	**Vx**	Digital Power Supply for Oscillator, LVDSH and A2 pads (3.3V). The supply pin inturn supplies the main XTAL Oscillator/PLL (3.3V) . A higher decoupling capacitor is therefore recommended to the VSS pin for better noise immunity.
155	VDDFL3	I	**Vx**	Flash Power Supply (3.3V)
164	VFLEX	I	**Vx**	Digital Power Supply for Flex Port Pads (5V / 3.3V)
53	VSSM	I	**Vx**	Analog Ground for VDDM

Legend:

Column "**Ctrl.**":

I = Input (for GPIO port Lines with IOCR bit field Selection PCx = $0XXX_B$)

O = Output
O0 = Output with IOCR bit field selection PCx = $1X000_B$
O1 = Output with IOCR bit field selection PCx = $1X001_B$ (ALT1)
O2 = Output with IOCR bit field selection PCx = $1X010_B$ (ALT2)

O3 = Output with IOCR bit field selection PCx = $1X011_B$ (ALT3)
O4 = Output with IOCR bit field selection PCx = $1X100_B$ (ALT4)
O5 = Output with IOCR bit field selection PCx = $1X101_B$ (ALT5)
O6 = Output with IOCR bit field selection PCx = $1X110_B$ (ALT6)
O7 = Output with IOCR bit field selection PCx = $1X111_B$ (ALT7)

Column “**Type**”:

LP = Pad class LP (5V/3.3V, LVTTL)
MP = Pad class MP (5V/3.3V, LVTTL)
MP+ = Pad class MP+ (5V/3.3V, LVTTL)
MPR = Pad class MPR (5V/3.3V, LVTTL)
A2 = Pad class A2 (3.3V, LVTTL)
LVDSM = Pad class LVDSM (LVDS/CMOS 5V/3.3V)
LVDSH = Pad class LVDSH (LVDS/CMOS 3.3V)
S = Pad class S (ADC overlayed with General Purpose Input)
D = Pad class D (ADC)
PU = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)
PU1 = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]
PD = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)
PD1 = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]
PX = Behavior depends on usage: PD in EVR13 SMPS Mode and PU1 in GPIO Mode
OD = open drain during reset ($\overline{\text{PORST}}$ = 0)
HighZ = tri-state during reset ($\overline{\text{PORST}}$ = 0)
$\overline{\text{PORST}}$ = $\overline{\text{PORST}}$ input pad
XTAL1 = XTAL1 input pad
XTAL2 = XTAL2 input pad
VGATE1P = VGATE1P
VGATE3P = VGATE3P
Vx = Supply (the Exposed Pad is also considered as VSS and shall be connected to ground)
NC = These pins are reserved for future extensions and shall not be connected externally
NC1 = These pins are not connected on package level and will not be used for future extensions
NCVDDPSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.
NCVDDSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.

2.1.2 Emergency Stop Function

The Emergency Stop function can be used to force GPIOs (General Purpose Inputs/Outputs) via an external input signal (EMGSTOPA or EMGSTOPB) into a defined state:

- Input state and
- PU or High-Z depending on HWCFG[6] level latched during $\overline{\text{PORST}}$ active

Control of the Emergency Stop function:

1) The default state of GPIOs (Px.y) during and after $\overline{\text{PORST}}$ active is controllled via HWCFG[6] (P14.4). HWCFG[6] has a weak internal pull-up active at start-up if the pin is left unconnected.See also User´s Manual, “Introduction Chapter”, “General Purpose I/O Ports and Peripheral I/O Lines”, Figure: “Default state of port pins during and after reset”.
2) If HWCFG[6] is left unconnected or is externally pulled high, weak internal pull-ups (PU1) / pull-downs (PD1) are active during and after reset.
3) If HWCFG[6] is connected to ground, the PD1 / PU1 pins are predominantly in HighZ during and after reset.

- The Emergency Stop function can be enabled/disabled in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- The Emergency Stop input signal, EMGSTOPA (P33.8) / EMGSTOPB (P21.2) , can selected in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- On port level, each GPIO can be enabled/disabled for the Emergency Stop function via the Px_ESR (Port x Emergency Stop) registers in the port control logic (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, “Emergency Stop Register”).

The Emergency Stop function is available for all GPIO Ports with the following exceptions:

- Not available for P20.2 (General Purpose Input/GPI only, overlayed with Testmode)
- Not available for P40.x (analoge input ANx overlayed with GPI)
- Not available for P32.0 EVR13 SMPS mode.
- Not available for dedicated I/O without General Purpose Output function (e.g ESRx, TMS, TCK)

The Emergency Stop function can be overruled on the following GPIO Ports:

- P00.x: Emergency Stop can be overruled by the VADC. Overruling can be disabled via the control register P00_SCR (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, P00)
- P14.0 and P14.1: Emergency Stop can be overruled in the DXCPL mode (DAP over can physical layer mode). No Overruling in the DXCM (Debug over can message) mode
- P21.6: Emergency Stop can be overruled in JTAG mode if this pin is used as TDI
- P21.7: Emergency Stop can be overruled in JTAG or Three Pin DAP mode
- P20.0: Emergency Stop can be overruled in JTAG mode if this GPIO is used as TDI

2.1.3 Pull-Up/Pull-Down Reset Behavior of the Pins

Table 2-18 List of Pull-Up/Pull-Down Reset Behavior of the Pins

Pins	$\overline{\text{PORST}}$ = 0	$\overline{\text{PORST}}$ = 1
$\overline{\text{all GPIOs}}$	Pull-up if HWCFG[6] = 1 or High-Z if HWCFG[6] = 0	
$\overline{\text{TDI}}$, $\overline{\text{TESTMODE}}$	Pull-up	
$\overline{\text{PORST}}$[1)]	Pull-down with I_{PORST} relevant	Pull-down with I_{PDLI} relevant
$\overline{\text{TRST}}$, TCK, TMS	Pull-down	
$\overline{\text{ESR0}}$	The open-drain driver is used to drive low.[2)]	Pull-up[3)]
$\overline{\text{ESR1}}$	Pull-up[3)]	
TDO	Pull-up	High-Z/Pull-up[4)]

1) Pull-down with I_{PORST} relevant is always activated when a primary supply monitor detects a violation.

2)Valid additionally after deactivation of $\overline{\text{PORST}}$ until the internal reset phase has finished. See the SCU chapter for details.

3) See the SCU_IOCR register description.

4) Depends on JTAG/DAP selection with $\overline{\text{TRST}}$.

In case of leakage test ($\overline{\text{PORST}}$ = 0 and $\overline{\text{TESTMODE}}$ = 0), the pull-down of the $\overline{\text{TRST}}$ pin is switched off. In case of an user application ($\overline{\text{TESTMODE}}$ = 1), the pull-down of the $\overline{\text{TRST}}$ is always switched on.

2.2 TC277x Pin Definition and Functions: BGA292

Figure 2-2 is showing the TC277x Logic Symbol for the package variant: BGA292.

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
Y	VSS	P32.3	P32.2	P32.0	P33.13	P33.11	P33.9	P33.7	P33.5	P33.3	P33.1	AN5	AN10	VAGND1	VAREF1	VDDM	VSSM	AN20	AN21	NC	Y
W	VEXT	VSS	P32.4	VGATE1P	P33.12	P33.10	P33.8	P33.6	P33.4	P33.2	P33.0	AN2	AN8	AN11	AN13	AN16	AN18	AN19	AN24	AN25	W
V	P23.0	VEXT																	AN26	AN27	V
U	P23.2	P23.1	U	VSS	P32.7	P32.6	P33.15	P34.5	P34.3	P34.1	AN1	AN3	AN7	AN9	AN14	AN17	NC	U	AN28	AN29	U
T	P23.4	P23.3	T	P23.5	VSS	P32.5	P33.14	P34.4	P34.2	VEVRSB	AN0	AN4	AN6	AN12	AN15	AN22	AN30	T	VAGND2	VAREF2	T
R	P22.2	P22.3	R	P23.6	P23.7	Top-View										AN23	AN31	R	AN35	AN33	R
P	P22.0	P22.1	P	P22.5	P22.4			VDD	VSS	VSS (AGBT TXDP)	VSS (AGBT TXDN)	VSS	VDD			AN34	AN32	P	AN37	AN39	P
N	VDDP3	VDD	N	P22.7	P22.6		VDD		VSS	VSS	VSS	VSS		VDD		AN38	AN36	N	AN45	AN44	N
M	XTAL1	XTAL2	M	P22.9	P22.8		VSS	VSS		VSS	VSS		VSS	VSS		AN40	AN41	M	AN47	AN46	M
L	VSS	TRST	L	P22.11	P22.10		VSS (AGBT ERR)	VSS	VSS	VSS	VSS	VSS	VSS	VSS (AGBT CLKN)		AN42	AN43	L	P00.12	P00.11	L
K	P21.4	P21.2	K	P21.0	TMS		NC (VDDPSB)	VSS	VSS	VSS	VSS	VSS	VSS	VSS (AGBT CLKP)		P00.10	P00.8	K	P00.9	P00.7	K
J	P21.5	P21.3	J	P21.1	TCK		VSS	VSS		VSS	VSS		VSS	VSS		P01.7	P00.6	J	P00.5	P00.4	J
H	P20.0	P20.2	H	P21.6	P21.7		VDD		VSS	VSS	VSS	VSS		VDD (VDDSB)		P01.5	P01.6	H	P00.3	P00.2	H
G	P20.3	P20.1	G	PORST	ESR1			VDD	VSS	VSS	VSS	VSS	VDD (VDDSB)			P01.3	P01.4	G	P00.1	P00.0	G
F	P20.8	P20.7	F	P20.6	ESR0											P02.10	P02.11	F	P02.7	P02.8	F
E	P20.11	P20.10	E	P20.9	VSS	VDDFL3	P15.5	P14.2	P12.0	P12.1	P11.0	P11.1	P11.7	P11.8	P11.13	VSS	P02.9	E	P02.5	P02.6	E
D	P20.13	P20.12	D	VSS	VDDFL3	P15.7	P15.8	P14.7	P14.9	P14.10	P11.4	P11.6	P11.5	P11.14	P11.15	VFLEX	VSS	D	P02.3	P02.4	D
C	P20.14	P15.2		17	16	15	14	13	12	11	10	9	8	7	6	5	4		P02.1	P02.2	C
B	P15.0	VSS	VDDP3	P15.3	P14.0	P14.4	P14.3	P14.6	P13.0	P13.2	P11.3	P11.10	P11.12	P10.1	P10.4	P10.5	P10.8	VEXT	VSS	P02.0	B
A	VSS	VDDP3	P15.1	P15.4	P15.6	P14.1	P14.5	P14.8	P13.1	P13.3	P11.2	P11.9	P11.11	P10.0	P10.3	P10.2	P10.6	P10.7	VEXT	NC	A
	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

Figure 2-2 TC277x Logic Symbol for the package variant BGA292.

2.2.1 TC277xBGA292 Package Variant Pin Configuration

Table 2-19 Port 00 Functions

Pin	Symbol	Ctrl	Type	Function
G1	P00.0	I	**MP / PU1 / VEXT**	General-purpose input
	TIN9			GTM input
	$\overline{\text{CTRAPA}}$			CCU61 input
	T12HRE			CCU60 input
	INJ00			MSC0 input
	CIFD9			CIF input
	P00.0	O0		General-purpose output
	TOUT9	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	ATX3	O3		ASCLIN3 output
	–	O4		Reserved
	TXDCAN1	O5		CAN node 1 output
	–	O6		Reserved
	COUT63	O7		CCU60 output
	ETHMDIOA	HWOUT		ETH input/output
G2	P00.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN10			GTM input
	ARX3E			ASCLIN3 input
	RXDCAN1D			CAN node 1 input
	PSIRX0A			PSI5 input
	SENT0B			SENT input
	CC60INB			CCU60 input
	CC60INA			CCU61 input
	DSCIN5A			DSADC channel 5 input A
	DS5NA			DSADC negative analog input of channel 5, pin A
	VADCG7.5			VADC analog input channel 5 of group 7
	CIFD10			CIF input
	P00.1	O0		General-purpose output
	TOUT10	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT5	O4		DSADC channel 5 output
	–	O5		Reserved
	SPC0	O6		SENT output
	CC60	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
H1	P00.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN11			GTM input
	SENT1B			SENT input
	DSDIN5A			DSADC channel 5 input A
	DS5PA			DSADC positive analog input of channel 5, pin A
	VADCG7.4			VADC analog input channel 4 of group 7
	CIFD11			CIF input
	P00.2	O0		General-purpose output
	TOUT11	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	PSITX0	O4		PSI5 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	COUT60	O7		CCU61 output
H2	P00.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN12			GTM input
	RXDCAN3A			CAN node 3 input
	PSIRX1A			PSI5 input
	PSISRXA			PSI5-S input
	SENT2B			SENT input
	CC61INB			CCU60 input
	CC61INA			CCU61 input
	DSCIN3A			DSADC channel 3 input A
	VADCG7.3			VADC analog input channel 3 of group 7
	DSITR5F			DSADC channel 5 input F
	CIFD12			CIF input
	P00.3	O0		General-purpose output
	TOUT12	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT3	O4		DSADC channel 3 output
	–	O5		Reserved
	SPC2	O6		SENT output
	CC61	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
J1	P00.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN13			GTM input
	REQ7			SCU input
	SENT3B			SENT input
	DSDIN3A			DSADC channel 3 input A
	DSSGNA			DSADC input
	VADCG7.2			VADC analog input channel 2 of group 7 (MD)
	CIFD13			CIF input
	P00.4	O0		General-purpose output
	TOUT13	O1		GTM output
	PSISTX	O2		PSI5-S output
	–	O3		Reserved
	PSITX1	O4		PSI5 output
	VADCG4BFL0	O5		VADC output
	SPC3	O6		SENT output
	COUT61	O7		CCU61 output
J2	P00.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN14			GTM input
	PSIRX2A			PSI5 input
	SENT4B			SENT input
	CC62INB			CCU60 input
	CC62INA			CCU61 input
	DSCIN2A			DSADC channel 2 input A
	VADCG7.1			VADC analog input channel 1 of group 7 (MD)
	CIFD14			CIF input
	P00.5	O0		General-purpose output
	TOUT14	O1		GTM output
	DSCGPWMN	O2		DSADC output
	–	O3		Reserved
	DSCOUT2	O4		DSADC channel 2 output
	VADCG4BFL1	O5		VADC output
	SPC4	O6		SENT output
	CC62	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
J4	P00.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN15			GTM input
	SENT5B			SENT input
	DSDIN2A			DSADC channel 2 input A
	VADCG7.0			VADC analog input channel 0 of group 7
	DSITR4F			DSADC channel 4 input F
	CIFD15			CIF input
	P00.6	O0		General-purpose output
	TOUT15	O1		GTM output
	DSCGPWMP	O2		DSADC output
	VADCG4BFL2	O3		VADC output
	PSITX2	O4		PSI5 output
	VADCEMUX10	O5		VADC output
	SPC5	O6		SENT output
	COUT62	O7		CCU61 output
K1	P00.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN16			GTM input
	SENT6B			SENT input
	CC60INC			CCU61 input
	CCPOS0A			CCU61 input
	T12HRB			CCU60 input
	T2INA			GPT120 input
	DSCIN4A			DSADC channel 4 input A
	DS4NA			DSADC negative analog input of channel 4, pin A
	VADCG6.5			VADC analog input channel 5 of group 6
	CIFCLK			CIF input
	P00.7	O0		General-purpose output
	TOUT16	O1		GTM output
	–	O2		Reserved
	VADCG4BFL3	O3		VADC output
	DSCOUT4	O4		DSADC channel 4 output
	VADCEMUX11	O5		VADC output
	SPC6	O6		SENT output
	CC60	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
K4	P00.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN17			GTM input
	SENT7B			SENT input
	CC61INC			CCU61 input
	CCPOS1A			CCU61 input
	T13HRB			CCU60 input
	T2EUDA			GPT120 input
	DSDIN4A			DSADC channel 4 input A
	DS4PA			DSADC channel 4 input A
	VADCG6.4			VADC analog input channel 4 of group 6
	CIFVSNC			CIF input
	P00.8	O0		General-purpose output
	TOUT17	O1		GTM output
	SLSO36	O2		QSPI3 output
	–	O3		Reserved
	–	O4		Reserved
	VADCEMUX12	O5		VADC output
	SPC7	O6		SENT output
	CC61	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
K2	P00.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN18			GTM input
	SENT8B			SENT input
	CC62INC			CCU61 input
	CCPOS2A			CCU61 input
	T13HRC			CCU60 input
	T12HRC			CCU60 input
	T4EUDA			GPT120 input
	DSCIN1A			DSADC channel 1 input A
	VADCG6.3			VADC analog input channel 3 of group 6
	DSITR3F			DSADC channel 3 input F
	CIFHSNC			CIF input
	P00.9	O0		General-purpose output
	TOUT18	O1		GTM output
	SLSO37	O2		QSPI3 output
	ARTS3	O3		ASCLIN3 output
	DSCOUT1	O4		DSADC channel 1 output
	–	O5		Reserved
	SPC8	O6		SENT output
	CC62	O7		CCU61 output
K5	P00.10	I	**LP / PU1 / VEXT**	General-purpose input
	TIN19			GTM input
	SENT9B			SENT input
	DSDIN1A			DSADC channel 1 input A
	VADCG6.2			VADC analog input channel 2 of group 6 (MD)
	P00.10	O0		General-purpose output
	TOUT19	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	SPC9	O6		SENT output
	COUT63	O7		CCU61 output

Table 2-19 Port 00 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
L1	P00.11	I	**LP / PU1 / VEXT**	General-purpose input
	TIN20			GTM input
	CTRAPA			CCU60 input
	T12HRE			CCU61 input
	DSCIN0A			DSADC channel 0 input A
	VADCG6.1			VADC analog input channel 1 of group 6 (MD)
	P00.11	O0		General-purpose output
	TOUT20	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	DSCOUT0	O4		DSADC channel 0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
L2	P00.12	I	**LP / PU1 / VEXT**	General-purpose input
	TIN21			GTM input
	ACTS3A			ASCLIN3 input
	DSDIN0A			DSADC channel 0 input A
	VADCG6.0			VADC analog input channel 0 of group 6
	P00.12	O0		General-purpose output
	TOUT21	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT63	O7		CCU61 output

Table 2-20 Port 01 Functions

Pin	Symbol	Ctrl	Type	Function
G5	P01.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN111			GTM input
	$\overline{\text{SLSI3B}}$			QSPI3 input
	P01.3	O0		General-purpose output
	TOUT111	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO39	O4		QSPI3 output
	TXDCAN1	O5		CAN node 1 output
	–	O6		Reserved
	–	O7		Reserved
G4	P01.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN112			GTM input
	RXDCAN1C			CAN node 1 input
	P01.4	O0		General-purpose output
	TOUT112	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO310	O4		QSPI3 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
H5	P01.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN113			GTM input
	MRST3C			QSPI3 input
	P01.5	O0		General-purpose output
	TOUT113	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MRST3	O4		QSPI3 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-20 Port 01 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
H4	P01.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN114			GTM input
	MTSR3C			QSPI3 input
	P01.6	O0		General-purpose output
	TOUT114	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MTSR3	O4		QSPI3 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
J5	P01.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN115			GTM input
	SCLK3C			QSPI3 input
	P01.7	O0		General-purpose output
	TOUT115	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SCLK3	O4		QSPI3 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-21 Port 02 Functions

Pin	Symbol	Ctrl	Type	Function
B1	P02.0	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN0			GTM input
	ARX2G			ASCLIN2 input
	REQ6			SCU input
	CC60INA			CCU60 input
	CC60INB			CCU61 input
	CIFD0			CIF input
	P02.0	O0		General-purpose output
	TOUT0	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO31	O3		QSPI3 output
	DSCGPWMN	O4		DSADC output
	TXDCAN0	O5		CAN node 0 output
	TXDA	O6		ERAY output
	CC60	O7		CCU60 output
C2	P02.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN1			GTM input
	REQ14			SCU input
	ARX2B			ASCLIN2 input
	RXDCAN0A			CAN node 0 input
	RXDA2			ERAY input
	CIFD1			CIF input
	P02.1	O0		General-purpose output
	TOUT1	O1		GTM output
	–	O2		Reserved
	SLSO32	O3		QSPI3 output
	DSCGPWMP	O4		DSADC output
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
C1	P02.2	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN2			GTM input
	CC61INA			CCU60 input
	CC61INB			CCU61 input
	CIFD2			CIF input
	P02.2	O0		General-purpose output
	TOUT2	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO33	O3		QSPI3 output
	PSITX0	O4		PSI5 output
	TXDCAN2	O5		CAN node 2 output
	TXDB	O6		ERAY output
	CC61	O7		CCU60 output
D2	P02.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN3			GTM input
	ARX1G			ASCLIN1 input
	RXDCAN2B			CAN node 2 input
	RXDB2			ERAY input
	PSIRX0B			PSI5 input
	DSCIN5B			DSADC channel 5 input B
	SDI11			MSC1 input
	CIFD3			CIF input
	P02.3	O0		General-purpose output
	TOUT3	O1		GTM output
	ASLSO2	O2		ASCLIN2 output
	SLSO34	O3		QSPI3 output
	DSCOUT5	O4		DSADC channel 5 output
	–	O5		Reserved
	–	O6		Reserved
	COUT61	O7		CCU60 output

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
D1	P02.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN4			GTM input
	SLSI3A			QSPI3 input
	ECTT1			TTCAN input
	RXDCAN0D			CAN node 0 input
	CC62INA			CCU60 input
	CC62INB			CCU61 input
	DSDIN5B			DSADC channel 5 input B
	SDA0A			I2C0 input
	CIFD4			CIF input
	P02.4	O0		General-purpose output
	TOUT4	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	SLSO30	O3		QSPI3 output
	PSISCLK	O4		PSI5-S output
	SDA0	O5		I2C0 output
	TXENA	O6		ERAY output
	CC62	O7		CCU60 output
E2	P02.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN5			GTM input
	MRST3A			QSPI3 input
	ECTT2			TTCAN input
	PSIRX1B			PSI5 input
	PSISRXB			PSI5-S input
	SENT3C			SENT input
	DSCIN4B			DSADC channel 4 input B
	SCL0A			I2C0 input
	CIFD5			CIF input
	P02.5	O0		General-purpose output
	TOUT5	O1		GTM output
	TXDCAN0	O2		CAN node 0 output
	MRST3	O3		QSPI3 output
	DSCOUT4	O4		DSADC channel 4 output
	SCL0	O5		I2C0 output
	TXENB	O6		ERAY output
	COUT62	O7		CCU60 output

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
E1	P02.6	I	**MP / PU1 / VEXT**	General-purpose input
	TIN6			GTM input
	MTSR3A			QSPI3 input
	SENT2C			SENT input
	CC60INC			CCU60 input
	CCPOS0A			CCU60 input
	T12HRB			CCU61 input
	T3INA			GPT120 input
	CIFD6			CIF input
	DSDIN4B			DSADC channel 4 input B
	DSITR5E			DSADC channel 5 input E
	P02.6	O0		General-purpose output
	TOUT6	O1		GTM output
	PSISTX	O2		PSI5-S output
	MTSR3	O3		QSPI3 output
	PSITX1	O4		PSI5 output
	VADCEMUX00	O5		VADC output
	–	O6		Reserved
	CC60	O7		CCU60 output

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
F2	P02.7	I	**MP / PU1 / VEXT**	General-purpose input
	TIN7			GTM input
	SCLK3A			QSPI3 input
	PSIRX2B			PSI5 input
	SENT1C			SENT input
	CC61INC			CCU60 input
	CCPOS1A			CCU60 input
	T13HRB			CCU61 input
	T3EUDA			GPT120 input
	CIFD7			CIF input
	DSCIN3B			DSADC channel 3 input B
	DSITR4E			DSADC channel 4 input E
	P02.7	O0		General-purpose output
	TOUT7	O1		GTM output
	–	O2		Reserved
	SCLK3	O3		QSPI3 output
	DSCOUT3	O4		DSADC channel 3 output
	VADCEMUX01	O5		VADC output
	SPC1	O6		SENT output
	CC61	O7		CCU60 output

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
F1	P02.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN8			GTM input
	SENT0C			SENT input
	CC62INC			CCU60 input
	CCPOS2A			CCU60 input
	T12HRC			CCU61 input
	T13HRC			CCU61 input
	T4INA			GPT120 input
	CIFD8			CIF input
	DSDIN3B			DSADC channel 3 input B
	DSITR3E			DSADC channel 3 input E
	P02.8	O0		General-purpose output
	TOUT8	O1		GTM output
	SLSO35	O2		QSPI3 output
	–	O3		Reserved
	PSITX2	O4		PSI5 output
	VADCEMUX02	O5		VADC output
	ETHMDC	O6		ETH output
	CC62	O7		CCU60 output
E4	P02.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN116			GTM input
	P02.9	O0		General-purpose output
	TOUT116	O1		GTM output
	ATX2	O2		ASCLIN2 output
	–	O3		Reserved
	–	O4		Reserved
	TXDCAN1	O5		CAN node 1 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-21 Port 02 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
F5	P02.10	I	**LP / PU1 / VEXT**	General-purpose input
	TIN117			GTM input
	ARX2C			ASCLIN2 input
	RXDCAN1E			CAN node 1 input
	P02.10	O0		General-purpose output
	TOUT117	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
F4	P02.11	I	**LP / PU1 / VEXT**	General-purpose input
	TIN118			GTM input
	P02.11	O0		General-purpose output
	TOUT118	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-22 Port 10 Functions

Pin	Symbol	Ctrl	Type	Function
A7	P10.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN102			GTM input
	T6EUDB			GPT120 input
	P10.0	O0		General-purpose output
	TOUT102	O1		GTM output
	–	O2		Reserved
	SLSO110	O3		QSPI1 output
	–	O4		Reserved
	VADCG6BFL0	O5		VADC output
	–	O6		Reserved
	–	O7		Reserved

Table 2-22 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B7	P10.1	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN103			GTM input
	MRST1A			QSPI1 input
	T5EUDB			GPT120 input
	P10.1	O0		General-purpose output
	TOUT103	O1		GTM output
	MTSR1	O2		QSPI1 output
	MRST1	O3		QSPI1 output
	EN01	O4		MSC0 output
	VADCG6BFL1	O5		VADC output
	END03	O6		MSC0 output
	–	O7		Reserved
A5	P10.2	I	**MP / PU1 / VEXT**	General-purpose input
	TIN104			GTM input
	SCLK1A			QSPI1 input
	T6INB			GPT120 input
	REQ2			SCU input
	RXDCAN2E			CAN node 2 input
	SDI01			MSC0 input
	P10.2	O0		General-purpose output
	TOUT104	O1		GTM output
	–	O2		Reserved
	SCLK1	O3		QSPI1 output
	EN00	O4		MSC0 output
	VADCG6BFL2	O5		VADC output
	END02	O6		MSC0 output
	–	O7		Reserved

Table 2-22 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A6	P10.3	I	**MP / PU1 / VEXT**	General-purpose input
	TIN105			GTM input
	MTSR1A			QSPI1 input
	REQ3			SCU input
	T5INB			GPT120 input
	P10.3	O0		General-purpose output
	TOUT105	O1		GTM output
	VADCG6BFL3	O2		VADC output
	MTSR1	O3		QSPI1 output
	EN00	O4		MSC0 output
	END02	O5		MSC0 output
	TXDCAN2	O6		CAN node 2 output
	–	O7		Reserved
B6	P10.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN106			GTM input
	MTSR1C			QSPI1 input
	CCPOS0C			CCU60 input
	T3INB			GPT120 input
	P10.4	O0		General-purpose output
	TOUT106	O1		GTM output
	–	O2		Reserved
	SLSO18	O3		QSPI1 output
	MTSR1	O4		QSPI1 output
	EN00	O5		MSC0 output
	END02	O6		MSC0 output
	–	O7		Reserved
B5	P10.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN107			GTM input
	HWCFG4			SCU input
	INJ01			MSC0 input
	P10.5	O0		General-purpose output
	TOUT107	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO38	O3		QSPI3 output
	SLSO19	O4		QSPI1 output
	T6OUT	O5		GPT120 output
	ASLSO2	O6		ASCLIN2 output
	-	O7		Reserved

Table 2-22 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A4	P10.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN108			GTM input
	ARX2D			ASCLIN2 input
	MTSR3B			QSPI3 input
	HWCFG5			SCU input
	P10.6	O0		General-purpose output
	TOUT108	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	MTSR3	O3		QSPI3 output
	T3OUT	O4		GPT120 output
	-	O5		Reserved
	MRST1	O6		QSPI1 output
	VADCG7BFL0	O7		VADC output
A3	P10.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN109			GTM input
	ACTS2A			ASCLIN2 input
	MRST3B			QSPI3 input
	REQ4			SCU input
	CCPOS1C			CCU60 input
	T3EUDB			GPT120 input
	P10.7	O0		General-purpose output
	TOUT109	O1		GTM output
	–	O2		Reserved
	MRST3	O3		QSPI3 output
	VADCG7BFL1	O4		VADC output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-22 Port 10 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B4	P10.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN110			GTM input
	SCLK3B			QSPI3 input
	REQ5			SCU input
	CCPOS2C			CCU60 input
	T4INB			GPT120 input
	P10.8	O0		General-purpose output
	TOUT110	O1		GTM output
	ARTS2	O2		ASCLIN2 output
	SCLK3	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-23 Port 11 Functions

Pin	Symbol	Ctrl	Type	Function
E10	P11.0	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN119			GTM input
	ARX3B			ASCLIN3 input
	P11.0	O0		General-purpose output
	TOUT119	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHTXD3	O6		ETH output
	–	O7		Reserved
E9	P11.1	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN120			GTM input
	P11.1	O0		General-purpose output
	TOUT120	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	ATX3	O3		ASCLIN3 output
	–	O4		Reserved
	–	O5		Reserved
	ETHTXD2	O6		ETH output
	–	O7		Reserved

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A10	P11.2	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN95			GTM input
	P11.2	O0		General-purpose output
	TOUT95	O1		GTM output
	END03	O2		MSC0 output
	SLSO05	O3		QSPI0 output
	SLSO15	O4		QSPI1 output
	EN01	O5		MSC0 output
	ETHTXD1	O6		ETH output
	COUT63	O7		CCU60 output
B10	P11.3	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN96			GTM input
	MRST1B			QSPI1 input
	SDI03			MSC0 input
	P11.3	O0		General-purpose output
	TOUT96	O1		GTM output
	–	O2		Reserved
	MRST1	O3		QSPI1 output
	TXDA	O4		ERAY output
	–	O5		Reserved
	ETHTXD0	O6		ETH output
	COUT62	O7		CCU60 output
D10	P11.4	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN121			GTM input
	ETHRXCLKB			ETH input
	P11.4	O0		General-purpose output
	TOUT121	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHTXER	O6		ETH output
	–	O7		Reserved

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
D8	P11.5	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN122			GTM input
	ETHTXCLKA			ETH input
	P11.5	O0		General-purpose output
	TOUT122	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
D9	P11.6	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN97			GTM input
	SCLK1B			QSPI1 input
	P11.6	O0		General-purpose output
	TOUT97	O1		GTM output
	$\overline{\text{TXENB}}$	O2		ERAY output
	SCLK1	O3		QSPI1 output
	$\overline{\text{TXENA}}$	O4		ERAY output
	FCLP0	O5		MSC0 output
	ETHTXEN	O6		ETH output
	COUT61	O7		CCU60 output
E8	P11.7	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN123			GTM input
	ETHRXD3			ETH input
	P11.7	O0		General-purpose output
	TOUT123	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
E7	P11.8	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN124			GTM input
	ETHRXD2			ETH input
	P11.8	O0		General-purpose output
	TOUT124	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
A9	P11.9	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN98			GTM input
	MTSR1B			QSPI1 input
	RXDA1			ERAY input
	ETHRXD1			ETH input
	P11.9	O0		General-purpose output
	TOUT98	O1		GTM output
	–	O2		Reserved
	MTSR1	O3		QSPI1 output
	–	O4		Reserved
	SOP0	O5		MSC0 output
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B9	P11.10	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN99			GTM input
	REQ12			SCU input
	ARX1E			ASCLIN1 input
	$\overline{\text{SLSI1A}}$			QSPI1 input
	RXDCAN3D			CAN node 3 input
	RXDB1			ERAY input
	ETHRXD0			ETH input
	SDI00			MSC0 input
	P11.10	O0		General-purpose output
	TOUT99	O1		GTM output
	–	O2		Reserved
	SLSO03	O3		QSPI0 output
	SLSO13	O4		QSPI1 output
	–	O5		Reserved
	–	O6		Reserved
	CC62	O7		CCU60 output
A8	P11.11	I	**MP+ / PU1 / VFLEX**	General-purpose input
	TIN100			GTM input
	ETHCRSDVA			ETH input
	ETHRXDVA			ETH input
	ETHCRSB			ETH input
	P11.11	O0		General-purpose output
	TOUT100	O1		GTM output
	END02	O2		MSC0 output
	SLSO04	O3		QSPI0 output
	SLSO14	O4		QSPI1 output
	EN00	O5		MSC0 output
	$\overline{\text{TXENB}}$	O6		ERAY output
	CC61	O7		CCU60 output

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B8	P11.12	I	**MPR / PU1 / VFLEX**	General-purpose input
	TIN101	O0		GTM input
	ETHREFCLK			ETH input
	ETHTXCLKB			ETH input (Not for productive purposes)
	P11.12			General-purpose output
	TOUT101	O1		GTM output
	ATX1	O2		ASCLIN1 output
	GTMCLK2	O3		GTM output
	TXDB	O4		ERAY output
	TXDCAN3	O5		CAN node 3 output
	EXTCLK1	O6		SCU output
	CC60	O7		CCU60 output
E6	P11.13	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN125			GTM input
	ETHRXERA			ETH input
	P11.13	O0		General-purpose output
	TOUT125	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
D7	P11.14	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN126			GTM input
	ETHCRSDVB			ETH input
	ETHRXDVB			ETH input
	ETHCRSA			ETH input
	P11.14	O0		General-purpose output
	TOUT126	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-23 Port 11 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
D6	P11.15	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN127			GTM input
	ETHCOL			ETH input
	P11.15	O0		General-purpose output
	TOUT127	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-24 Port 12 Functions

Pin	Symbol	Ctrl	Type	Function
E12	P12.0	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN128			GTM input
	ETHRXCLKC			ETH input
	RXDCAN0C			CAN node 0 input
	P12.0	O0		General-purpose output
	TOUT128	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHMDC	O6		ETH output
	–	O7		Reserved
E11	P12.1	I	**LP / PU1 / VFLEX**	General-purpose input
	TIN129			GTM input
	P12.1	O0		General-purpose output
	TOUT129	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	TXDCAN0	O5		CAN node 0 output
	–	O6		Reserved
	–	O7		Reserved
	ETHMDIOC	HWOUT		ETH input/output

Table 2-25 Port 13 Functions

Pin	Symbol	Ctrl	Type	Function
B12	P13.0	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN91			GTM input
	P13.0	O0		General-purpose output
	TOUT91	O1		GTM output
	END03	O2		MSC0 output
	SCLK2N	O3		QSPI2 output (LVDS)
	EN01	O4		MSC0 output
	FCLN0	O5		MSC0 output (LVDS)
	FCLND0	O6		MSC0 output (LVDS)
	–	O7		Reserved
A12	P13.1	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN92			GTM input
	SCL0B			I2C0 input
	P13.1	O0		General-purpose output
	TOUT92	O1		GTM output
	–	O2		Reserved
	SCLK2P	O3		QSPI2 output (LVDS)
	–	O4		Reserved
	FCLP0	O5		MSC0 output (LVDS)
	SCL0	O6		I2C0 output
	–	O7		Reserved
B11	P13.2	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN93			GTM input
	CAPINA			GPT120 input
	SDA0B			I2C0 input
	P13.2	O0		General-purpose output
	TOUT93	O1		GTM output
	–	O2		Reserved
	MTSR2N	O3		QSPI2 output (LVDS)
	FCLP0	O4		MSC0 output
	SON0	O5		MSC0 output (LVDS)
	SDA0	O6		I2C0 output
	SOND0	O7		MSC0 output (LVDS)

Table 2-25 Port 13 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A11	P13.3	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN94			GTM input
	P13.3	O0		General-purpose output
	TOUT94	O1		GTM output
	–	O2		Reserved
	MTSR2P	O3		QSPI2 output (LVDS)
	–	O4		Reserved
	SOP0	O5		MSC0 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved

Table 2-26 Port 14 Functions

Pin	Symbol	Ctrl	Type	Function
B16	P14.0	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN80			GTM input
	P14.0	O0		General-purpose output
	TOUT80	O1		GTM output
	ATX0	O2		ASCLIN0 output Recommended as Boot loader pin.
	TXDA	O3		ERAY output
	TXDB	O4		ERAY output
	TXDCAN1	O5		CAN node 1 output Used for single pin DAP (SPD) function.
	ASCLK0	O6		ASCLIN0 output
	COUT62	O7		CCU60 output

Table 2-26 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A15	P14.1	I	**MP / PU1 / VEXT**	General-purpose input
	TIN81			GTM input
	REQ15			SCU input
	ARX0A			ASCLIN0 input Recommended as Boot loader pin.
	RXDCAN1B			CAN node 1 input Used for single pin DAP (SPD) function.
	RXDA3			ERAY input
	RXDB3			ERAY input
	EVRWUPA			SCU input
	P14.1	O0		General-purpose output
	TOUT81	O1		GTM output
	ATX0	O2		ASCLIN0 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT63	O7		CCU60 output
E13	P14.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN82			GTM input
	HWCFG2 EVR13			SCU input Latched at cold power on reset to decide EVR13 activation.
	P14.2	O0		General-purpose output
	TOUT82	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO21	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	ASCLK2	O6		ASCLIN2 output
	–	O7		Reserved

Table 2-26 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B14	P14.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN83			GTM input
	ARX2A			ASCLIN2 input
	REQ10			SCU input
	HWCFG3_BMI			SCU input
	SDI02			MSC0 input
	P14.3	O0		General-purpose output
	TOUT83	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO23	O3		QSPI2 output
	ASLSO1	O4		ASCLIN1 output
	ASLSO3	O5		ASCLIN3 output
	–	O6		Reserved
	–	O7		Reserved
B15	P14.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN84			GTM input
	HWCFG6			SCU input Latched at cold power on reset to decide default pad reset state (PU or HighZ).
	P14.4	O0		General-purpose output
	TOUT84	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-26 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A14	P14.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN85			GTM input
	HWCFG1 EVR33			SCU input Latched at cold power on reset to decide EVR33 activation.
	P14.5	O0		General-purpose output
	TOUT85	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	TXDB	O6		ERAY output
	–	O7		Reserved
B13	P14.6	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN86			GTM input
	HWCFG0 DCLDO			SCU input If EVR13 active, latched at cold power on reset to decide between LDO and SMPS mode.
	P14.6	O0		General-purpose output
	TOUT86	O1		GTM output
	–	O2		Reserved
	SLSO22	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	$\overline{\text{TXENB}}$	O6		ERAY output
	–	O7		Reserved
D13	P14.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN87			GTM input
	RXDB0			ERAY input
	P14.7	O0		General-purpose output
	TOUT87	O1		GTM output
	ARTS0	O2		ASCLIN0 output
	SLSO24	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-26 Port 14 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
A13	P14.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN88			GTM input
	ARX1D			ASCLIN1 input
	RXDCAN2D			CAN node 2 input
	RXDA0			ERAY input
	P14.8	O0		General-purpose output
	TOUT88	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
D12	P14.9	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN89			GTM input
	ACTS0A			ASCLIN0 input
	P14.9	O0		General-purpose output
	TOUT89	O1		GTM output
	END03	O2		MSC0 output
	EN01	O3		MSC0 output
	–	O4		Reserved
	$\overline{\text{TXENB}}$	O5		ERAY output
	$\overline{\text{TXENA}}$	O6		ERAY output
	–	O7		Reserved
D11	P14.10	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN90			GTM input
	P14.10	O0		General-purpose output
	TOUT90	O1		GTM output
	END02	O2		MSC0 output
	EN00	O3		MSC0 output
	ATX1	O4		ASCLIN1 output
	TXDCAN2	O5		CAN node 2 output
	TXDA	O6		ERAY output
	–	O7		Reserved

Table 2-27 Port 15 Functions

Pin	Symbol	Ctrl	Type	Function
B20	P15.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN71			GTM input
	P15.0	O0		General-purpose output
	TOUT71	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO013	O3		QSPI0 output
	–	O4		Reserved
	TXDCAN2	O5		CAN node 2 output
	ASCLK1	O6		ASCLIN1 output
	–	O7		Reserved
A18	P15.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN72			GTM input
	REQ16			SCU input
	ARX1A			ASCLIN1 input
	RXDCAN2A			CAN node 2 input
	$\overline{\text{SLSI2B}}$			QSPI2 input
	EVRWUPB			SCU input
	P15.1	O0		General-purpose output
	TOUT72	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO25	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
C19	P15.2	I	**MP / PU1 / VEXT**	General-purpose input
	TIN73			GTM input
	$\overline{\text{SLSI2A}}$			QSPI2 input
	MRST2E			QSPI2 input
	P15.2	O0		General-purpose output
	TOUT73	O1		GTM output
	ATX0	O2		ASCLIN0 output
	SLSO20	O3		QSPI2 output
	–	O4		Reserved
	TXDCAN1	O5		CAN node 1 output
	ASCLK0	O6		ASCLIN0 output
	–	O7		Reserved

Table 2-27 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
B17	P15.3	I	**MP / PU1 / VEXT**	General-purpose input
	TIN74			GTM input
	ARX0B			ASCLIN0 input
	SCLK2A			QSPI2 input
	RXDCAN1A			CAN node 1 input
	P15.3	O0		General-purpose output
	TOUT74	O1		GTM output
	ATX0	O2		ASCLIN0 output
	SCLK2	O3		QSPI2 output
	END03	O4		MSC0 output
	EN01	O5		MSC0 output
	–	O6		Reserved
	–	O7		Reserved
A17	P15.4	I	**MP / PU1 / VEXT**	General-purpose input
	TIN75			GTM input
	MRST2A			QSPI2 input
	REQ0			SCU input
	SCL0C			I2C0 input
	P15.4	O0		General-purpose output
	TOUT75	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MRST2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	SCL0	O6		I2C0 output
	CC62	O7		CCU60 output

Table 2-27 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
E14	P15.5	I	**MP / PU1 / VEXT**	General-purpose input
	TIN76			GTM input
	ARX1B			ASCLIN1 input
	MTSR2A			QSPI2 input
	REQ13			SCU input
	SDA0C			I2C0 input
	P15.5	O0		General-purpose output
	TOUT76	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MTSR2	O3		QSPI2 output
	END02	O4		MSC0 output
	EN00	O5		MSC0 output
	SDA0	O6		I2C0 output
	CC61	O7		CCU60 output
A16	P15.6	I	**MP / PU1 / VEXT**	General-purpose input
	TIN77			GTM input
	MTSR2B			QSPI2 input
	P15.6	O0		General-purpose output
	TOUT77	O1		GTM output
	ATX3	O2		ASCLIN3 output
	MTSR2	O3		QSPI2 output
	–	O4		Reserved
	SCLK2	O5		QSPI2 output
	ASCLK3	O6		ASCLIN3 output
	CC60	O7		CCU60 output
D15	P15.7	I	**MP / PU1 / VEXT**	General-purpose input
	TIN78			GTM input
	ARX3A			ASCLIN3 input
	MRST2B			QSPI2 input
	P15.7	O0		General-purpose output
	TOUT78	O1		GTM output
	ATX3	O2		ASCLIN3 output
	MRST2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU60 output

Table 2-27 Port 15 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
D14	P15.8	I	**MP / PU1 / VEXT**	General-purpose input
	TIN79			GTM input
	SCLK2B			QSPI2 input
	REQ1			SCU input
	P15.8	O0		General-purpose output
	TOUT79	O1		GTM output
	–	O2		Reserved
	SCLK2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	ASCLK3	O6		ASCLIN3 output
	COUT61	O7		CCU60 output

Table 2-28 Port 20 Functions

Pin	Symbol	Ctrl	Type	Function
H20	P20.0	I	**MP / PU1 / VEXT**	General-purpose input
	TIN59			GTM input
	RXDCAN3C			CAN node 3 input
	T6EUDA			GPT120 input
	REQ9			SCU input
	SYSCLK			HSCT input
	$\overline{\text{TGI0}}$			OCDS input
	P20.0	O0		General-purpose output
	TOUT59	O1		GTM output
	ATX3	O2		ASCLIN3 output
	ASCLK3	O3		ASCLIN3 output
	–	O4		Reserved
	SYSCLK	O5		HSCT output
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO0}}$	HWOUT		OCDS; ENx

Table 2-28 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
G19	P20.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN60			GTM input
	$\overline{\text{TGI1}}$			OCDS input
	P20.1	O0		General-purpose output
	TOUT60	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO1}}$	HWOUT		OCDS; ENx
H19	P20.2	I	**LP / PU / VEXT**	General-purpose input This pin is latched at power on reset release to enter test mode.
	$\overline{\text{TESTMODE}}$			OCDS input
	P20.2	O0		Output function not available
	–	O1		Output function not available
	–	O2		Output function not available
	–	O3		Output function not available
	–	O4		Output function not available
	–	O5		Output function not available
	–	O6		Output function not available
	–	O7		Output function not available
G20	P20.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN61			GTM input
	T6INA			GPT120 input
	ARX3C			ASCLIN3 input
	P20.3	O0		General-purpose output
	TOUT61	O1		GTM output
	ATX3	O2		ASCLIN3 output
	SLSO09	O3		QSPI0 output
	SLSO29	O4		QSPI2 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-28 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
F17	P20.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN62			GTM input
	P20.6	O0		General-purpose output
	TOUT62	O1		GTM output
	ARTS1	O2		ASCLIN1 output
	SLSO08	O3		QSPI0 output
	SLSO28	O4		QSPI2 output
	–	O5		Reserved
	WDT2LCK	O6		SCU output
	–	O7		Reserved
F19	P20.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN63			GTM input
	ACTS1A			ASCLIN1 input
	RXDCAN0B			CAN node 0 input
	P20.7	O0		General-purpose output
	TOUT63	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	WDT1LCK	O6		SCU output
	COUT63	O7		CCU61 output
F20	P20.8	I	**MP / PU1 / VEXT**	General-purpose input
	TIN64			GTM input
	P20.8	O0		General-purpose output
	TOUT64	O1		GTM output
	ASLSO1	O2		ASCLIN1 output
	SLSO00	O3		QSPI0 output
	SLSO10	O4		QSPI1 output
	TXDCAN0	O5		CAN node 0 output
	WDT0LCK	O6		SCU output
	CC60	O7		CCU61 output

Table 2-28 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
E17	P20.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN65			GTM input
	ARX1C			ASCLIN1 input
	RXDCAN3E			CAN node 3 input
	REQ11			SCU input
	$\overline{\text{SLSI0B}}$			QSPI0 input
	P20.9	O0		General-purpose output
	TOUT65	O1		GTM output
	–	O2		Reserved
	SLSO01	O3		QSPI0 output
	SLSO11	O4		QSPI1 output
	–	O5		Reserved
	WDTSLCK	O6		SCU output
	CC61	O7		CCU61 output
E19	P20.10	I	**MP / PU1 / VEXT**	General-purpose input
	TIN66			GTM input
	P20.10	O0		General-purpose output
	TOUT66	O1		GTM output
	ATX1	O2		ASCLIN1 output
	SLSO06	O3		QSPI0 output
	SLSO27	O4		QSPI2 output
	TXDCAN3	O5		CAN node 3 output
	ASCLK1	O6		ASCLIN1 output
	CC62	O7		CCU61 output
E20	P20.11	I	**MP / PU1 / VEXT**	General-purpose input
	TIN67			GTM input
	SCLK0A			QSPI0 input
	P20.11	O0		General-purpose output
	TOUT67	O1		GTM output
	–	O2		Reserved
	SCLK0	O3		QSPI0 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU61 output

Table 2-28 Port 20 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
D19	P20.12	I	**MP / PU1 / VEXT**	General-purpose input
	TIN68			GTM input
	MRST0A			QSPI0 input
	P20.12	O0		General-purpose output
	TOUT68	O1		GTM output
	–	O2		Reserved
	MRST0	O3		QSPI0 output
	MTSR0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	COUT61	O7		CCU61 output
D20	P20.13	I	**MP / PU1 / VEXT**	General-purpose input
	TIN69			GTM input
	$\overline{\text{SLSI0A}}$			QSPI0 input
	P20.13	O0		General-purpose output
	TOUT69	O1		GTM output
	–	O2		Reserved
	SLSO02	O3		QSPI0 output
	SLSO12	O4		QSPI1 output
	SCLK0	O5		QSPI0 output
	–	O6		Reserved
	COUT62	O7		CCU61 output
C20	P20.14	I	**MP / PU1 / VEXT**	General-purpose input
	TIN70			GTM input
	MTSR0A			QSPI0 input
	P20.14	O0		General-purpose output
	TOUT70	O1		GTM output
	–	O2		Reserved
	MTSR0	O3		QSPI0 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-29 Port 21 Functions

Pin	Symbol	Ctrl	Type	Function
K17	P21.0	I	**A2 / PU1 / VDDP3**	General-purpose input
	TIN51			GTM input
	P21.0	O0		General-purpose output
	TOUT51	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHMDC	O6		ETH output
	–	O7		Reserved
	HSM1	HWOUT		HSM output 1
J17	P21.1	I	**A2 / PU1 / VDDP3**	General-purpose input
	TIN52			GTM input
	ETHMDIOB			ETH input (Not for production purposes)
	P21.1	O0		General-purpose output
	TOUT52	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	ETHMDIO	O6		ETH output (Not for production purposes)
	–	O7		Reserved
	HSM2	HWOUT		HSM output 2

Table 2-29 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
K19	P21.2	I	**LVDSH_N/ PU1 / VDDP3**	General-purpose input
	TIN53			GTM input
	MRST2CN			QSPI2 input (LVDS)
	MRST3FN			QSPI3 input (LVDS)
	ARX3GN			ASCLIN3 input (LVDS)
	EMGSTOPB			SCU input
	RXDN			HSCT input (LVDS)
	P21.2	O0		General-purpose output
	TOUT53	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	ETHMDC	O5		ETH output
	–	O6		Reserved
	–	O7		Reserved
J19	P21.3	I	**LVDSH_P/ PU1 / VDDP3**	General-purpose input
	TIN54			GTM input
	MRST2CP			QSPI2 input (LVDS)
	MRST3FP			QSPI3 input (LVDS)
	ARX3GP			ASCLIN3 input (LVDS)
	RXDP			HSCT input (LVDS)
	P21.3	O0		General-purpose output
	TOUT54	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	ETHMDIOD	HWOUT		ETH input/output

Table 2-29 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
K20	P21.4	I	**LVDSH_N/ PU1 / VDDP3**	General-purpose input
	TIN55			GTM input
	P21.4	O0		General-purpose output
	TOUT55	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	TXDN	HSCT		HSCT output (LVDS)
J20	P21.5	I	**LVDSH_P/ PU1 / VDDP3**	General-purpose input
	TIN56			GTM input
	P21.5	O0		General-purpose output
	TOUT56	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	TXDP	HSCT		HSCT output (LVDS)
H17	P21.6	I	**A2 / PU / VDDP3**	General-purpose input
	TIN57			GTM input
	ARX3F			ASCLIN3 input
	$\overline{\text{TGI2}}$			OCDS input
	TDI			OCDS (JTAG) input
	T5EUDA			GPT120 input
	P21.6	O0		General-purpose output
	TOUT57	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	SYSCLK	O5		HSCT output
	–	O6		Reserved
	T3OUT	O7		GPT120 output
	$\overline{\text{TGO2}}$	HWOUT		OCDS; ENx

Table 2-29 Port 21 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
H16	P21.7	I	**A2 / PU / VDDP3**	General-purpose input
	TIN58			GTM input
	DAP2			OCDS input
	$\overline{\text{TGI3}}$			OCDS input
	TDO			OCDS (JTAG) input The JTAG TDO function is overlayed with P21.7 via a double bond. In JTAG mode this pin is used as TDO, after power-on reset it is HighZ. In DAP mode this pin is used as P21.7 and controlled by the related port control logic
	ETHRXERB			ETH input
	T5INA			GPT120 input
	P21.7	O0		General-purpose output
	TOUT58	O1		GTM output
	ATX3	O2		ASCLIN3 output
	ASCLK3	O3		ASCLIN3 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	T6OUT	O7		GPT120 output
	$\overline{\text{TGO3}}$	HWOUT		OCDS; ENx
	TDO			OCDS (JTAG); ENx The JTAG TDO function is overlayed with P21.7 via a double bond. In JTAG mode this pin is used as TDO, after power-on reset it is HighZ. In DAP mode this pin is used as P21.7 and controlled by the related port control logic

Table 2-30 Port 22 Functions

Pin	Symbol	Ctrl	Type	Function
P20	P22.0	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN47			GTM input
	MTSR3E			QSPI3 input
	P22.0	O0		General-purpose output
	TOUT47	O1		GTM output
	ATX3N	O2		ASCLIN3 output (LVDS)
	MTSR3	O3		QSPI3 output
	SCLK3N	O4		QSPI3 output (LVDS)
	FCLN1	O5		MSC1 output (LVDS)
	FCLND1	O6		MSC1 output (LVDS)
	–	O7		Reserved
P19	P22.1	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN48			GTM input
	MRST3E			QSPI3 input
	P22.1	O0		General-purpose output
	TOUT48	O1		GTM output
	ATX3P	O2		ASCLIN3 output (LVDS)
	MRST3	O3		QSPI3 output
	SCLK3P	O4		QSPI3 output (LVDS)
	FCLP1	O5		MSC1 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved
R20	P22.2	I	**LVDSM_N / PU1 / VEXT**	General-purpose input
	TIN49			GTM input
	$\overline{\text{SLSI3D}}$			QSPI3 input
	P22.2	O0		General-purpose output
	TOUT49	O1		GTM output
	–	O2		Reserved
	SLSO312	O3		QSPI3 output
	MTSR3N	O4		QSPI3 output (LVDS)
	SON1	O5		MSC1 output (LVDS)
	SOND1	O6		MSC1 output (LVDS)
	–	O7		Reserved

Table 2-30 Port 22 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
R19	P22.3	I	**LVDSM_P / PU1 / VEXT**	General-purpose input
	TIN50			GTM input
	SCLK3E			QSPI3 input
	P22.3	O0		General-purpose output
	TOUT50	O1		GTM output
	–	O2		Reserved
	SCLK3	O3		QSPI3 output
	MTSR3P	O4		QSPI3 output (LVDS)
	SOP1	O5		MSC1 output (LVDS)
	–	O6		Reserved
	–	O7		Reserved
P16	P22.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN130			GTM input
	P22.4	O0		General-purpose output
	TOUT130	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO012	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
P17	P22.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN131			GTM input
	MTSR0C			QSPI0 input
	P22.5	O0		General-purpose output
	TOUT131	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MTSR0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-30 Port 22 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
N16	P22.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN132			GTM input
	MRST0C			QSPI0 input
	P22.6	O0		General-purpose output
	TOUT132	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MRST0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
N17	P22.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN133			GTM input
	SCLK0C			QSPI0 input
	P22.7	O0		General-purpose output
	TOUT133	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SCLK0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
M16	P22.8	I	**LP / PU1 / VEXT**	General-purpose input
	TIN134			GTM input
	SCLK0B			QSPI0 input
	P22.8	O0		General-purpose output
	TOUT134	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SCLK0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-30 Port 22 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
M17	P22.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN135			GTM input
	MRST0B			QSPI0 input
	P22.9	O0		General-purpose output
	TOUT135	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MRST0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
L16	P22.10	I	**LP / PU1 / VEXT**	General-purpose input
	TIN136			GTM input
	MTSR0B			QSPI0 input
	P22.10	O0		General-purpose output
	TOUT136	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MTSR0	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
L17	P22.11	I	**LP / PU1 / VEXT**	General-purpose input
	TIN137			GTM input
	P22.11	O0		General-purpose output
	TOUT137	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO010	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-31 Port 23 Functions

Pin	Symbol	Ctrl	Type	Function
V20	P23.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN41			GTM input
	P23.0	O0		General-purpose output
	TOUT41	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
U19	P23.1	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN42			GTM input
	SDI10			MSC1 input
	P23.1	O0		General-purpose output
	TOUT42	O1		GTM output
	ARTS1	O2		ASCLIN1 output
	SLSO313	O3		QSPI3 output
	GTMCLK0	O4		GTM output
	–	O5		Reserved
	EXTCLK0	O6		SCU output
	–	O7		Reserved
U20	P23.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN43			GTM input
	P23.2	O0		General-purpose output
	TOUT43	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-31 Port 23 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
T19	P23.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN44			GTM input
	INJ10			MSC1 input
	P23.3	O0		General-purpose output
	TOUT44	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
T20	P23.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN45			GTM input
	P23.4	O0		General-purpose output
	TOUT45	O1		GTM output
	–	O2		Reserved
	SLSO35	O3		QSPI3 output
	END12	O4		MSC1 output
	EN10	O5		MSC1 output
	–	O6		Reserved
	–	O7		Reserved
T17	P23.5	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN46			GTM input
	P23.5	O0		General-purpose output
	TOUT46	O1		GTM output
	–	O2		Reserved
	SLSO34	O3		QSPI3 output
	END13	O4		MSC1 output
	EN11	O5		MSC1 output
	–	O6		Reserved
	–	O7		Reserved

Table 2-31 Port 23 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
R17	P23.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN138			GTM input
	P23.6	O0		General-purpose output
	TOUT138	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO011	O4		QSPI0 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
R16	P23.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN139			GTM input
	P23.7	O0		General-purpose output
	TOUT139	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-32 Port 32 Functions

Pin	Symbol	Ctrl	Type	Function
Y17	P32.0	I	**LP / EVR13 SMPS -> PD, GPIO - > PU / VEXT**	General-purpose input
	TIN36			GTM input
	FDEST			PMU input
	VGATE1N			SMPS mode: analog output. External Pass Device gate control for EVR13
	P32.0	O0		General-purpose output
	TOUT36	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved

Table 2-32 Port 32 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
Y18	P32.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN38			GTM input
	ARX3D			ASCLIN3 input
	RXDCAN3B			CAN node 3 input
	P32.2	O0		General-purpose output
	TOUT38	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	DCDCSYNC	O6		SCU output
	–	O7		Reserved
Y19	P32.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN39			GTM input
	P32.3	O0		General-purpose output
	TOUT39	O1		GTM output
	ATX3	O2		ASCLIN3 output
	–	O3		Reserved
	ASCLK3	O4		ASCLIN3 output
	TXDCAN3	O5		CAN node 3 output
	–	O6		Reserved
	–	O7		Reserved
W18	P32.4	I	**MP+ / PU1 / VEXT**	General-purpose input
	TIN40			GTM input
	ACTS1B			ASCLIN1 input
	SDI12			MSC1 input
	P32.4	O0		General-purpose output
	TOUT40	O1		GTM output
	–	O2		Reserved
	END12	O3		MSC1 output
	GTMCLK1	O4		GTM output
	EN10	O5		MSC1 output
	EXTCLK1	O6		SCU output
	COUT63	O7		CCU60 output

Table 2-32 Port 32 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
T15	P32.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN140			GTM input
	P32.5	O0		General-purpose output
	TOUT140	O1		GTM output
	ATX2	O2		ASCLIN2 output
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	TXDCAN2	O6		CAN node 2 output
	–	O7		Reserved
U15	P32.6	I	**LP / PU1 / VEXT**	General-purpose input
	$\overline{\text{TGI4}}$			OCDS input
	TIN141			GTM input
	RXDCAN2C			CAN node 2 input
	ARX2F			ASCLIN2 input
	P32.6	O0		General-purpose output
	TOUT141	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO212	O4		QSPI2 output
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO4}}$	HWOUT		OCDS; ENx
U16	P32.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN142			GTM input
	$\overline{\text{TGI5}}$			OCDS input
	P32.7	O0		General-purpose output
	TOUT142	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	–	O7		Reserved
	$\overline{\text{TGO5}}$	HWOUT		OCDS; ENx

Table 2-33 Port 33 Functions

Pin	Symbol	Ctrl	Type	Function
W10	P33.0	I	**LP / PU1 / VEXT**	General-purpose input
	TIN22			GTM input
	DSITR0E			DSADC channel 0 input E
	P33.0	O0		General-purpose output
	TOUT22	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	VADCG2BFL0	O6		VADC output
	–	O7		Reserved
Y10	P33.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN23			GTM input
	PSIRX0C			PSI5 input
	SENT9C			SENT input
	DSCIN2B			DSADC channel 2 input B
	DSITR1E			DSADC channel 1 input E
	P33.1	O0		General-purpose output
	TOUT23	O1		GTM output
	ASLSO3	O2		ASCLIN3 output
	–	O3		Reserved
	DSCOUT2	O4		DSADC channel 2 output
	VADCEMUX02	O5		VADC output
	VADCG2BFL1	O6		VADC output
	–	O7		Reserved
W11	P33.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN24			GTM input
	SENT8C			SENT input
	DSDIN2B			DSADC channel 2 input B
	DSITR2E			DSADC channel 2 input E
	P33.2	O0		General-purpose output
	TOUT24	O1		GTM output
	ASCLK3	O2		ASCLIN3 output
	–	O3		Reserved
	PSITX0	O4		PSI5 output
	VADCEMUX01	O5		VADC output
	VADCG2BFL2	O6		VADC output
	–	O7		Reserved

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
Y11	P33.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN25			GTM input
	PSIRX1C			PSI5 input
	SENT7C			SENT input
	DSCIN1B			DSADC channel 1 input B
	P33.3	O0		General-purpose output
	TOUT25	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	DSCOUT1	O4		DSADC channel 1 output
	VADCEMUX00	O5		VADC output
	VADCG2BFL3	O6		VADC output
	–	O7		Reserved
W12	P33.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN26			GTM input
	SENT6C			SENT input
	$\overline{\text{CTRAPC}}$			CCU61 input
	DSDIN1B			DSADC channel 1 input B
	DSITR0F			DSADC channel 0 input F
	P33.4	O0		General-purpose output
	TOUT26	O1		GTM output
	ARTS2	O2		ASCLIN2 output
	–	O3		Reserved
	PSITX1	O4		PSI5 output
	VADCEMUX12	O5		VADC output
	VADCG0BFL0	O6		VADC output
	–	O7		Reserved

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
Y12	P33.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN27			GTM input
	ACTS2B			ASCLIN2 input
	PSIRX2C			PSI5 input
	PSISRXC			PSI5-S input
	SENT5C			SENT input
	CCPOS2C			CCU61 input
	T4EUDB			GPT120 input
	DSCIN0B			DSADC channel 0 input B
	DSITR1F			DSADC channel 1 input F
	P33.5	O0		General-purpose output
	TOUT27	O1		GTM output
	SLSO07	O2		QSPI0 output
	SLSO17	O3		QSPI1 output
	DSCOUT0	O4		DSADC channel 0 output
	VADCEMUX11	O5		VADC output
	VADCG0BFL1	O6		VADC output
	–	O7		Reserved
W13	P33.6	I	**LP / PU1 / VEXT**	General-purpose input
	TIN28			GTM input
	SENT4C			SENT input
	CCPOS1C			CCU61 input
	T2EUDB			GPT120 input
	DSDIN0B			DSADC channel 0 input B
	DSITR2F			DSADC channel 2 input F
	P33.6	O0		General-purpose output
	TOUT28	O1		GTM output
	ASLSO2	O2		ASCLIN2 output
	-	O3		Reserved
	PSITX2	O4		PSI5 output
	VADCEMUX10	O5		VADC output
	VADCG1BFL0	O6		VADC output
	PSISTX	O7		PSI5-S output

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
Y13	P33.7	I	**LP / PU1 / VEXT**	General-purpose input
	TIN29			GTM input
	RXDCAN0E			CAN node 0 input
	REQ8			SCU input
	CCPOS0C			CCU61 input
	T2INB			GPT120 input
	P33.7	O0		General-purpose output
	TOUT29	O1		GTM output
	ASCLK2	O2		ASCLIN2 output
	SLSO37	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	VADCG1BFL1	O6		VADC output
	–	O7		Reserved
W14	P33.8	I	**MP / HighZ/ VEXT**	General-purpose input
	TIN30			GTM input
	ARX2E			ASCLIN2 input
	EMGSTOPA			SCU input
	P33.8	O0		General-purpose output
	TOUT30	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO32	O3		QSPI3 output
	–	O4		Reserved
	TXDCAN0	O5		CAN node 0 output
	–	O6		Reserved
	COUT62	O7		CCU61 output
	SMUFSP	HWOUT		SMU
Y14	P33.9	I	**LP / PU1 / VEXT**	General-purpose input
	TIN31			GTM input
	P33.9	O0		General-purpose output
	TOUT31	O1		GTM output
	ATX2	O2		ASCLIN2 output
	SLSO31	O3		QSPI3 output
	ASCLK2	O4		ASCLIN2 output
	–	O5		Reserved
	–	O6		Reserved
	CC62	O7		CCU61 output

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
W15	P33.10	I	**MP / PU1 / VEXT**	General-purpose input
	TIN32			GTM input
	SLSI3C			QSPI3 input
	P33.10	O0		General-purpose output
	TOUT32	O1		GTM output
	SLSO16	O2		QSPI1 output
	SLSO311	O3		QSPI3 output
	ASLSO1	O4		ASCLIN1 output
	PSISCLK	O5		PSI5-S output
	–	O6		Reserved
	COUT61	O7		CCU61 output
Y15	P33.11	I	**MP / PU1 / VEXT**	General-purpose input
	TIN33			GTM input
	SCLK3D			QSPI3 input
	P33.11	O0		General-purpose output
	TOUT33	O1		GTM output
	ASCLK1	O2		ASCLIN1 output
	SCLK3	O3		QSPI3 output
	–	O4		Reserved
	–	O5		Reserved
	DSCGPWMN	O6		DSADC output
	CC61	O7		CCU61 output
W16	P33.12	I	**MP / PU1 / VEXT**	General-purpose input
	TIN34			GTM input
	MTSR3D			QSPI3 input
	P33.12	O0		General-purpose output
	TOUT34	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MTSR3	O3		QSPI3 output
	ASCLK1	O4		ASCLIN1 output
	–	O5		Reserved
	DSCGPWMP	O6		DSADC output
	COUT60	O7		CCU61 output

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
Y16	P33.13	I	**MP / PU1 / VEXT**	General-purpose input
	TIN35			GTM input
	ARX1F			ASCLIN1 input
	MRST3D			QSPI3 input
	DSSGNB			DSADC input
	INJ11			MSC1 input
	P33.13	O0		General-purpose output
	TOUT35	O1		GTM output
	ATX1	O2		ASCLIN1 output
	MRST3	O3		QSPI3 output
	SLSO26	O4		QSPI2 output
	–	O5		Reserved
	DCDCSYNC	O6		SCU output
	CC60	O7		CCU61 output
T14	P33.14	I	**LP / PU1 / VEXT**	General-purpose input
	TIN143			GTM input
	$\overline{\text{TGI6}}$			OCDS input
	SCLK2D			QSPI2 input
	P33.14	O0		General-purpose output
	TOUT143	O1		GTM output
	–	O2		Reserved
	SCLK2	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	CC62	O7		CCU60 output
	$\overline{\text{TGO6}}$	HWOUT		OCDS; ENx

Table 2-33 Port 33 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
U14	P33.15	I	**LP / PU1 / VEXT**	General-purpose input
	TIN144			GTM input
	$\overline{\text{TGI7}}$			OCDS input
	P33.15	O0		General-purpose output
	TOUT144	O1		GTM output
	–	O2		Reserved
	SLSO211	O3		QSPI2 output
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	COUT62	O7		CCU60 output
	$\overline{\text{TGO7}}$	HWOUT		OCDS; ENx

Table 2-34 Port 34 Functions

Pin	Symbol	Ctrl	Type	Function
U11	P34.1	I	**LP / PU1 / VEXT**	General-purpose input
	TIN146			GTM input
	P34.1	O0		General-purpose output
	TOUT146	O1		GTM output
	ATX0	O2		ASCLIN0 output
	–	O3		Reserved
	TXDCAN0	O4		CAN node 0 output
	–	O5		Reserved
	–	O6		Reserved
	COUT63	O7		CCU60 output
T12	P34.2	I	**LP / PU1 / VEXT**	General-purpose input
	TIN147			GTM input
	ARX0D			ASCLIN0 input
	RXDCAN0G			CAN node 0 input
	P34.2	O0		General-purpose output
	TOUT147	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	–	O4		Reserved
	–	O5		Reserved
	–	O6		Reserved
	CC60	O7		CCU60 output

Table 2-34 Port 34 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
U12	P34.3	I	**LP / PU1 / VEXT**	General-purpose input
	TIN148			GTM input
	P34.3	O0		General-purpose output
	TOUT148	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	SLSO210	O4		QSPI2 output
	–	O5		Reserved
	–	O6		Reserved
	COUT60	O7		CCU60 output
T13	P34.4	I	**LP / PU1 / VEXT**	General-purpose input
	TIN149			GTM input
	MRST2D			QSPI2 input
	P34.4	O0		General-purpose output
	TOUT149	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MRST2	O4		QSPI2 output
	–	O5		Reserved
	–	O6		Reserved
	CC61	O7		CCU60 output
U13	P34.5	I	**LP / PU1 / VEXT**	General-purpose input
	TIN150			GTM input
	MTSR2D			QSPI2 input
	P34.5	O0		General-purpose output
	TOUT150	O1		GTM output
	–	O2		Reserved
	–	O3		Reserved
	MTSR2	O4		QSPI2 output
	–	O5		Reserved
	–	O6		Reserved
	COUT61	O7		CCU60 output

Table 2-35 Port 40 Functions

Pin	Symbol	Ctrl	Type	Function
W2	P40.0	I	**S / HighZ / VDDM**	General-purpose input
	VADCG3.0			VADC analog input channel 0 of group 3
	DS2PB			DSADC: positive analog input channe of DSADC 2, pin B
	CCPOS0D			CCU60 input
	SENT0A			SENT input
W1	P40.1	I	**S / HighZ / VDDM**	General-purpose inpu.t
	VADCG3.1			VADC analog input channel 1 of group 3 (MD)
	DS2NB			DSADC: negative analog of input channel 2, pin B
	CCPOS1B			CCU60 input
	SENT1A			SENT input
V2	P40.2	I	**S / HighZ / VDDM**	General-purpose inpu.t
	VADCG3.2			VADC analog input channel 2 of group 3 (MD)
	CCPOS1D			CCU60 input
	SENT2A			SENT input
V1	P40.3	I	**S / HighZ / VDDM**	General-purpose input
	VADCG3.3			VADC analog input channel 3 of group 3 (with pull down diagnostics)
	CCPOS2B			CCU60 input
	SENT3A			SENT input
P4	P40.4	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.0			VADC analog input channel 0 of group 4
	CCPOS2D			CCU60 input
	SENT4A			SENT input
R1	P40.5	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.1			VADC analog input channel 1 of group 4 (MD)
	CCPOS0D			CCU61 input
	SENT5A			SENT input
N4	P40.6	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.4			VADC analog input channel 4 of group 4
	DS3PA			DSADC: positive analog input of channel 3, pin A
	CCPOS1B			CCU61 input
	SENT6A			SENT input
P2	P40.7	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.5			VADC analog input channel 5 of group 4
	DS3NA			DSADC: negative analog input of channel 3, pin A
	CCPOS1D			CCU61 input
	SENT7A			SENT input

Table 2-35 Port 40 Functions (cont'd)

Pin	Symbol	Ctrl	Type	Function
N5	P40.8	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.6			VADC analog input channel 6 of group 4
	DS3PB			DSADC: positive analog input of channel 3, pin B
	CCPOS2B			CCU61 input
	SENT8A			SENT input
P1	P40.9	I	**S / HighZ / VDDM**	General-purpose input
	VADCG4.7			VADC analog input channel 7 of group 4
	DS3NB			DSADC: negative analog input of channel 3, pin B
	CCPOS2D			CCU61 input
	SENT9A			SENT input

Table 2-36 Analog Inputs

Pin	Symbol	Ctrl	Type	Function
T10	AN0	I	**D / HighZ / VDDM**	Analog input 0
	VADCG0.0			VADC analog input channel 0 of group 0
	DS1PA			DSADC: positive analog of input channel 1, pin A
U10	AN1	I	**D / HighZ / VDDM**	Analog input 1
	VADCG0.1			VADC analog input channel 1 of group 0 (MD)
	DS1NA			DSADC: negative analog input of channel 1, pin A
W9	AN2	I	**D / HighZ / VDDM**	Analog input 2
	VADCG0.2			VADC analog input channel 2 of group 0 (MD)
	DS0PA			DSADC: positive analog input of channel 0, pin A
U9	AN3	I	**D / HighZ / VDDM**	Analog input 3
	VADCG0.3			VADC analog input channel 3 of group 0
	DS0NA			DSADC: negative analog input of channel 0, pin A
T9	AN4	I	**D / HighZ / VDDM**	Analog input 4
	VADCG0.4			VADC analog input channel 4 of group 0
Y9	AN5	I	**D / HighZ / VDDM**	Analog input 5
	VADCG0.5			VADC analog input channel 5 of group 0
T8	AN6	I	**D / HighZ / VDDM**	Analog input 6
	VADCG0.6			VADC analog input channel 6 of group 0
U8	AN7	I	**D / HighZ / VDDM**	Analog input 7
	VADCG0.7			VADC analog input channel 7 of group 0 (with pull down diagnostics)
W8	AN8	I	**D / HighZ / VDDM**	Analog input 8
	VADCG1.0			VADC analog input channel 0 of group 1

Table 2-36 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
U7	AN9	I	**D / HighZ / VDDM**	Analog input 9
	VADCG1.1			VADC analog input channel 1 of group 1 (MD)
Y8	AN10	I	**D / HighZ / VDDM**	Analog input 10
	VADCG1.2			VADC analog input channel 2 of group 1 (MD)
W7	AN11	I	**D / HighZ / VDDM**	Analog input 11
	VADCG1.3			VADC analog input channel 3 of group 1 (with pull down diagnostics)
T7	AN12	I	**D / HighZ / VDDM**	Analog input 12
	VADCG1.4			VADC analog input channel 4 of group 1
W6	AN13	I	**D / HighZ / VDDM**	Analog input 13
	VADCG1.5			VADC analog input channel 5 of group 1
U6	AN14	I	**D / HighZ / VDDM**	Analog input 14
	VADCG1.6			VADC analog input channel 6 of group 1
T6	AN15	I	**D / HighZ / VDDM**	Analog input 15
	VADCG1.7			VADC analog input channel 7 of group 1
W5	AN16	I	**D / HighZ / VDDM**	Analog input 16
	VADCG2.0			VADC analog input channel 0 of group 2
U5	AN17	I	**D / HighZ / VDDM**	Analog input 17
	VADCG2.1			VADC analog input channel 1 of group 2 (MD)
W4	AN18	I	**D / HighZ / VDDM**	Analog input 18
	VADCG2.2			VADC analog input channel 2 of group 2 (MD)
W3	AN19	I	**D / HighZ / VDDM**	Analog input 19
	VADCG2.3			VADC analog input channel 3 of group 2 (with pull down diagnostics)
Y3	AN20	I	**D / HighZ / VDDM**	Analog input 20
	VADCG2.4	I		VADC analog input channel 4 of group 2
	DS2PA	I		DSADC: positive analog input of channel 2, pin A
Y2	AN21	I	**D / HighZ / VDDM**	Analog input 21
	VADCG2.5	I		VADC analog input channel 5 of group 2
	DS2NA	I		DSADC: negative analog input of channel of DSADC 2, pin A
T5	AN22	I	**D / HighZ / VDDM**	Analog input 22
	VADCG2.6			VADC analog input channel 6 of group 2

Table 2-36 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
R5	AN23	I	**D / HighZ / VDDM**	Analog input 23
	VADCG2.7			VADC analog input channel 7 of group 2
W2	AN24	I	**S / HighZ / VDDM**	Analog input 24
	VADCG3.0			VADC analog input channel 0 of group 3
	DS2PB			DSADC: positive analog input of channel 2, pin B
	SENT0A			SENT input channel 0, pin A
W1	AN25	I	**S / HighZ / VDDM**	Analog input 24
	VADCG3.1			VADC analog input channel 1 of group 3 (MD)
	DS2NB			DSADC: negative analog input of channel 2, pin B
	SENT1A			SENT input channel 1, pin A
V2	AN26	I	**S / HighZ / VDDM**	Analog input 26
	VADCG3.2			VADC analog input channel 2 of group 3 (MD)
	SENT2A			SENT input channel 2, pin A
V1	AN27	I	**S / HighZ / VDDM**	Analog input 27
	VADCG3.3			VADC analog input channel 3 of group 3 (with pull down diagnostics)
	SENT3A			SENT input channel 3, pin A
U2	AN28	I	**D / HighZ / VDDM**	Analog input 28
	VADCG3.4			VADC analog input channel 4 of group 3
U1	AN29	I	**D / HighZ / VDDM**	Analog input 29
	VADCG3.5			VADC analog input channel 5 of group 3
T4	AN30	I	**D / HighZ / VDDM**	Analog input 30
	VADCG3.6			VADC analog input channel 6 of group 3
R4	AN31	I	**D / HighZ / VDDM**	Analog input 31
	VADCG3.7			VADC analog input channel 7 of group 3
P4	AN32	I	**S / HighZ / VDDM**	Analog input 32
	VADCG4.0			VADC analog input channel 0 of group 4
	SENT4A			SENT input channel 4, pin A
R1	AN33	I	**S / HighZ / VDDM**	Analog input 33
	VADCG4.1			VADC analog input channel 1 of group 4 (MD)
	SENT5A			SENT input channel 5, pin A
P5	AN34	I	**D / HighZ / VDDM**	Analog input 34
	VADCG4.2			VADC analog input channel 2 of group 4 (MD)

Table 2-36 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
R2	AN35	I	**D / HighZ / VDDM**	Analog input 35
	VADCG4.3			VADC analog input channel 3 of group 4 (with pull down diagnostics)
N4	AN36	I	**S / HighZ / VDDM**	Analog input 34
	VADCG4.4			VADC analog input channel 4 of group 4
	DS3PA			DSADC: positive analog input of channel of DSADC 3, pin A
	SENT6A			SENT input channel 6, pin A
P2	AN37	I	**S / HighZ / VDDM**	Analog input 37
	VADCG4.5			VADC analog input channel 5 of group 4
	DS3NA			DSADC: negative analog input of channel of DSADC 3, pin A
	SENT7A			SENT input channel 7, pin A
N5	AN38	I	**S / HighZ / VDDM**	Analog input 38
	VADCG4.6			VADC analog input channel 6 of group 4
	DS3PB			DSADC: positive analog input of channel of DSADC 3, pin B
	SENT8A			SENT input channel 8, pin A
P1	AN39	I	**S / HighZ / VDDM**	Analog input 39
	VADCG4.7			VADC analog input channel 7 of group 4
	DS3NB			DSADC: negative analog input of channel of DSADC 3, pin B
	SENT9A			SENT input channel 9, pin A
M5	AN40	I	**D / HighZ / VDDM**	Analog input 40
	VADCG5.0			VADC analog input channel 0 of group 5
M4	AN41	I	**D / HighZ / VDDM**	Analog input 41
	VADCG5.1			VADC analog input channel 1 of group 5 (MD)
L5	AN42	I	**D / HighZ / VDDM**	Analog input 42
	VADCG5.2			VADC analog input channel 2 of group 5 (MD)
L4	AN43	I	**D / HighZ / VDDM**	Analog input 43
	VADCG5.3			VADC analog input channel 3 of group 5 (with pull down diagnostics)
N1	AN44	I	**D / HighZ / VDDM**	Analog input 44
	VADCG5.4			VADC analog input channel 4 of group 5
	DS3PC			DSADC: positive analog input of channel of DSADC 3, pin C

Table 2-36 Analog Inputs (cont'd)

Pin	Symbol	Ctrl	Type	Function
N2	AN45	I	**D / HighZ / VDDM**	Analog input 45
	VADCG5.5			VADC analog input channel 5 of group 5
	DS3NC			DSADC: negative analog input of channel of DSADC 3, pin C
M1	AN46	I	**D / HighZ / VDDM**	Analog input 46
	VADCG5.6			VADC analog input channel 6 of group 5
	DS3PD			DSADC: positive analog input of channel of DSADC 3, pin D
M2	AN47	I	**D / HighZ / VDDM**	Analog input 47
	VADCG5.7			VADC analog input channel 7 of group 5
	DS3ND			DSADC: negative analog input of channel of DSADC 3, pin D

Table 2-37 System I/O

Pin	Symbol	Ctrl	Type	Function
G17	$\overline{\text{PORST}}$	I	**I / PD / VEXT**	Power On Reset Input Additional strong PD in case of power fail.
F16	$\overline{\text{ESR0}}$	I/O	**MP / OD / VEXT**	External System Request Reset 0 Default configuration during and after reset is open-drain driver. The driver drives low during power-on reset. This is valid additionally after deactivation of $\overline{\text{PORST}}$ until the internal reset phase has finished. See also SCU chapter for details. Default after power-on can be different. See also SCU chapter ´Reset Control Unit´ and SCU_IOCR register description.
	EVRWUP	I		EVR Wakeup Pin
G16	$\overline{\text{ESR1}}$	I/O	**MP / PU1 / VEXT**	External System Request Reset 1 Default NMI function. See also SCU chapter ´Reset Control Unit´ and SCU_IOCR register description.
	EVRWUP	I		EVR Wakeup Pin
W17	VGATE1P	O	**VGATE1P / - / VEXT**	External Pass Device gate control for EVR13
K16	TMS	I	**A2 / PD / VDDP3**	JTAG Module State Machine Control Input
	DAP1	I/O		Device Access Port Line 1
L19	$\overline{\text{TRST}}$	I	**A2 / PD / VDDP3**	JTAG Module Reset/Enable Input

Table 2-37 System I/O (cont'd)

Pin	Symbol	Ctrl	Type	Function
J16	TCK	I	**A2 / PD / VDDP3**	JTAG Module Clock Input
	DAP0	I		Device Access Port Line 0
M20	XTAL1	I	**XTAL1 / - / VDDP3**	Main Oscillator/PLL/Clock Generator Input
M19	XTAL2	O	**XTAL2 / - / VDDP3**	Main Oscillator/PLL/Clock Generator Output

Table 2-38 Supply

Pin	Symbol	Ctrl	Type	Function
Y6	VAREF1	I	**Vx**	Positive Analog Reference Voltage 1
Y7	VAGND1	I	**Vx**	Negative Analog Reference Voltage 1
T1	VAREF2	I	**Vx**	Positive Analog Reference Voltage 2
T2	VAGND2	I	**Vx**	Negative Analog Reference Voltage 2
Y5	VDDM	I	**Vx**	ADC Analog Power Supply (3.3V / 5V)
G8, H7	VDD / VDDSB	I	**Vx**	Emulation Device: Emulation SRAM Standby Power Supply (1.3V) (Emulation Device only). Production Device: VDD (1.3V).
P8, P13, N7, N14, H14, G13	VDD	I	**Vx**	Digital Core Power Supply (1.3V)
N19	VDD	I	**Vx**	Digital Core Power Supply (1.3V). The supply pin inturn supplies the main XTAL Oscillator/PLL (1.3V) . A higher decoupling capacitor is therefore recommended to the VSS pin for better noise immunity.
A2, B3, V19, W20	VEXT	I	**Vx**	External Power Supply (5V / 3.3V)
B18, A19	VDDP3	I	**Vx**	Digital Power Supply for Flash (3.3V). Can be also used as external 3.3V Power Supply for VFLEX.
N20	VDDP3	I	**Vx**	Digital Power Supply for Oscillator, LVDSH and A2 pads (3.3V). The supply pin inturn supplies the main XTAL Oscillator/PLL (3.3V) . A higher decoupling capacitor is therefore recommended to the VSS pin for better noise immunity.

Table 2-38 Supply (cont'd)

Pin	Symbol	Ctrl	Type	Function
E15, D16	VDDFL3	I	**Vx**	Flash Power Supply (3.3V)
D5	VFLEX	I	**Vx**	Digital Power Supply for Flex Port Pads (5V / 3.3V)
Y4	VSSM	I	**Vx**	Analog Ground for VDDM
T11	VEVRSB	I	**Vx**	Standby Power Supply (3.3V/5V) for the Standby SRAM (CPU0.DSPR). If Standby mode is not used: To be handled like VEXT (3.3V/5V).
B2, D4, E5, L20, T16, U17, W19, Y20	VSS	I	**Vx**	Digital Ground
E16, D17, B19, A20	VSS	I	**Vx**	Digital Ground (outer balls)
P9, P12, N9, N10, N11, N12	VSS	I	**Vx**	Digital Ground (center balls)
M7, M8, M10, M11, M13, M14	VSS	I	**Vx**	Digital Ground (center balls)
L8, L9, L10, L11, L12, L13	VSS	I	**Vx**	Digital Ground (center balls)
K8, K9, K10, K11, K12, K13	VSS	I	**Vx**	Digital Ground (center balls)
J7, J8, J10, J11, J13, J14	VSS	I	**Vx**	Digital Ground (center balls)
H9, H10, H11, H12, G9, G10, G11, G12	VSS	I	**Vx**	Digital Ground (center balls)
P10	VSS	I	**Vx**	Digital Ground (center balls) This ball is used in the Emulation Device as AGBT TX0N
P11	VSS	I	**Vx**	Digital Ground (center balls) This ball is used in the Emulation Device as AGBT TX0P
L7	VSS	I	**Vx**	Digital Ground (center balls) This ball is used in the Emulation Device as AGBT CLKN

Table 2-38 Supply (cont'd)

Pin	Symbol	Ctrl	Type	Function
K7	VSS	I	**Vx**	Digital Ground (center balls) This ball is used in the Emulation Device as AGBT CLKP
L14	VSS	I	**Vx**	Digital Ground (center balls) This ball is used in the Emulation Device as AGBT ERR
K14	NC / VDDPSB	I	**NCVDDPSB**	Emulation Device: Power Supply (3.3V) for DAP/JTAG pad group. Can be connected to VDDP or can be left unsupplied (see document ´AurixED´ / Aurix Emulation Devices specification). Production Device: This pin is not connected on package level. It can be connected on PCB level to VDDP or Ground or can be left unsupplied.
A1, Y1, U4	NC	I	**NC**	Not Connected. These pins are not connected on package level and will not be used for future extensions.

Legend:

Column "**Ctrl.**":

I = Input (for GPIO port Lines with IOCR bit field Selection PCx = $0XXX_B$)

O = Output
O0 = Output with IOCR bit field selection PCx = $1X000_B$
O1 = Output with IOCR bit field selection PCx = $1X001_B$ (ALT1)
O2 = Output with IOCR bit field selection PCx = $1X010_B$ (ALT2)
O3 = Output with IOCR bit field selection PCx = $1X011_B$ (ALT3)
O4 = Output with IOCR bit field selection PCx = $1X100_B$ (ALT4)
O5 = Output with IOCR bit field selection PCx = $1X101_B$ (ALT5)
O6 = Output with IOCR bit field selection PCx = $1X110_B$ (ALT6)
O7 = Output with IOCR bit field selection PCx = $1X111_B$ (ALT7)

Column "**Type**":

LP = Pad class LP (5V/3.3V, LVTTL)
MP = Pad class MP (5V/3.3V, LVTTL)
MP+ = Pad class MP+ (5V/3.3V, LVTTL)
MPR = Pad class MPR (5V/3.3V, LVTTL)
A2 = Pad class A2 (3.3V, LVTTL)
LVDSM = Pad class LVDSM (LVDS/CMOS 5V/3.3V)
LVDSH = Pad class LVDSH (LVDS/CMOS 3.3V)
S = Pad class S (ADC overlayed with General Purpose Input)
D = Pad class D (ADC)
PU = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)
PU1 = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]

1) The default state of GPIOs (Px.y) during and after $\overline{\text{PORST}}$ active is controllled via HWCFG[6] (P14.4). HWCFG[6] has a weak internal pull-up active at start-up if the pin is left unconnected.See also User´s Manual, "Introduction Chapter", "General Purpose I/O Ports and Peripheral I/O Lines", Figure: "Default state of port pins during and after reset".

PD = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)
PD1 = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]
PX = Behavior depends on usage: PD in EVR13 SMPS Mode and PU1 in GPIO Mode
OD = open drain during reset ($\overline{\text{PORST}}$ = 0)
HighZ = tri-state during reset ($\overline{\text{PORST}}$ = 0)
$\overline{\text{PORST}}$ = $\overline{\text{PORST}}$ input pad
XTAL1 = XTAL1 input pad
XTAL2 = XTAL2 input pad
VGATE1P = VGATE1P
VGATE3P = VGATE3P
Vx = Supply
NC = These pins are reserved for future extensions and shall not be connected externally
NC1 = These pins are not connected on package level and will not be used for future extensions
NCVDDPSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.
NCVDDSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.

2.2.2 Emergency Stop Function

The Emergency Stop function can be used to force GPIOs (General Purpose Inputs/Outputs) via an external input signal (EMGSTOPA or EMGSTOPB) into a defined state:

- Input state and
- PU or High-Z depending on HWCFG[6] level latched during $\overline{\text{PORST}}$ active

Control of the Emergency Stop function:

- The Emergency Stop function can be enabled/disabled in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- The Emergency Stop input signal, EMGSTOPA (P33.8) / EMGSTOPB (P21.2) , can selected in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- On port level, each GPIO can be enabled/disabled for the Emergency Stop function via the Px_ESR (Port x Emergency Stop) registers in the port control logic (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, “Emergency Stop Register”).

The Emergency Stop function is available for all GPIO Ports with the following exceptions:

- Not available for P20.2 (General Purpose Input/GPI only, overlayed with Testmode)
- Not available for P40.x (analoge input ANx overlayed with GPI)
- Not available for P32.0 EVR13 SMPS mode.
- Not available for dedicated I/O without General Purpose Output function (e.g ESRx, TMS, TCK)

The Emergency Stop function can be overruled on the following GPIO Ports:

- P00.x: Emergency Stop can be overruled by the VADC. Overruling can be disabled via the control register P00_SCR (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, P00)
- P14.0 and P14.1: Emergency Stop can be overruled in the DXCPL mode (DAP over can physical layer mode). No Overruling in the DXCM (Debug over can message) mode
- P21.6: Emergency Stop can be overruled in JTAG mode if this pin is used as TDI
- P21.7: Emergency Stop can be overruled in JTAG or Three Pin DAP mode

2) If HWCFG[6] is left unconnected or is externally pulled high, weak internal pull-ups (PU1) / pull-downs (PD1) are active during and after reset.

3) If HWCFG[6] is connected to ground, the PD1 / PU1 pins are predominantly in HighZ during and after reset.

- P20.0: Emergency Stop can be overruled in JTAG mode if this GPIO is used as TDI

2.2.3 Pull-Up/Pull-Down Reset Behavior of the Pins

Table 2-39 List of Pull-Up/Pull-Down Reset Behavior of the Pins

Pins	$\overline{\text{PORST}}$ = 0	$\overline{\text{PORST}}$ = 1
all GPIOs	Pull-up if HWCFG[6] = 1 or High-Z if HWCFG[6] = 0	
$\overline{\text{TDI}}$, $\overline{\text{TESTMODE}}$	Pull-up	
$\overline{\text{PORST}}$[1)]	Pull-down with I_{PORST} relevant	Pull-down with I_{PDLI} relevant
$\overline{\text{TRST}}$, TCK, TMS	Pull-down	
$\overline{\text{ESR0}}$	The open-drain driver is used to drive low.[2)]	Pull-up[3)]
$\overline{\text{ESR1}}$	Pull-up[3)]	
TDO	Pull-up	High-Z/Pull-up[4)]

1) Pull-down with I_{PORST} relevant is always activated when a primary supply monitor detects a violation.

2)Valid additionally after deactivation of $\overline{\text{PORST}}$ until the internal reset phase has finished. See the SCU chapter for details.

3) See the SCU_IOCR register description.

4) Depends on JTAG/DAP selection with $\overline{\text{TRST}}$.

In case of leakage test ($\overline{\text{PORST}}$ = 0 and $\overline{\text{TESTMODE}}$ = 0), the pull-down of the $\overline{\text{TRST}}$ pin is switched off. In case of an user application ($\overline{\text{TESTMODE}}$ = 1), the pull-down of the $\overline{\text{TRST}}$ is always switched on.

2.3 TC270x Bare Die Pad Definition

The TC270x Bare Die Logic Symbol is shown in **Figure 2-3**.

Table 2-40 describes the pads of the TC270x Bare Die. It describes also the mapping of VADC / DS-ADC channels to the analog inputs (ANx) and the mapping of Port functions to the pads.

Note: The detailed description of the port functions (Px.y) can be found in the User's Manual chapter "General Purpose I/O Ports and Peripheral I/O LInes (Ports)".

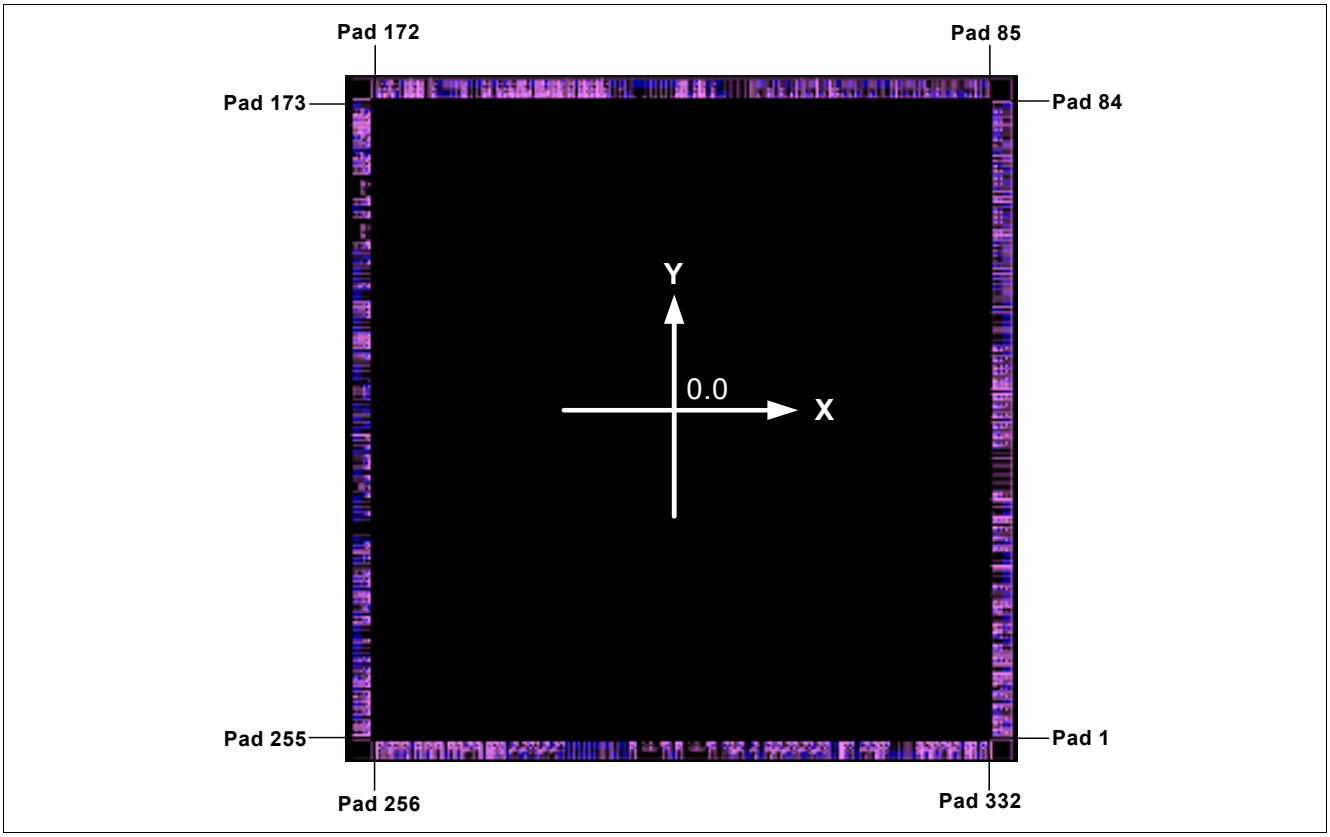


Figure 2-3 TC270x Logic Symbol for the Bare Die.

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
1	P10.8	LP / PU1 / VEXT	3265500	-3460000	GPIO
2	P02.0	MP+ / PU1 / VEXT	3374000	-3380000	GPIO
3	P02.9	LP / PU1 / VEXT	3265500	-3300000	GPIO
4	P02.1	LP / PU1 / VEXT	3265500	-3200000	GPIO
5	VSS	Vx	3374000	-3125000	Must be bonded to VSS
6	P02.10	LP / PU1 / VEXT	3265500	-3050000	GPIO
7	P02.2	MP+ / PU1 / VEXT	3374000	-2950000	GPIO
8	P02.11	LP / PU1 / VEXT	3265500	-2850000	GPIO
9	VEXT	Vx	3374000	-2775000	Must be bonded to VEXT
10	P02.3	LP / PU1 / VEXT	3265500	-2670000	GPIO

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
11	P02.4	MP+ / PU1 / VEXT	3265500	-2540000	GPIO
12	VSS	Vx	3374000	-2465000	Must be bonded to VSS
13	P02.5	MP+ / PU1 / VEXT	3265500	-2390000	GPIO
14	P02.6	MP / PU1 / VEXT	3374000	-2300000	GPIO
15	VEXT	Vx	3374000	-2195000	Must be bonded to VEXT
16	P02.7	MP / PU1 / VEXT	3265500	-2110000	GPIO
17	P02.8	LP / PU1 / VEXT	3374000	-2040000	GPIO
18	VSS	Vx	3374000	-1940000	Must be bonded to VSS
19	P01.3	LP / PU1 / VEXT	3265500	-1883500	GPIO
20	VDD	Vx	3374000	-1818500	Must be bonded to VDD
21	VSS	Vx	3374000	-1688500	Must be bonded to VSS
22	VSS	Vx	3374000	-1644500	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 22.
23	VDD	Vx	3374000	-1514500	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 21.
24	P01.4	LP / PU1 / VEXT	3265500	-1449500	GPIO
25	VSS	Vx	3374000	-1394500	Must be bonded to VSS
26	P01.5	LP / PU1 / VEXT	3265500	-1339500	GPIO
27	P01.6	LP / PU1 / VEXT	3265500	-1239500	GPIO
28	P01.7	LP / PU1 / VEXT	3265500	-1139500	GPIO
29	VEXT	Vx	3374000	-1068500	Must be bonded to VEXT
30	VSS	Vx	3374000	-968500	Must be bonded to VSS
31	P00.0	MP / PU1 / VEXT	3265500	-868500	GPIO
32	P00.1	LP / PU1 / VEXT	3265500	-241000	GPIO
33	P00.2	LP / PU1 / VEXT	3265500	-141000	GPIO
34	P00.3	LP / PU1 / VEXT	3265500	-41000	GPIO
35	VSS	Vx	3374000	19000	Must be bonded to VSS
36	P00.4	LP / PU1 / VEXT	3265500	79000	GPIO
37	P00.5	LP / PU1 / VEXT	3265500	179000	GPIO
38	P00.6	LP / PU1 / VEXT	3265500	279000	GPIO
39	VEXT	Vx	3374000	339000	Must be bonded to VEXT
40	P00.7	LP / PU1 / VEXT	3265500	399000	GPIO
41	P00.8	LP / PU1 / VEXT	3374000	459000	GPIO
42	P00.9	LP / PU1 / VEXT	3265500	549000	GPIO

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
43	P00.10	LP / PU1 / VEXT	3374000	609000	GPIO
44	P00.11	LP / PU1 / VEXT	3265500	689000	GPIO
45	VSS	Vx	3374000	749000	Must be bonded to VSS
46	P00.12	LP / PU1 / VEXT	3265500	809000	GPIO
47	VDD	Vx	3374000	864000	Must be bonded to VDD
48	VSS	Vx	3374000	964000	Must be bonded to VSS
49	VSS	Vx	3374000	1064000	Must be bonded to VSS
50	VDD	Vx	3374000	1164000	Must be bonded to VDD
51	VEXT	Vx	3265500	1239000	Must be bonded to VEXT
52	VSS	Vx	3374000	1299000	Must be bonded to VSS
53	VAREF3	Vx	3374000	1419000	Positive Analog Reference Voltage 3
54	VAREF2	Vx	3265500	1479000	Positive Analog Reference Voltage 2
55	VAGND3	Vx	3374000	1539000	Negative Analog Reference Voltage 3
56	VAGND2	Vx	3265500	1599000	Negative Analog Reference Voltage 2
57	VDDM	Vx	3374000	1659000	Must be bonded to VEXT
58	AN47 (VADC5.7 / DS3ND)	D	3265500	1719000	Analog input
59	AN46 (VADC5.6 / DS3PD)	D	3374000	1779000	Analog input
60	AN45 (VADC5.5 / DS3NC)	D	3265500	1839000	Analog input
61	AN44 (VADC5.4 / DS3PC)	D	3374000	1899000	Analog input
62	AN43 (VADC5.3)	D	3265500	1959000	Analog input (with pull down diagnostics)
63	AN42 (VADC5.2)	D	3374000	2019000	Analog input
64	AN41 (VADC5.1)	D	3265500	2079000	Analog input
65	AN40 (VADC5.0)	D	3374000	2139000	Analog input
66	AN39 (VADC4.7 / DS3NB), P40.9 (SENT9A)	S	3265500	2199000	Analog input, GPI (SENT)
67	AN38 (VADC4.6 / DS3PB), P40.8 (SENT8A)	S	3374000	2259000	Analog input, GPI (SENT)
68	AN37 (VADC4.5 / DS3NA), P40.7 (SENT7A)	S	3265500	2319000	Analog input, GPI (SENT)

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
69	VDDM	Vx	3374000	2379000	Must be bonded to VEXT
70	AN36 (VADC4.4 / DS3PA), P40.6 (SENT6A)	S	3265500	2439000	Analog input, GPI (SENT)
71	VSSM	Vx	3374000	2499000	Must be bonded to VSS
72	AN35 (VADC4.3)	D	3265500	2559000	Analog input (with pull down diagnostics)
73	AN34 (VADC4.2)	D	3374000	2619000	Analog input
74	AN33 (VADC4.1), P40.5 (SENT5A)	S	3265500	2679000	Analog input, GPI (SENT)
75	AN32 (VADC4.0), P40.4 (SENT4A)	S	3374000	2765000	Analog input, GPI (SENT)
76	AN31 (VADC3.7)	D	3265500	2825000	Analog input
77	AN30 (VADC3.6)	D	3374000	2885000	Analog input
78	AN29 (VADC3.5)	D	3265500	2945000	Analog input
79	AN28 (VADC3.4)	D	3374000	3045000	GPIO
80	AN27 (VADC3.3), P40.3 (SENT3A)	S	3265500	3105000	Analog input (with pull down diagnostics), GPI (SENT)
81	AN26 (VADC3.2), P40.2 (SENT2A)	S	3265500	3205000	Analog input, GPI (SENT)
82	AN25 (VADC3.1 / DS2NB), P40.1 (SENT1A)	S	3265500	3305000	Analog input, GPI (SENT)
83	AN24 (VADC3.0 / DS2PB), P40.0 (SENT0A)	S	3265500	3405000	Analog input, GPI (SENT)
84	VDDM	Vx	3374000	3465000	Must be bonded to VEXT
85	VSSM	Vx	3134000	3705000	Must be bonded to VSS
86	AN23 (VADC2.7)	D	3074000	3596500	Analog input
87	AN22 (VADC2.6)	D	3014000	3705000	Analog input
88	AN21 (VADC2.5 / DS2NA)	D	2954000	3596500	Analog input
89	AN20 (VADC2.4 / DS2PA)	D	2854000	3596500	Analog input
90	AN19 (VADC2.3)	D	2754000	3596500	Analog input (with pull down diagnostics)
91	AN18 (VADC2.2)	D	2654000	3596500	Analog input
92	AN17 (VADC2.1)	D	2554000	3596500	Analog input

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
93	AN16 (VADC2.0)	D	2494000	3705000	Analog input
94	AN15 (VADC1.7)	D	2434000	3596500	Analog input
95	VAGND1	Vx	2374000	3705000	Negative Analog Reference Voltage 1
96	VAGND0	Vx	2314000	3596500	Negative Analog Reference Voltage 0
97	VAREF1	Vx	2254000	3705000	Positive Analog Reference Voltage 1
98	VAREF0	Vx	2194000	3596500	Positive Analog Reference Voltage 0
99	VSSM	Vx	2134000	3705000	Must be bonded to VSS
100	VSSM	Vx	2074000	3596500	Must be bonded to VSS
101	VSSMREF	Vx	2014000	3705000	Must be bonded to VSS
102	AN14 (VADC1.6)	D	1954000	3596500	Analog input
103	VDDM	Vx	1894000	3705000	Must be bonded to VEXT
104	VDDM	Vx	1829000	3596500	Must be bonded to VEXT
105	AN13 (VADC1.5)	D	1724000	3596500	Analog input
106	AN12 (VADC1.4)	D	1664000	3705000	Analog input
107	AN11 (VADC1.3)	D	1604000	3596500	Analog input (with pull down diagnostics)
108	AN10 (VADC1.2)	D	1544000	3705000	Analog input
109	AN9 (VADC1.1)	D	1484000	3569500	Analog input
110	AN8 (VADC1.0)	D	1424000	3705000	Analog input
111	AN7 (VADC0.7)	D	1364000	3596500	Analog input (with pull down diagnostics)
112	AN6 (VADC0.6)	D	1304000	3705000	Analog input
113	AN5 (VADC0.5)	D	1244000	3596500	Analog input
114	AN4 (VADC0.4)	D	1184000	3705000	Analog input
115	AN3 (VADC0.3 / DS0NA)	D	1124000	3596500	Analog input
116	VSSM	Vx	1064000	3705000	Must be bonded to VSS
117	AN2 (VADC0.2 / DS0PA)	D	1004000	3596500	Analog input
118	VDDM	Vx	944000	3705000	Must be bonded to VEXT
119	AN1 (VADC0.1 / DS1NA)	D	884000	3596500	Analog input
120	AN0 (VADC0.0 / DS1PA)	D	807000	3705000	Analog input
121	VEXT	Vx	427000	3596500	Must be bonded to VEXT
122	VSS	Vx	377000	3705000	Must be bonded to VSS

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
123	P34.1	LP / PU1 / VEXT	322000	3596500	GPIO
124	VSS	Vx	267000	3705000	Must be bonded to VSS
125	P34.2	LP / PU1 / VEXT	212000	3596500	GPIO
126	P34.3	LP / PU1 / VEXT	142000	3705000	GPIO
127	VEXT	Vx	87000	3596500	Must be bonded to VEXT
128	P34.4	LP / PU1 / VEXT	22000	3705000	GPIO
129	P34.5	LP / PU1 / VEXT	-38000	3596500	GPIO
130	VSS	Vx	-93000	3705000	Must be bonded to VSS
131	VDD	Vx	-193000	3705000	Must be bonded to VDD
132	VSS	Vx	-323000	3705000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 131.
133	VSS	Vx	-363000	3705000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 130.
134	VDD	Vx	-493000	3705000	Must be bonded to VDD
135	VEVRSB	Vx	-560000	3596500	Must be bonded to VEXT
136	EVR_OFF	Vx	-625000	3705000	Must be bonded to VSS+F178
137	VEXT	Vx	-725000	3705000	Must be bonded to VEXT
138	P33.0	LP / PU1 / VEXT	-790000	3596500	GPIO
139	P33.1	LP / PU1 / VEXT	-855000	3705000	GPIO
140	P33.2	LP / PU1 / VEXT	-915000	3596500	GPIO
141	P33.3	LP / PU1 / VEXT	-985000	3705000	GPIO
142	P33.4	LP / PU1 / VEXT	-1045000	3596500	GPIO
143	VSS	Vx	-1100000	3705000	Must be bonded to VSS
144	P33.5	LP / PU1 / VEXT	-1155000	3596500	GPIO
145	P33.6	LP / PU1 / VEXT	-1250000	3705000	GPIO
146	P33.7	LP / PU1 / VEXT	-1310000	3596500	GPIO
147	P33.8	MP / HighZ / VEXT	-1420000	3705000	GPIO
148	P33.9	LP / PU1 / VEXT	-1490000	3596500	GPIO
149	VEXT	Vx	-1545000	3705000	Must be bonded to VEXT
150	P33.10	MP / PU1 / VEXT	-1610000	3596500	GPIO
151	P33.14	LP / PU1 / VEXT	-1680000	3705000	GPIO
152	P33.11	MP / PU1 / VEXT	-1750000	3596500	GPIO
153	P33.15	LP / PU1 / VEXT	-1820000	3705000	GPIO
154	P33.12	MP / PU1 / VEXT	-1890000	3596500	GPIO

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
155	VSS	Vx	-1955000	3705000	Must be bonded to VSS
156	P33.13	MP / PU1 / VEXT	-2040000	3596500	GPIO
157	VSS	Vx	-2105000	3705000	Must be bonded to VSS
158	VDD	Vx	-2205000	3705000	Must be bonded to VDD
159	P32.0	LP / EVR13 SMPS -> PD, GPIO -> PU1 / VEXT	-2260000	3596500	GPIO
160	VGATE1N (SMPS)	VGATE1N	-2315000	3705000	Must be bonded to VSS if EVR13 SMPS is not used. Must be bonded to NMOS gate if EVR13 SMPS used.
161	VGATE1P (SMPS)	VGATE1P	-2365000	3596500	Must be bonded to VEXT if EVR13 SMPS is not used. Must be bonded to PMOS gate if EVR13 SMPS used.
162	VGATE3P (LDO)	VGATE3P	-2415000	3705000	Must be bonded to VSS
163	VGATE1P (LDO)	VGATE1P	-2465000	3596500	Must be bonded to VSS if no external P channel MOSFET used for EVR13 LDO generation. Must be bonded to external P channnel MOSFET if external LDO pass device used.
164	VEXT	Vx	-2515000	3705000	Must be bonded to VEXT
165	P32.2	LP / PU1 / VEXT	-2570000	3596500	GPIO
166	P32.3	LP / PU1 / VEXT	-2714000	3596500	GPIO
167	P32.6	LP / PU1 / VEXT	-2774000	3705000	GPIO
168	P32.5	LP / PU1 / VEXT	-2849000	3596500	GPIO
169	VSS	Vx	-2904000	3705000	Must be bonded to VSS
170	P32.4	MP+ / PU1 / VEXT	-2989000	3596500	GPIO
171	P32.7	LP / PU1 / VEXT	-3069000	3705000	GPIO
172	P23.0	LP / PU1 / VEXT	-3129000	3596500	GPIO
173	VSS	Vx	-3374000	3391000	Must be bonded to VSS
174	P23.1	MP+ / PU1 / VEXT	-3265500	3316000	GPIO
175	P23.2	LP / PU1 / VEXT	-3374000	3236000	GPIO
176	P23.3	LP / PU1 / VEXT	-3265500	3125000	GPIO
177	P23.4	MP+ / PU1 / VEXT	-3374000	3045000	GPIO

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
178	P23.6	LP / PU1 / VEXT	-3265500	2965000	GPIO
179	VEXT	Vx	-3374000	2910000	Must be bonded to VEXT
180	P23.5	MP+ / PU1 / VEXT	-3265500	2835000	GPIO
181	P23.7	LP / PU1 / VEXT	-3374000	2755000	GPIO
182	P22.0	MP / LVDSM_N / PU1 / VEXT	-3265500	2685000	GPIO
183	P22.1	MP / LVDS_P / PU1 / VEXT	-3265500	2335000	GPIO
184	VSS	Vx	-3374000	2270000	Must be bonded to VSS
185	P22.2	MP / LVDSM_N / PU1 / VEXT	-3265500	2205000	GPIO
186	P22.3	MP / LVDS_P / PU1 / VEXT	-3265500	1855000	GPIO
187	VEXT	Vx	-3374000	1790000	Must be bonded to VEXT
188	VEXT	Vx	-3265500	1735000	Must be bonded to VEXT
189	Reserved	Vx	-3374000	1680000	Must be bonded to VSS
190	VDD	Vx	-3374000	1580000	Must be bonded to VDD
191	VSS	Vx	-3374000	1480000	Must be bonded to VSS
192	P22.4	LP / PU1 / VEXT	-3265500	1425000	GPIO
193	VSS	Vx	-3374000	1370000	Must be bonded to VSS
194	VDD	Vx	-3374000	1270000	Must be bonded to VDD
195	P22.5	LP / PU1 / VEXT	-3265500	1215000	GPIO
196	P22.6	LP / PU1 / VEXT	-3374000	1155000	GPIO
197	P22.7	LP / PU1 / VEXT	-3265500	1095000	GPIO
198	VSS	Vx	-3374000	1040000	Must be bonded to VSS
199	VDD	Vx	-3374000	940000	Must be bonded to VDD
200	P22.8	LP / PU1 / VEXT	-3265500	885000	GPIO
201	P22.9	LP / PU1 / VEXT	-3374000	825000	GPIO
202	P22.10	LP / PU1 / VEXT	-3265500	765000	GPIO
203	VSS	Vx	-3374000	710000	Must be bonded to VSS
204	P22.11	LP / PU1 / VEXT	-3265500	655000	GPIO
205	VDDOSC	Vx	-3374000	520000	Must be bonded to VDD
206	VSSOSC	Vx	-3374000	420000	Must be bonded to VSS
207	XTAL1	XTAL1	-3265500	312500	Main Oscillator/PLL/Clock Generator Input. Must be bonded to external quartz or resonator

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
208	XTAL2	XTAL2	-3265500	212500	Main Oscillator/PLL/Clock Generator Input. Must be bonded to external quartz or resonator
209	VSSOSC3	Vx	-3374000	105000	Must be bonded to VSS
210	VDDOSC3	Vx	-3265500	55000	Must be bonded to VDDP3
211	VDDP3	Vx	-3374000	-35000	Must be bonded to VDDP3
212	VDDP3	Vx	-3265500	-95000	Must be bonded to VDDP3
213	VSS	Vx	-3374000	-145000	Must be bonded to VSS
214	P21.0	A2 / PU1 / VDDP3	-3374000	-245000	GPIO
215	P21.1	A2 / PU1 / VDDP3	-3265500	-345000	GPIO
216	VSS	Vx	-3374000	-395000	Must be bonded to VSS
217	P21.2	LVDSH_N / PU1 / VDDP3	-3265500	-457500	GPIO
218	P21.3	LVDSH_P / PU1 / VDDP3	-3265500	-557500	GPIO
219	VDDP3	Vx	-3374000	-620000	Must be bonded to VDDP3
220	P21.4	LVDSH_N / PU1 / VDDP3	-3265500	-694500	GPIO
221	P21.5	LVDSH_P / PU1 / VDDP3	-3265500	-845500	GPIO
222	VDD	Vx	-3374000	-920000	Must be bonded to VDD
223	VSS	Vx	-3374000	-1020000	Must be bonded to VSS
224	P21.6	A2 / PU / VDDP3	-3265500	-1070000	GPIO, TDI
225	VDDP3	Vx	-3374000	-1120000	Must be bonded to VDDP3
226	VSS	Vx	-3374000	-1345000	Must be bonded to VSS
227	TMS / DAP1	A2 / PD / VDDP3	-3265500	-1395000	JTAG Module State Machine Control Input / Device Access Port Line 1
228	P21.7	A2 / PU / VDDP3	-3374000	-1445000	GPIO, TDO
229	TRST (N)	A2 / PU / VDDP3	-3265500	-1535000	JTAG Module Reset/Enable Input
230	TCK / DAP0	A2 / PU / VDDP3	-3374000	-1585000	JTAG Module Clock Input / Device Access Port Line 0
231	P20.0	MP / PU1 / VEXT	-3265500	-1720000	GPIO
232	P20.1	LP / PU1 / VEXT	-3374000	-1790000	GPIO
233	P20.2	LP / PU / VEXT	-3265500	-1845000	Testmode pin must be bonded
234	VSS	Vx	-3374000	-1895000	Must be bonded to VSS

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
235	P20.3	LP / PU1 / VEXT	-3265500	-1950000	GPIO
236	ESR1 (N) / EVRWUP	MP / PU1 / VEXT	-3374000	-2020000	External System Request Reset 1. Default NMI function. EVR Wakeup Pin.
237	PORST (N)	I / PD1 / VEXT	-3265500	-2102500	Power On Reset Input. Additional strong PD in case of power fail.
238	VEXT	Vx	-3374000	-2170000	Must be bonded to VEXT
239	ESR0 (N) / EVRWUP	MP / OD	-3265500	-2235000	External System Request Reset 0. Default configuration during and after reset is open-drain driver. The driver drives low during power-on reset. EVR Wakeup Pin.
240	VDD	Vx	-3374000	-2310000	Must be bonded to VDD
241	VSS	Vx	-3374000	-2440000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 240.
242	VSS	Vx	-3374000	-2480000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 239.
243	VDD	Vx	-3374000	-2610000	Must be bonded to VDD
244	P20.6	LP / PU1 / VEXT	-3265500	-2665000	GPIO
245	VSS	Vx	-3374000	-2720000	Must be bonded to VSS
246	P20.7	LP / PU1 / VEXT	-3265500	-2775000	GPIO
247	P20.8	MP / PU1 / VEXT	-3374000	-2865000	GPIO
248	P20.9	LP / PU1 / VEXT	-3265500	-2935000	GPIO
249	VEXT	Vx	-3374000	-2990000	Must be bonded to VEXT
250	P20.10	MP / PU1 / VEXT	-3265500	-3055000	GPIO
251	P20.11	MP / PU1 / VEXT	-3374000	-3155000	GPIO
252	P20.12	MP / PU1 / VEXT	-3265500	-3235000	GPIO
253	VSS	Vx	-3374000	-3300000	Must be bonded to VSS
254	P20.13	MP / PU1 / VEXT	-3265500	-3365000	GPIO
255	P20.14	MP / PU1 / VEXT	-3265500	-3465000	GPIO
256	P15.0	LP / PU1 / VEXT	-3134000	-3596500	GPIO
257	P15.1	LP / PU1 / VEXT	-3034000	-3596500	GPIO
258	P15.2	MP / PU1 / VEXT	-2964000	-3705000	GPIO
259	P15.3	MP / PU1 / VEXT	-2864000	-3705000	GPIO
260	VEXT	Vx	-2799000	-3596500	Must be bonded to VEXT

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
261	P15.4	MP / PU1 / VEXT	-2734000	-3705000	GPIO
262	P15.5	MP / PU1 / VEXT	-2634000	-3705000	GPIO
263	P15.6	MP / PU1 / VEXT	-2522000	-3596500	GPIO
264	VSS	Vx	-2457000	-3705000	Must be bonded to VSS
265	P15.7	MP / PU1 / VEXT	-2392000	-3596500	GPIO
266	P15.8	MP / PU1 / VEXT	-2312000	-3705000	GPIO
267	P14.0	MP+ / PU1 / VEXT	-2222000	-3596500	GPIO
268	P14.1	MP / PU1 / VEXT	-2122000	-3596500	GPIO
269	VEXT	Vx	-2057000	-3705000	Must be bonded to VEXT
270	P14.2	LP / PU1 / VEXT	-2002000	-3596500	Must be bonded to VEXT if EVR13 active. Must be bonded to VSS if EVR13 inactive.
271	P14.3	LP / PU1 / VEXT	-1942000	-3705000	GPIO
272	P14.4	LP / PU1 / VEXT	-1872000	-3596500	GPIO
273	VSS	Vx	-1817000	-3705000	Must be bonded to VSS
274	P14.5	MP+ / PU1 / VEXT	-1742000	-3596500	GPIO
275	P14.6	MP+ / PU1 / VEXT	-1642000	-3705000	GPIO
276	P14.7	LP / PU1 / VEXT	-1562000	-3596500	GPIO
277	P14.8	LP / PU1 / VEXT	-1502000	-3705000	GPIO
278	P14.9	MP+ / PU1 / VEXT	-1422000	-3596500	GPIO
279	P14.10	MP+ / PU1 / VEXT	-1322000	-3596500	GPIO
280	Reserved	Vx	-1247000	-3705000	Must be bonded to VSS
281	VEXT	Vx	-1197000	-3596500	Must be bonded to VEXT
282	VSS	Vx	-1147000	-3705000	Must be bonded to VSS
283	VEXT	Vx	-1097000	-3596500	Must be bonded to VEXT
284	VSS	Vx	-1017000	-3705000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 284.
285	VDDP3	Vx	-994500	-3596500	Must be bonded to VDDP3
286	VSS	Vx	-972000	-3705000	Must be bonded to VSS. Double Pad (Elephant Pad), shared with Pad Nr 282.
287	VDDP3	Vx	-877000	-3596500	Must be bonded to VDDP3

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
288	VDDFL3	Vx	-777000	-3596500	Must be bonded to VDDP3
289	VDDFL3	Vx	-697000	-3705000	Must be bonded to VDDP3
290	VDDFL3	Vx	-629500	-3596500	Must be bonded to VDDP3
291	VSS	Vx	-577000	-3705000	Must be bonded to VSS
292	P13.0	MP / LVDSM_N / PU1 / VEXT	-512000	-3596500	GPIO
293	P13.1	MP / LVDS_P / PU1 / VEXT	-162000	-3596500	GPIO
294	VEXT	Vx	-97000	-3705000	Must be bonded to VEXT
295	P13.2	MP / LVDSM_N / PU1 / VEXT	-32000	-3596500	GPIO
296	P13.3	MP / LVDS_P / PU1 / VEXT	318000	-3596500	GPIO
297	P12.0	LP / PU1 / VFLEX	458000	-3596500	GPIO
298	P12.1	LP / PU1 / VFLEX	518000	-3705000	GPIO
299	P11.0	MP+ / PU1 / VFLEX	598000	-3596500	GPIO
300	VSSFLEX	Vx	673000	-3705000	Must be bonded to VSS
301	P11.1	MP+ / PU1 / VFLEX	748000	-3596500	GPIO
302	VFLEX	Vx	823000	-3705000	Must be bonded to VEXT or VDDP3
303	P11.2	MPR / PU1 / VFLEX	898000	-3596500	GPIO
304	P11.3	MPR / PU1 / VFLEX	998000	-3596500	GPIO
305	P11.4	MP+ / PU1 / VFLEX	1098000	-3705000	GPIO
306	P11.5	LP / PU1 / VFLEX	1178000	-3596500	GPIO
307	P11.6	MPR / PU1 / VFLEX	1258000	-3705000	GPIO
308	P11.7	LP / PU1 / VFLEX	1338000	-3596500	GPIO
309	P11.9	MP+ / PU1 / VFLEX	1418000	-3705000	GPIO
310	P11.8	LP / PU1 / VFLEX	1498000	-3596500	GPIO
311	VSSFLEX	Vx	1553000	-3705000	Must be bonded to VSS

Table 2-40 List of the TC270x Bare Die Pads

Number	Pad Name	Pad Type	X	Y	Comment
312	VFLEX	Vx	1603000	-3596500	Must be bonded to VEXT or VDDP3
313	P11.10	LP / PU1 / VFLEX	1698000	-3705000	GPIO
314	P11.13	LP / PU1 / VFLEX	1758000	-3596500	GPIO
315	VSSFLEX	Vx	1813000	-3705000	Must be bonded to VSS
316	P11.11	MP+ / PU1 / VFLEX	1888000	-3596500	GPIO
317	P11.12	MPR / PU1 / VFLEX	1988000	-3596500	GPIO
318	P11.14	LP / PU1 / VFLEX	2068000	-3705000	GPIO
319	P11.15	LP / PU1 / VFLEX	2128000	-3596500	GPIO
320	VDD	Vx	2183000	-3705000	Must be bonded to VDD
321	VSS	Vx	2283000	-3705000	Must be bonded to VSS
322	VSS	Vx	2403000	-3705000	Must be bonded to VSS
323	P10.0	LP / PU1 / VEXT	2458000	-3596500	GPIO
324	P10.1	MP+ / PU1 / VEXT	2543000	-3705000	GPIO
325	P10.2	MP / PU1 / VEXT	2643000	-3705000	GPIO
326	P10.3	MP / PU1 / VEXT	2723000	-3596500	GPIO
327	P10.4	MP+ / PU1 / VEXT	2834000	-3705000	GPIO
328	VEXT	Vx	2909000	-3596500	Must be bonded to VEXT
329	P10.5	LP / PU1 / VEXT	2964000	-3705000	GPIO
330	P10.6	LP / PU1 / VEXT	3024000	-3596500	GPIO
331	VSS	Vx	3079000	-3705000	Must be bonded to VSS
332	P10.7	LP / PU1 / VEXT	3134000	-3596500	GPIO

Legend:

Column “**Number**”:

Running number of pads in the pad frame

Column “**Name**”:

Symbolic name of the pad.

The functions mapped on GPIO pads “Px.y” are described in the User’s Manual chapter ”General Purpose I/O Ports and Peripheral I/O LInes (Ports)”

Column “**Type**”:

LP = Pad class LP (5V/3.3V, LVTTL)
MP = Pad class MP (5V/3.3V, LVTTL)
MP+ = Pad class MP+ (5V/3.3V, LVTTL)

MPR = Pad class MPR (5V/3.3V, LVTTL)
A2 = Pad class A2 (3.3V, LVTTL)
LVDSM = Pad class LVDSM (LVDS/CMOS 5V/3.3V)
LVDSH = Pad class LVDSH (LVDS/CMOS 3.3V)
S = Pad class S (ADC overlayed with General Purpose Input)
D = Pad class D (ADC)
PU = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)
PU1 = with pull-up device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]
PD = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)
PD1 = with pull-down device connected during reset ($\overline{\text{PORST}}$ = 0)[1) 2) 3)]
PX = Behavior depends on usage: PD in EVR13 SMPS Mode and PU1 in GPIO Mode
OD = open drain during reset ($\overline{\text{PORST}}$ = 0)
HighZ = tri-state during reset ($\overline{\text{PORST}}$ = 0)
$\overline{\text{PORST}}$ = $\overline{\text{PORST}}$ input pad
XTAL1 = XTAL1 input pad
XTAL2 = XTAL2 input pad
VGATE1P = VGATE1P
VGATE3P = VGATE3P
Vx = Supply
NC = These pins are reserved for future extensions and shall not be connected externally
NC1 = These pins are not connected on package level and will not be used for future extensions
NCVDDPSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.
NCVDDSB = This pin has a different functionality in an Production Device and an Emulation Device. For details pls. see Pin/Ball description of this pin.

Column “**X**” / “**Y**”:

Pad opening center coordinates (in nm)

2.3.1 Pad Openings

Two different pad openings are used:

- Standard Pad Opening is 70um x 75um where 70um is the width of the opening (width as seen from the die side) and 75um is the depth of the opening (from the die side into the silicon).
- Double Pad or Elephant Pad Opening is 130um x 75um where 130um is the width of the opening (width as seen from the die side) and 75um is the depth of the opening (from the die side into the silicon). The Double Pad openings are represented with two opening coordinates and two pad numbers. Double Pads are used only for supply and can be identified by the words ´Double Pad´ or ´Elephant Pad´ in the Comment column.

2.3.2 Emergency Stop Function

The Emergency Stop function can be used to force GPIOs (General Purpose Inputs/Outputs) via an external input signal (EMGSTOPA or EMGSTOPB) into a defined state:

1)The default state of GPIOs (Px.y) during and after $\overline{\text{PORST}}$ active is controllled via HWCFG[6] (P14.4). HWCFG[6] has a weak internal pull-up active at start-up if the pin is left unconnected.See also User´s Manual, “Introduction Chapter”, “General Purpose I/O Ports and Peripheral I/O Lines”, Figure: “Default state of port pins during and after reset”.

2) If HWCFG[6] is left unconnected or is externally pulled high, weak internal pull-ups are active at GPIOs (Px.y) pins during and after reset. Exceptions are P33.8 (HighZ), P40.x (default configuration during and after reset: analog inputs, port input funtion disabled), ESR0, P21.6 / P21.7 (port pins overlayed with JTAG functionality).

3) If HWCFG[6] is connected to ground, port pins are predominantly in HighZ during and after reset. Exceptions are P33.8 (HighZ), P40.x (default configuration during and after reset: analog inputs, port input funtion disabled), ESR0, P21.6 / P21.7 (port pins overlayed with JTAG functionality).

- Input state and
- PU or HighZ depending on HWCFG[6] level latched during $\overline{\text{PORST}}$ active

Control of the Emergency Stop function:

- The Emergency Stop function can be enabled/disabled in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- The Emergency Stop input signal, EMGSTOPA (P33.8) / EMGSTOPB (P21.2) , can selected in the SCU (see chapter “SCU”, “Emergency Stop Control”)
- On port level, each GPIO can be enabled/disabled for the Emergency Stop function via the Px_ESR (Port x Emergency Stop) registers in the port control logic (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, “Emergency Stop Register”).

The Emergency Stop function is available for all GPIO Ports with the following exceptions:

- Not available for P20.2 (General Purpose Input/GPI only, overlayed with Testmode)
- Not available for P40.x (analoge input ANx overlayed with GPI)
- Not available for P32.0 EVR13 SMPS mode.
- Not available for dedicated I/O without General Purpose Output function (e.g ESRx, TMS, TCK)

The Emergency Stop function can be overruled on the following GPIO Ports:

- P00.x: Emergency Stop can be overruled by the VADC. Overruling can be disabled via the control register P00_SCR (see chapter “General Purpose I/O Ports and Peripheral I/O Lines”, P00)
- P14.0 and P14.1: Emergency Stop can be overruled in the DXCPL mode (DAP over can physical layer mode). No Overruling in the DXCM (Debug over can message) mode
- P21.6: Emergency Stop can be overruled in JTAG mode if this pin is used as TDI
- P21.7: Emergency Stop can be overruled in JTAG or Three Pin DAP mode
- P20.0: Emergency Stop can be overruled in JTAG mode if this GPIO is used as TDI

2.3.3 Pull-Up/Pull-Down Reset Behavior of the Pins

Table 2-41 List of Pull-Up/Pull-Down Reset Behavior of the Pins

Pins	$\overline{\text{PORST}}$ = 0	$\overline{\text{PORST}}$ = 1
all GPIOs	Pull-up if HWCFG[6] = 1 or High-Z if HWCFG[6] = 0	
$\overline{\text{TDI}}$, $\overline{\text{TESTMODE}}$	Pull-up	
$\overline{\text{PORST}}$[1)]	Pull-down with I_{PORST} relevant	Pull-down with I_{PDLI} relevant
$\overline{\text{TRST}}$, TCK, TMS	Pull-down	
$\overline{\text{ESR0}}$	The open-drain driver is used to drive low.[2)]	Pull-up[3)]
$\overline{\text{ESR1}}$	Pull-up[3)]	
TDO	Pull-up	High-Z/Pull-up[4)]

1) Pull-down with I_{PORST} relevant is always activated when a primary supply monitor detects a violation.
2) Valid additionally after deactivation of $\overline{\text{PORST}}$ until the internal reset phase has finished. See the SCU chapter for details.
3) See the SCU_IOCR register description.
4) Depends on JTAG/DAP selection with $\overline{\text{TRST}}$.

- In case of leakage test ($\overline{\text{PORST}}$ = 0 and $\overline{\text{TESTMODE}}$ = 0), the pull-down of the $\overline{\text{TRST}}$ pin is switched off. In case of an user application ($\overline{\text{TESTMODE}}$ = 1), the pull-down of the $\overline{\text{TRST}}$ is always switched on.

3 Electrical Specification

3.1 Parameter Interpretation

The parameters listed in this section partly represent the characteristics of the TC270 / TC275 / TC277 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are marked with an two-letter abbreviation in column “Symbol”:

- **CC**
  Such parameters indicate **C**ontroller **C**haracteristics which are a distinctive feature of the TC270 / TC275 / TC277 and must be regarded for a system design.
- **SR**
  Such parameters indicate **S**ystem **R**equirements which must provided by the microcontroller system in which the TC270 / TC275 / TC277 designed in.

3.2 Absolute Maximum Ratings

Stresses above the values listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the Operational Conditions of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Table 3-1 Absolute Maximum Ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Storage Temperature	T_{ST} SR	-65	-	170	°C	upto 65h @ T_J = 150°C; upto 15h @ T_J = 170°C
Voltage at V_{DD} power supply pins with respect to V_{SS} 1)	V_{DD} SR	-	-	1.9	V	
Voltage at V_{DDP3} and V_{DDFL3} power supply pins with respect to V_{SS} 1)	V_{DDP3} SR	-	-	4.43	V	
Voltage at V_{DDM}, V_{EXT} and V_{FLEX} power supply pins with respect to V_{SS} 1)	V_{DDM} SR	-	-	7.0	V	
Voltage on any class A2 and LVDSH input pin with respect to V_{SS} 1)2)	V_{IN} SR	-0.5	-	min(V_{DDP3} + 0.6 , 4.23)	V	Whatever is lower
Voltage on all other input pins with respect to V_{SS} 1)2)	V_{IN} SR	-0.5	-	7.0	V	
Input current on any pin during overload condition 3)	I_{IN} SR	-10	-	10	mA	
Absolute maximum sum of all input circuit currents during overload condition 3)	ΣI_{IN} SR	-100	-	100	mA	

1) Valid for cumulated for up to 2.8h and pulse forms following a power supply switch on phase, where the rise and fall times are releated to the system capacities and coils.

2) Voltages below V_{INmin} have no Impact to the device reliabiltiy as Long as the times and currents defined in section Pin Reliability in Overload for the affected pad(s) are not violated.

3) This parameter is an Absolute Maximum Rating. Exposure to Absolute Maximum Ratings for extended periods of time may damage the device.

3.3 Pin Reliability in Overload

When receiving signals from higher voltage devices, low-voltage devices experience overload currents and voltages that go beyond their own IO power supplies specification.

The following table defines overload conditions that will not cause any negative reliability impact if all the following conditions are met:

- full operation life-time is not exceeded
- **Operating Conditions** are met for
  - pad supply levels
  - temperature

If a pin current is out of the **Operating Conditions** but within the overload parameters, then the parameters functionality of this pin as stated in the Operating Conditions can no longer be guaranteed. Operation is still possible in most cases but with relaxed parameters.

Note: An overload condition on one or more pins does not require a reset.

Table 3-2 Overload Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input current on any digital pin during overload condition	I_{IN}	-5	-	5	mA	except LVDS pins
		-15 [1]	-	15 [1]	mA	except LVDS pins; limited to max. 20 pulses with 1ms pulse length
Input current on LVDS pin during overload condition	I_{INLVDS}	-3	-	3	mA	
Absolute maximum sum of all input circuit currents during overload condition	I_{ING}	-50	-	50	mA	
Input current on analog input pin during overload condition	I_{INANA}	-3	-	3	mA	
		-5	-	5	mA	limited to 60h over lifetime
Absolute sum of all ADC inputs during overload condition	I_{INSCA}	-20	-	20	mA	
Absolute maximum sum of all input circuit currents during overload condition	ΣI_{INS}	-100	-	100	mA	
Signal voltage over/undershoot at GPIOs	V_{OUS}	V_{SS} - 2	-	$V_{EXT/FLEX}$ + 2	V	limited to 60h over lifetime; Valid for LP, MP, MP+, and MPR pads
Inactive device pin current during overload condtion [2]	I_{ID}	-1	-	1	mA	All power supply voltages V_{DDx} = 0
Sum of all inactive device pin currents [2]	I_{IDS}	-100	-	100	mA	

Table 3-2 Overload Parameters (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Overload coupling factor for digital inputs, negative [3]	K_{OVDN} CC	-	$2*10^{-4}$	$6*10^{-4}$		Overload injected on GPIO non LVDS pad and affecting neighbor LP and A2 pads; -2mA < I_{IN} < 0mA
		-	-	$1*10^{-2}$		Overload injected on GPIO non LVDS pad and affecting neighbor LP and A2 pads; -5mA < I_{IN} < -2mA
		-	-	$1.7*10^{-3}$		Overload injected on GPIO non LVDS pad and affecting neighbor MP, MP+, and MPR pads; -2mA < I_{IN} < 0mA
		-	-	$2*10^{-2}$		Overload injected on GPIO non LVDS pad and affecting neighbor MP, MP+, and MPR pads; -5mA < I_{IN} < -2mA
		-	-	0.3		Overload injected on LVDS pad and affecting neighbor LVDS pads
		-	-	0.93		coupling between pads 21.2 and 21.3
Overload coupling factor for digital inputs, positive [3]	K_{OVDP} CC	-	-	$1*10^{-5}$		Overload injected on GPIO non LVDS pad and affecting neighbor GPIO non LVDS pads
		-	-	$1*10^{-4}$		Overload injected on GPIO pad and affecting neighbor P32.0 pad
		-	-	$5*10^{-4}$		Overload injected on LVDS pad and affecting neighbor LVDS pads

Table 3-2 Overload Parameters (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Overload coupling factor for analog inputs, negative	K_{OVAN} CC	-	-	$6*10^{-4}$ 4)		Analog Inputs overlaid with class LP pads or pull down diagnostics; -1mA < I_{IN} < 0mA
		-	-	$1*10^{-2}$		Analog Inputs overlaid with class LP pads or pull down diagnostics; -5mA < I_{IN} < -1mA
		-	-	$1*10^{-4}$		else; -5mA < I_{IN} < 0mA
Overload coupling factor for analog inputs, positive	K_{OVAP} CC	-	-	$1*10^{-5}$		5mA < I_{IN} < 0mA

1) Reduced VADC / DSADC result accuracy and / or GPIO input levels (V_{IL} and V_{IH}) can differ from specified parameters.
2) Limitations for time and supply levels specified in this section are not valid for this parameter.
3) Overload is measured as increase of pad leakage caused by injection on neighbor pad.
4) For analogue inputs overlaid with DSADC function the VCM holdbuffer shall be enabled, in case DSADCs are enabled.

Note: DSADC input pins count as analog pins as they are overlaid with VADC pins.

Table 3-3 PN-Junction Characteristics for positive Overload

Pad Type	I_{IN} = 3 mA	I_{IN} = 5 mA
F / A2	$U_{IN} = V_{DDP3}$ + 0.5 V	$U_{IN} = V_{DDP3}$ + 0.6 V
LP / MP / MP+ / MPR	$U_{IN} = V_{EXT / FLEX}$ + 0.75 V	$U_{IN} = V_{EXT / FLEX}$ + 0.8 V
LVDSM	$U_{IN} = V_{EXT}$ + 0.75 V	-
LVDSH	$U_{IN} = V_{DDP3}$ + 0.5 V	-
D	$U_{IN} = V_{DDM}$ + 0.75 V	-

Table 3-4 PN-Junction Characteristics for negative Overload

Pad Type	I_{IN} = -3 mA	I_{IN} = -5 mA
F / A2	$U_{IN} = V_{SS}$ - 0.5 V	$U_{IN} = V_{SS}$ - 0.6 V
LP / MP / MP+ / MPR	$U_{IN} = V_{SS}$ - 0.75 V	$U_{IN} = V_{SS}$ - 0.8 V
LVDSM	$U_{IN} = V_{SS}$ - 0.75 V	-
LVDSH	$U_{IN} = V_{SS}$ - 0.5 V	-
D	$U_{IN} = V_{SS}$ - 0.75 V	-

3.4 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the TC270 / TC275 / TC277. All parameters specified in the following tables refer to these operating conditions, unless otherwise noticed.

Digital supply voltages applied to the TC270 / TC275 / TC277 must be static regulated voltages.

All parameters specified in the following tables refer to these operating conditions (see table below), unless otherwise noticed in the Note / Test Condition column.

Table 3-5 Operating Conditions

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SRI frequency	f_{SRI} SR	-	-	200	MHz	
Max System Frequency	f_{MAX} SR	-	-	200	MHz	
CPU0 Frequency	f_{CPU0} SR	-	-	200	MHz	
CPU1 Frequency	f_{CPU1} SR	-	-	200	MHz	
CPU2 Frequency	f_{CPU2} SR	-	-	200	MHz	
PLL output frequency	f_{PLL} SR	20	-	200	MHz	
PLL_ERAY output frequency	$f_{PLLERAY}$ SR	20	-	400	MHz	
SPB frequency	f_{SPB} SR	-	-	100	MHz	
ASCLIN fast frequency	$f_{ASCLINF}$ SR	-	-	200	MHz	
ASCLIN slow frequency	$f_{ASCLINS}$ SR	-	-	100	MHz	
Baud2 frequency	f_{BAUD2} SR	-	-	200	MHz	
Baud1 frequency	f_{BAUD1} SR	-	-	100	MHz	
FSI2 frequency	f_{FSI2} SR	-	-	200	MHz	
FSI frequency	f_{FSI} SR	-	-	100	MHz	
GTM frequency	f_{GTM} SR	-	-	100	MHz	
STM frequency	f_{STM} SR	-	-	100	MHz	
ERAY frequency	f_{ERAY} SR	-	-	80	MHz	
BBB frequency	f_{BBB} SR	-	-	100	MHz	
MultiCAN frequency	f_{CAN} SR	-	-	100	MHz	
Absolute sum of short circuit currents of the device	ΣI_{SC_D} SR	-	-	100	mA	
Ambient Temperature	T_A SR	-40	-	125	°C	valid for all SAK products
		-40	-	150	°C	valid for all SAL products
		-40	-	170	°C	valid for all SAL products without package
Junction Temperature	T_J SR	-40	-	150	°C	valid for all SAK products
		-40	-	170	°C	valid for all SAL products

Table 3-5 Operating Conditions (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Core Supply Voltage [1]	V_{DD} SR	1.17	1.3	1.43 [2]	V	Only required if externally supplied
ADC analog supply voltage	V_{DDM} SR	2.97	5.0	5.5 [3]	V	
Digital external supply voltage for LP, MP, MP+ and LVDSM pads and EVR [4]	V_{EXT} SR	2.97	-	4.5	V	3.3V pad parameters are valid
		4.5	5.0	5.5 [3]	V	5V pad parameters are valid
Digital supply voltage for Flex port	V_{FLEX} SR	2.97	-	4.5	V	3.3V pad parameters are valid
		4.5	5.0	5.5 [3]	V	5V pad parameters are valid
Digital supply voltage for LVDSH and A2 pads [5]	V_{DDP3} SR	2.97	3.3	3.63 [6]	V	3.3V pad parameters are valid; only required if externally supplied
Flash supply voltage 3.3V [1]	V_{DDFL3} SR	2.97	3.3	3.63	V	Only required if externally supplied
Digital ground voltage	V_{SS} SR	0	-	-	V	
Analog ground voltage for V_{DDM}	V_{SSM} CC	-0.1	0	0.1	V	
Voltage to ensure defined pad states [7]	V_{DDPPA} CC	0.72	-	-	V	A2 and LVDSH
		1.4	-	-	V	LP, MP, MP+, MPR and LVDSM
Digital external supply voltage for EVR and during Standby mode	V_{EVRSB} SR	2.97	-	5.5	V	only available in BGA package. V_{EVRSB} is bonded together with V_{EXT} supply pin in LQFP package.

1) No external inductive load permissible if EVR is used. All V_{DD} pins shall be connected together externally on the PCB.
2) Voltage overshoot to 1.69V is permissible, provided the duration is less than 2h cumulated. Reduced ADC accuracy and leakage is increased.
3) Voltage overshoot to 6.5V is permissible, provided the duration is less than 2h cumulated. Reduced ADC accuracy and leakage is increased.
4) All V_{EXT} pins shall be connected together externally on the PCB.
5) All V_{DDP3} pins shall be connected together externally on the PCB.
6) Voltage overshoot to 4.29V is permissible, provided the duration is less than 2h cumulated. Reduced ADC accuracy and leakage is increased.
7) This parameter is valid under the assumption the PORST signal is constantly at low level during the power-up/power-down of V_{DDP3}.

3.5 5 V / 3.3 V switchable Pads

Pad classes LP, MP, MP+, and MPR support both Automotive Level (AL) or TTL level (TTL) operation. Parameters are defined for AL operation and degrade in TTL operation.

Table 3-6 Standard_Pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pin capacitance (digital inputs/outputs)	C_{IO} CC	-	6	10	pF	
Spike filter always blocked pulse duration	t_{SF1} CC	-	-	80	ns	PORST only
Spike filter pass-through pulse duration	t_{SF2} CC	220	-	-	ns	PORST only
PORST pad output current [1]	I_{PORST} CC	11	-	-	mA	V_{EXT} = 3.0V; V_{PORST} = 0.9V; T_J = 165°C
		13	-	-	mA	V_{EXT} = 4.5V; V_{PORST} = 1.0V

1) Pull-down with I_{PORST} relevant is always activated when a primary supply monitor detects a violation.

Table 3-7 Class LP 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input Hysteresis for LP pad [1]	$HYSLP$ CC	0.09 * $V_{EXT/FLEX}$	-	-	V	AL
		0.075 * $V_{EXT/FLEX}$	-	-	V	TTL
Input Leakage current for LP pad	I_{OZLP} CC	-150	-	150	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-350	-	350	nA	else
Input leakage current for P32.0	I_{OZP320} CC	-4900	-	4900	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-9400	-	9400	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); for T_J > 150°C
		-5800	-	5800	nA	else
		-12000	-	12000	nA	else; for T_J > 150°C
Pull-up current for LP pad	I_{PUHLP} CC	|30|	-	-	µA	V_{IHmin}; AL
		|43|	-	-	µA	V_{IHmin}; TTL
		-	-	|107|	µA	V_{ILmax}; AL and TTL

Table 3-7 Class LP 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pull-down current for LP pad	I_{PDLLP} CC	-	-	|100|	µA	V_{IHmin}; AL and TTL
		|46|	-	-	µA	V_{ILmax}; AL
		|21|	-	-	µA	V_{ILmax}; TTL
On-Resistance for LP pad, weak driver [2]	$R_{DSONLPW}$ CC	200	620	1040	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On-Resistance for LP pad, medium driver [2]	$R_{DSONLPM}$ CC	50	155	260	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
Rise / fall time for LP pad [3]	t_{LP} CC	-	-	95+2.1 * C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	200+2.9 * (C_L - 50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	25+0.5 * C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	50+0.75 * (C_L - 50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
Input high voltage for LP pad	V_{IHLP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		2.03 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for LP pad	V_{ILLP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.8 [5]	V	Hysteresis active, TTL
Input low / high voltage for LP pad	V_{ILHLP} CC	1.85	-	3.0	V	Hysteresis inactive; not available for P14.2, P14.4, and P15.1
Pad set-up time for LP pad	t_{SET_LP} CC	-	-	100	ns	
Input leakage current for P02.1	I_{OZ021} CC	-150	-	1030	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); T_J > 150°C
		-150	-	340	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); T_J = 150°C
		-420	-	1100	nA	else; T_J > 150°C
		-350	-	380	nA	else; T_J = 150°C
Pull down current for P32_0 pin	$I_{PDLP320}$ CC	-	-	|105|	µA	V_{IHmin}; AL and TTL
		|41|	-	-	µA	V_{ILmax}; AL
		|16|	-	-	µA	V_{ILmax}; TTL

Table 3-7 Class LP 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pull Up Current for P32_0 pin	$I_{PUHP320}$ CC	|25|	-	-	µA	V_{IHmin}; AL
		|38|	-	-	µA	V_{IHmin}; TTL
		-	-	|112|	µA	V_{ILmax}; AL and TTL
Short Circuit current for LP pad 6)	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-8 Class LP 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	50	MHz	Hysteresis active
		-	-	100	MHz	Hysteresis inactive
Input Hysteresis for LP pad 1)	$HYSLP$ CC	0.05 * $V_{EXT/FLEX}$	-	-	V	AL and TTL
Input Leakage current for LP pad	I_{OZLP} CC	-150	-	150	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-350	-	350	nA	else
Input leakage current for P32.0	I_{OZP320} CC	-4900	-	4900	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-9400	-	9400	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); for T_J > 150 °C
		-5800	-	5900	nA	else
		-12000	-	12000	nA	else; for T_J > 150°C
Pull-up current for LP pad	I_{PUHLP} CC	|17|	-	-	µA	V_{IHmin}; AL
		|19|	-	-	µA	V_{IHmin}; TTL
		-	-	|75|	µA	V_{ILmax}; AL and TTL
Pull-down current for LP pad	I_{PDLLP} CC	-	-	|75|	µA	V_{IHmin}; AL and TTL
		|22|	-	-	µA	V_{ILmax}; AL
		|11|	-	-	µA	V_{ILmax}; TTL
On-Resistance for LP pad, weak driver 2)	$R_{DSONLPW}$ CC	250	875	1500	Ohm	; NMOS/PMOS ; I_{OH}=0.25mA ; I_{OL}=0.25mA

Table 3-8 Class LP 3.3V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
On-Resistance for LP pad, medium driver [2]	$R_{DSONLPM}$ CC	70	235	400	Ohm	; NMOS/PMOS ; I_{OH}=1mA ; I_{OL}=1mA
Rise / fall time for LP pad [3]	t_{LP} CC	-	-	150+3.4 * C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	320+4.5 * (C_L - 50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	30+0.8*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	70+1.1 * (C_L - 50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
Input high voltage for LP pad	V_{IHLP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		1.6 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for LP pad	V_{ILLP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.5 [5]	V	Hysteresis active, TTL
Input low / high voltage for LP pad	V_{ILHLP} CC	1.1	-	1.9	V	Hysteresis inactive; not available for P14.2, P14.4, and P15.1
Pad set-up time for LP pad	t_{SET_LP} CC	-	-	100	ns	
Input leakage current for P02.1	I_{OZ021} CC	-150	-	920	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); T_J > 150°C
		-150	-	330	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$); T_J = 150°C
		-360	-	1000	nA	else; T_J > 150°C
		-350	-	375	nA	else; T_J = 150°C
Pull down current for P32_0 pin	$I_{PDLP320}$ CC	-	-	|80|	µA	V_{IHmin}; AL and TTL
		|17|	-	-	µA	V_{ILmax}; AL
		|6|	-	-	µA	V_{ILmax}; TTL
Pull Up Current for P32_0 pin	$I_{PUHP320}$ CC	|12|	-	-	µA	V_{IHmin}; AL
		|14|	-	-	µA	V_{IHmin}; TTL
		-	-	|80|	µA	V_{ILmax}; AL and TTL
Short Circuit current for LP pad [6]	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-9 Class MP 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input Hysteresis for MP pad 1)	$HYSMP$ CC	0.09 * $V_{EXT/FLEX}$	-	-	V	AL
		0.075 * $V_{EXT/FLEX}$	-	-	V	TTL
Input Leakage current for MP pad	I_{OZMP} CC	-500	-	500	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1000	-	1000	nA	else
Pull-up current for MP pad	I_{PUHMP} CC	|30|	-	-	µA	V_{IHmin}; AL
		|43|	-	-	µA	V_{IHmin}; TTL
		-	-	|107|	µA	V_{ILmax}; AL and TTL
Pull-down current for MP pad	I_{PDLMP} CC	-	-	|100|	µA	V_{IHmin}; AL and TTL
		|46|	-	-	µA	V_{ILmax}; AL
		|21|	-	-	µA	V_{ILmax}; TTL
On-Resistance for MP pad, weak driver 2)	$R_{DSONMPW}$ CC	200	620	1040	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On-Resistance for MP pad, medium driver 2)	$R_{DSONMPM}$ CC	50	155	260	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
On-Resistance for MP pad, strong driver 2)	$R_{DSONMPS}$ CC	20	75	130	Ohm	PMOS/NMOS ; I_{OH}=8mA ; I_{OL}=8mA

Table 3-9 Class MP 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise / fall time for MP pad [3]	t_{MP} CC	-	-	95+2.1*C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	200+2.9*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	25+0.5*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	50 + 0.75 * (CL - 50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	17.5+0.25 *C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	30+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	7+0.2*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	17+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong
Input high voltage for MP pad	V_{IHMP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		2.03 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for MP pad	V_{ILMP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.8 [5]	V	Hysteresis active, TTL
Input low / high voltage for MP pad	V_{ILHMP} CC	1.85	-	3.0	V	Hysteresis inactive
Pad set-up time for MP pad	t_{SET_MP} CC	-	-	100	ns	
Short Circuit current for MP pad [6]	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-10 Class MP 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	50	MHz	Hysteresis active
		-	-	100	MHz	Hysteresis inactive
Input Hysteresis for MP pad [1]	$HYSMP$ CC	0.05 * $V_{EXT/FLEX}$	-	-	V	AL and TTL
Input Leakage current for MP pad	I_{OZMP} CC	-500	-	500	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1000	-	1000	nA	else
Pull-up current for MP pad	I_{PUHMP} CC	|17|	-	-	µA	V_{IHmin}; AL
		|19|	-	-	µA	V_{IHmin}; TTL
		-	-	|75|	µA	V_{ILmax}; AL and TTL
Pull-down current for MP pad	I_{PDLMP} CC	-	-	|75|	µA	V_{IHmin}; AL and TTL
		|22|	-	-	µA	V_{ILmax}; AL
		|11|	-	-	µA	V_{ILmax}; TTL
On-Resistance for MP pad, weak driver [2]	$R_{DSONMPW}$ CC	250	875	1500	Ohm	; NMOS/PMOS ; I_{OH}=0.25mA ; I_{OL}=0.25mA
On-Resistance for MP pad, medium driver [2]	$R_{DSONMPM}$ CC	70	235	400	Ohm	; NMOS/PMOS ; I_{OH}=1mA ; I_{OL}=1mA
On-Resistance for MP pad, strong driver [2]	$R_{DSONMPS}$ CC	20	110	200	Ohm	PMOS/NMOS ; I_{OH}=4mA ; I_{OL}=4mA
Rise / fall time for MP pad [3]	t_{MP} CC	-	-	150+3.4* C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	320+4.5*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	30+0.8*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	70+1.1*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	32.5+0.35 *C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	50+0.45*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	14.5+0.35 *C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	32+0.5*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong

Table 3-10 Class MP 3.3V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input high voltage for MP pad	V_{IHMP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		1.6 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for MP pad	V_{ILMP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.5 [5]	V	Hysteresis active, TTL
Input low / high voltage for MP pad	V_{ILHMP} CC	1.1	-	1.9	V	Hysteresis inactive
Pad set-up time for MP pad	t_{SET_MP} CC	-	-	100	ns	
Short Circuit current for MP pad [6]	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-11 Class MP+ 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input hysteresis for MP+ pad [1]	$HYSMPP$ CC	0.09 * $V_{EXT/FLEX}$	-	-	V	AL
		0.075 * $V_{EXT/FLEX}$	-	-	V	TTL
Input leakage current for MP+ pad	I_{OZMPP} CC	-750	-	750	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1500	-	1500	nA	else
Pull-up current for MP+ pad	I_{PUHMPP} CC	|30|	-	-	µA	V_{IHmin}; AL
		|43|	-	-	µA	V_{IHmin}; TTL
		-	-	|107|	µA	V_{ILmax}; AL and TTL
Pull-down current for MP+ pad	I_{PDLMPP} CC	-	-	|100|	µA	V_{IHmin}; AL and TTL
		|46|	-	-	µA	V_{ILmax}; AL
		|21|	-	-	µA	V_{ILmax}; TTL

Table 3-11 Class MP+ 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
On-resistance for MP+ pad, weak driver [2]	$R_{DSONMPPW}$ CC	200	620	1040	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On-resistance for MP+ pad, medium driver [2]	$R_{DSONMPPM}$ CC	50	155	260	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
On-resistance for MP+ pad, strong driver [2]	$R_{DSONMPPS}$ CC	20	55	90	Ohm	PMOS/NMOS ; I_{OH}=8mA ; I_{OL}=8mA
Rise/fall time for MP+ pad [3]	t_{MPP} CC	-	-	95+2.1*C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	200+2.9*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	25+0.5*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	50+0.75*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	9+0.16*C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	17+0.2*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	4+0.16*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	12+0.21*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong
		-	-	5	ns	from 0.8V to 2.0V (RMII) ; C_L=25pF ; edge=sharp ; pin out driver=strong
		-	-	4.5	ns	C_L=15pF ; edge=sharp ; pin out driver=strong
Input high voltage for MP+ pad	V_{IHMPP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		2.03 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for MP+ pad	V_{ILMPP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.8 [5]	V	Hysteresis active, TTL
Input low / high voltage for MP+ pad	V_{ILHMPP} CC	1.85	-	3.0	V	Hysteresis inactive

Table 3-11 Class MP+ 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pad set-up time for MP+ pad	t_{SET_MPP} CC	-	-	100	ns	
Short circuit current for MP+ pad [6]	I_{SCMPP} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-12 Class MP+ 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	50	MHz	Hysteresis active
		-	-	100	MHz	Hysteresis inactive
Input hysteresis for MP+ pad [1]	$HYSMPP$ CC	0.05 * $V_{EXT/FLEX}$	-	-	V	AL and TTL
Input leakage current for MP+ pad	I_{OZMPP} CC	-750	-	750	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1500	-	1500	nA	else
Pull-up current for MP+ pad	I_{PUHMPP} CC	|17|	-	-	µA	V_{IHmin}; AL
		|19|	-	-	µA	V_{IHmin}; TTL
		-	-	|75|	µA	V_{ILmax}; AL and TTL
Pull-down current for MP+ pad	I_{PDLMPP} CC	-	-	|75|	µA	V_{IHmin}; AL and TTL
		|22|	-	-	µA	V_{ILmax}; AL
		|11|	-	-	µA	V_{ILmax}; TTL
On-resistance for MP+ pad, weak driver [2]	$R_{DSONMPPW}$ CC	250	875	1500	Ohm	; NMOS/PMOS ; I_{OH}=0.25mA ; I_{OL}=0.25mA
On-resistance for MP+ pad, medium driver [2]	$R_{DSONMPPM}$ CC	70	235	400	Ohm	; NMOS/PMOS ; I_{OH}=1mA ; I_{OL}=1mA
On-resistance for MP+ pad, strong driver [2]	$R_{DSONMPPS}$ CC	20	75	130	Ohm	PMOS/NMOS ; I_{OH}=4mA ; I_{OL}=4mA

Table 3-12 Class MP+ 3.3V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise/fall time for MP+ pad [3]	t_{MPP} CC	-	-	150+3.4* C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	320+4.5*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	30+0.8*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	70+1.1*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	20+0.2*C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	30+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	13+0.2*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	23+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong
		-	-	5	ns	from 0.8V to 2.0V (RMII) ; C_L=25pF ; edge=sharp ; pin out driver=strong
		-	-	4.5	ns	from 0.2 * $V_{EXT/FLEX}$ to 0.8 * $V_{EXT/FLEX}$; C_L=15pF ; edge=sharp ; pin out driver=strong
Input high voltage for MP+ pad	V_{IHMPP} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		1.6 [4]	-	-	V	Hysteresis active, TTL
Input low voltage for MP+ pad	V_{ILMPP} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.5 [5]	V	Hysteresis active, TTL
Input low / high voltage for MP+ pad	V_{ILHMPP} CC	1.1	-	1.9	V	Hysteresis inactive
Pad set-up time for MP+ pad	t_{SET_MPP} CC	-	-	100	ns	
Short circuit current for MP+ pad [6]	I_{SCMPP} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$
6) The values are only valid if the pad is not used during operation, otherwise I_{SC} defines the limits for operation.

Table 3-13 Class MPR 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input Hysteresis for MPR pads [1]	$HYSMPR$ CC	0.09 * $V_{EXT/FLEX}$	-	-	V	AL
		0.075* $V_{EXT/FLEX}$	-	-	V	TTL
Input leakage current class MPR	I_{OZMPR} CC	-750	-	750	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1500	-	1500	nA	else
Pull-up current	I_{PUHMPR} CC	|30|	-	-	µA	V_{IHmin}; AL
		|43|	-	-	µA	V_{IHmin}; TTL
		-	-	|107|	µA	V_{ILmax}; AL and TTL
Pull-down current	I_{PDLMPR} CC	-	-	|100|	µA	V_{IHmin}; AL and TTL
		|46|	-	-	µA	V_{ILmax}; AL
		|21|	-	-	µA	V_{ILmax}; TTL
On-resistance of the MPR pad, weak driver [2]	$R_{DSONMPRW}$ CC	200	620	1040	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On-resistance of the MPR pad, medium driver [2]	$R_{DSONMPRM}$ CC	50	155	260	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
On-resistance of the MPR pad, strong driver [2]	$R_{DSONMPRS}$ CC	20	55	90	Ohm	PMOS/NMOS ; I_{OH}=8mA ; I_{OL}=8mA

Table 3-13 Class MPR 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise/fall time [3]	t_{MPR} CC	-	-	95+2.1*C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	200+2.9*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	25+0.5*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	50+0.75*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	9+0.16*C_L	ns	C_L≥0pF ; C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	17+0.2*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	4+0.16*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	12+0.21*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong
		-	-	5	ns	from 0.8V to 2.0V (RMII) ; C_L=25pF ; edge=sharp ; pin out driver=strong
		-	-	4.5	ns	from 0.2 * $V_{EXT/FLEX}$ to 0.8 * $V_{EXT/FLEX}$; C_L=15pF ; edge=sharp ; pin out driver=strong
Input high voltage, class MPR pads	V_{IHMPR} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		2.03 [4]	-	-	V	Hysteresis active, TTL
Input low voltage, class MPR pads	V_{ILMPR} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.8 [5]	V	Hysteresis active, TTL
Input low / high voltage, class MPR pads	V_{ILHMPR} SR	1.2	-	2.3	V	Hysteresis inactive
Pad set-up time	t_{SET_MPR} CC	-	-	100	ns	
Short circuit current Class MPR	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$

Table 3-14 Class MPR 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	50	MHz	Hysteresis active
		-	-	100	MHz	Hysteresis inactive
Input Hysteresis for MPR pads [1]	$HYSMPR$ CC	0.05 * $V_{EXT/FLEX}$	-	-	V	AL and TTL
Input leakage current class MPR	I_{OZMPR} CC	-750	-	750	nA	(0.1*$V_{EXT/FLEX}$) < V_{IN} < (0.9*$V_{EXT/FLEX}$)
		-1500	-	1500	nA	else
Pull-up current	I_{PUHMPR} CC	|17|	-	-	µA	V_{IHmin}; AL
		|19|	-	-	µA	V_{IHmin}; TTL
		-	-	|75|	µA	V_{ILmax}; AL and TTL
Pull-down current	I_{PDLMPR} CC	-	-	|75|	µA	V_{IHmin}; AL and TTL
		|22|	-	-	µA	V_{ILmax}; AL
		|11|	-	-	µA	V_{ILmax}; TTL
On-resistance of the MPR pad, weak driver [2]	$R_{DSONMPRW}$ CC	250	875	1500	Ohm	; NMOS/PMOS ; I_{OH}=0.25mA ; I_{OL}=0.25mA
On-resistance of the MPR pad, medium driver [2]	$R_{DSONMPRM}$ CC	70	235	400	Ohm	; NMOS/PMOS ; I_{OH}=1mA ; I_{OL}=1mA
On-resistance of the MPR pad, strong driver [2]	$R_{DSONMPRS}$ CC	20	75	130	Ohm	PMOS/NMOS ; I_{OH}=4mA ; I_{OL}=4mA

Table 3-14 Class MPR 3.3V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise/fall time [3]	t_{MPR} CC	-	-	150+3.4* C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	320+4.5*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	30+0.8*C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	70+1.1*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	20+0.2*C_L	ns	C_L≥0pF ; C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	30+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	13+0.2*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	23+0.3*(C_L-50)	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong
		-	-	5	ns	from 0.8V to 2.0V (RMII) ; C_L=25pF ; edge=sharp ; pin out driver=strong
		-	-	4.5	ns	from 0.2 * $V_{EXT/FLEX}$ to 0.8 * $V_{EXT/FLEX}$; C_L=15pF ; edge=sharp ; pin out driver=strong
Input high voltage, class MPR pads	V_{IHMPR} SR	(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active, AL
		1.6 [4]	-	-	V	Hysteresis active, TTL
Input low voltage, class MPR pads	V_{ILMPR} SR	-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active, AL
		-	-	0.5 [5]	V	Hysteresis active, TTL
Input low / high voltage, class MPR pads	V_{ILHMPR} SR	0.8	-	1.7	V	Hysteresis inactive
Pad set-up time	t_{SET_MPR} CC	-	-	100	ns	
Short circuit current Class MPR	I_{SC} SR	-10	-	10	mA	absolute max value (PSI5)

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.

2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.

3) Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.
4) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V
5) V_{ILx} = 0.17 * $V_{EXT/FLEX}$

Table 3-15 Class S

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input Hysteresis for S pad [1]	$HYSS$ CC	0.3	-	-	V	
Pull-up current for S pad	I_{PUHS} CC	|30|	-	-	µA	V_{IHmin}
		-	-	|107|	µA	V_{ILmax}
Pull-down current for S pad	I_{PDLS} CC	-	-	|100|	µA	V_{IHmin}
		|46|	-	-	µA	V_{ILmax}
Input Leakage current Class S	I_{OZS} CC	-350	-	350	nA	Analog Inputs with pull down diagnostics
		-150	-	150	nA	else
Input voltage high for S pad	V_{IHS} SR	-	-	(0.73*V_{DDM})-0.25	V	Hysteresis active
Input voltage low for S pad	V_{ILS} SR	(0.52*V_{DDM})-0.25	-	-	V	Hysteresis active
Input low threshold variation for S pad [2]	V_{ILSD} SR	-50	-	50	mV	max. variation of 1ms; V_{DDM}=constant
Input capacitance for S pad	C_{INS} CC	-	-	10	pF	
Pad set-up time for S pad	t_{SETS} CC	-	-	100	ns	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) VILSD is implemented to ensure J2716 specification. For details of dedicated pins please see AP32286 for details.

Table 3-16 Class I 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	Hysteresis active
		-	-	150	MHz	Hysteresis inactive
Input Hysteresis for I pad [1]	$HYSI$ CC	0.07 * $V_{EXT/FLEX}$	-	-	V	$\overline{\text{PORST}}$ pad only
		0.09 * $V_{EXT/FLEX}$	-	-	V	AL
		0.075 * $V_{EXT/FLEX}$	-	-	V	TTL
Pull-up current for I pad	I_{PUHI} CC	|30|	-	-	µA	V_{IHmin}; AL
		|43|	-	-	µA	V_{IHmin}; TTL
		-	-	|107|	µA	V_{ILmax}; AL and TTL

Table 3-16 Class I 5V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Pull-down current for I pad	I_{PDLI} CC	-	-	|100|	µA	V_{IHmin}; AL and TTL
		|46|	-	-	µA	V_{ILmax}; AL
		|21|	-	-	µA	V_{ILmax}; TTL
Input Leakage Current for I pad	I_{OZI} CC	-150	-	150	nA	$(0.1*V_{EXT/FLEX}) < V_{IN} < (0.9*V_{EXT/FLEX})$
		-350	-	350	nA	else
Input high voltage for I pad	V_{IHI} SR	2.03 [2]	-	-	V	Hysteresis active, TTL
		$(0.73*V_{EXT/FLEX})$-0.25	-	-	V	Hysteresis active; AL; not available for the $\overline{\text{PORST}}$ pad
Input low voltage for I pad	V_{ILI} SR	-	-	0.8 [3]	V	Hysteresis active, TTL
		-	-	$(0.52*V_{EXT/FLEX})$-0.25	V	Hysteresis active; AL; not available for the $\overline{\text{PORST}}$ pad
Input low / high voltage for I pad	V_{ILHI} CC	1.85	-	3.0	V	Hysteresis inactive
Pad set-up time for I pad	t_{SETI} CC	-	-	100	ns	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) $V_{IHx} = 0.27 * V_{EXT/FLEX} + 0.545V$
3) $V_{ILx} = 0.17 * V_{EXT/FLEX}$

Table 3-17 Class I 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	50	MHz	Hysteresis active
		-	-	100	MHz	Hysteresis inactive
Input Hysteresis for I pad [1]	$HYSI$ CC	0.045 * $V_{EXT/FLEX}$	-	-	V	$\overline{\text{PORST}}$ pad only
		0.05 * $V_{EXT/FLEX}$	-	-	V	AL and TTL
Pull-up current for I pad	I_{PUHI} CC	|17|	-	-	µA	V_{IHmin}; AL
		|19|	-	-	µA	V_{IHmin}; TTL
		-	-	|75|	µA	V_{ILmax}; AL and TTL
Pull-down current for I pad	I_{PDLI} CC	-	-	|75|	µA	V_{IHmin}; AL and TTL
		|22|	-	-	µA	V_{ILmax}; AL
		|11|	-	-	µA	V_{ILmax}; TTL
Input Leakage Current for I pad	I_{OZI} CC	-150	-	150	nA	$(0.1*V_{EXT/FLEX}) < V_{IN} < (0.9*V_{EXT/FLEX})$
		-350	-	350	nA	else

Table 3-17 Class I 3.3V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input high voltage for I pad	V_{IHI} SR	1.6 [2]	-	-	V	Hysteresis active, TTL
		(0.73*$V_{EXT/FLEX}$)-0.25	-	-	V	Hysteresis active; AL; not available for the $\overline{\text{PORST}}$ pad
Input low voltage for I pad	V_{ILI} SR	-	-	0.5 [3]	V	Hysteresis active, TTL
		-	-	(0.52*$V_{EXT/FLEX}$)-0.25	V	Hysteresis active; AL; not available for the $\overline{\text{PORST}}$ pad
Input low / high voltage for I pad	V_{ILHI} CC	1.1	-	1.9	V	Hysteresis inactive
Pad set-up time for I pad	t_{SETI} CC	-	-	100	ns	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.

2) V_{IHx} = 0.27 * $V_{EXT/FLEX}$ + 0.545V

3) V_{ILx} = 0.17 * $V_{EXT/FLEX}$

Table 3-18 Driver Mode Selection for LP Pads

PDx.2	PDx.1	PDx.0	Port Functionality	Driver Setting
X	X	0	Speed grade 1	medium (LPm)
X	X	1	Speed grade 2	weak (LPw)

Table 3-19 Driver Mode Selection for MP / MP+ Pads

PDx.2	PDx.1	PDx.0	Port Functionality	Driver Setting
X	0	0	Speed grade 1	Strong sharp edge (MPss / MP+ss / MPRss)
X	0	1	Speed grade 2	Strong medium edge (MPsm / MP+sm)
X	1	0	Speed grade 3	medium (MPm / MP+m / MPRm)
X	1	1	Speed grade 4	weak (MPw / MP+w / MPRw)

3.6 3.3 V only Pads

Pad classes LP, MP and MP+ support both Automotive Level (AL) or TTL level (TTL) operation. Parameters are defined for AL operation and degrade in TTL operation.

Table 3-20 Class A2

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	160	MHz	
Input Hysteresis for A2 pad [1]	$HYSA2$ CC	0.1 * V_{DDP3}	-	-	V	TTL;else
		0.06 * V_{DDP3}	-	-	V	valid for P21.6 and P21.7
Input Leakage current for A2 pad	I_{OZA2} CC	-300	-	300	nA	$(0.1*V_{EXT/FLEX}) < V_{IN} < (0.9*V_{EXT/FLEX})$
		-800	-	500	nA	else
Pull-up current for A2 pad	I_{PUHA2} CC	-	-	|100|	µA	V_{IHmin}
		|25|	-	-	µA	V_{ILmax}
Pull-down current for A2 pad	I_{PDLA2} CC	|23|	-	-	µA	V_{IHmin}
		-	-	|100|	µA	V_{ILmax}
On-Resistance for A2 pad, weak driver [2]	$R_{DSONA2W}$ CC	100	200	325	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On-Resistance for A2 pad, medium driver [2]	$R_{DSONA2M}$ CC	40	70	100	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
On-Resistance for A2 pad, strong driver [2]	$R_{DSONA2S}$ CC	20	35	50	Ohm	PMOS/NMOS ; I_{OH}=8mA ; I_{OL}=8mA
Rise/fall time for A2 pad [3]	t_{A2} CC	-	-	20+0.8*C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	17.5+0.85 *C_L	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	12+0.16* C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	11.5+0.17 *C_L	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	6+0.06*C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=strong
		-	-	5.5+0.07* C_L	ns	C_L≥50pF ; C_L≤200pF ; edge=medium ; pin out driver=strong
		-	-	0.0+0.12* C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=strong
		-	-	0.0+0.12* C_L	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=strong

Table 3-20 Class A2 (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input high voltage for A2 pad	V_{IHA2} SR	2.04 4)	-	-	V	TTL;valid for all A2 pads except TMS/DAP1, TRST, and TCK/DAP0
		0.7 * V_{DDP3}	-	-	V	valid for TMS/DAP1, TRST, and TCK/DAP0
Input low voltage for A2 pad	V_{ILA2} SR	-	-	0.8 5)	V	TTL;valid for all A2 pads except TMS/DAP1, TRST, and TCK/DAP0
		-	-	0.3 * V_{DDP3}	V	valid for TMS/DAP1, TRST, and TCK/DAP0
Pad set-up time for A2 pad	t_{SETA2} CC	-	-	100	ns	
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of V_{DDP3}.
4) V_{IHx} = 0.57 * V_{DDP3} - 0.03V
5) V_{ILx} = 0.25 * V_{DDP3} + 0.058V

Table 3-21 Driver Mode Selection for A2 Pads

PDx.2	PDx.1	PDx.0	Port Functionality	Driver Setting
X	0	0	Speed grade 1	Strong sharp edge
X	0	1	Speed grade 2	Strong medium edge
X	1	0	Speed grade 3	medium
X	1	1	Speed grade 4	weak

Table 3-22 Driver Mode Selection for F Pads

PDx.2	PDx.1	PDx.0	Port Functionality	Driver Setting
X	0	0	Speed grade 1	Reduced Strong sharp edge
X	0	1	Speed grade 2	Reduced Strong medium edge
X	1	0	Speed grade 3	medium
X	1	1	Speed grade 4	weak

3.7 High performance LVDS Pads (LVDSH)

This LVDS pad type is used for the high speed chip to chip communication inferface of the new TC270 / TC275 / TC277. It compose out of a LVDSH pad and a Class F pad.

This pad combination is always supplied by the 3.3V supply rail.

Table 3-23 Class F

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{IN} SR	-	-	75	MHz	
Input Hysteresis for F pad [1]	$HYSF$ CC	0.1 * V_{DDP3}	-	-	V	TTL
Input Leakage Current for F pad	I_{OZF} CC	-1000	-	1000	nA	(0.1*V_{DDP3}) < V_{IN} < (0.9*V_{DDP3}); valid for P21.2 and P21.3; T_J = 150°C
		-1500	-	1500	nA	(0.1*V_{DDP3}) < V_{IN} < (0.9*V_{DDP3}); valid for P21.2 and P21.3; T_J = 170°C
		-300	-	300	nA	(0.1*V_{DDP3}) < V_{IN} < (0.9*V_{DDP3}); valid for P21.4 and P21.5
		-2000	-	2000	nA	else; valid for P21.2 and P21.3; T_J = 150°C
		-3000	-	3000	nA	else; valid for P21.2 and P21.3; T_J = 170°C
		-600	-	600	nA	else; valid for P21.4 and P21.5
Pull-up current for F pad	I_{PUHF} CC	|25|	-	-	µA	V_{IHmin}
		-	-	|100|	µA	V_{ILmax}
Pull-down current for class F pads	I_{PDLF} CC	-	-	|100|	µA	V_{IHmin}
		|25|	-	-	µA	V_{ILmax}
On resistance for F pad, weak driver [2]	R_{DSONFW} CC	100	200	325	Ohm	PMOS/NMOS ; I_{OH}=0.5mA ; I_{OL}=0.5mA
On resistance for F pad, medium driver [2]	R_{DSONFM} CC	40	70	100	Ohm	PMOS/NMOS ; I_{OH}=2mA ; I_{OL}=2mA
On resistance for F pad, strong driver [2]	R_{DSONFS} CC	20	50	80	Ohm	PMOS/NMOS ; I_{OH}=4mA ; I_{OL}=4mA

Table 3-23 Class F (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise/fall time for F pad [3]	t_{rfF} CC	-	-	20+0.8*C_L	ns	C_L≤50pF ; pin out driver=weak
		-	-	17.5+0.85 *C_L	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=weak
		-	-	12+0.16* C_L	ns	C_L≤50pF ; pin out driver=medium
		-	-	11.5+0.17 *C_L	ns	C_L≥50pF ; C_L≤200pF ; pin out driver=medium
		-	-	7+0.16*C_L	ns	C_L≤50pF ; edge=medium ; pin out driver=reduced strong
		-	-	6.5+0.17* C_L	ns	C_L≥50pF ; C_L≤200pF ; edge=meduim ; pin out driver>reduced strong
		-	-	4+0.16*C_L	ns	C_L≤50pF ; edge=sharp ; pin out driver=reduced strong
		-	-	3.5+0.17* C_L	ns	C_L≥50pF ; C_L≤200pF ; edge=sharp ; pin out driver=reduced strong
Input high voltage for F pad	V_{IHF} SR	2.04 [4]	-	-	V	TTL
Input low voltage for F pad	V_{ILF} SR	-	-	0.8 [5]	V	TTL
Pad set-up time for F pad	t_{SETF} CC	-	-	100	ns	
Deviation of symmetry for rising and falling edges	SYM CC	-	-	20	%	

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can't be guaranteed that it suppresses switching due to external system noise.
2) For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.
3) Rise / fall times are defined 10% - 90% of V_{DDP3}.
4) V_{IHx} = 0.57 * V_{DDP3} - 0.03V
5) V_{ILx} = 0.25 * V_{DDP3} + 0.058V

C_L = 2.5 pF for all LVDSH parameters.

Table 3-24 LVDSH - IEEE standard LVDS general purpose link (GPL)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output impedance	R_0 CC	40	-	140	Ohm	Vcm = 1.0 V and 1.4 V
Rise time [1]	t_{rise20} CC	-	-	0.5	ns	ZL = 100 Ohm ±5% @2 pF
Fall time [1]	t_{fall20} CC	-	-	0.5	ns	ZL = 100 Ohm ±5% @ 2 pF
Output differential voltage	V_{OD} CC	250	-	400	mV	RT = 100 Ohm ±5%

Table 3-24 LVDSH - IEEE standard LVDS general purpose link (GPL) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output voltage high	V_{OH} CC	-	-	1475	mV	RT = 100 Ohm ±5% (400 mV/2) + 1275 mV
Output voltage low	V_{OL} CC	925	-	-	mV	RT = 100 Ohm ±5%
Output offset (Common mode) voltage	V_{OS} CC	1125	-	1275	mV	RT = 100 Ohm ±5%
Input voltage range	V_I SR	0	-	1600	mV	Driver ground potential difference < 925 mV; RT = 100 Ohm ±10%
		0	-	2000	mV	Driver ground potential difference < 925 mV; RT = 100 Ohm ±20%
Input differential threshold	V_{idth} SR	-100	-	100	mV	Driver ground potential difference < 925 mV
Delta output impedance	$dR0$ SR	-	-	10	%	Vcm = 1.0 V and 1.4 V (mismatch Pd and Pn)
Change in VOS between 0 and 1	$dVOS$ CC	-	-	25	mV	RT = 100 Ohm ±5%
Change in Vod between 0 and 1	$dVod$ CC	-	-	25	mV	RT = 100 Ohm ±5%
Duty cycle	t_{duty} CC	45	-	55	%	

1) Rise / fall times are defined for 20% - 80% of V_{OD}

Table 3-25 LVDSH - IEEE standard LVDS reduced link (REDL)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output impedance	R_0 CC	40	-	140	Ohm	Vcm = 1.0 V and 1.4 V
Output differential voltage	V_{OD} CC	150	-	250	mV	RT = 100 Ohm ±5%
Output voltage high	V_{OH} CC	-	-	1375	mV	RT = 100 Ohm ±5%
Output voltage low	V_{OL} CC	1025	-	-	mV	RT = 100 Ohm ±5%
Output offset (Common mode) voltage	V_{OS} CC	1125	-	1275	mV	RT = 100 Ohm ±5%
Input voltage range	V_I SR	825	-	1575	mV	Driver ground potential difference < 50 mV
Input differential threshold	V_{idth} SR	-100	-	100	mV	Driver ground potential difference < 50 mV
Change in VOS between 0 and 1	$dVOS$ CC	-	-	25	mV	RT = 100 Ohm ±5%
Change in Vod between 0 and 1	$dVod$ CC	-	-	25	mV	RT = 100 Ohm ±5%
Duty cycle	t_{duty} CC	45	-	55	%	

Table 3-25 LVDSH - IEEE standard LVDS reduced link (REDL) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
V_{OD} Fall time 1)	t_{fall10} CC	-	-	0.5	ns	ZL = 100 Ohm ±5% @ 2pF
V_{OD} Rise time 1)	t_{rise10} CC	-	-	0.5	ns	ZL = 100 Ohm ±5% @ 2pF

1) Rise / fall times are defined for 10% - 90% of V_{OD}

default after start-up = CMOS function

3.8 Medium performance LVDS Pads (LVDSM)

This LVDS pad type is used for the medium speed chip to chip communication inferface of the new TC270 / TC275 / TC277. It compose out of a LVDSM pad and a MP pad.

This pad combination is always supplied by the 5V or 3.3V.

For the parameters of the MP pad please see **Chapter 3.5**.

Table 3-26 LVDSM

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output impedance	R_O CC	40	100	140	Ohm	
Fall time	t_F CC	-	-	2.5	ns	Z_{load} = 100 Ohm; termination 100 Ohm ±1%
Rise time	t_R CC	-	-	2.5	ns	Z_{load} = 100 Ohm; termination 100 Ohm ±1%
Pad set-up time	t_{SET_LVDS} CC	-	10	13	µs	
Output Differential Voltage	V_{OD} CC	250	-	400	mV	termination 100 Ohm ±1%
Output voltage high	V_{OH} CC	-	-	1475	mV	termination 100 Ohm ±1%
Output voltage low	V_{OL} CC	925	-	-	mV	termination 100 Ohm ±1%
Output Offset Voltage	V_{OS} CC	1125	-	1275	mV	termination 100 Ohm ±1%

default after start-up = CMOS function

3.9 VADC Parameters

VADC parameter are valid for V_{DDM} = 4.5 V to 5.5 V.

This tables also covers the parameters for Class D pads.

Table 3-27 VADC

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog reference voltage [1]	V_{AREF} SR	V_{AGND} + 1.0	-	V_{DDM} + 0.05	V	
Analog reference ground	V_{AGND} SR	V_{SSM} - 0.05	-	V_{SSM} + 0.05	V	
Analog input voltage range	V_{AIN} SR	V_{AGND}	-	V_{AREF}	V	
Converter reference clock	f_{ADCI} SR	2	-	20	MHz	
Charge consumption per conversion [2] [3]	Q_{CONV} CC	-	50	75	pC	V_{AIN} = 5 V, charge consumed from reference pin, precharging disabled
		-	10	22	pC	V_{AIN} = 5 V, charge consumed from reference pin, precharging enabled
Conversion time for 12-bit result	t_{C12} CC	-	(16 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time and post calibration
Conversion time for 10-bit result	t_{C10} CC	-	(14 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Conversion time for 8-bit result	t_{C8} CC	-	(12 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Conversion time for fast compare mode	t_{CF} CC	-	(4 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Broken wire detection delay against V_{AGND} [4]	t_{BWG} CC	-	-	120	cycles	Result below 10%
Broken wire detection delay against V_{AREF} [5]	t_{BWR} CC	-	-	60	cycles	Result above 80%
Input leakage at analog inputs	I_{OZ1} CC	-350	-	350	nA	Analog Inputs overlaid with class LP pads or pull down diagnostics
		-150	-	150	nA	else
Total Unadjusted Error [1]	TUE CC	-4 [6]	-	4 [6]	LSB	12-bit resolution

Table 3-27 VADC (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
INL Error	EA_{INL} CC	-3	-	3	LSB	12-bit resolution
Gain Error [1]	EA_{GAIN} CC	-3.5	-	3.5	LSB	12-bit resolution
DNL error [1]	EA_{DNL} CC	-3	-	3	LSB	12-bit resolution
Offset Error [1]	EA_{OFF} CC	-4	-	4	LSB	12-bit resolution
Total capacitance of an analog input	C_{AINT} CC	-	-	30	pF	
Switched capacitance of an analog input	C_{AINS} CC	2	4	7	pF	
Resistance of the analog input path	R_{AIN} CC	-	-	1.5	kOhm	else
		-	-	1.8	kOhm	valid for analog inputs mapped to GPIOs
Switched capacitance of a reference input	C_{AREFS} CC	-	-	30	pF	
RMS Noise [7]	EN_{RMS} CC	-	0.5	0.8 [6][8]	LSB	
Positive reference V_{AREFx} pin leakage	I_{OZ2} CC	-7	-	7	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} > V_{DDM}$V; $T_J > 150$°C
		-4	-	4	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} > V_{DDM}$V; $T_J \leq 150$°C
		-2	-	3	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} \leq V_{DDM}$V; $T_J > 150$°C
		-1	-	1	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} \leq V_{DDM}$V; $T_J \leq 150$°C
Negative reference V_{AGNDx} pin leakage	I_{OZ3} CC	-13	-	13	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AGND} < V_{SSM}$V; $T_J > 150$°C
		-7	-	7	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AGND} < V_{SSM}$V; $T_J \leq 150$°C
		-3.3	-	2.5	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AREF} \leq V_{DDM}$V; $T_J > 150$°C
		-2.85	-	1	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AREF} \leq V_{DDM}$V; $T_J \leq 150$°C
Resistance of the reference input path	R_{AREF} CC	-	-	1	kOhm	
CSD resistance [9]	R_{CSD} CC	-	-	28	kOhm	

Table 3-27 VADC (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistance of the multiplexer diagnostics pull-down device	R_{MDD} CC	25 + 1*V_{IN}	-	35 - 8*V_{IN}	kOhm	0 V ≤ V_{IN} ≤ 2.5 V
		-5 + 13*V_{IN}	-	15 + 16*V_{IN}	kOhm	2.5 V ≤ V_{IN} ≤ V_{DDM}
Resistance of the multiplexer diagnostics pull-up device	R_{MDU} CC	45 - 6*V_{IN}	-	90 - 16*V_{IN}	kOhm	0 V ≥ V_{IN} ≤ 2.5 V
		40 - 4*V_{IN}	-	65 - 6*V_{IN}	kOhm	2.5 V ≤ V_{IN} ≤ V_{DDM}
Resistance of the pull-down test device [10]	R_{PDD} CC	-	-	0.3	kOhm	
CSD voltage accuracy [11] [12]	$dVCSD$ CC	-	-	10	%	
Wakeup time	t_{WU} CC	-	-	12	µs	

1) If the reference voltage is reduced by the factor k (k < 1), TUE,DNL,INL,Gain, and Offset errors increase also by the factor 1/k. V_{AREF} must be decoupled with an external capacitor.
2) For QCONV = X pC and a conversion time of 1 µs a rms value of X µA results for I_{AREFx}.
3) For the details of the mapping for a VADC group to pin V_{AREFx} please see the User's Manual.
4) The broken wire detection delay against V_{AGND} is measured in numbers of consecutive precharge cycles at a conversion rate higher than 1 conversion per 500 ms.
5) The broken wire detection delay against V_{AREF} is measured in numbers of consecutive precharge cycles at a conversion rate higher than 1 conversion per 10 ms. This function is influenced by leakage current, in particular at high temperature.
6) Resulting worst case combined error is arithmetic combination of TUE and EN_{RMS}.
7) This parameter is valid for soldered devices and requires careful analog board design.
8) Value is defined for one sigma Gauss distribution.
9) In order to avoid an additional error due to incomplete sampling, the sampling time shall be set greater than 5 * R_{CSD} * C_{AINS}.
10) The pull-down resistor R_{PDD} is connected between the input pad and the analog multiplexer. The input pad itself adds another 200-Ohm series resistance, when measuring through the pin.
11) CSD: Converter Self Diagnostics, for details please consult the User's Manual.
12) Note, that in case CSD voltage is chosen to nom. 1/3 or 2/3 of V_{AREF} voltage, the reference voltage is loaded with a current of max. V_{AREF} / 45 kOhm.

The following VADC parameter are valid for V_{DDM} = 2.97 V to 3.63 V.

Table 3-28 VADC_33V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog reference voltage [1]	V_{AREF} SR	V_{AGND} + 1.0	-	V_{DDM} + 0.05	V	
Analog reference ground	V_{AGND} SR	V_{SSM} - 0.05	-	V_{SSM} + 0.05	V	
Analog input voltage range	V_{AIN} SR	V_{AGND}	-	V_{AREF}	V	
Converter reference clock	f_{ADCI} SR	2	-	20	MHz	

Table 3-28 VADC_33V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Charge consumption per conversion [2) 3)]	Q_{CONV} CC	-	35	50	pC	V_{AIN} = 3.3 V, charge consumed from reference pin, precharging disabled
		-	8	17	pC	V_{AIN} = 3.3 V, charge consumed from reference pin, precharging enabled
Conversion time for 12-bit result	t_{C12} CC	-	(16 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time and post calibration
Conversion time for 10-bit result	t_{C10} CC	-	(14 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Conversion time for 8-bit result	t_{C8} CC	-	(12 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Conversion time for fast compare mode	t_{CF} CC	-	(4 + STC) x t_{ADCI} + 2 x t_{VADC}	-		Includes sample time
Broken wire detection delay against V_{AGND} [4)]	t_{BWG} CC	-	-	120	cycles	Result below 10%
Broken wire detection delay against V_{AREF} [5)]	t_{BWR} CC	-	-	60	cycles	Result above 80%
Input leakage at analog inputs	I_{OZ1} CC	-350	-	350	nA	Analog Inputs overlaid with class LP pads or pull down diagnostics
		-150	-	150	nA	else
Total Unadjusted Error [1)]	TUE CC	-12 [6)]	-	12 [6)]	LSB	12-bit Resolution; T_J > 150 °C
		-6 [6)]	-	6 [6)]	LSB	12-bit Resolution; T_J ≤ 150 °C
INL Error	EA_{INL} CC	-12	-	12	LSB	12-bit Resolution; T_J > 150 °C
		-5	-	5	LSB	12-bit Resolution; T_J ≤ 150 °C
Gain Error [1)]	EA_{GAIN} CC	-6	-	6	LSB	12-bit Resolution; T_J > 150 °C
		-5.5	-	5.5	LSB	12-bit Resolution; T_J ≤ 150 °C

Table 3-28 VADC_33V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
DNL error [1]	EA_{DNL} CC	-4	-	4	LSB	12-bit resolution
Offset Error [1]	EA_{OFF} CC	-6	-	6	LSB	12-bit Resolution; T_J > 150 °C
		-5	-	5	LSB	12-bit Resolution; T_J ≤ 150 °C
Total capacitance of an analog input	C_{AINT} CC	-	-	30	pF	
Switched capacitance of an analog input	C_{AINS} CC	2	4	7	pF	
Resistance of the analog input path	R_{AIN} CC	-	-	4.5	kOhm	
Switched capacitance of a reference input	C_{AREFS} CC	-	-	30	pF	
RMS Noise [7]	EN_{RMS} CC	-	-	1.7 [6][8]	LSB	
Positive reference V_{AREFx} pin leakage	I_{OZ2} CC	-6	-	6	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} > V_{DDM}$V; T_J>150°C
		-3.5	-	3.5	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} > V_{DDM}$V; T_J≤150°C
		-2	-	2.5	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} ≤ V_{DDM}$V; T_J>150°C
		-1	-	1	µA	$V_{AREFx} = V_{AREF2}$; $V_{AREF} ≤ V_{DDM}$V; T_J≤150°C
Negative reference V_{AGNDx} pin leakage	I_{OZ3} CC	-12	-	12	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AGND} < V_{SSM}$V; T_J>150°C
		-6.5	-	6.5	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AGND} < V_{SSM}$V; T_J≤150°C
		-2.2	-	2	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AREF} ≤ V_{DDM}$V; T_J>150°C
		-1	-	1	µA	$V_{AGNDx} = V_{AGND2}$; $V_{AREF} ≤ V_{DDM}$V; T_J≤150°C
Resistance of the reference input path	R_{AREF} CC	-	-	3	kOhm	
CSD resistance [9]	R_{CSD} CC	-	-	28	kOhm	

Table 3-28 VADC_33V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistance of the multiplexer diagnostics pull-down device	R_{MDD} CC	$25 + 3*V_{IN}$	-	$40 + 12*V_{IN}$	kOhm	$0\ V \le V_{IN} \le 1.667\ V$
		$0 + 18*V_{IN}$	-	$0 + 18*V_{IN}$	kOhm	$1.667\ V \le V_{IN} \le V_{DDM}$
Resistance of the multiplexer diagnostics pull-up device	R_{MDU} CC	$60 - 12*V_{IN}$	-	$120 - 30*V_{IN}$	kOhm	$0\ V \le V_{IN} \le 1.667\ V$
		$55 - 9*V_{IN}$	-	$95 - 15*V_{IN}$	kOhm	$1.667\ V \le V_{IN} \le V_{DDM}$
Resistance of the pull-down test device [10]	R_{PDD} CC	-	-	0.9	kOhm	
CSD voltage accuracy [11] [12]	$dVCSD$ CC	-	-	10	%	
Wakeup time	t_{WU} CC	-	-	12	µs	

1) If the reference voltage is reduced by the factor k (k < 1), TUE,DNL,INL,Gain, and Offset errors increase also by the factor 1/k. V_{AREF} must be decoupled with an external capacitor.
2) For QCONV = X pC and a conversion time of 1 µs a rms value of X µA results for I_{AREFx}.
3) For the details of the mapping for a VADC group to pin V_{AREFx} please see the User's Manual.
4) The broken wire detection delay against V_{AGND} is measured in numbers of consecutive precharge cycles at a conversion rate higher than 1 conversion per 500 ms.
5) The broken wire detection delay against V_{AREF} is measured in numbers of consecutive precharge cycles at a conversion rate higher than 1 conversion per 10 ms. This function is influenced by leakage current, in particular at high temperature.
6) Resulting worst case combined error is arithmetic combination of TUE and EN_{RMS}.
7) This parameter is valid for soldered devices and requires careful analog board design.
8) Value is defined for one sigma Gauss distribution.
9) In order to avoid an additional error due to incomplete sampling, the sampling time shall be set greater than $5 * R_{CSD} * C_{AINS}$.
10) The pull-down resistor R_{PDD} is connected between the input pad and the analog multiplexer. The input pad itself adds another 200-Ohm series resistance, when measuring through the pin.
11) CSD: Converter Self Diagnostics, for details please consult the User's Manual.
12) Note, that in case CSD voltage is chosen to nom. 1/3 or 2/3 of V_{AREF} voltage, the reference voltage is loaded with a current of max. V_{AREF} / 45 kOhm.

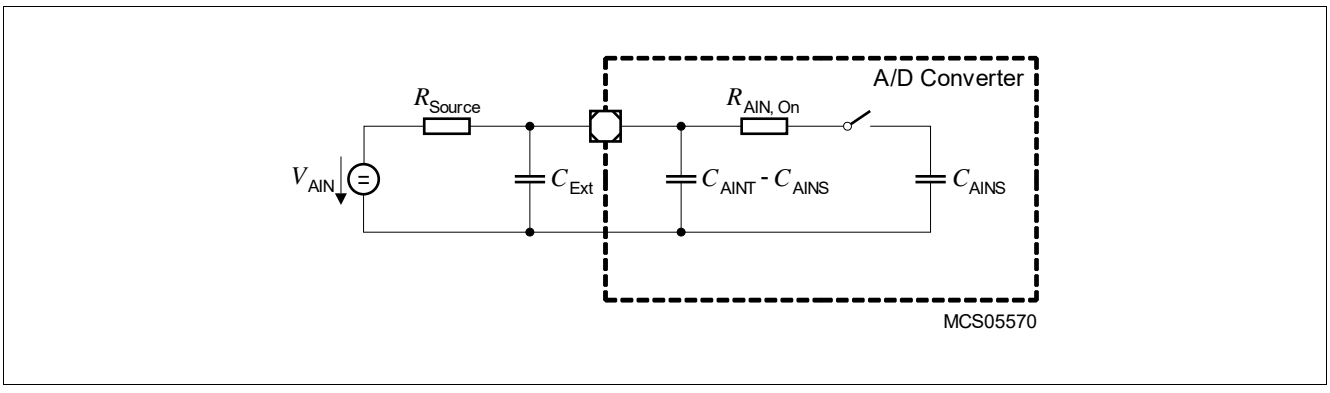


Figure 3-1 Equivalent Circuitry for Analog Inputs

3.10 DSADC Parameters

The following DSADC parameter are valid for V_{DDM} = 4.5 V to 5.5 V.

Table 3-29 DSADC

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog input voltage range [1]	V_{DSIN} SR	0	-	5	V	single ended
		0	-	10	V	differential; V_{DSxP} - V_{DSxN}
Reference load current	I_{REF} SR	-	4.5	6.3	µA	per twin-modulator (1 or 2 channels)
Modulator clock frequency [2]	f_{MOD} SR	10	-	20	MHz	
Gain error	ED_{GAIN} CC	-1	-	1 [3]	%	Calibrated once
		-3.5 [4]	-	3.5 [4]	%	Uncalibrated
		-0.2	-	0.2 [5]	%	calibrated; GAIN = 1; MODCFG.INCFGx=01
DC offset error	ED_{OFF} CC	-5	-	5 [5]	mV	calibrated
		-50	-	50	mV	calibrated once
		-100 [4]	0[4]	100 [4]	mV	gain = 1; uncalibrated
Common Mode Rejection Ratio	ED_{CM} CC	200	500	-		
Input impedance [6]	R_{DAIN} CC	100	130	170	kOhm	Exact value (±1%) available in UCB
Signal-Noise Ratio [7] [8] [9] [10]	SNR CC	80	-	-	dB	f_{PB} = 30 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
		78	-	-	dB	f_{PB} = 50 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
		70	-	-	dB	f_{PB} = 100 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
		74	-	-	dB	f_{PB} = 100 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
		76	-	-	dB	f_{PB} = 30 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
		74	-	-	dB	f_{PB} = 50 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
Pass band	f_{PB} CC	10 [11]	-	100	kHz	Output data rate f_D = f_{PB} * 3
Pass band ripple [8]	df_{PB} CC	-1	-	1	%	
Output sampling rate	f_D CC	30	-	330	kHz	

Table 3-29 DSADC (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
DC compensation factor	DCF CC	-3	-	-	dB	$10^{-5} f_D$
Positive reference V_{AREF1} pin leakage	I_{OZ5} CC	-2	-	2	µA	all ADCs disabled
Negative reference V_{AGND1} pin leakage	I_{OZ6} CC	-2	-	2	µA	all ADCs disabled
Stop band attenuation [8]	SBA CC	40	-	-	dB	0.5 ... 1 f_D
		45	-	-	dB	1 ... 1.5 f_D
		50	-	-	dB	1.5 ... 2 f_D
		55	-	-	dB	2 ... 2.5 f_D
		60	-	-	dB	2.5 ... OSR/2 f_D
Reference ground voltage	V_{AGND} SR	V_{SSM} - 0.05	-	V_{SSM} + 0.05	V	
Positive reference voltage	V_{AREF} SR	V_{DDMnom} * 0.9	-	V_{DDM} + 0.05	V	
Common mode voltage accuracy	dV_{CM} CC	-100	-	100	mV	from selected voltage
Common mode hold voltage deviation [12]	dV_{CMH} CC	-200	-	200	mV	From common mode voltage
Analog filter settling time	t_{AFSET} CC	-	2	4	µs	If enabled
Modulator recovery time	t_{MREC} CC	-	3.5	5.5	µs	After leaving overdrive state
Modulator settling time [13]	t_{MSET} CC	-	1	-	µs	After switching on, voltage regulator already running
Spurious Free Dynamic Range [7][14]	SFDR CC	60	-	-	dB	V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±10%

1) The maximum input range for symmetrical signals (e.g. AC-coupled inputs) depends on the selected internal/external common mode voltage. In this case the Amplitude is limited to V_{CM} * 2.
2) All modulators must run on the same frequency.
3) The calibration sequence must be executed once after an Application Reset
4) The total DC error for the uncalibrated case can be calculated by the geometric addition of ED_{GAIN} and ED_{OFF}
5) Recalibration needed in case of a temperature change > 20ºC
6) The variation of the impedance between different channels is < 1.5%.
7) Derating factors:
   -2 dB in standard-performance mode.
   -3 dB for CMV = 10_B, i.e. V_{CM} = (V_{AREF}±2%) / 2.0.
8) CIC3, FIR0, FIR1 filters enabled.
9) Single-ended mode reduces the SNR by 6 dB if the unused input is grounded, by 3 dB if the unused input connects to V_{CM} (GAIN = 2).
10) The defined limits are only valid if the following condition is not applicable: T_J > 150°C and V_{VAREF} > V_{DDM}.
11) 10 kHz only reachable with 10 MHz modulator clock frequency.
12) Voltage V_{CM} is proportional to V_{AREF}, voltage V_{CMH} is proportional to V_{DDM}.
13) The modulator needs to settle after being switched on and after leaving the overdrive state.
14) SFDR = 20 * log(INL / 2^N); N = amount of bits

The following DSADC parameter are valid for V_{DDM} = 2.97 V to 3.63 V.

Table 3-30 DSADC_33V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog input voltage range [1]	V_{DSIN} SR	0	-	3.3	V	single ended
		0	-	6.6	V	differential; V_{DSxP} - V_{DSxN}
Reference load current	I_{REF} SR	-	4.5	5.8	µA	per twin-modulator (1 or 2 channels)
Modulator clock frequency [2]	f_{MOD} SR	10	-	20	MHz	
Gain error	ED_{GAIN} CC	-1.5	-	1.5 [3]	%	Calibrated once
		-10 [4]	-	10 [4]	%	Uncalibrated
		-0.3	-	0.3 [5]	%	calibrated; GAIN = 1; MODCFG.INCFGx=01
DC offset error	ED_{OFF} CC	-5	-	5 [5]	mV	calibrated
		-50	-	50	mV	calibrated once
		-100 [4]	-	100 [4]	mV	gain = 1; uncalibrated
		-	0[4]	-	mV	gain = 1; uncalibrated; uncalibrated
Common Mode Rejection Ratio	ED_{CM} CC	200	500	-		
Input impedance [6]	R_{DAIN} CC	100	130	170	kOhm	Exact value (±1%) available in UCB
Signal-Noise Ratio [7] [8] [9] [10]	SNR CC	45	63	-	dB	f_{PB} = 100kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
		60	69	-	dB	f_{PB} = 100kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
		60	68	-	dB	f_{PB} = 30kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
		69	74	-	dB	f_{PB} = 30kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
		55	66	-	dB	f_{PB} = 50kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1
		65	72	-	dB	f_{PB} = 50kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1
Pass band	f_{PB} CC	10 [11]	-	100	kHz	Output data rate f_D = f_{PB} * 3
Pass band ripple [8]	df_{PB} CC	-1	-	1	%	

Table 3-30 DSADC_33V (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output sampling rate	f_D CC	30	-	330	kHz	
DC compensation factor	DCF CC	-3	-	-	dB	$10^{-5} f_D$
Positive reference V_{AREF1} pin leakage	I_{OZ5} CC	-2	-	2	µA	
Negative reference V_{AGND1} pin leakage	I_{OZ6} CC	-2	-	2	µA	
Stop band attenuation [8]	SBA CC	40	-	-	dB	0.5 ... 1 f_D
		45	-	-	dB	1 ... 1.5 f_D
		50	-	-	dB	1.5 ... 2 f_D
		55	-	-	dB	2 ... 2.5 f_D
		60	-	-	dB	2.5 ... OSR/2 f_D
Reference ground voltage	V_{AGND} SR	V_{SSM} - 0.05	-	V_{SSM} + 0.05	V	
Positive reference voltage	V_{AREF} SR	V_{DDMnom} * 0.9	-	V_{DDM} + 0.05	V	
Common mode voltage accuracy	dV_{CM} CC	-100	-	100	mV	from selected voltage
Common mode hold voltage deviation [12]	dV_{CMH} CC	-200	-	200	mV	From common mode voltage
Analog filter settling time	t_{AFSET} CC	-	2	4	µs	If enabled
Modulator recovery time	t_{MREC} CC	-	3.5	-	µs	After leaving overdrive state
Modulator settling time [13]	t_{MSET} CC	-	1	-	µs	After switching on, voltage regulator already running
Spurious Free Dynamic Range [7][14]	SFDR CC	52	-	-	dB	V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±10%
		60	-	-	dB	V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±5%

1) The maximum input range for symmetrical signals (e.g. AC-coupled inputs) depends on the selected internal/external common mode voltage. In this case the Amplitude is limited to V_{CM} * 2.
2) All modulators must run on the same frequency.
3) The calibration sequence must be executed once after an Application Reset
4) The total DC error for the uncalibrated case can be calculated by the geometric addition of ED_{GAIN} and ED_{OFF}
5) Recalibration needed in case of a temperature change > 20ºC.
6) The variation of the impedance between different channels is < 1.5%.
7) Derating factors:
   -2 dB in standard-performance mode.
   -3 dB for CMV = 10_B, i.e. V_{CM} = (V_{AREF}±2%) / 2.0.
8) CIC3, FIR0, FIR1 filters enabled.
9) Single-ended mode reduces the SNR by 6 dB if the unused input is grounded, by 3 dB if the unused input connects to V_{CM} (GAIN = 2).
10) The defined limits are only valid if the following condition is not applicable: T_J > 150°C and V_{VAREF} > V_{DDM}.

11) 10 kHz bandwidth only with 10Mhz modulator clock frequency reachable
12) Voltage V_{CM} is proportional to V_{AREF}, voltage V_{CMH} is proportional to V_{DDM}.
13) The modulator needs to settle after being switched on and after leaving the overdrive state.
14) SFDR = 20 * log(INL / 2^N); N = amount of bits

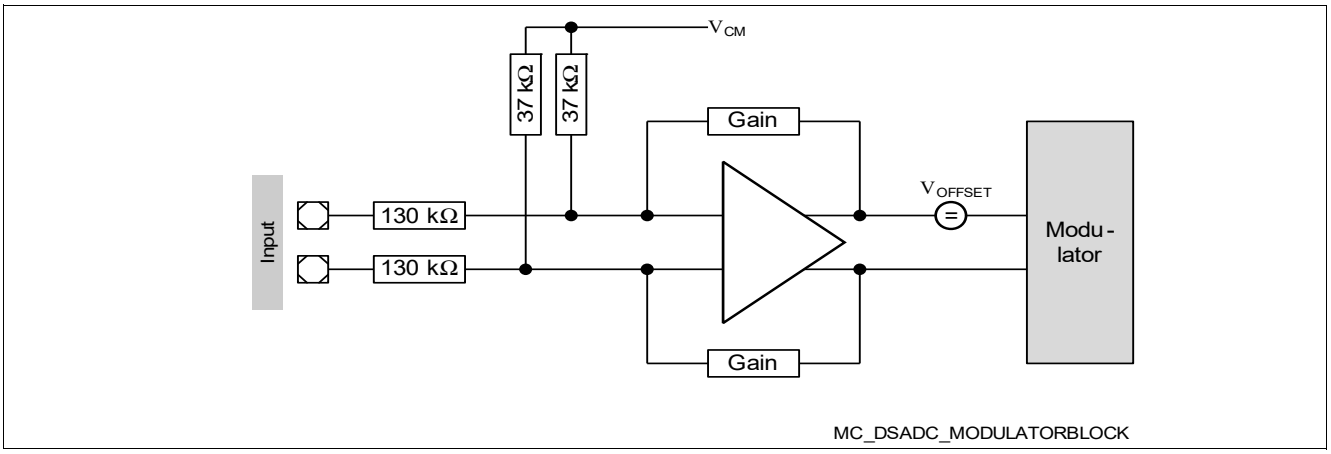


Figure 3-2 DSADC Analog Inputs

3.11 MHz Oscillator

OSC_XTAL is used as accurate and exact clock source. OSC_XTAL supports 8 MHz to 40 MHz crystals external outside of the device. Support of ceramic resonators is also provided.

Table 3-31 OSC_XTAL

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input current at XTAL1	I_{IX1} CC	-25	-	25	µA	V_{IN}>0V ; V_{IN}<V_{DDP3}V
Oscillator frequency	f_{OSC} SR	4	-	40	MHz	Direct Input Mode selected
		8	-	40	MHz	External Crystal Mode selected
Oscillator start-up time [1]	t_{OSCS} CC	-	-	5 [2]	ms	
Input high voltage at XTAL1	V_{IHBX} SR	0.8	-	V_{DDP3} + 0.5	V	If shaper is bypassed
Input low voltage at XTAL1	V_{ILBX} SR	-0.5	-	0.4	V	If shaper is bypassed
Input voltage at XTAL1	V_{IX} SR	-0.5	-	V_{DDP3} + 0.5	V	If shaper is not bypassed
Input amplitude (peak to peak) at XTAL1	V_{PPX} SR	0.3 * V_{DDP3}	-	V_{DDP3} + 1.0	V	If shaper is not bypassed; f_{OSC} > 25MHz
		0.4 * V_{DDP3}	-	V_{DDP3} + 1.0	V	If shaper is not bypassed; f_{OSC} ≤ 25MHz
Internal load capacitor	C_{L0} CC	2	2.35	2.7	pF	
Internal load capacitor	C_{L1} CC	2	2.35	2.7	pF	
Internal load capacitor	C_{L2} CC	3	3.5	4	pF	
Internal load capacitor	C_{L3} CC	5.1	5.9	6.6	pF	

1) t_{OSCS} is defined from the moment when V_{DDP3} = 3.13V until the oscillations reach an amplitude at XTAL1 of 0.3 * V_{DDP3}. The external oscillator circuitry must be optimized by the customer and checked for negative resistance as recommended and specified by crystal suppliers.

2) This value depends on the frequency of the used external crystal. For faster crystal frequencies this value decrease.

Note: It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimal parameters for the oscillator operation. Please refer to the limits specified by the crystal or ceramic resonator supplier.

3.12 Back-up Clock

The back-up clock provides an alternative clock source.

Table 3-32 Back-up Clock

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Back-up clock before trimming	f_{BACKUT} CC	75	100	125	MHz	V_{EXT}≥2.97V
Back-up clock after trimming	f_{BACKT} CC	97.5	100	102.5	MHz	V_{EXT}≥2.97V

3.13 Temperature Sensor

Table 3-33 DTS

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Measurement time	t_M CC	-	-	100	µs	
Calibration reference accuracy	T_{CALACC} CC	-1	-	1	°C	calibration points @ T_J=-40°C and T_J=127°C
Non-linearity accuracy over temperature range	T_{NL} CC	-2	-	2	°C	
Temperature sensor range	T_{SR} SR	-40	-	170	°C	
Start-up time after resets inactive	t_{TSST} SR	-	-	20	µs	

The following formula calculates the temperature measured by the DTS in [°C] from the RESULT bit field of the DTSSTAT register.

(3.1)

$$Tj = \frac{DTSSTATRESULT - (607)}{2,13}$$

3.14 Power Supply Current

The total power supply current defined below consists of leakage and switching component.

Application relevant values are typically lower than those given in the following table and depend on the customer's system operating conditions (e.g. thermal connection or used application configurations).

The operating conditions for the parameters in the following table are:

The real (realisic) power pattern defines the following conditions:

- T_J = 150 °C
- $f_{SRI} = f_{MAX} = f_{CPU0}$ = 200 MHz
- $f_{SPB} = f_{STM} = f_{GTM} = f_{BAUD1} = f_{BAUD2} = f_{ASCLIN}$ = 40 MHz
- V_{DD} = 1.326 V
- V_{DDP3} = 3.366 V
- $V_{EXT / FLEX} = V_{DDM}$ = 5.1 V
- all cores are active including one lockstep core
- the following peripherals are inactive: HSM, HSCT, Ethernet, PSI5, I2C, FCE, MTU, and 50% of the DSADC channels

The max power pattern defines the following conditions:

- T_J = 150 °C
- $f_{SRI} = f_{MAX} = f_{CPU0}$ = 200 MHz
- $f_{SPB} = f_{STM} = f_{GTM} = f_{BAUD1} = f_{BAUD2} = f_{ASCLIN}$ = 100 MHz
- V_{DD} = 1.43 V
- V_{DDP3} = 3.63 V
- $V_{EXT / FLEX} = V_{DDM}$ = 5.5 V
- all cores and lockstep cores are active
- all peripherals are active

Table 3-34 Power Supply

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
∑ Sum of I_{DD} 1.3 V core and peripheral supply currents	I_{DD} CC	-	-	550	mA	max power pattern
		-	-	350	mA	real power pattern
I_{DD} core current during active power-on reset (PORST held low)	$I_{DDPORST}$ CC	-	-	80	mA	T_J=125°C
		-	-	160	mA	T_J=150°C
		-	-	215	mA	T_J=165°C
I_{DD} core current of CPU0 lockstep core active	I_{DDC01} CC	-	-	36	mA	real power pattern
I_{DD} core current of CPU1 main core with CPU1 lockstep core inactive	I_{DDC10} CC	-	-	43	mA	real power pattern
I_{DD} core current of CPU1 main core with lockstep core active	I_{DDC11} CC	-	-	I_{DDC10} + 36	mA	real power pattern
I_{DD} core current of CPU2 main core	I_{DDC20} CC	-	-	37	mA	real power pattern

Table 3-34 Power Supply (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
I_{DD} core current added by HSM	I_{DDHSM} CC	-	-	20	mA	HSM running at 100MHz.
∑ Sum of 3.3 V supply currents without pad activity	$I_{DDx3RAIL}$ CC	-	-	57	mA	real power pattern
I_{DDFL3} Flash memory current	I_{DDFL3} CC	-	-	42 [1]	mA	flash read current
		-	-	42 [2]	mA	flash read current while programming Dflash
I_{DDP3} supply current without pad activity	I_{DDP3} CC	-	-	15 [1]	mA	real power pattern; incl. OSC current & flash read current
		-	-	37 [3]	mA	incl. OSC current and flash 3.3V programming current when using external 5V supply
		-	-	39 [2]	mA	incl. OSC current and flash programming current at 3.3V
I_{DDP3} supply current for LVDSH pads in LVDS mode	$I_{DDP3LVDSH}$ CC	-	-	16	mA	
Σ Sum of external and ADC supply currents (incl. $I_{EXTFLEX}$+I_{DDM}+$I_{EXTLVDSM}$)	$I_{EXTRAIL}$ CC	-	-	62	mA	real power pattern
Sum of I_{EXT} and I_{FLEX} supply current without pad activity	$I_{EXT/FLEX}$ CC	-	-	4	mA	real power pattern; PORST output inactive.
I_{EXT} supply current for LVDSM pads in LVDS mode	$I_{EXTLVDSM}$ CC	-	-	14 [4]	mA	real power pattern

Table 3-34 Power Supply (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
I_{DDM} supply current	I_{DDM} CC	-	-	44	mA	real power pattern; sum of currents of DSADC and VADC modules
		-	-	30	mA	current for DSADC module only; 50% DSADC channels active.
		-	-	14	mA	real pattern; current for VADC only
		-	-	59 [5]	mA	max power pattern; All DSADC channels active 100% time.
		-	-	17 [6]	mA	max power pattern; All VADC converters are active 100% time
Σ Sum of all currents (incl. $I_{EXTRAIL}$+$I_{DDx3RAIL}$+I_{DD})	I_{DDTOT} CC	-	-	469	mA	real power pattern
Σ Sum of all currents with DC-DC EVR13 regulator active [7]	$I_{DDTOTDC3}$ CC	-	-	302	mA	real power pattern; V_{EXT} = 3.3V
Σ Sum of all currents with DC-DC EVR13 regulator active [7]	$I_{DDTOTDC5}$ CC	-	-	240	mA	real power pattern; V_{EXT} = 5V
∑ Sum of all currents (STANDBY mode)	I_{EVRSB} CC	-	-	150 [8]	µA	Standby RAM is active. Power to remaining domains switched off. T_J = 25°C; V_{EVRSB} = 5V
∑ Sum of all currents (SLEEP mode)	I_{SLEEP} CC	-	-	15	mA	All CPUs in idle, All peripherals in sleep, $f_{SRI/SPB}$ = 1 MHz via LPDIV divider; T_J = 25°C
Maximum power dissipation	PD CC	-	-	1480	mW	max power pattern
		-	-	1014	mW	real power pattern

1) Realistic Pflash read pattern with 70% Pflash bandwidth utlilization and a code mix of 50% 0s and 50% 1s. A common decoupling capacitor of atleast 100nF for (V_{DDFL3}+V_{DDP3}) is used. Dflash read current is also included. Flash read current is predominantly drawn from V_{DDFL3} pin and a minor part drawn from the neighbouring V_{DDP3} pin.

2) Continuous Dflash programming in burst mode with 3.3 V supply and realistic Pflash read access in parallel. Erase currents of the corresponding flash modules are less than the respective programming currents at V_{DDP3} pin. Programming and erasing flash may generate transient current spikes of up to x mA for maximum x us which is handled by the decoupling and buffer capacitors. This parameter is relevant for external power supply dimensioning and not for thermal considerations.

3) In addition to the current specified, upto 4 mA is additionally drawn at V_{EXT} supply in burst programming mode with 5V external supply. Erase currents of the corresponding flash modules are less than the respective programming currents at V_{DDP3} supply. This parameter is relevant for external power supply dimensioning and not for thermal considerations.

4) The current consumption is for 2 pairs of LVDSM differential pads (8 pins). A single pair of LVDSM differential pads (4 pins) consumes 7 mA.
5) The current consumption is for 6 DS channels with standard performance (MCFG=11b). A single DS channel instance consumes 6-8 mA.
6) A single converter instance of VADC unit consumes 2 mA.
7) The total current drawn from external regulator is estimated with 72% EVR13 SMPS regulator Efficiency. $I_{DDTOTDC}$x is calculated from I_{DDTOT} using the scaled core current [(I_{DD} x V_{DD})/(VinxEfficiency)] and constitutes all other rail currents and I_{DDM}.
8) Current at V_{EVRSB} supply pin during normal RUN mode is less than 5 mA at Tj =150 degC. The transition between RUN mode to STANDBY mode has a duration of less than 100us during which the current is higher but is less than 8 mA at Tj =150 degC. Once STANDBY mode is entered with only Standby RAM active the current is less than 5mA at Tj = 150 degC. It is recommended to have atleast 100 nF decoupling capacitor at this pin.

3.14.1 Calculating the 1.3 V Current Consumption

The current consumption of the 1.3 V rail compose out of two parts:

- Static current consumption
- Dynamic current consumption

The static current consumption is related to the device temperature T_J and the dynamic current consumption depends of the configured clocking frequencies and the software application executed. These two parts needs to be added in order to get the rail current consumption.

(3.2)

$$I_0 = 1,135\left[\frac{mA}{C}\right] \times e^{0,02689 \times T_J[C]}$$

(3.3)

$$I_0 = 3,264\left[\frac{mA}{C}\right] \times e^{0,0259 \times T_J[C]}$$

Function 2 defines the typical static current consumption and Function 3 defines the maximum static current consumption. Both functions are valid for V_{DD} = 1.326 V.

3.15 Power-up and Power-down

3.15.1 External Supply Mode

5 V & 1.3 V supplies are externally supplied. 3.3V is generated internally by EVR33.

- External supplies VEXT and VDD may ramp-up or ramp-down independent of each other with regards to start, rise and fall time(s). Voltage Ramp-up from a residual threshold (Eg : up to 1 V) should also lead to a normal startup of the device.
- The rate at which current is drawn from the external regulator (dIEXT /dt or dIDD /dt) is limited in the Start-up phase to a maximum of 50 mA/100 us.
- PORST is active/asserted when either PORST (input) or PORST (output) is active/asserted.
- PORST (input) active means that the reset is held active by external agents by pulling the PORST pin low. It is recommended to keep the PORST (input) asserted until all the external supplies are above their primary reset thresholds.
- PORST (output) active means that µC asserts the reset internally and drives the PORST pin low thus propagating the reset to external devices. The PORST (output) is asserted by the µC when atleast one among the three supply domains (1.3 V, 3.3 V or 5 V) violate their primary under-voltage reset thresholds.The PORST (output) is deasserted by the µC when all supplies are above their primary reset thresholds and the basic supply and clock infrastructure is available.
- The power sequence as shown in **Figure 3-3** is enumerated below
  - T1 refers to the point in time when basic supply and clock infrastructure is available as the external supplies ramp up. The supply mode is evaluated based on the HWCFG [0:2] pins and consequently a soft start of EVR33 regulator is initiated.
  - T2 refers to the point in time when all supplies are above their primary reset thresholds. EVR33 regulator has ramped up. PORST (output) is deasserted and HWCFG [0:7] pins are latched on PORST rising edge. Firmware execution is initiated.
  - T3 refers to the point in time when Firmware execution is completed. User code execution starts with a default frequency of 100 MHz.
  - T4 refers to the point in time during the Ramp-down phase when atleast one of the externally provided or generated supplies (1.3 V, 3.3 V or 5 V) drop below their respective primary under-voltage reset thresholds.

Please note that there is no special requirements for $\overline{\text{PORST}}$ slew rates.

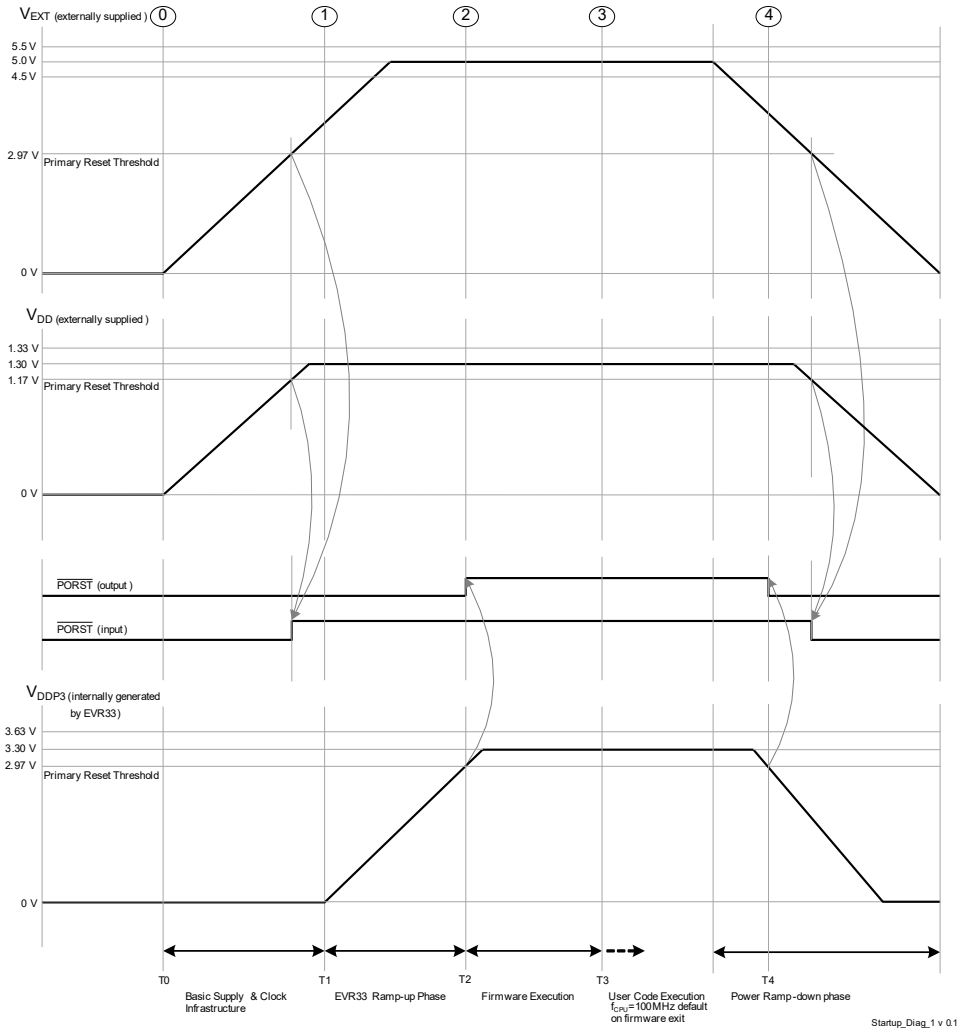


Figure 3-3 External Supply Mode - 5 V and 1.3 V externally supplied

3.15.2 Single Supply Mode

5 V single supply mode. 1.3 V & 3.3 V are generated internally by EVR13 & EVR33.

- The rate at which current is drawn from the external regulator (dIEXT /dt) is limited in the Start-up phase to a maximum of 50 mA/100 us.
- PORST is active/asserted when either PORST (input) or PORST (output) is active/asserted.
- PORST (input) active means that the reset is held active by external agents by pulling the PORST pin low. It is recommended to keep the PORST (input) asserted until the external supply is above the respective primary reset threshold.
- PORST (output) active means that µC asserts the reset internally and drives the PORST pin low thus propagating the reset to external devices. The PORST (output) is asserted by the µC when atleast one among the three supply domains (1.3 V, 3.3 V or 5 V) violate their primary under-voltage reset thresholds.The PORST (output) is deasserted by the µC when all supplies are above their primary reset thresholds and the basic supply and clock infrastructure is available.
- The power sequence as shown in **Figure 3-4** is enumerated below
  - T1 refers to the point in time when basic supply and clock infrastructure is available as the external supply ramps up. The supply mode is evaluated based on the HWCFG [0:2] pins and consequently a soft start of EVR13 and EVR33 regulators are initiated.
  - T2 refers to the point in time when all supplies are above their primary reset thresholds. EVR13 and EVR33 regulators have ramped up. PORST (output) is deasserted and HWCFG [0:7] pins are latched on PORST rising edge. Firmware execution is initiated.
  - T3 refers to the point in time when Firmware execution is completed. User code execution starts with a default frequency of 100 MHz.
  - T4 refers to the point in time during the Ramp-down phase when atleast one of the externally provided or generated supplies (1.3 V, 3.3 V or 5 V) drop below their respective primary under-voltage reset thresholds.

Please note that there is no special requirements for $\overline{\text{PORST}}$ slew rates.

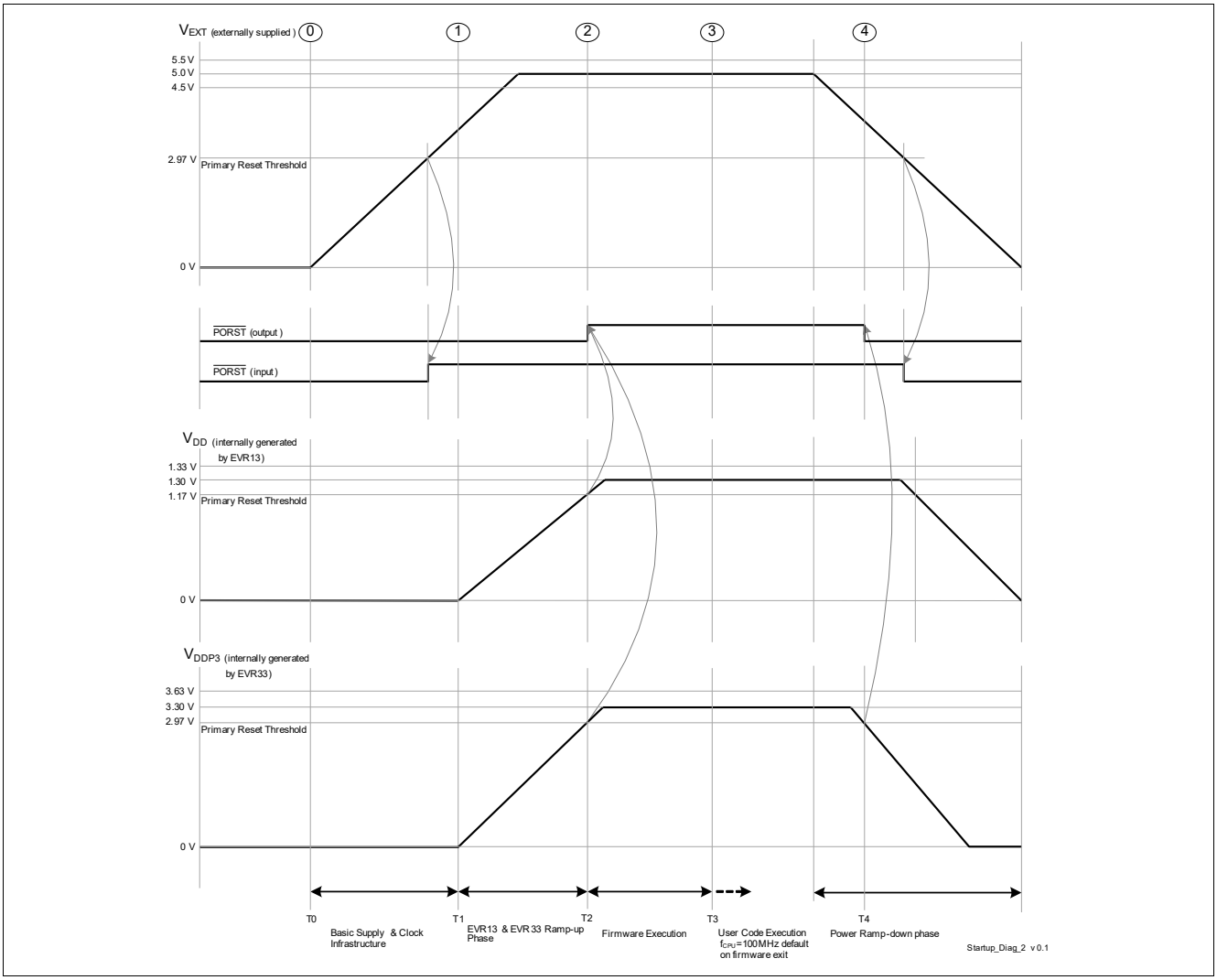


Figure 3-4 Single Supply Mode - 5 V single supply

3.15.3 External Supply Mode

All supplies, namely 5 V, 3.3 V & 1.3 V, are externally supplied.

- External supplies VEXT ,, VDDP3 & VDD may ramp-up or ramp-down independent of each other with regards to start, rise and fall time(s).
- The rate at which current is drawn from the external regulator (dIEXT /dt, dIDD /dt or dIDDP3 /dt) is limited in the Start-up phase to a maximum of 50 mA/100 us.
- PORST is active/asserted when either PORST (input) or PORST (output) is active/asserted.
- PORST (input) active means that the reset is held active by external agents by pulling the PORST pin low. It is recommended to keep the PORST (input) asserted until all the external supplies are above their primary reset thresholds.
- PORST (output) active means that µC asserts the reset internally and drives the PORST pin low thus propagating the reset to external devices. The PORST (output) is asserted by the µC when atleast one among the three supply domains (1.3 V, 3.3 V or 5 V) violate their primary under-voltage reset thresholds.The PORST (output) is deasserted by the µC when all supplies are above their primary reset thresholds and the basic supply and clock infrastructure is available.
- The power sequence as shown in **Figure 3-5** is enumerated below
  - T1 refers to the point in time when all supplies are above their primary reset thresholds and basic clock infrastructure is available. The supply mode is evaluated based on the HWCFG [0:2] pins. PORST (output) is deasserted and HWCFG [0:7] pins are latched on PORST rising edge. Firmware execution is initiated.
  - T2 refers to the point in time when Firmware execution is completed. User code execution starts with a default frequency of 100 MHz.
  - T3 refers to the point in time during the Ramp-down phase when atleast one of the externally provided supplies (1.3 V, 3.3 V or 5 V) drop below their respective primary under-voltage reset thresholds.

Please note that there is no special requirements for $\overline{\text{PORST}}$ slew rates.

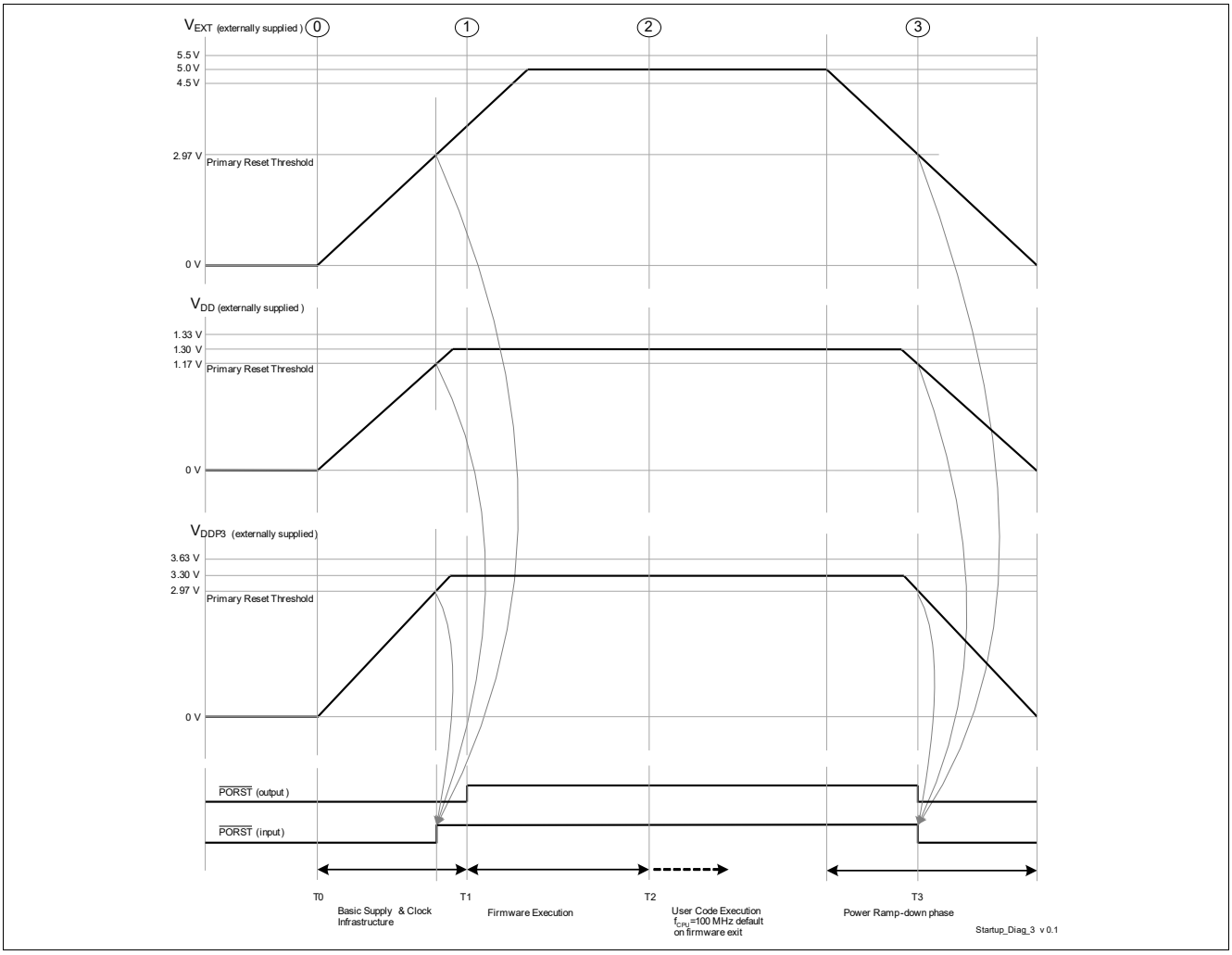


Figure 3-5 External Supply Mode - 5 V, 3.3 V & 1.3 V externally supplied

3.15.4 Single Supply Mode

3.3 V single supply mode. 1.3 V is generated internally by EVR13.

- The rate at which current is drawn from the external regulator (dIEXT /dt) is limited in the Start-up phase to a maximum of 50 mA/100 us.
- PORST is active/asserted when either PORST (input) or PORST (output) is active/asserted.
- PORST (input) active means that the reset is held active by external agents by pulling the PORST pin low. It is recommended to keep the PORST (input) asserted until the external supply is above the respective primary reset threshold.
- PORST (output) active means that µC asserts the reset internally and drives the PORST pin low thus propagating the reset to external devices. The PORST (output) is asserted by the µC when atleast one among the three supply domains (1.3 V or 3.3 V) violate their primary under-voltage reset thresholds.The PORST (output) is deasserted by the µC when all supplies are above their primary reset thresholds and the basic supply and clock infrastructure is available.
- The power sequence as shown in **Figure 3-6** is enumerated below
  - T1 refers to the point in time when basic supply and clock infrastructure is available as the external supply ramps up. The supply mode is evaluated based on the HWCFG [0:2] pins and consequently a soft start of EVR13 regulator is initiated.
  - T2 refers to the point in time when all supplies are above their primary reset thresholds. EVR13 regulator has ramped up. PORST (output) is deasserted and HWCFG [0:7] pins are latched on PORST rising edge. Firmware execution is initiated.
  - T3 refers to the point in time when Firmware execution is completed. User code execution starts with a default frequency of 100 MHz.
  - T4 refers to the point in time during the Ramp-down phase when atleast one of the externally provided or generated supplies (1.3 V or 3.3 V) drop below their respective primary under-voltage reset thresholds.

Please note that there is no special requirements for $\overline{\text{PORST}}$ slew rates.

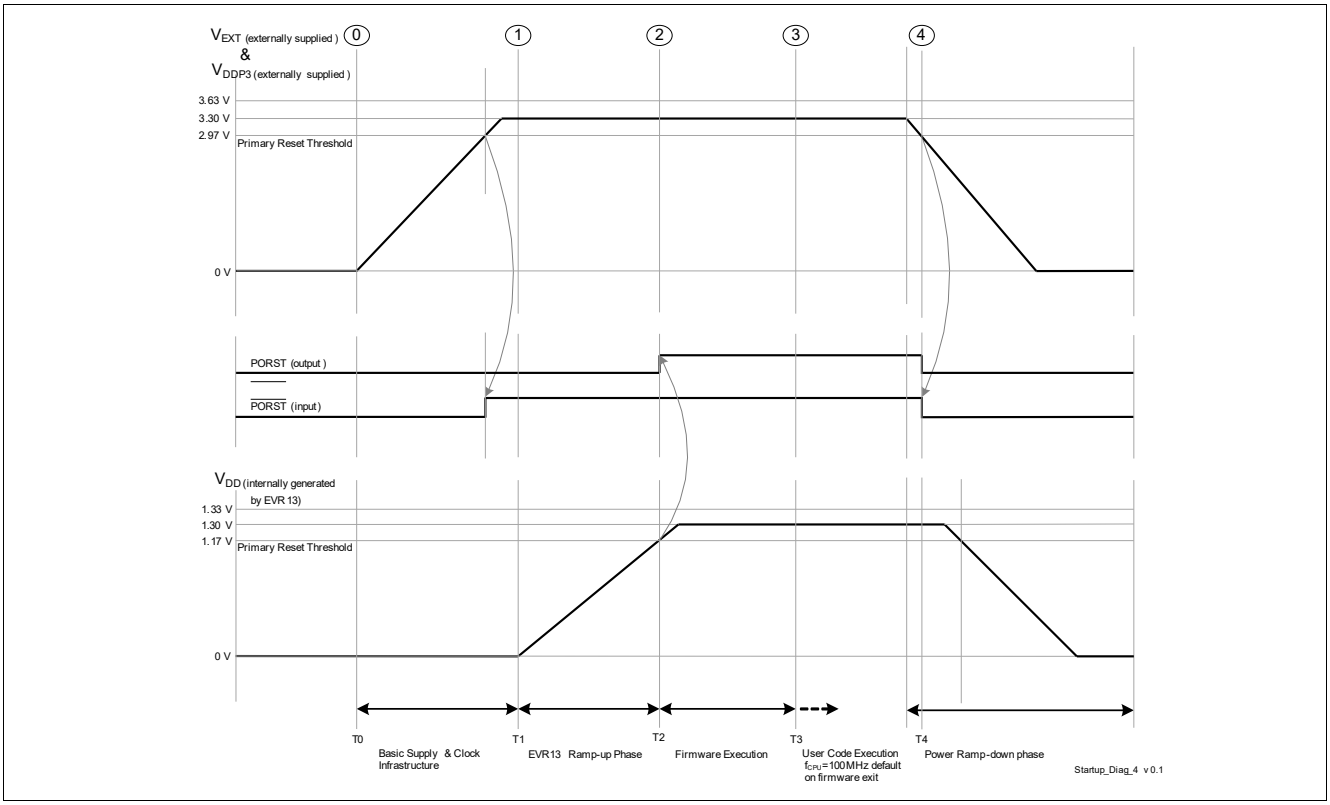


Figure 3-6 Single Supply Mode - 3.3 V single supply

3.16 Reset Timing

Table 3-35 Reset Timings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Application Reset Boot Time [1]	t_B CC	-	-	350 [2]	µs	operating with max. frequencies.
System Reset Boot Time	t_{BS} CC	-	-	1	ms	
Power on Reset Boot Time [3]	t_{BP} CC	-	-	2.5 [2]	ms	dV/dT=1V/ms. including EVR ramp-up and Firmware execution time
		-	-	1.11 [2]	ms	Firmware execution time; without EVR operation (external supply only)
Minimum PORST hold time incase of power fail event issued by EVR primary monitor	t_{EVRPOR} CC	10	-	-	µs	
EVR start-up or ramp-up time	$t_{EVRstartup}$ CC	-	-	1	ms	dV/dT=1V/ms. EVR13 and EVR33 active
Minimum PORST active hold time after power supplies are stable at operating levels [4]	t_{POA} CC	1	-	-	ms	
Configurable PORST digital filter delay in addition to analog pad filter delay	$t_{PORSTDF}$ CC	600	-	1200	ns	
HWCFG pins hold time from ESR0 rising edge	t_{HDH} CC	16 / f_{SPB}	-	-	ns	
HWCFG pins setup time to ESR0 rising edge	t_{HDS} CC	0	-	-	ns	
Ports inactive after ESR0 reset active	t_{PI} CC	-	-	8/f_{SPB}	ns	
Ports inactive after PORST reset active [5]	t_{PIP} CC	-	-	150	ns	
Hold time from PORST rising edge	t_{POH} SR	150	-	-	ns	
Setup time to PORST rising edge	t_{POS} SR	0	-	-	ns	

1) The duration of the boot time is defined between the rising edge of the internal application reset and the clock cycle when the first user instruction has entered the CPU pipeline and its processing starts.

2) The timing values assumes programmed BMI with ESR0CNT inactive.

3) The duration of the boot time is defined by all external supply voltages are inside there operation condictions and the clock cycle when the first user instruction has entered the CPU pipeline and its processing starts.

4) The regulator that supplies V_{EXT} should ensure that V_{EXT} is in the operational region before PORST is externally released by the regulator. Incase of 5V nominal supply, it should be ensured that V_{EXT} > 4V before PORST is released. Incase of 3.3V nominal supply , it should be ensured that V_{EXT} > 3V before PORST is released. The additional minimum PORST hold time is required as an additional mechanism to avoid consecutive PORST toggling owing to slow supply slopes or residual supply ramp-ups. It is also required to activate external PORST atleast 100us before power-fail is recognised to avoid consecutive PORST toggling on a power fail event.
5) This parameter includes the delay of the analog spike filter in the $\overline{\text{PORST}}$ pad.

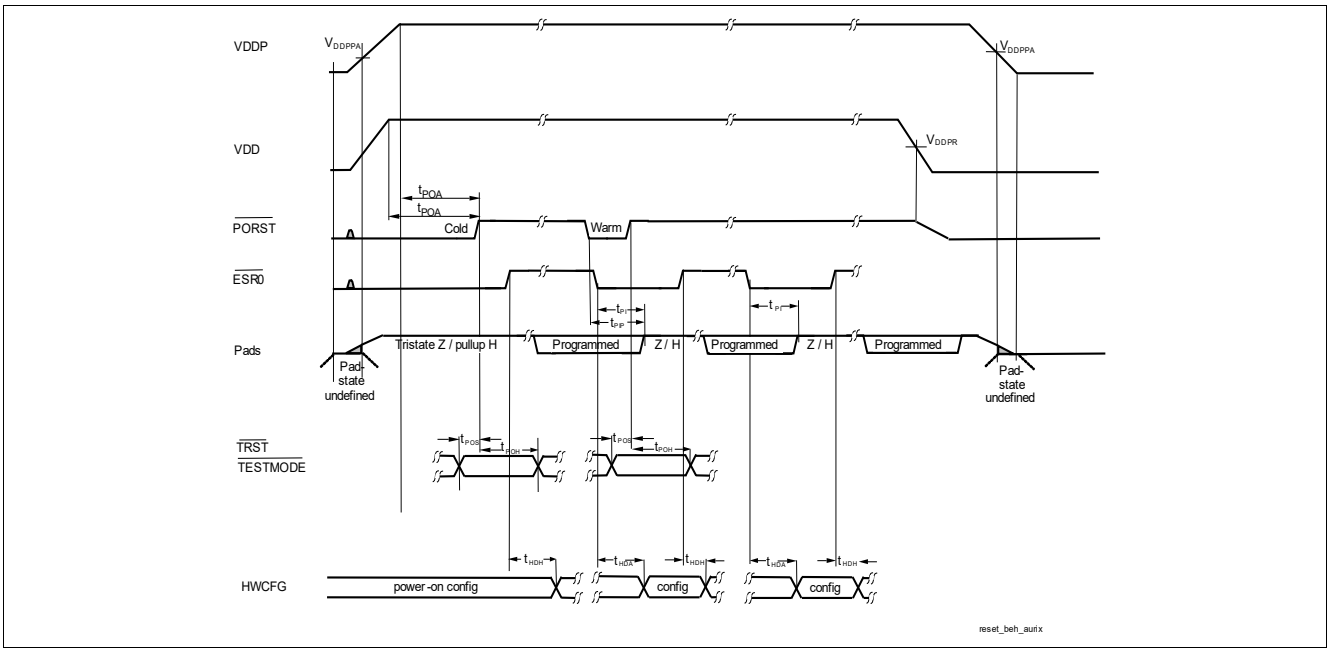


Figure 3-7 Power, Pad and Reset Timing

3.17 EVR

Table 3-36 3.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input voltage range [1]	V_{IN} SR	4	-	5.50	V	pass device=on chip
Output voltage operational range including load/line regulation and aging incase of LDO regulator	V_{OUT} CC	2.97	3.3	3.63	V	pass device=on chip
Output V_{DDx3} static voltage accuracy after trimming and aging without dynamic load/line Regulation incase of LDO regulator.	V_{OUTT} CC	3.225	3.3	3.375	V	pass device=on chip
Output buffer capacitance on V_{OUT} [2]	C_{OUT} CC	-	1	-	µF	pass device=on chip
Primary Undervoltage Reset threshold for V_{DDx3} [3]	V_{RST33} CC	-	-	3.0	V	by reset release before EVR trimming on supply ramp-up.
Startup time	t_{STR} CC	-	-	1000	µs	Only EVR33 active. ; pass device=on chip
External V_{IN} supply ramp [4]	$dVin/dT$ SR	-	1	50	V/ms	pass device=on chip
Load step response	$dVout/dIout$ CC	-	-	240	mV	dI=-70mA/20ns; $Tsettle$=20us; pass device=on chip
		-240	-	-	mV	dI=50mA/20ns; $Tsettle$=100us; pass device=on chip
Line step response	$dVout/dVin$ CC	-20	-	20	mV	dV/dT=1V/ms; pass device=on chip

1) A maximum pass device dropout voltage of 700mV is included in the minimum input voltage to ensure optimal pass device operation.

2) It is recommended to select a capacitor with ESR less than 50 mOhm (0.5MHz - 10 MHz). It is also recommended that the resistance of the supply trace from the pin to the EVR output capacitor is less than 100 mOhm.

3) The reset release on supply ramp-up is delayed by a time duration 20-40 us after reaching undervoltage reset threshold. This serves as a time hysteresis to avoid multiple consecutive cold PORST events during slow supply ramp-ups owing to voltage drop/current jumps when reset is released. The reset limit of 2,97V at pin is for the case with 3.3V generated internally from EVR33. In case the 3.3V supply is provided externally, the bondwire drop will cause a reset at a higher voltage of 3.0V at the V_{DDP3} pin.

4) EVR robust against residual voltage ramp-up starting between 0-1 V.

Table 3-37 1.3V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input voltage range [1]	V_{IN} SR	2.97	-	5.5	V	pass device=off chip
Output voltage operational range including load/line regulation and aging incase of LDO regulator	V_{OUT} CC	1.17	1.3	1.43	V	pass device=off chip
Output V_{DD} static voltage accuracy after trimming without dynamic load/line regulation with aging incase of LDO regulator.	V_{OUTT} CC	1.275	1.3	1.325	V	pass device=off chip
Output buffer capacitance on V_{OUT} [2]	C_{OUT} CC	3	4.7	6.3	µF	pass device=off chip
Primary undervoltage reset threshold for V_{DD} [3]	V_{RST13} CC	-	-	1.17	V	by reset release before EVR trimming on supply ramp-up. pass device=off chip
Startup time	t_{STR} CC	-	-	1000	µs	pass device=off chip. Only EVR13 active.
External V_{IN} supply ramp [4]	$dVin/dT$ SR	-	1	50	V/ms	pass device=off chip
Load step response	$dVout/dIout$ CC	-	-	100	mV	dI=-150mA; $Tsettle$=20μs; pass device=off chip
		-100	-	-	mV	dI=100mA; $Tsettle$=20μs; pass device=off chip
Line step response	$dVout/dVin$ CC	-10	-	10	mV	dV/dT=1V/ms; pass device=off chip

1) A maximum pass device dropout voltage of 700mV is included in the minimum input voltage to ensure optimal pass device operation.

2) It is recommended to select a capacitor with ESR less than 50 mOhm (0.5MHz - 10 MHz). It is also recommended that the resistance of the supply trace from the pin to the EVR output capacitor is less than 100 mOhm.

3) The reset release on supply ramp-up is delayed by a time duration 30-60 µs after reaching undervoltage reset threshold. This serves as a time hysteresis to avoid multiple consecutive cold PORST events during slow supply ramp-ups owing to voltage drop/current jumps when reset is released.

4) EVR robust against residual voltage ramp-up starting between 0-1 V.

Table 3-38 Supply Monitoring

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
V_{EXT} primary undervoltage monitor accuracy after trimming [1]	$V_{EXTPRIUV}$ SR	2.86	2.92	2.97	V	V_{EXT} = Undervoltage Reset Threshold
V_{DDP3} primary undervoltage monitor accuracy after trimming [1]	$V_{DDP3PRIUV}$ SR	2.86	2.90	2.97	V	V_{DDP3} = Undervoltage Reset Threshold
V_{DD} primary undervoltage monitor accuracy after trimming [1]	$V_{DDPRIUV}$ SR	1.13	1.15	1.17	V	V_{DD} = Undervoltage Reset Threshold
V_{EXT} secondary supply monitor accuracy	V_{EXTMON} CC	4.9	5.0	5.1	V	SWDxxVAL V_{EXT} monitoring threshold=5V=DBh
V_{DDP3} secondary supply monitor accuracy	$V_{DDP3MON}$ CC	3.23	3.30	3.37	V	EVR33xxVAL V_{DDP3} monitoring threshold=3.3V=91h
V_{DD} secondary supply monitor accuracy	V_{DDMON} CC	1.27	1.30	1.33	V	EVR13xxVAL V_{DD} monitoring threshold=1.3V=E4h
EVR primary and secondary monitor measurement latency for a new supply value	t_{EVRMON} CC	-	-	1.8	µs	after trimming

1) The monitor tolerances constitute the inherent variation of the bandgap and ADC over process, voltage and temperature operational ranges. The xxxPRIUV parameters are device individually tested in production with ±1% tolerance about the min and max xxxPRIUV limits.

Table 3-39 EVR13 SMPS External components

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
External output capacitor value [1]	C_{OUTDC} SR	15.4	22	29.7	µF	I_{DDDC}=1A
		6.5	10	13.5	µF	I_{DDDC}=400mA
External output capacitor ESR	C_{DC_ESR} SR	-	-	50	mOhm	f≥0.5MHz ; f≤10MHz
		-	-	100	Ohm	f=10Hz
External input capacitor value [1]	C_{IN} SR	6.5	10	13.5	µF	I_{DDDC}=1A
		4.42	6.8	9.18	µF	I_{DDDC}=400mA
External input capacitor ESR	C_{IN_ESR} SR	-	-	50	mOhm	f≥0.5MHz ; f≤10MHz
		-	-	100	Ohm	f=100Hz
External inductor value [2]	L_{DC} SR	2.31	3.3	4.29	µH	f_{DCDC}=1.5MHz
		3.29	4.7	6.11	µH	f_{DCDC}=1MHz
External inductor ESR	L_{DC_ESR} SR	-	-	0.2	Ohm	
P + N-channel MOSFET logic level	V_{LL} SR	-	-	2.5	V	

Table 3-39 EVR13 SMPS External components (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
P + N-channel MOSFET drain source breakdown voltage	$\lvert V_{BR_DS}\rvert$ SR	-	-	7	V	
P + N-channel MOSFET drain source ON-state resistance	R_{ON} SR	-	-	150	mOhm	I_{DDDC}=1A;V_{GS}=2.5V ; T_A=25$°C$
		-	-	200	mOhm	I_{DDDC}=400mA;V_{GS}=2.5 V ; T_A=25$°C$
P + N-channel MOSFET Gate Charge	Q_{ac} SR	-	4	-	nC	I_{DDDC}=1A; MOS-V_{GS}=5V
		-	8	-	nC	I_{DDDC}=400mA; MOS-V_{GS}=5V
External MOSFET commutation time	t_c SR	10	30	40	ns	configurable
N-channel MOSFET reverse diode forward voltage	V_{RDN} SR	-	0.8	-	V	

1) Capacitor min-max range represent typical ±35% tolerance including DC bias effect. The trace resistance from the capacitor to the supply or ground rail should be limited to 25 mOhm.

2) External inductor min-max range represent typical ±30% tolerance at a DC bias current of 100mA.

Table 3-40 EVR13 SMPS

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input V_{EXT} Voltage range	V_{IN} SR	2.97	-	5.5	V	
SMPS regulator output voltage range including load/line regulation and aging [1)]	V_{DDDC} CC	1.17	-	1.43	V	V_{DD}≥2.97V ; V_{DD}≤5.5V ; I_{DDDC}≥1mA ; I_{DDDC}≤1A
SMPS regulator static voltage output accuracy after trimming without dynamic load/line Regulation with aging. [2)]	V_{DDDCT} CC	1.275	1.3	1.325	V	V_{DD}≥2.97V ; V_{DD}≤5.5V ; I_{DDDC}≥1mA ; I_{DDDC}≤1A
Programmable switching frequency	f_{DCDC} CC	0.4	-	2.0	MHz	
Switching frequency modulation spread	Δf_{DCSPR} CC	-	-	2%	MHz	
Maximum ripple at I_{MAX} (peak-to-peak) [3)]	ΔV_{DDDC} CC	-	-	15	mV	V_{DD}≥2.97V ; V_{DD}≤5.5V ; I_{DDDC}≥300mA ; I_{DDDC}≤1A
No load current consumption of SMPS regulator	I_{DCNL} CC	-	5	10	mA	f_{DCDC}=1MHz

Table 3-40 EVR13 SMPS (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SMPS regulator load transient response	*dVout/dIout* CC	-25	-	25	mV	dI < 200mA ; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V
		-65	-	65	mV	dI < 400mA ; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V
		-130	-	130	mV	dI < 700mA ; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V
Maximum output current of the regulator	I_{MAX} SR	-	-	1	A	limited by thermal constraints and component choice
SMPS regulator efficiency	n_{DC} CC	-	85	-	%	V_{IN}=3.3V; I_{DDDC}=300mA; f_{DCDC}=1MHz
		-	75	-	%	V_{IN}=5V; I_{DDDC}=400mA; f_{DCDC}=1.5MHz
		-	80	-	%	V_{IN}=5V; I_{DDDC}=400mA; f_{DCDC}=1MHz

1) Incase of SMPS mode, It shall be ensured that the V_{DD} output pin shall be connected on PCB level to all other V_{DD} Input pins.
2) Incase of f_{SRI} running with max frequency, it shall be ensured that the V_{DD} operating range is limited to 1.235V upto 1.430V. The DCDC may be configured in this case with a nominal voltage of 1.33V±7.5%. The static accuracy and regulation parameter ranges remain also valid for this case.
3) If frequency spreading (SDFREQSPRD = 1) is activated, an additional ripple of 1% need to be considered.

3.18 Phase Locked Loop (PLL)

Table 3-41 PLL

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
PLL base frequency	$f_{PLLBASE}$ CC	80	150	360	MHz	
VCO frequency range	f_{VCO} SR	400	-	800	MHz	
VCO Input frequency range	f_{REF} CC	8	-	24	MHz	
Modulation Amplitude	MA CC	0	-	2	%	
Peak Period jitter	DP CC	-200	-	200	ps	
Peak Accumulated Jitter	D_{PP} CC	-5	-	5	ns	without modulation
Total long term jitter	J_{TOT} CC	-	-	11.5	ns	including modulation; MA ≤ 1%
System frequency deviation	f_{SYSD} CC	-	-	0.01	%	with active modulation
Modulation variation frequency	f_{MV} CC	2	3.6	5.4	MHz	
PLL lock-in time	t_L CC	11.5	-	200	µs	

Note: The specified PLL jitter values are valid if the capacitive load per pin does not exceed C_L = 20 pF with the maximum driver and sharp edge.

Note: The maximum peak-to-peak noise on the power supply voltage, is limited to a peak-to-peak voltage of V_{PP} = 100 mV for noise frequencies below 300 KHz and V_{PP} = 40 mV for noise frequencies above 300 KHz. These conditions can be achieved by appropriate blocking of the supply voltage as near as possible to the supply pins and using PCB supply and ground planes.

3.19 ERAY Phase Locked Loop (ERAY_PLL)

Table 3-42 PLL_ERAY

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
PLL Base Frequency of the ERAY PLL	$f_{PLLBASE_ERAY}$ CC	50	200	320	MHz	
VCO frequency range of the ERAY PLL	f_{VCO_ERAY} SR	400	-	480	MHz	
VCO input frequency of the ERAY PLL	f_{REF} SR	16	-	24	MHz	
Accumulated_Jitter	D_P CC	-0.5	-	0.5	ns	
Accumulated jitter at SYSCLK pin	D_{PP} CC	-0.8	-	0.8	ns	
PLL lock-in time	t_L CC	5.6	-	200	µs	

Note: The specified PLL jitter values are valid if the capacitive load per pin does not exceed C_L = 20 pF with the maximum driver and sharp edge.

Note: The maximum peak-to-peak noise on the power supply voltage, is limited to a peak-to-peak voltage of V_{PP} = 100 mV for noise frequencies below 300 KHz and V_{PP} = 40 mV for noise frequencies above 300 KHz. These conditions can be achieved by appropriate blocking of the supply voltage as near as possible to the supply pins and using PCB supply and ground planes.

3.20 AC Specifications

All AC parameters are specified for the complette operating range defined in **Chapter 3.4** unless otherwise noted in colum Note / test Condition.

Unless otherwise noted in the figures the timings are defined with the following guidelines:

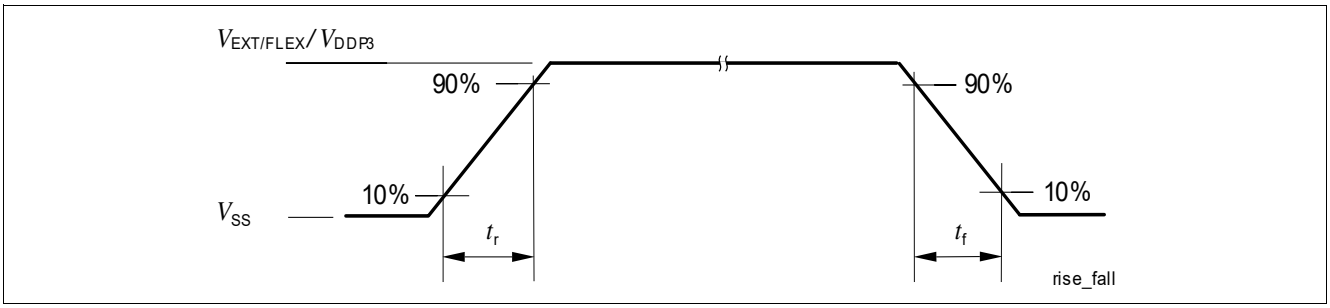


Figure 3-8 Definition of rise / fall times

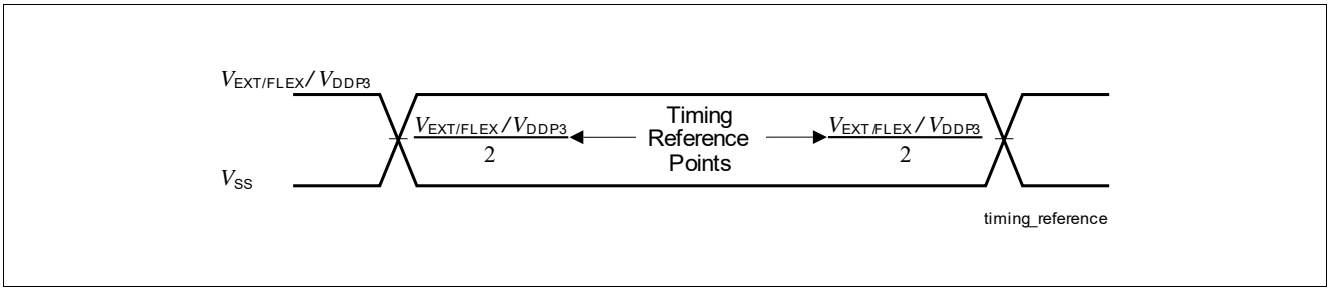


Figure 3-9 Time Reference Point Definition

3.21 JTAG Parameters

The following parameters are applicable for communication through the JTAG debug interface. The JTAG module is fully compliant with IEEE1149.1-2000.

Table 3-43 JTAG

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
TCK clock period	t_1 SR	25	-	-	ns	
TCK high time	t_2 SR	10	-	-	ns	
TCK low time	t_3 SR	10	-	-	ns	
TCK clock rise time	t_4 SR	-	-	4	ns	
TCK clock fall time	t_5 SR	-	-	4	ns	
TDI/TMS setup to TCK rising edge	t_6 SR	6.0	-	-	ns	
TDI/TMS hold after TCK rising edge	t_7 SR	6.0	-	-	ns	
TDO valid after TCK falling edge (propagation delay) [1]	t_8 CC	3.0	-	-	ns	C_L≤20pF
		-	-	16	ns	C_L≤50pF
TDO hold after TCK falling edge [1]	t_{18} CC	2	-	-	ns	
TDO high impedance to valid from TCK falling edge [1][2]	t_9 CC	-	-	17.5	ns	C_L≤50pF
TDO valid output to high impedance from TCK falling edge [1]	t_{10} CC	-	-	17	ns	C_L≤50pF

1) The falling edge on TCK is used to generate the TDO timing.

2) The setup time for TDO is given implicitly by the TCK cycle time.

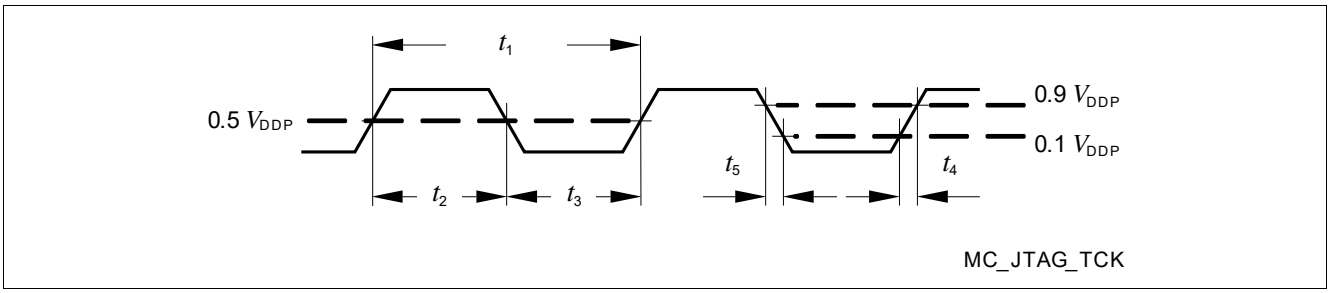


Figure 3-10 Test Clock Timing (TCK)

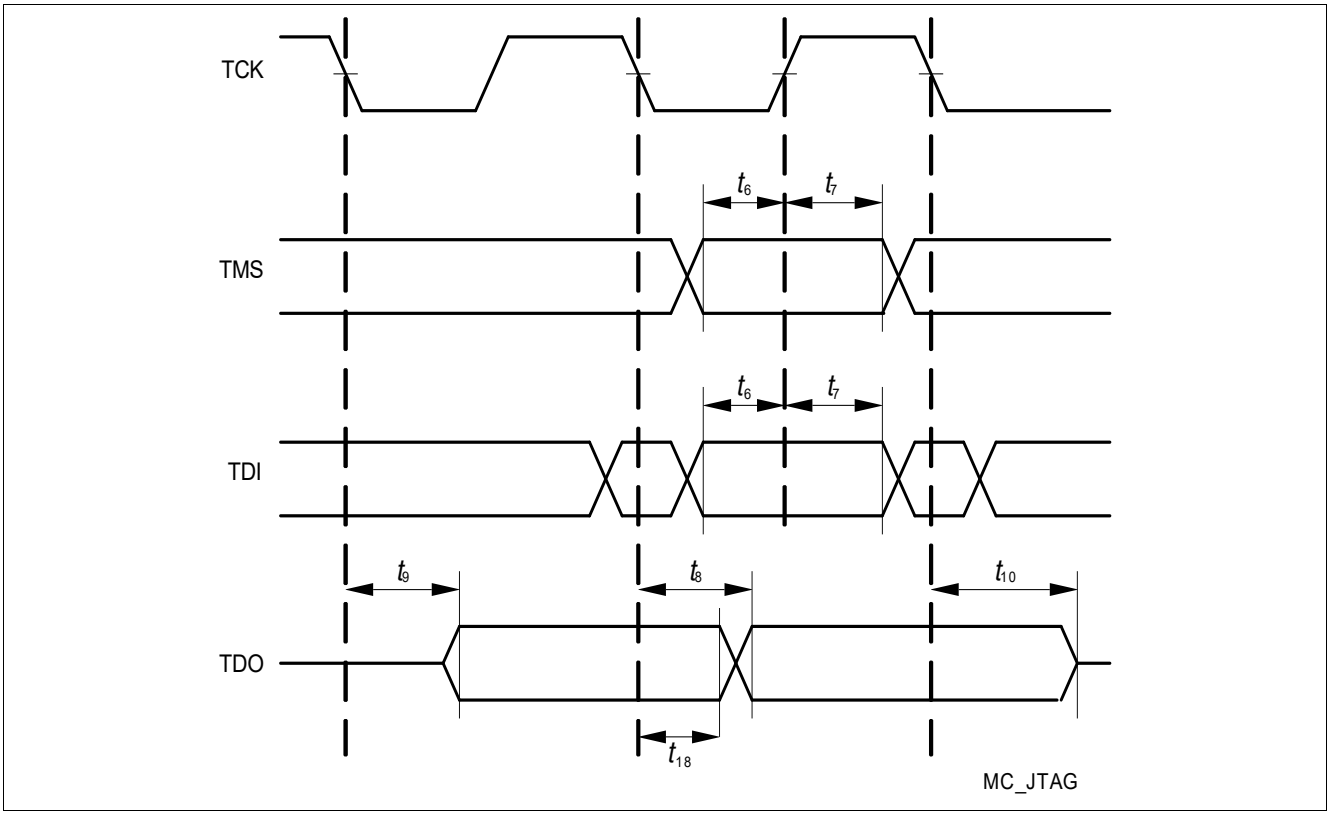


Figure 3-11 JTAG Timing

3.22 DAP Parameters

The following parameters are applicable for communication through the DAP debug interface.

Table 3-44 DAP

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
DAP0 clock period	t_{11} SR	6.25	-	-	ns	
DAP0 high time	t_{12} SR	2	-	-	ns	
DAP0 low time	t_{13} SR	2	-	-	ns	
DAP0 clock rise time	t_{14} SR	-	-	1	ns	f=160MHz
		-	-	2	ns	f=80MHz
DAP0 clock fall time	t_{15} SR	-	-	1	ns	f=160MHz
		-	-	2	ns	f=80MHz
DAP1 setup to DAP0 rising edge	t_{16} SR	4	-	-	ns	
DAP1 hold after DAP0 rising edge	t_{17} SR	2	-	-	ns	
DAP1 valid per DAP0 clock period [1]	t_{19} CC	3	-	-	ns	C_L=20pF ; f=160MHz
		8	-	-	ns	C_L=20pF ; f=80MHz
		10	-	-	ns	C_L=50pF ; f=40MHz

1) The Host has to find a suitable sampling point by analyzing the sync telegram response.

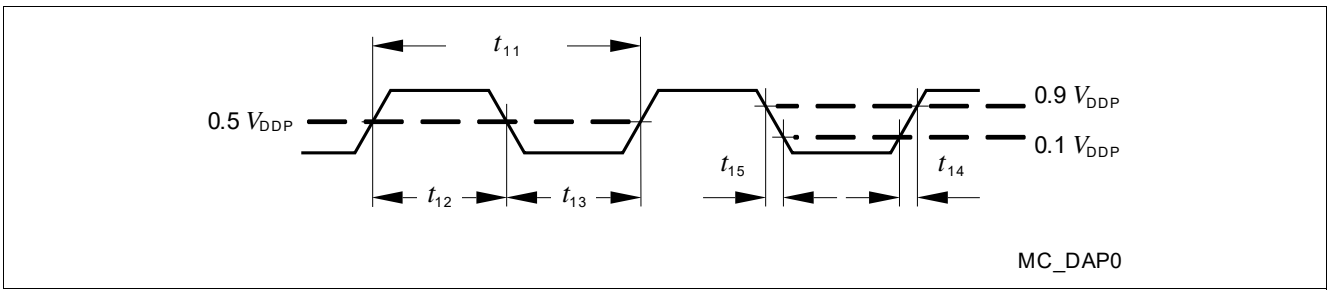


Figure 3-12 Test Clock Timing (DAP0)

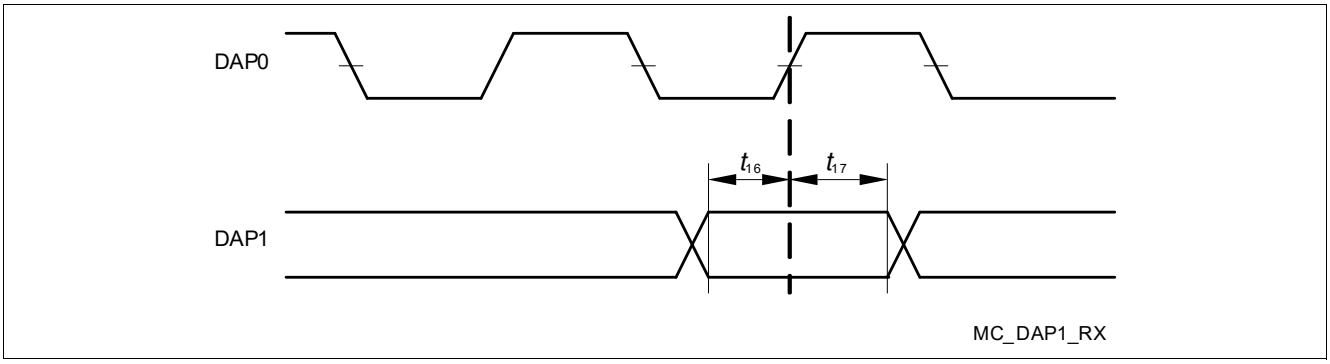


Figure 3-13 DAP Timing Host to Device

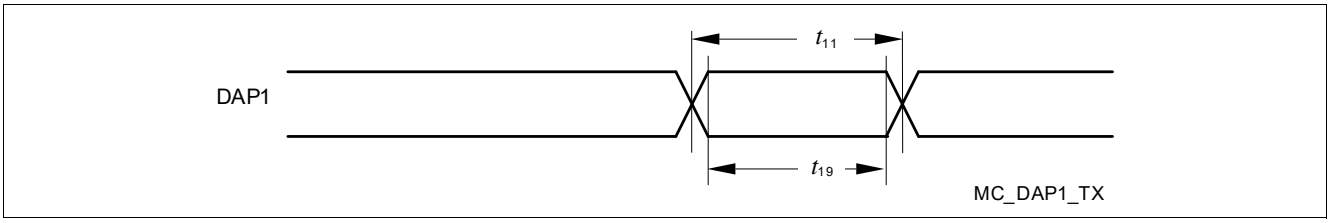


Figure 3-14 DAP Timing Device to Host (DAP1 and DAP2 pins)

Note: The DAP1 and DAP2 device to host timing is individual for both pins. There is no guaranteed max. signal skew.

3.23 ASCLIN SPI Master Timing

This section defines the timings for the ASCLIN in the TC270 / TC275 / TC277, for 5V power supply.

Note: Pad asymmetry is already included in the following timings.

Table 3-45 Master Mode MP+ss/MPRss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	20	-	-	ns	C_L=25pF
Deviation from ideal duty cycle [2]	t_{500} CC	-3	-	3	ns	0 < C_L < 50pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-7	-	6	ns	C_L=25pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	5	-	35	ns	C_L=25pF; pad used = LPm
MRST setup to ASCLKO latching edge	t_{52} SR	28	-	-	ns	C_L=25pF
MRST hold from ASCLKO latching edge	t_{53} SR	-6	-	-	ns	C_L=25pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-46 Master Mode MP+sm/MPRsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	50	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-2	-	3+0.01 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-10	-	10	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	5	-	35	ns	C_L=50pF; pad used = LPm
MRST setup to ASCLKO latching edge	t_{52} SR	50	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-10	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-47 Master Mode MPss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	20	-	-	ns	C_L=25pF
Deviation from ideal duty cycle [2]	t_{500} CC	-2	-	3.5+0.035 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-7	-	6	ns	C_L=25pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-7	-	6	ns	C_L=25pF
MRST setup to ASCLKO latching edge	t_{52} SR	30	-	-	ns	C_L=25pF, else
		33 [3]	-	-	ns	C_L=25pF, for P14.2, P14.4, and P15.1
MRST hold from ASCLKO latching edge	t_{53} SR	-5	-	-	ns	C_L=25pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
3) Please note that these pins didn't support the hystereses inactive feature.

Table 3-48 Master Mode MPsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	100	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-3	-	4+0.04 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-11	-	10	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-11	-	10	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	60	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-10	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-49 Master Mode medium output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	200	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-8	-	4+0.04 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-20	-	15	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-20	-	20	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	70	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-10	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-50 Master Mode weak output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	1000	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-30	-	30+0.15 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-75	-	75	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-65	-	65	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	510	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-50	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

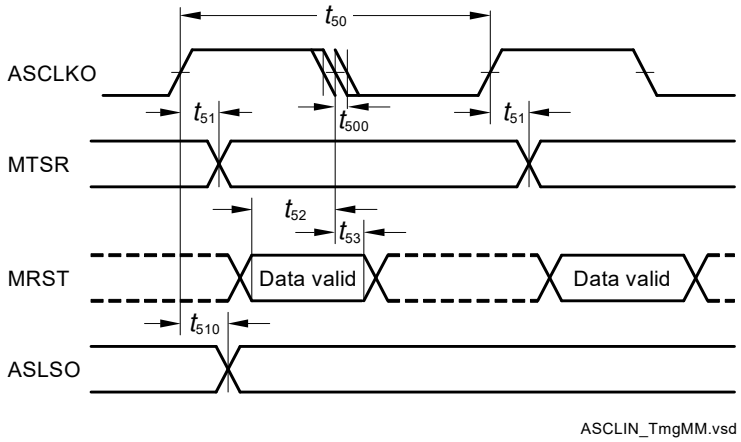


Figure 3-15 ASCLIN SPI Master Timing

3.24 ASCLIN SPI Master Timing

This section defines the timings for the ASCLIN in the TC270 / TC275 / TC277, for 3.3V power supply, Medium Performance pads, strong sharp edge (MPss), C_L=25pF.

Note: Pad asymmetry is already included in the following timings.

Table 3-51 Master Mode MP+ss/MPRss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	40	-	-	ns	C_L=25pF
Deviation from ideal duty cycle [2]	t_{500} CC	-5	-	5	ns	0 < C_L < 50pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-12	-	12	ns	C_L=25pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	0	-	60	ns	C_L=25pF; pad used = LPm
MRST setup to ASCLKO latching edge	t_{52} SR	50	-	-	ns	C_L=25pF
MRST hold from ASCLKO latching edge	t_{53} SR	-5	-	-	ns	C_L=25pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-52 Master Mode MP+sm/MPRsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	100	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-3	-	7	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-17	-	17	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	0	-	60	ns	C_L=50pF; pad used = LPm
MRST setup to ASCLKO latching edge	t_{52} SR	85	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-5	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-53 Master Mode MPss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	40	-	-	ns	C_L=25pF
Deviation from ideal duty cycle [2]	t_{500} CC	-5	-	7+0.07 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-12	-	12	ns	C_L=25pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-12	-	12	ns	C_L=25pF
MRST setup to ASCLKO latching edge	t_{52} SR	50	-	-	ns	C_L=25pF
MRST hold from ASCLKO latching edge	t_{53} SR	-5	-	-	ns	C_L=25pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-54 Master Mode MPsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	200	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-5	-	9+0.06 * C_L	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-19	-	17	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-19	-	17	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	100	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-13	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of T_{MAX} = 1 / f_{MAX}.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-55 Master Mode medium output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period [1]	t_{50} CC	400	-	-	ns	C_L=50pF
Deviation from ideal duty cycle [2]	t_{500} CC	-6-0.07 * C_L	-	6+0.07 * C_L	ns	0 < C_L < 200pF

Table 3-55 Master Mode medium output pads (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
MTSR delay from ASCLKO shifting edge	t_{51} CC	-33	-	25	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-35	-	35	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	120	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-13	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of $T_{MAX} = 1 / f_{MAX}$.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-56 Master Mode weak output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period 1)	t_{50} CC	2000	-	-	ns	C_L=50pF
Deviation from ideal duty cycle 2)	t_{500} CC	-110	-	150	ns	0 < C_L < 200pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-170	-	170	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-170	-	170	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	510	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	-40	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of $T_{MAX} = 1 / f_{MAX}$.

2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-57 Master Mode A2ss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period 1)	t_{50} CC	20	-	-	ns	C_L=50pF
Deviation from ideal duty cycle 2)	t_{500} CC	-3	-	3	ns	C_L=50pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-4	-	4	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-5	-	4	ns	C_L=50pF

Table 3-57 Master Mode A2ss output pads (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
MRST setup to ASCLKO latching edge	t_{52} SR	17	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	0	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of $T_{MAX} = 1 / f_{MAX}$.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

Table 3-58 Master Mode A2sm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ASCLKO clock period 1)	t_{50} CC	40	-	-	ns	C_L=50pF
Deviation from ideal duty cycle 2)	t_{500} CC	-4	-	4	ns	C_L=50pF
MTSR delay from ASCLKO shifting edge	t_{51} CC	-8	-	6	ns	C_L=50pF
ASLSOn delay from the first ASCLKO edge	t_{510} CC	-8	-	9	ns	C_L=50pF
MRST setup to ASCLKO latching edge	t_{52} SR	26	-	-	ns	C_L=50pF
MRST hold from ASCLKO latching edge	t_{53} SR	0	-	-	ns	C_L=50pF

1) PLL Jitter not included. Should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the BITCON.SAMPLEPOINT bitfield with the finest granularity of $T_{MAX} = 1 / f_{MAX}$.
2) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

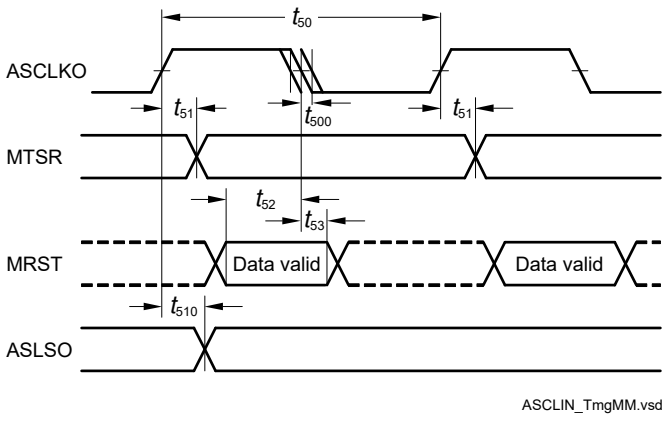


Figure 3-16 ASCLIN SPI Master Timing

3.25 QSPI Timings, Master and Slave Mode

This section defines the timings for the QSPI in the TC270 / TC275 / TC277, for 5V pad power supply.
It is assumed that SCLKO, MTSR, and SLSO pads have the same pad settings:

- LVDSM output pads,LVDSH input pad, master mode, C_L=25pF
- Medium Performance Plus Pads (MP+):
  - strong sharp edge (MP+ss), C_L=25pF
  - strong medium edge (MP+sm), C_L=50pF
  - medium edge (MP+m), C_L=50pF
  - weak edge (MP+w), C_L=50pF
- Medium Performance Pads (MP):
  - strong sharp edge (MPss), C_L=25pF
  - strong medium edge (MPsm), C_L=50pF
- Medium and Low Performance Pads (MP/LP), the identical output strength settings:
  - medium edge (LP/MPm), C_L=50pF
  - weak edge (MPw), C_L=50pF

Note: Pad asymmetry is already included in the following timings.

Table 3-59 Master Mode Timing, LVDSM output pads for data and clock

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	20 [2]	-	-	ns	C_L=25pF
Deviation from the ideal duty cycle [3] [4]	t_{500} CC	-1	-	1	ns	C_L=25pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-3	-	3	ns	C_L=25pF
SLSOn deviation from the ideal programmed position	t_{510} CC	0	-	30	ns	C_L=25pF; MPsm
		-5	-	7	ns	C_L=25pF; MPss
		-4	-	7	ns	MP+ss; C_L=25pF
		-1	-	15	ns	MP+sm; C_L=25pF
MRST setup to SCLK latching edge [5]	t_{52} SR	19 [5]	-	-	ns	C_L=25pF; LVDSM 5V output and LVDSH 3.3V input
MRST hold from SCLK latching edge	t_{53} SR	-6 [5]	-	-	ns	C_L=25pF; LVDSM 5V output and LVDSH 3.3V input

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The capacitive load on the LVDS pins is differential, the capacitive load on the CMOS pins is single ended.
3) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
4) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
5) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.

Table 3-60 Master Mode MP+ss/MPRss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	20	-	-	ns	C_L=25pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-3	-	3	ns	0 < C_L < 50pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-7	-	6	ns	C_L=25pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-7	-	6	ns	C_L=25pF
MRST setup to SCLK latching edge [4]	t_{52} SR	27 [4][5]	-	-	ns	C_L=25pF
MRST hold from SCLK latching edge	t_{53} SR	-6 [4][5]	-	-	ns	C_L=25pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-61 Master Mode MP+sm/MPRsm output pads for data and clock

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	50	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-2	-	3+0.01 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-10	-	10	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-10	-	10	ns	MP+sm; C_L=50pF
		-13	-	1	ns	MPss; C_L=50pF
		0	-	40	ns	MP+m, MPm, LPm; C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	50 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-10 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-62 Master Mode timing MPsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	100	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-3	-	4+0.04 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-11	-	10	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-11	-	10	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	60 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-10 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-63 Master Mode timing MPRm/MP+m/MPm/LPm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	200	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-10	-	10+0.04 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-15	-	19	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-20	-	20	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	70 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-10 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-64 Master Mode Weak output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	1000	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-30	-	30+0.15 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-65	-	65	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-70	-	65	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	300 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-40 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

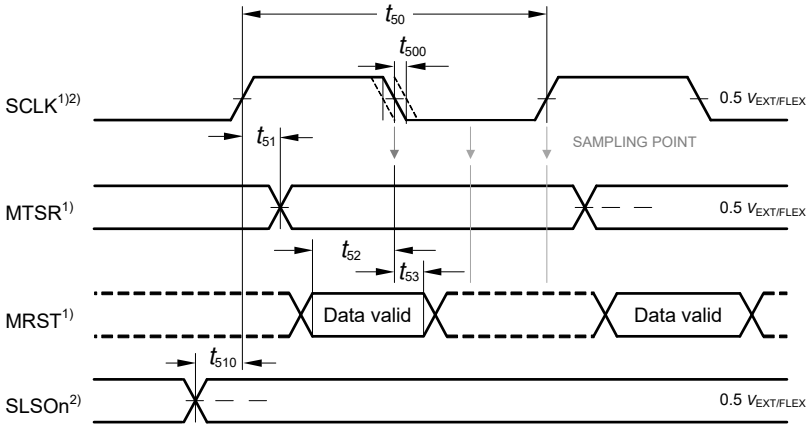
Table 3-65 Slave mode timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLK clock period	t_{54} SR	4 x T_{MAX}	-	-	ns	
SCLK duty cycle	$t_{55/t54}$ SR	40	-	60	%	
MTSR setup to SCLK latching edge	t_{56} SR	4 [1]	-	-	ns	Hystheresis Inactive
		5 [1]	-	-	ns	Input Level AL
		5 [1]	-	-	ns	Input Level TTL
MTSR hold from SCLK latching edge	t_{57} SR	3 [1]	-	-	ns	Hystheresis Inactive
		6 [1]	-	-	ns	Input Level AL
		9 [1]	-	-	ns	Input Level TTL
SLSI setup to first SCLK shift edge	t_{58} SR	5 [1]	-	-	ns	Hystheresis Inactive
		4 [1]	-	-	ns	Input Level AL
		8 [1]	-	-	ns	Input Level TTL
		6	-	-	ns	Only for pin 15.1, AL

Table 3-65 Slave mode timing (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SLSI hold from last SCLK latching edge	t_{59} SR	3 [1]	-	-	ns	Hystheresis Inactive
		4 [1]	-	-	ns	Input Level AL
		8 [1]	-	-	ns	Input Level TTL
MRST delay from SCLK shift edge	t_{60} CC	10	-	70	ns	MP+m/MPRm; C_L=50pF
		10	-	50	ns	MP+sm/MPRsm; C_L=50pF
		5	-	30	ns	MP+ss/MPRss; C_L=25pF
		40	-	300	ns	MP+w/MPRw; C_L=50pF
		10	-	70	ns	MPm/LPm; C_L=50pF
		10	-	55	ns	MPsm; C_L=50pF
		5	-	30	ns	MPss; C_L=25pF
		40	-	300	ns	MPw/LPw; C_L=50pF
SLSI to valid data on MRST	t_{61} SR	-	-	5	ns	

1) Except pin P15.1.



1) This timing is based on the following setup: ECON.CPH = 1, ECON.CPOL = 0, ECON.B=0 (no sampling point delay).

2) t510 is the deviation from the ideal position configured with the leading delay, BACON.LPRE and BACON.LEAD > 0.

QSPI_TmgMM.vsd

Figure 3-17 Master Mode Timing

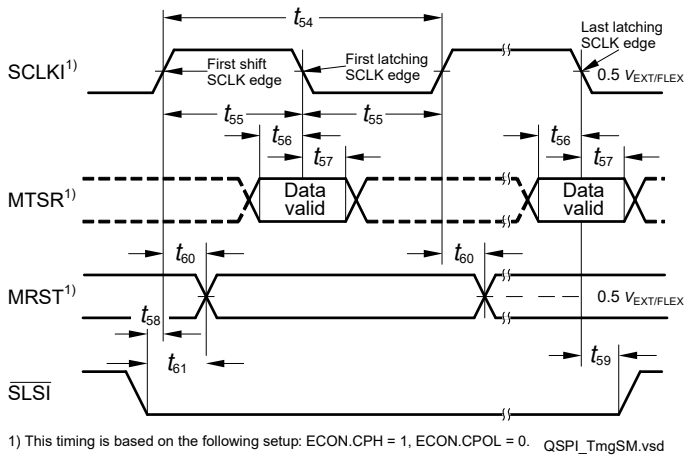


Figure 3-18 Slave Mode Timing

3.26 QSPI Timings, Master and Slave Mode

This section defines the timings for the QSPI in the TC270 / TC275 / TC277, for 3.3V pad power supply.
It is assumed that SCLKO, MTSR, and SLSO pads have the same pad settings:

- LVDSM output pads, LVDSH input pad, master mode, C_L=25pF
- Medium Performance Plus Pads (MP+):
  - strong sharp edge (MP+ss), C_L=25pF
  - strong medium edge (MP+sm), C_L=50pF
  - medium edge (MP+m), C_L=50pF
  - weak edge (MP+w), C_L=50pF
- Medium Performance Pads (MP):
  - strong sharp edge (MPss), C_L=25pF
  - strong medium edge (MPsm), C_L=50pF
- Medium and Low Performance Pads (MP/LP), the identical output strength settings:
  - medium edge (LP/MPm), C_L=50pF
  - weak edge (MPw), C_L=50pF

Note: Pad asymmetry is already included in the following timings.

Table 3-66 Master Mode Timing, LVDSM output pads for data and clock

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period 1)	t_{50} CC	20	-	-	ns	C_L=25pF
Deviation from the ideal duty cycle 2) 3)	t_{500} CC	-2	-	2	ns	C_L=25pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-5	-	5	ns	C_L=25pF

Table 3-66 Master Mode Timing, LVDSM output pads for data and clock (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SLSOn deviation from the ideal programmed position	t_{510} CC	-2	-	55	ns	C_L=25pF; MPsm
		-9	-	12	ns	C_L=25pF; MPss
		-7	-	12	ns	MP+ss; C_L=25pF
		-2	-	26	ns	MP+sm; C_L=25pF
MRST setup to SCLK latching edge [4]	t_{52} SR	20	-	-	ns	C_L=25pF; LVDSM 5V output and LVDSH 3.3V input
MRST hold from SCLK latching edge	t_{53} SR	-6	-	-	ns	C_L=25pF; LVDSM 5V output and LVDSH 3.3V input

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.

Table 3-67 Master Mode MP+ss/MPRss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	40	-	-	ns	C_L=25pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-5	-	5	ns	0 < C_L < 50pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-12	-	12	ns	C_L=25pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-12	-	12	ns	C_L=25pF
MRST setup to SCLK latching edge [4]	t_{52} SR	50 [4][5]	-	-	ns	C_L=25pF
MRST hold from SCLK latching edge	t_{53} SR	-6 [4][5]	-	-	ns	C_L=25pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-68 Master Mode MP+sm/MPRsm output pads for data and clock

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	100	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-3	-	7	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-17	-	17	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-17	-	17	ns	MP+sm; C_L=50pF
		-22	-	2	ns	MPss; C_L=50pF
		0	-	70	ns	MP+m; MPm; LPm; C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	85 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-10 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-69 Master Mode timing MPss output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	40	-	-	ns	C_L=25pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-5	-	7+0.07 * C_L	ns	C_L=25pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-10	-	10	ns	C_L=25pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-10	-	10	ns	C_L=25pF
MRST setup to SCLK latching edge [4]	t_{52} SR	50 [4][5]	-	-	ns	C_L=25pF
MRST hold from SCLK latching edge	t_{53} SR	-6 [4][5]	-	-	ns	C_L=25pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-70 Master Mode timing MPsm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	200	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-5	-	9+0.06 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-19	-	19	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-19	-	17	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	100 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-13 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-71 Master Mode timing MPRm/MP+m/MPm/LPm output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	400	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-6-0.07 * C_L	-	6+0.07 * C_L	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-25	-	33	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-35	-	35	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	120 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-13 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

Table 3-72 Master Mode Weak output pads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLKO clock period [1]	t_{50} CC	2000	-	-	ns	C_L=50pF
Deviation from the ideal duty cycle [2] [3]	t_{500} CC	-110	-	110	ns	0 < C_L < 200pF
MTSR delay from SCLKO shifting edge	t_{51} CC	-170	-	170	ns	C_L=50pF
SLSOn deviation from the ideal programmed position	t_{510} CC	-170	-	170	ns	C_L=50pF
MRST setup to SCLK latching edge [4]	t_{52} SR	510 [4][5]	-	-	ns	C_L=50pF
MRST hold from SCLK latching edge	t_{53} SR	-40 [4][5]	-	-	ns	C_L=50pF

1) Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted using the bit fields ECONz.A, B and C with the finest granularity of T_{MAX} = 1 / f_{MAX}.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) For compensation of the average on-chip delay the QSPI module provides the bit fields ECONz.A, B and C.
5) The setup and hold times are valid for both settings of the input pads thresholds: TTL and AL.

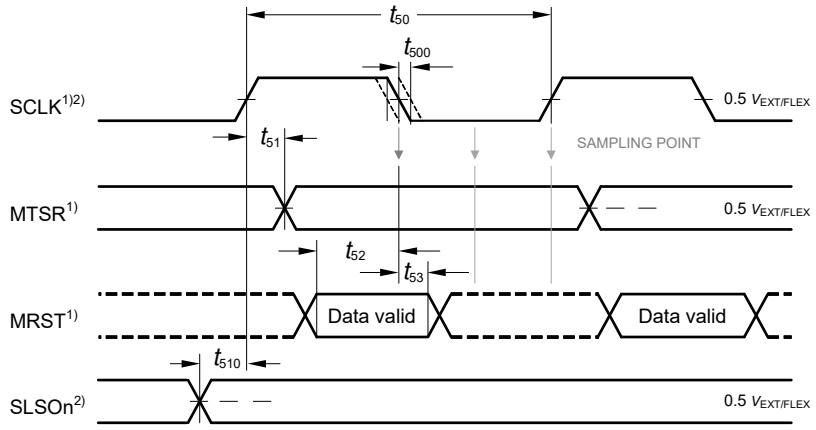
Table 3-73 Slave mode timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SCLK clock period	t_{54} SR	4 x T_{MAX}	-	-	ns	
SCLK duty cycle	$t_{55/t54}$ SR	40	-	60	%	
MTSR setup to SCLK latching edge	t_{56} SR	7 [1]	-	-	ns	Hystheresis inactive
		9 [1]	-	-	ns	Input Level AL
		7 [1]	-	-	ns	Input Level TTL
MTSR hold from SCLK latching edge	t_{57} SR	5 [1]	-	-	ns	Hystheresis inactive
		11 [1]	-	-	ns	Input Level AL
		16 [1]	-	-	ns	Input Level TTL
SLSI setup to first SCLK shift edge	t_{58} SR	7 [1]	-	-	ns	Hystheresis inactive
		7 [1]	-	-	ns	Input Level AL
		14 [1]	-	-	ns	Input Level TTL
		11	-	-	ns	Only for pin P15.1, AL

Table 3-73 Slave mode timing (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SLSI hold from last SCLK latching edge	t_{59} SR	5 1)	-	-	ns	Hystheresis inactive
		7 1)	-	-	ns	Input Level AL
		14 1)	-	-	ns	Input Level TTL
MRST delay from SCLK shift edge	t_{60} CC	13	-	120	ns	MP+m/MPRm; C_L=50pF
		13	-	85	ns	MP+sm/MPRsm; C_L=50pF
		6	-	50	ns	MP+ss/MPRss; C_L=25pF
		70	-	500	ns	MP+w/MPRw; C_L=50pF
		13	-	120	ns	MPm/LPm; C_L=50pF
		13	-	100	ns	MPsm; C_L=50pF
		6	-	52	ns	MPss; C_L=25pF
		70	-	500	ns	MPw/LPw; C_L=50pF
SLSI to valid data on MRST	t_{61} SR	-	-	9	ns	

1) Except pin P15.1



1) This timing is based on the following setup: ECON.CPH = 1, ECON.CPOL = 0, ECON.B=0 (no sampling point delay).

2) t510 is the deviation from the ideal position configured with the leading delay, BACON.LPRE and BACON.LEAD > 0.

QSPI_TmgMM.vsd

Figure 3-19 Master Mode Timing

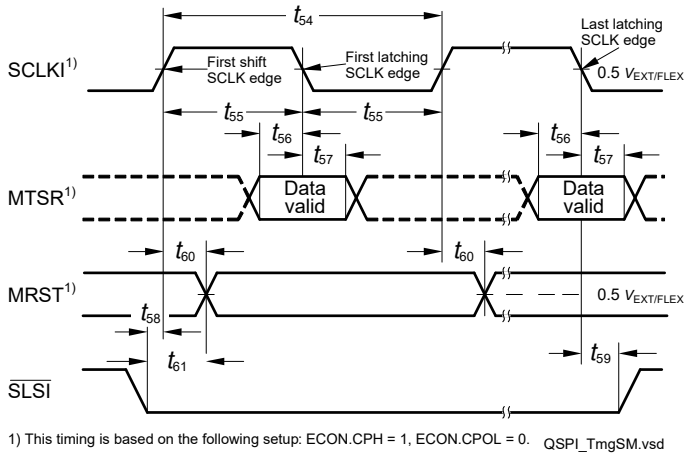


Figure 3-20 Slave Mode Timing

3.27 MSC Timing 5 V Operation

The following section defines the timings for 5V pad power supply.

Note: Pad asymmetry is already included in the following timings.

Note: Load for LVDS pads are defined as differential loads in the following timings.

Table 3-74 LVDS clock/data (LVDS pads in LVDS mode)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A [2] [3]	-	-	ns	LVDSM; C_L=50pF
Deviation from ideal duty cycle [4] [5]	t_{400} CC	-1	-	1	ns	LVDSM; 0 < C_L < 50pF
SOPx output delay [6]	t_{44} CC	-3	-	4	ns	LVDSM; C_L=50pF; option EN01
		-4	-	4.5	ns	LVDSM; C_L=50pF; option EN01D
ENx output delay [6]	t_{45} CC	-4	-	5	ns	MP+ss/MPRss; option EN01; C_L=25pF
		-3	-	7	ns	MP+ss/MPRss; option EN01; C_L=50pF
		-3	-	11	ns	MP+sm/MPRsm; option EN01D; C_L=50pF
		-2	-	9	ns	MP+ss/MPRss; option EN23; C_L=25pF
		-2	-	11	ns	MP+ss/MPRss; option EN23; C_L=50pF
		-3	-	11	ns	MPss; option EN01; C_L=50pF
		-7	-	2	ns	MP+ss/MPRss; option EN01; C_L=0pF
		-5	-	3	ns	MP+sm/MPRsm; option EN01D; C_L=0pF
		-4	-	5	ns	MP+ss/MPRss; option EN23; C_L=0pF
		-7	-	4	ns	MPss; option EN01; C_L=0pF
SDI bit time	t_{46} CC	8 * t_{MSC}	-	-	ns	Upstream Timing
SDI rise time [7]	t_{48} SR	-	-	200	ns	Upstream Timing
SDI fall time [7]	t_{49} SR	-	-	200	ns	Upstream Timing

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.

2) T_A depends on the clock source selected for baud rate generation in the ABRA block of the MSC.

3) The capacitive load on the LVDS pins is differential, the capacitive load on the CMOS pins is single ended.

4) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
5) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
6) From FCLP rising edge.
7) When using slow and asymmetrical edges, like in case of open drain upstream connection, the application must take care that the bit is long enough (the baud rate is low enough) so that under worst case conditions the three sampling points in the middle of the bit are not violated.

Timing Options for t_{45}

The wiring shown in the **Figure 3-21** provides three useful timing options for t_{45}. depending on the signals selected with the alternate output lines (ALT1 to ALT7) in the ports:

- EN01 - FCLN, SON, EN0, EN1 - t_{45} reference timing
- EN01D - FCLND, SOND, EN0, EN1 - t_{45} window shifted to the left
- EN23 - FCLN, SON, EN2, EN3 - t_{45} window shifted to the right

The timings corresponding to EN01, EN01D, and EN23 are defined in the LVDS. In order to use the EN23 timings, the application should use the EN2 and EN3 outputs of the MSC module.

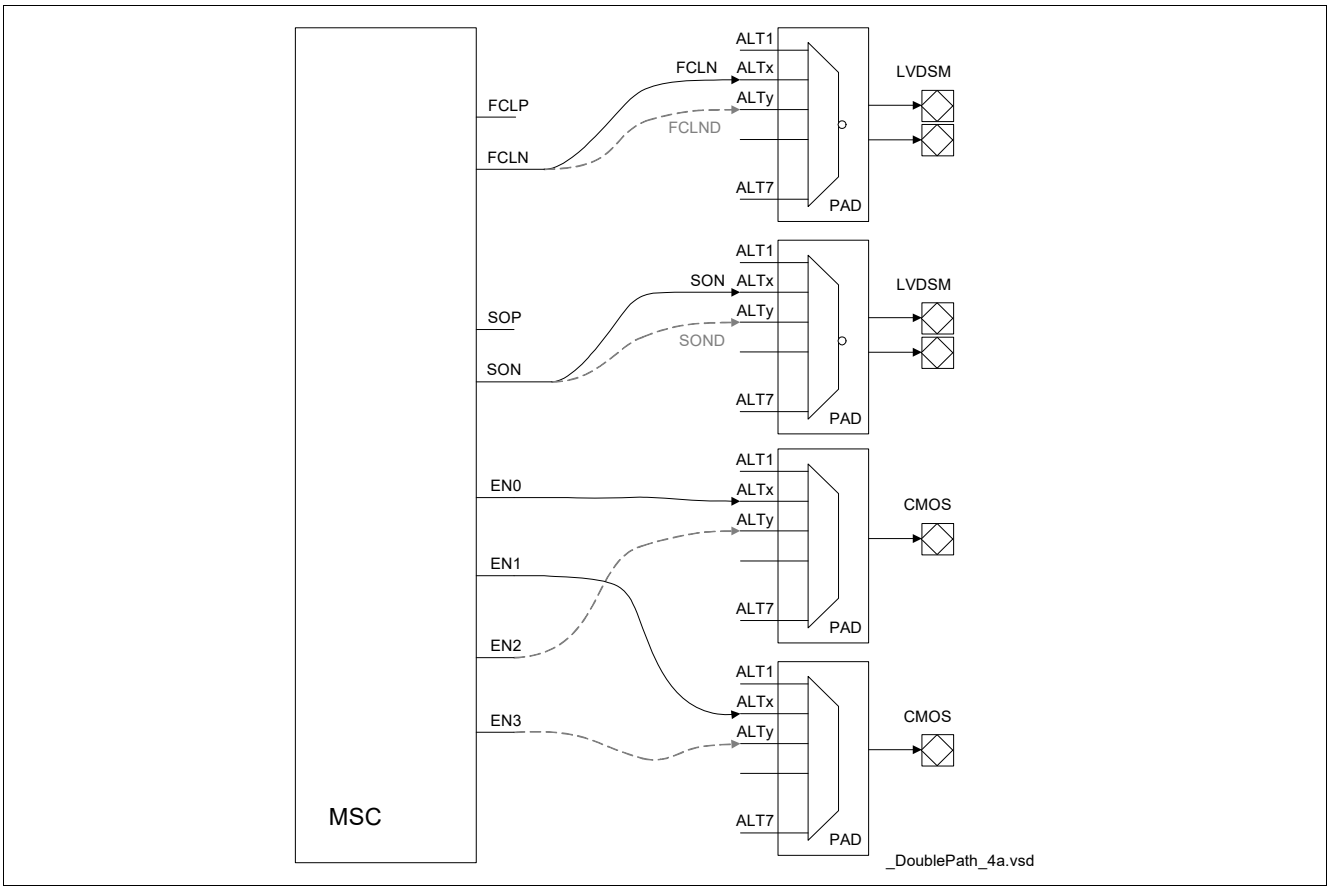


Figure 3-21 Timing Options for t_{45}

Table 3-75 MPss clock/data (LVDS pads in CMOS mode, option EN01)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A [2] [3]	-	-	ns	MPss; C_L=50pF
Deviation from ideal duty cycle [4] [5]	t_{400} CC	-2	-	6+0.035 * C_L	ns	MPss; 0 < C_L < 100pF
SOPx output delay [6]	t_{44} CC	-4	-	7	ns	MPss; C_L=50pF

Table 3-75 MPss clock/data (LVDS pads in CMOS mode, option EN01) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ENx output delay [6]	t_{45} CC	-5	-	7	ns	MP+ss/MPRss; C_L=50pF
		-2	-	15	ns	MP+sm/MPRsm; C_L=50pF
		-4	-	10	ns	MPss; C_L=50pF
		0	-	30	ns	MPsm; C_L=50pF; except pin P13.0
		0	-	31	ns	MPsm; C_L=50pF; pin P13.0
		6	-	45	ns	MPm/MP+m/MPRm; C_L=50pF
		-11	-	2	ns	MP+ss/MPRss; C_L=0pF
		-4	-	7	ns	MP+sm/MPRsm; C_L=0pF
		-10	-	2	ns	MPss; C_L=0pF
		-1	-	16	ns	MPsm; C_L=0pF
		-2	-	18	ns	MP+m/MPm/MPRm; C_L=0pF
SDI bit time	t_{46} CC	8 * t_{MSC}	-	-	ns	Upstream Timing
SDI rise time [7]	t_{48} SR	-	-	200	ns	Upstream Timing
SDI fall time [7]	t_{49} SR	-	-	200	ns	Upstream Timing

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) T_A depends on the clock source selected for baud rate generation in the ABRA block of the MSC.
3) FCLP signal high and low can be minimum 1 * T_{MSC}.
4) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
5) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
6) From FCLP rising edge.
7) When using slow and asymmetrical edges, like in case of open drain upstream connection, the application must take care that the bit is long enough (the baud rate is low enough) so that under worst case conditions the three sampling points in the middle of the bit are not violated.

Table 3-76 MP+sm/MPRsm clock/data

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A	-	-	ns	MP+sm/MPRsm; C_L=50pF
Deviation from ideal duty cycle [2] [3]	t_{400} CC	-2	-	3+0.01 * C_L	ns	MP+sm/MPRsm; 0 < C_L < 200pF
SOPx output delay [4]	t_{44} CC	-5	-	7	ns	MP+sm; C_L=50pF

Table 3-76 MP+sm/MPRsm clock/data (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ENx output delay [4]	t_{45} CC	-13	-	2 [5]	ns	MPss; C_L=50pF
		-5	-	11	ns	MP+sm/MPRsm; C_L=50pF
		1	-	24	ns	MPsm; C_L=50pF
		4	-	37	ns	MP+m/MPm/MPRm; C_L=50pF
		-19	-	-1	ns	MPss; C_L=0pF
		-13	-	2	ns	MP+sm; C_L=0pF
		-5	-	8	ns	MPsm; C_L=0pF
		-5	-	10	ns	MPm/MP+m/MPRm; C_L=0pF

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) From FCLP rising edge.
5) If EN1 is configured to P13.0 the max limt is increased by 0.5ns to 2.5ns.

Table 3-77 MPm/MP+m/MPRm clock/data

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A	-	-	ns	MPm/MP+m/MPRm; C_L=50pF
Deviation from ideal duty cycle [2] [3]	t_{400} CC	-8	-	15+0.04 * C_L	ns	MPm/MP+m; 0 < C_L < 200pF
SOPx output delay [4]	t_{44} CC	-11	-	9	ns	MPm/MP+m; C_L=50pF
ENx output delay [4]	t_{45} CC	-15	-	11	ns	MPm/MP+m/MPRm; C_L=50pF
		-33	-	-4	ns	MPm/MP+m/MPRm; C_L=0pF

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) From FCLP rising edge.

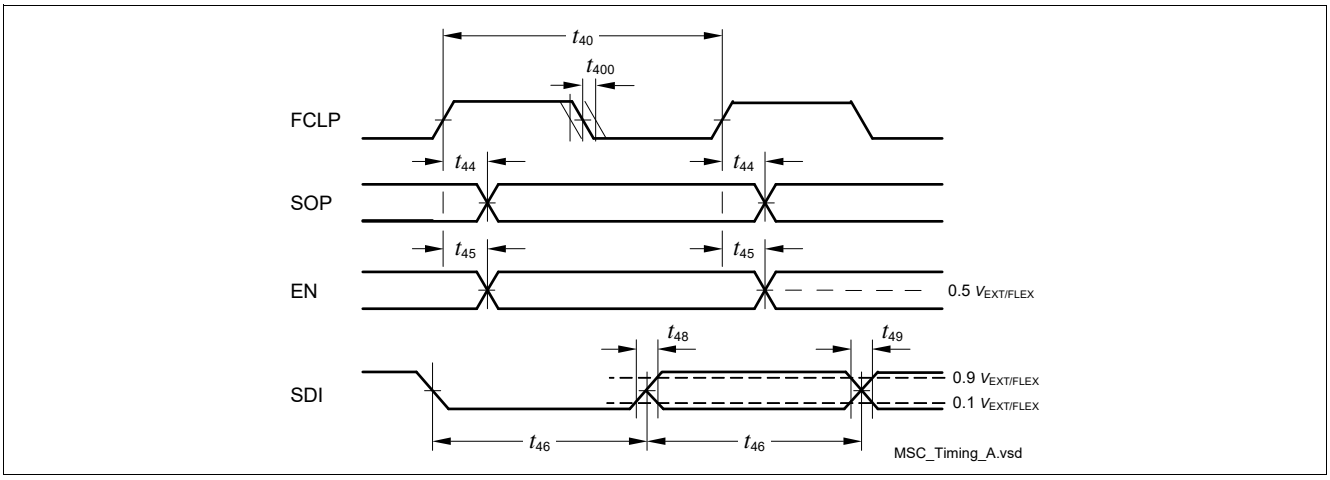


Figure 3-22 MSC Interface Timing

Note: The SOP data signal is sampled with the falling edge of FCLP in the target device.

3.28 MSC Timing 3.3 V Operation

The following section defines the timings for 3.3V pad power supply.

Note: Pad asymmetry is already included in the following timings.

Note: Load for LVDS pads are defined as differential loads in the following timings.

Mapping A, Combo Pads in LVDS Mode or CMOS Mode

The timing applies for the LVDS pads in LVDS operating mode:

- The LVDSM output pads for clock and data signals set in LVDS mode
- The CMOS MP pads for enable signals, with strong driver sharp edge (MPss) or strong driver medium edge (MPsm).

Table 3-78 LVDS clock/data (LVDS pads in LVDS mode)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A [2] [3]	-	-	ns	LVDSM; C_L=50pF
Deviation from ideal duty cycle [4] [5]	t_{400} CC	-2	-	2	ns	LVDSM; 0 < C_L < 50pF
SOPx output delay [6]	t_{44} CC	-5	-	5	ns	LVDSM; C_L=50pF; option EN01
		-7	-	7	ns	LVDSM; C_L=50pF; option EN01D

Table 3-78 LVDS clock/data (LVDS pads in LVDS mode) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ENx output delay [6]	t_{45} CC	-7	-	10	ns	MP+ss/MPRss; option EN01; C_L=25pF
		-5	-	13	ns	MP+ss/MPRss; option EN01; C_L=50pF
		-5	-	26	ns	MP+sm/MPRsm; option EN01D; C_L=50pF
		-4	-	16	ns	MP+ss/MPRss; option EN23; C_L=25pF
		-4	-	17	ns	MP+ss/MPRss; option EN23; C_L=50pF
		-5	-	19	ns	MPss; option EN01; C_L=50pF
		-12	-	4	ns	MP+ss/MPRss; option EN01; C_L=0pF
		-9	-	11	ns	MP+sm/MPRsm; option EN01D; C_L=0pF
		-7	-	9	ns	MP+ss/MPRss; option EN23; C_L=0pF
		-12	-	7	ns	MPss; option EN01; C_L=0pF
SDI bit time	t_{46} CC	8 * t_{MSC}	-	-	ns	Upstream Timing
SDI rise time [7]	t_{48} SR	-	-	200	ns	Upstream Timing
SDI fall time [7]	t_{49} SR	-	-	200	ns	Upstream Timing

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.

2) T_{Amin} = T_{MAX}. When T_{MAX} = 100 MHz,t_{40} = 20 ns

3) The capacitive load on the LVDS pins is differential, the capacitive load on the CMOS pins is single ended.

4) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.

5) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

6) From FCLP rising edge.

7) When using slow and asymmetrical edges, like in case of open drain upstream connection, the application must take care that the bit is long enough (the baud rate is low enough) so that under worst case conditions the three sampling points in the middle of the bit are not violated.

Table 3-79 MPss clock/data (LVDS pads in CMOS mode, option EN01)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A [2] [3]	-	-	ns	MPss; C_L=50pF
Deviation from ideal duty cycle [4] [5]	t_{400} CC	-5	-	7+0.07 * C_L	ns	MPss; 0 < C_L < 100pF

Table 3-79 MPss clock/data (LVDS pads in CMOS mode, option EN01) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SOPx output delay [6]	t_{44} CC	-7	-	12	ns	MPss; C_L=50pF
ENx output delay [6]	t_{45} CC	-9	-	12	ns	MP+ss/MPRss; C_L=50pF
		-4	-	26	ns	MP+sm/MPRsm; C_L=50pF
		-7	-	17	ns	MPss; C_L=50pF
		0	-	54	ns	MPsm; C_L=50pF; except pin P13.0
		0	-	58	ns	MPsm; C_L=50pF; pin P13.0
		4	-	77	ns	MPm/MP+m/MPRm; C_L=50pF
		-19	-	4	ns	MP+ss/MPRss; C_L=0pF
		-7	-	12	ns	MP+sm/MPRsm; C_L=0pF
		-17	-	4	ns	MPss; C_L=0pF
		-2	-	28	ns	MPsm; C_L=0pF
		-4	-	31	ns	MP+m/MPm/MPRm; C_L=0pF
SDI bit time	t_{46} CC	8 * t_{MSC}	-	-	ns	Upstream Timing
SDI rise time [7]	t_{48} SR	-	-	200	ns	Upstream Timing
SDI fall time [7]	t_{49} SR	-	-	200	ns	Upstream Timing

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) T_{Amin} = T_{MAX}. When T_{MAX} = 100 MHz,t_{40} = 20 ns
3) FCLP signal high and low can be minimum 1 * T_{MSC}.
4) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
5) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
6) From FCLP rising edge.
7) When using slow and asymmetrical edges, like in case of open drain upstream connection, the application must take care that the bit is long enough (the baud rate is low enough) so that under worst case conditions the three sampling points in the middle of the bit are not violated.

Mapping B, CMOS MP Pads

This timing applies for the dedicated CMOS pads, pin Mapping B:

- MP strong sharp (MPss) output pads for the clock and the data signals
- MP strong sharp or strong medium (MPss or MPsm) output pads for enable signals

Table 3-80 MP+sm/MPRsm clock/data

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A	-	-	ns	MP+sm/MPRsm; C_L=50pF
Deviation from ideal duty cycle [2] [3]	t_{400} CC	-3	-	7	ns	MP+sm/MPRsm; 0 < C_L < 200pF
SOPx output delay [4]	t_{44} CC	-9	-	12	ns	MP+sm; C_L=50pF
ENx output delay [4]	t_{45} CC	-20	-	4	ns	MPss; C_L=50pF
		-9	-	19	ns	MP+sm/MPRsm; C_L=50pF
		0	-	44	ns	MPsm; C_L=50pF
		0	-	63	ns	MP+m/MPm/MPRm; C_L=50pF
		-33	-	0	ns	MPss; C_L=0pF
		-23	-	4	ns	MP+sm/MPRsm; C_L=0pF
		-9	-	14	ns	MPsm; C_L=0pF
		-9	-	17	ns	MPm/MP+m/MPRm; C_L=0pF

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.
4) From FCLP rising edge.

Table 3-81 MPm/MP+m/MPRm clock/data

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
FCLPx clock period [1]	t_{40} CC	2 * T_A	-	-	ns	MPm/MP+m/MPRm; C_L=50pF
Deviation from ideal duty cycle [2] [3]	t_{400} CC	-6-0.07 * C_L	-	6+0.07 * C_L	ns	MPm/MP+m/MPRm; 0 < C_L < 200pF
SOPx output delay [4]	t_{44} CC	-19	-	17	ns	MPm/MP+m; C_L=50pF
ENx output delay [4]	t_{45} CC	-19	-	20	ns	MPm/MP+m/MPRm; C_L=50pF
		-57	-	0	ns	MPm/MP+m/MPRm; C_L=0pF

1) FCLP signal rise/fall times are the rise/fall times of the LVDSM pads, and the high/low times are min 1 * T_A.
2) The PLL jitter is not included. It should be considered additionally, corresponding to the used baudrate. The duty cycle can be adjusted if the ABRA block is used.
3) Positive deviation lenghtens the high time and shortens the low time of a clock period. Negative deviation does the opposite.

4) From FCLP rising edge.

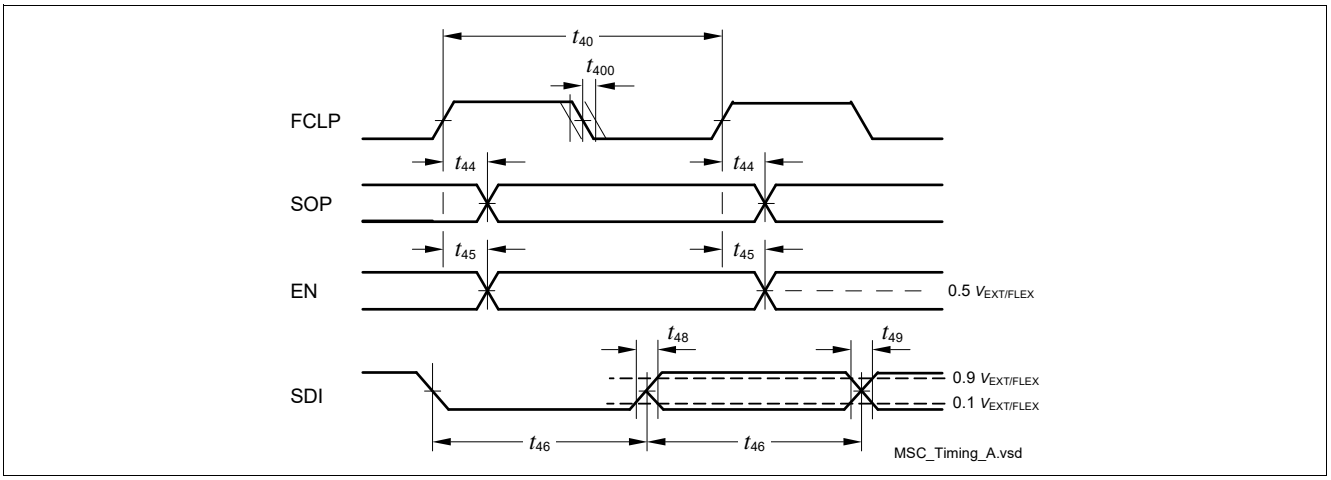


Figure 3-23 MSC Interface Timing

Note: The SOP data signal is sampled with the falling edge of FCLP in the target device.

3.29 Ethernet Interface (ETH) Characteristics

3.29.1 ETH Measurement Reference Points

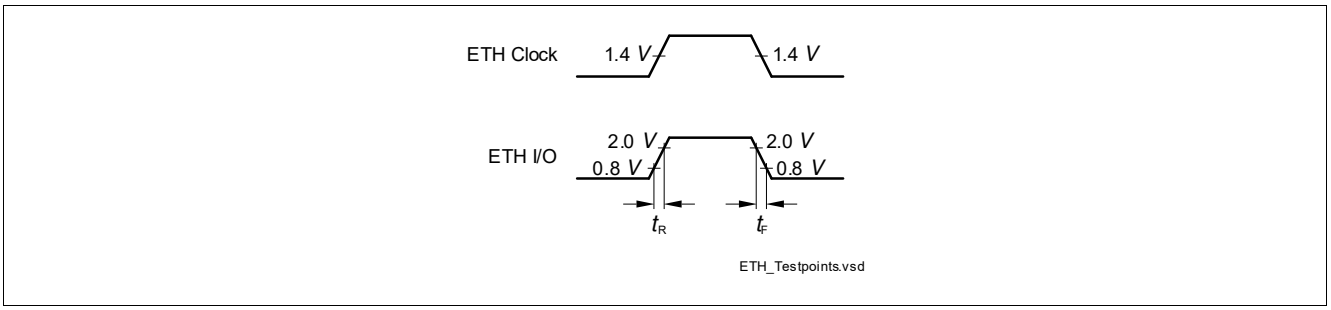


Figure 3-24 ETH Measurement Reference Points

3.29.2 ETH Management Signal Parameters (ETH_MDC, ETH_MDIO)

Table 3-82 ETH Management Signal Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ETH_MDC period	t_1 CC	400	-	-	ns	C_L=25pF
ETH_MDC high time	t_2 CC	160	-	-	ns	C_L=25pF
ETH_MDC low time	t_3 CC	160	-	-	ns	C_L=25pF
ETH_MDIO setup time (output)	t_4 CC	10	-	-	ns	C_L=25pF
ETH_MDIO hold time (output)	t_5 CC	10	-	-	ns	C_L=25pF
ETH_MDIO data valid (input)	t_6 SR	0	-	300	ns	C_L=25pF

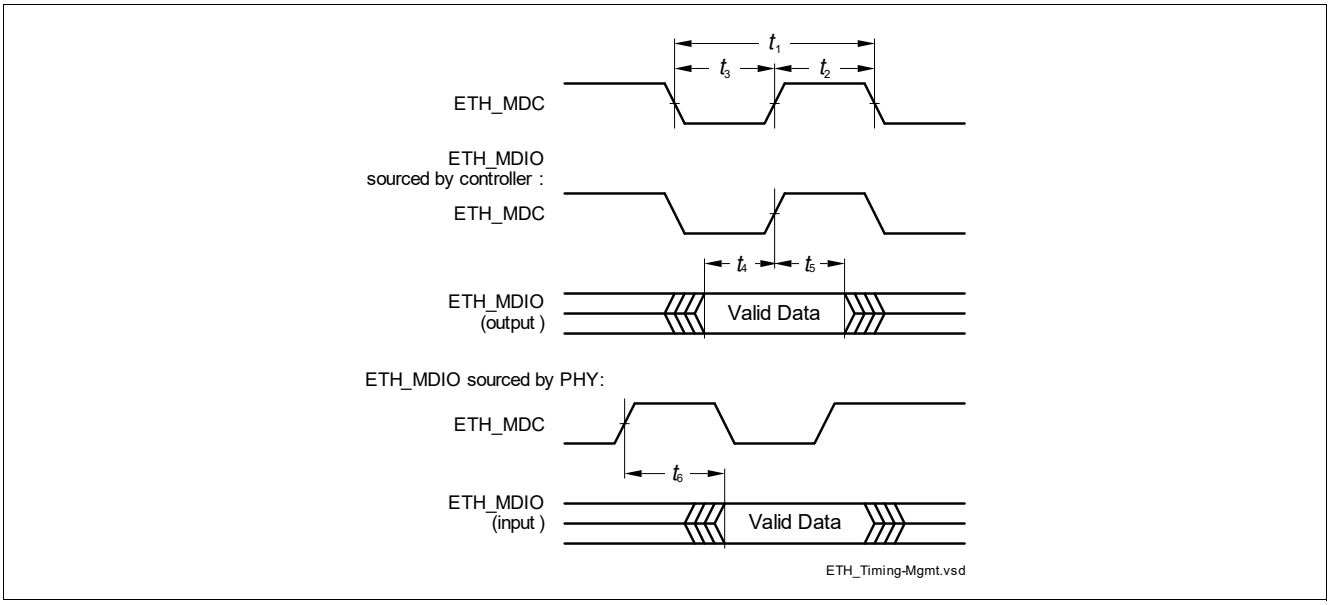


Figure 3-25 ETH Management Signal Timing

3.29.3 ETH MII Parameters

In the following, the parameters of the MII (Media Independent Interface) are described.

Table 3-83 ETH MII Signal Timing Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_7 SR	40	-	-	ns	C_L=25pF; baudrate=100Mbps
		400	-	-	ns	C_L=25pF; baudrate=10Mbps
Clock high time	t_8 SR	14	-	26	ns	C_L=25pF; baudrate=100Mbps
		140 1)	-	260 2)	ns	C_L=25pF; baudrate=10Mbps
Clock low time	t_9 SR	14	-	26	ns	C_L=25pF; baudrate=100Mbps
		140 1)	-	260 2)	ns	C_L=25pF; baudrate=10Mbps
Input setup time	t_{10} SR	10	-	-	ns	C_L=25pF
Input hold time	t_{11} SR	10	-	-	ns	C_L=25pF
Output valid time	t_{12} CC	0	-	25	ns	C_L=25pF

1) Defined by 35% of clock period.
2) Defined by 65% of clock period.

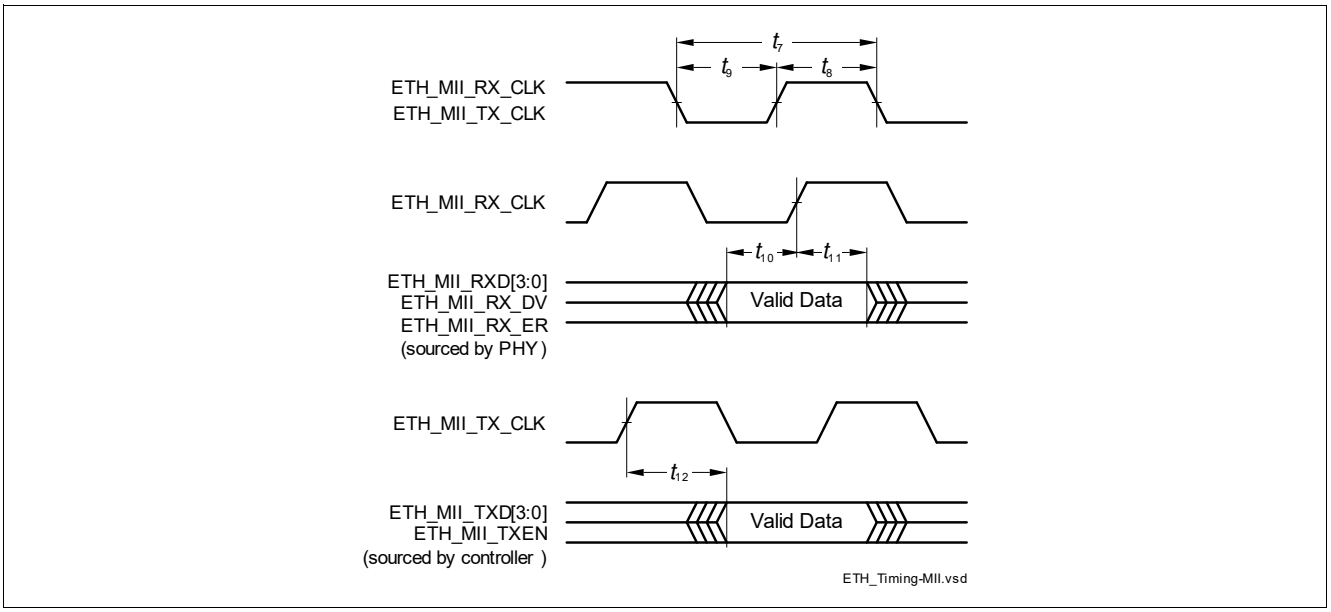


Figure 3-26 ETH MII Signal Timing

3.29.4 ETH RMII Parameters

In the following, the parameters of the RMII (Reduced Media Independent Interface) are described.

Table 3-84 ETH RMII Signal Timing Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ETH_RMII_REF_CL clock period	t_{13} CC	20	-	-	ns	C_L=25pF; 50ppm
ETH_RMII_REF_CL clock high time	t_{14} CC	7 [1]	-	13 [2]	ns	C_L=25pF
ETH_RMII_REF_CL clock low time	t_{15} CC	7 [1]	-	13 [2]	ns	C_L=25pF
ETHTXEN, ETHTXD[1:0], ETHRXD[1:0], ETHCRSDV, ETHRXER; setup time	t_{16} CC	4	-	-	ns	C_L=25pF
ETHTXEN, ETHTXD[1:0], ETHRXD[1:0], ETHCRSDV, ETHRXER; hold time	t_{17} CC	2	-	-	ns	C_L=25pF

1) Defined by 35% of clock period.

2) Defined by 65% of clock period.

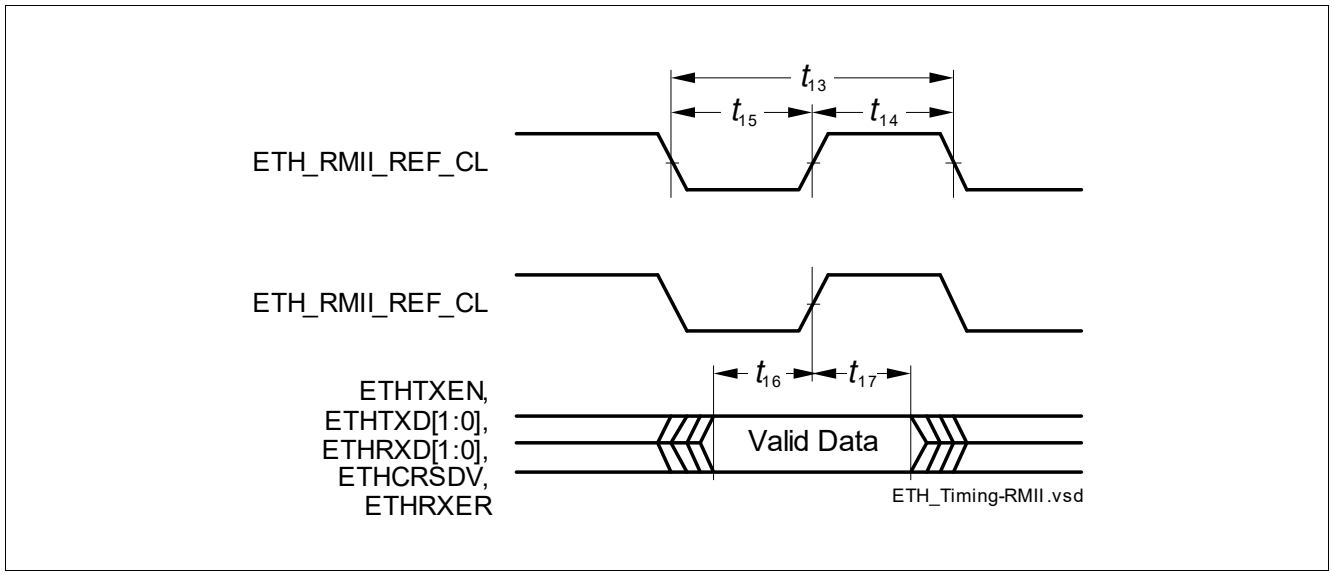


Figure 3-27 ETH RMII Signal Timing

3.30 E-Ray Parameters

The timings of this section are valid for the strong driver and either sharp edge settings of the output drivers with C_L = 25 pF. For the inputs the hysteresis has to be configured to inactive.

Table 3-85 Transmit Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rise time of TxEN	$t_{dCCTxENRise25}$ CC	-	-	9	ns	C_L=25pF
Fall time of TxEN	$t_{dCCTxENFall25}$ CC	-	-	9	ns	C_L=25pF
Sum of rise and fall time	$t_{dCCTxRise25+dCCTxFall25}$ CC	-	-	9	ns	20% - 80%; C_L=25pF
Sum of delay between TP1_FF and TP1_CC and delays derived from TP1_FFi, rising edge of TxEN	$t_{dCCTxEN01}$ CC	-	-	25	ns	
Sum of delay between TP1_FF and TP1_CC and delays derived from TP1_FFi, falling edge of TxEN	$t_{dCCTxEN10}$ CC	-	-	25	ns	
Asymmetry of sending	t_{tx_asym} CC	-2.45	-	2.45	ns	C_L=25pF
Sum of delay between TP1_FF and TP1_CC and delays derived from TP1_FFi, rising edge of TxD	$t_{dCCTxD01}$ CC	-	-	25	ns	
Sum of delay between TP1_FF and TP1_CC and delays derived from TP1_FFi, falling edge of TxD	$t_{dCCTxD10}$ CC	-	-	25	ns	
TxD signal sum of rise and fall time at TP1_BD	t_{txd_sum} CC	-	-	9	ns	

Table 3-86 Receive Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Acceptance of asymmetry at receiving part	$t_{dCCTxAsymAccept25}$ SR	-30.5	-	43.0	ns	C_L=25pF
Acceptance of asymmetry at receiving part	$t_{dCCTxAsymAccept15}$ SR	-31.5	-	44.0	ns	C_L=15pF
Threshold for detecting logical high	$T_{uCCLogic1}$ SR	35	-	70	%	
Threshold for detecting logical low	$T_{uCCLogic0}$ SR	30	-	65	%	

Table 3-86 Receive Parameters (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Sum of delay between TP4_CC and TP4_FF and delays derived from TP4_FFi, rising edge of RxD	$t_{dCCRxD01}$ CC	-	-	10	ns	
Sum of delay between TP1_CC and TP1_CC and delays derived from TP4_FFi, falling edge of RxD	$t_{dCCRxD10}$ CC	-	-	10	ns	

3.31 HSCT Parameters

Table 3-87 HSCT - Rx/Tx setup timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
RX o/p duty cycle	$DCrx$ CC	40	-	60	%	
Bias startup time	t_{bias} CC	-	5	10	µs	Bias distributor waking up from power down and provide stable Bias.
RX startup time	t_{rxi} CC	-	5	-	µs	Wake-up RX from power down.
TX startup time	t_{tx} CC	-	5	-	µs	Wake-up TX from power down.

Table 3-88 HSCT - Rx parasitics and loads

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Capacitance total budget	C_{total} CC	-	3.5	5	pF	Total Budget for complete receiver including silicon, package, pins and bond wire
Parasitic inductance budget	$Htotal$ CC	-	5	-	nH	

Table 3-89 LVDSH - Reduced TX and RX (RED)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output differential voltage	V_{OD} CC	150	200	285	mV	Rt = 100 Ohm ±20% @2pF
Output voltage high	V_{OH} CC	-	-	1463	mV	Rt = 100 Ohm ±20%
Output voltage low	V_{OL} CC	937	-	-	mV	Rt = 100 Ohm ±20%
Output offset (Common mode) voltage	V_{OS} CC	1.08	1.2	1.32	V	Rt = 100 Ohm ±20% @2pF
Input voltage range	V_I SR	-	-	1.6	V	Absolute max = 1.6 V + (285mV/2) = 1.743
		0.15	-	-	V	Absolute min = 0.15 V - (285 mV /2) = 0 V
Input differential threshold	V_{idth} SR	-100	-	100	mV	100 mV for 55% of bit period; Note Absolute Value (Vidth - Vidthl)
Data frequency	DR CC	5	-	320	Mbps	

Table 3-89 LVDSH - Reduced TX and RX (RED) (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Receiver differential input impedance	R_{in} CC	90	100	110	Ohm	0 V < V_I < 1.6V
		80	100	120	Ohm	1.6 V < V_I < 2.0V
Slew rate	$SRtx$ CC	-	-	2	V/ns	
Change in VOS between 0 and 1	$dVOS$ CC	-	-	50	mV	Peak to peak (including DC transients).
Change in Vod between 0 and 1	$dVod$ CC	-	-	50	mV	Peak to peak (including DC transients)
Fall time [1]	t_{fall} CC	0.26	-	1.2	ns	Rt = 100 Ohm ±20% @2pF
Rise time [1]	t_{rise} CC	0.26	-	1.2	ns	Rt = 100 Ohm ±20% @2pF

1) Rise / fall times are defined for 10% - 90% of V_{OD}

Table 3-90 HSCT PLL

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
PLL frequency range	f_{PLL} CC	12.5	320	320	MHz	
PLL input frequency	f_{REF} CC	10	-	20	MHz	
PLL lock-in time	t_{LOCK} CC	-	-	50	µs	
Bit Error Rate based on 10 MHz reference clock at Slave PLL side	BER_{10} CC	-	-	10EXP-9	-	Bit Error Rate based on Slave interface reference clock at 10 MHz
Bit Error Rate based on 20 MHz reference clock at Slave PLL side	BER_{20} CC	-	-	10EXP-12	-	Bit Error Rate based on Slave interface reference clock at 20 MHz
Absolute RMS Jitter (TX out)	J_{ABS10} CC	-125	-	125	ps	Measured at link TX out; valid for Reference frequency at 10 MHz
Absolute RMS Jitter (TX out)	J_{ABS20} CC	-85	-	85	ps	Measured at link TX out; valid for Reference frequency at 20 MHz

Table 3-90 HSCT PLL (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Accumulated RMS Jitter (RX side)	J_{ACC10} CC	-	-	145	ps	Measured at link RX input, based on 5000 measures, each 300 clock cycles; valid for Reference frequency at 10 MHz
Accumulated RMS Jitter (link RX side)	J_{ACC20} CC	-	-	115	ps	Measured at link RX input, based on 5000 measures, each 300 clock cycles; valid for Reference frequency at 20 MHz
Total Jitter peak to peak	TJ_{pp} CC	-	-	2083	ps	Total Jitter as sum of deterministic jitter and random jitter

Table 3-91 HSCT Sysclk

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Frequency	f_{SYSCLK} CC	10	-	20	MHz	
Frequency error	$dfERR$ CC	-1	-	1	%	
Duty Cycle	$DCsys$ CC	45	-	55	%	
Load impedance	R_{LOAD} CC	10	-	-	kOhm	
Load capacitance	C_{LOAD} CC	-	-	10	pF	
Integrated phase noise	I_{PN} CC	-	-	-58	dB	single sideband phase noise in 10 kHz to 10 Mhz at 20 MHz SysClk

3.32 Inter-IC (I2C) Interface Timing

This section defines the timings for I2C in the TC270 / TC275 / TC277.

All I2C timing parameter are SR for Master Mode and CC for Slave Mode.

Table 3-92 I2C Standard Mode Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1	-	-	300	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Capacitive load for each bus line	C_b SR	-	-	400	pF	
Bus free time between a STOP and ATART condition	t_{10}	4.7	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Rise time of both SDA and SCL	t_2	-	-	1000	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Data hold time	t_3	0	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Data set-up time	t_4	250	-	-	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Low period of SCL clock	t_5	4.7	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
High period of SCL clock	t_6	4	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Hold time for the (repeated) START condition	t_7	4	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line

Table 3-92 I2C Standard Mode Timing (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Set-up time for (repeated) START condition	t_8	4.7	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Set-up time for STOP condition	t_9	4	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line

Table 3-93 I2C Fast Mode Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Fall time of both SDA and SCL	t_1	20+0.1*C_b	-	300	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Capacitive load for each bus line	C_b SR	-	-	400	pF	
Bus free time between a STOP and ATART condition	t_{10}	1.3	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Rise time of both SDA and SCL	t_2	20+0.1*C_b	-	300	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Data hold time	t_3	0	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Data set-up time	t_4	100	-	-	ns	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Low period of SCL clock	t_5	1.3	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
High period of SCL clock	t_6	0.6	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line

Table 3-93 I2C Fast Mode Timing (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Hold time for the (repeated) START condition	t_7	0.6	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Set-up time for (repeated) START condition	t_8	0.6	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line
Set-up time for STOP condition	t_9	0.6	-	-	µs	Measured with a pull-up resistor of 4.7 kohms at each of the SCL and SDA line

3.33 Flash Target Parameters

Program Flash program and erase operation is only allowed up the T_J = 150°C.

Table 3-94 FLASH

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Program Flash Erase Time per logical sector	t_{ERP} CC	-	-	1	s	cycle count < 1000
		-	0.207 + 0.003 * (S [KByte]) / (f_{FSI} [MHz])[1)]	-	s	cycle count < 1000, for sector of size S
Program Flash Erase Time per Multi-Sector Command	t_{MERP} CC	-	-	1	s	For consecutive logical sectors in a physical sector, cycle count < 1000
		-	0.207 + 0.003 * (S [KByte]) / (f_{FSI} [MHz])[1)]	-	s	For consecutive logical sector range of size S in a physical sector, cycle count < 1000
Program Flash program time per page in 5 V mode	t_{PRP5} CC	-	-	50 + 3000/(f_{FSI} [MHz])	µs	32 Byte
Program Flash program time per page in 3.3 V mode	t_{PRP3} CC	-	-	81 + 3400/(f_{FSI} [MHz])	µs	32 Byte
Program Flash program time per burst in 5 V mode	t_{PRPB5} CC	-	-	125 + 9500/(f_{FSI} [MHz])	µs	256 Byte
Program Flash program time per burst in 3.3 V mode	t_{PRPB3} CC	-	-	410 + 12000/(f_{FSI} [MHz])	µs	256 Byte
Program Flash program time for 1 MByte with burst programming in 3 V mode excluding communication	t_{PRPB3_1MB} CC	-	-	2.2	s	Derived value for documentation purpose, valid for f_{FSI} = 100MHz
Program Flash program time for 1 MByte with burst programming in 5 V mode excluding communication	t_{PRPB5_1MB} CC	-	-	0.9	s	Derived value for documentation purpose, valid for f_{FSI} = 100MHz
Program Flash program time for complete PFlash with burst programming in 5 V mode excluding communication	t_{PRPB5_PF} CC	-	-	3.6	s	Derived value for documentation purpose, valid for f_{FSI} = 100MHz

Table 3-94 FLASH (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Write Page Once adder	t_{ADD} CC	-	-	15 + 500/(f_{FSI} [MHz])	µs	Adder to Program Time when using Write Page Once
Program Flash suspend to read latency	t_{SPNDP} CC	-	-	12000/(f_{FSI} [MHz])	µs	For Write Burst, Verify Erased and for multi-(logical) sector erase commands
Data Flash Erase Time per Sector [2]	t_{ERD} CC	-	0.12 + 0.08/(f_{FSI} [MHz])[1]	-	s	cycle count < 1000
		-	0.57 + 0.15/(f_{FSI} [MHz])[1]	0.928 + 0.15/(f_{FSI} [MHz])	s	cycle count < 125000
Data Flash Erase Time per Multi-Sector Command [2]	t_{MERD} CC	-	0.12 + 0.01 * (S [KByte]) / (f_{FSI} [MHz])[1]	-	s	For consecutive logical sector range of size S, cycle count < 1000
		-	0.57 + 0.019 * (S [KByte]) / (f_{FSI} [MHz])[1]	0.928 + 0.019 * (S [KByte]) / (f_{FSI} [MHz])	s	For consecutive logical sector range of size S, cycle count < 125000
Data Flash erase disturb limit	N_{DFD} CC	-	-	50	cycles	
Program time data flash per page [3]	t_{PRD} CC	-	-	50 + 2500/(f_{FSI} [MHz]) [3]	µs	8 Byte
Complete Device Flash Erase Time PFlash and DFlash [4]	t_{ER_Dev} CC	-	-	9	s	Derived value for documentation purpose (excl. UCBs and HSMs), valid for f_{FSI} = 100MHz
Data Flash program time per burst [3]	t_{PRDB} CC	-	-	96 + 4400/(f_{FSI} [MHz]) [3]	µs	32 Bytes
Data Flash suspend to read latency	t_{SPNDD} CC	-	-	12000/(f_{FSI} [MHz])	µs	
Wait time after margin change	$t_{FL_MarginDel}$ CC	-	-	10	µs	
Program Flash Retention Time, Sector	t_{RET} CC	20	-	-	years	Max. 1000 erase/program cycles
Data Flash Endurance per EEPROMx sector [5]	N_{E_EEP10} CC	125000	-	-	cycles	Max. data retention time 10 years

Table 3-94 FLASH (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Data Flash Endurance per HSMx sector [5]	N_{E_HSM} CC	125000	-	-	cycles	Max. data retention time 10 years
UCB Retention Time	t_{RTU} CC	20	-	-	years	Max. 100 erase/program cycles per UCB, max 400 erase/program cycles in total
Data Flash access delay	t_{DF} CC	-	-	100	ns	see PMU_FCON.WSDFLASH
Data Flash ECC Delay	t_{DFECC} CC	-	-	20	ns	see PMU_FCON.WSECDF
Program Flash access delay	t_{PF} CC	-	-	30	ns	see PMU_FCON.WSPFLASH
Program Flash ECC delay	t_{PFECC} CC	-	-	10	ns	see PMU_FCON.WSECPF
Number of erase operations on DF0 over lifetime	N_{ERD0} CC	-	-	750000	cycles	
Number of erase operations on DF1 over lifetime	N_{ERD1} CC	-	-	500000	cycles	
Junction temperature limit for PFlash program/erase operations	$T_{JPFlash}$ SR	-	-	150	°C	

1) All typical values were characterised, but are not tested. Typical values are safe median values at room temperature
2) Under out-of-spec conditions (e.g. over-cycling) or in case of activation of WL oriented defects, the duration of erase processes may be increased by up to 50%.
3) Time is not dependent on program mode (5V or 3.3V).
4) Using 512 KByte erase commands.
5) Only valid when a robust EEPROM emulation algorithm is used. For more details see the Users Manual.

3.34 Package Outline

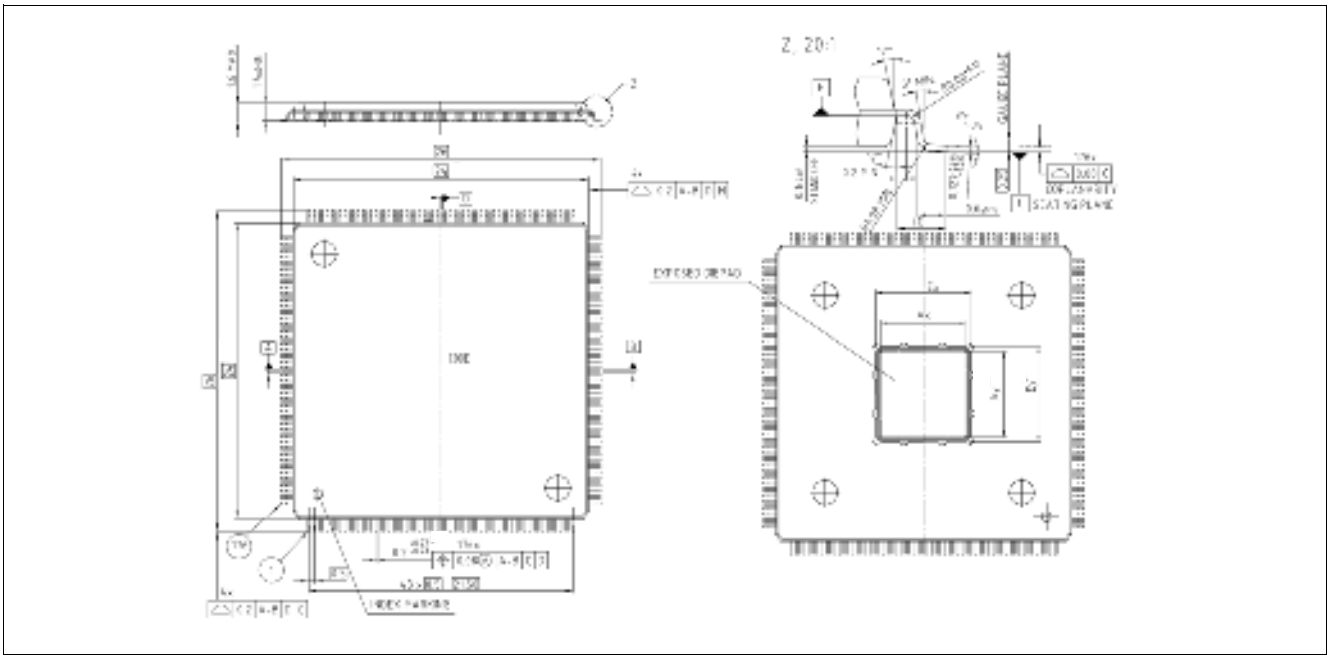


Figure 3-28 Package Outlines PG-LQFP-176-22

Table 3-95 Exposed Pad Dimensions

Ax (nominal EPad size)	7.9 mm ± 50 µm
Ay (nominal EPad size)	7.9 mm ± 50 µm
Ex (solder able EPad size)	8.7 mm ± 50 µm
Ey (solder able EPad size)	8.7 mm ± 50 µm

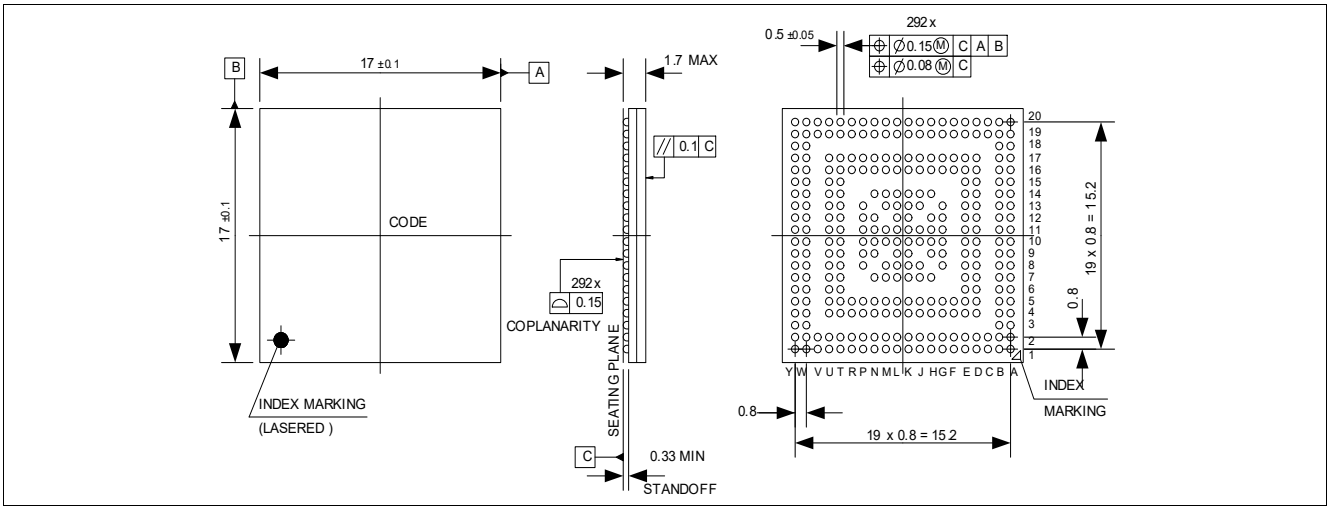


Figure 3-29 Package Outlines LF-BGA-292-6 / LF-BGA-292-10

You can find all of our packages, sorts of packing and others in our Infineon Internet Page “Products”: http://www.infineon.com/products.

3.34.1 Package Parameters

Table 3-96 Thermal Characteristics of the Package

Device	Package	RQJCT[1)]	RQJCB[1)]	RQJA	Unit	Note
TC275	PG-LQFP-176-22	9,6	1,25	14,7[2)]	K/W	with soldered exposed pad
TC277	LF-BGA-292-6 / LF-BGA-292-10	5,1	7,2	15,8[3)]	K/W	

1) The top and bottom thermal resistances between the case and the ambient (R_{TCAT}, R_{TCAB}) are to be combined with the thermal resistances between the junction and the case given above (R_{TJCT}, R_{TJCB}), in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCAT}, R_{TCAB}) depend on the external system (PCB, case) characteristics, and are under user responsibility.
The junction temperature can be calculated using the following equation: $T_J = T_A + R_{TJA} * P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances.
Thermal resistances as measured by the 'cold plate method' (MIL SPEC-883 Method 1012.1).

2) Value is defined in accordance with JEDEC JESD51-3, JESD51-5, and JESD51-7.

3) Value is defined in accordance with JEDEC JESD51-1.

3.34.2 TC270 Carrier Tape

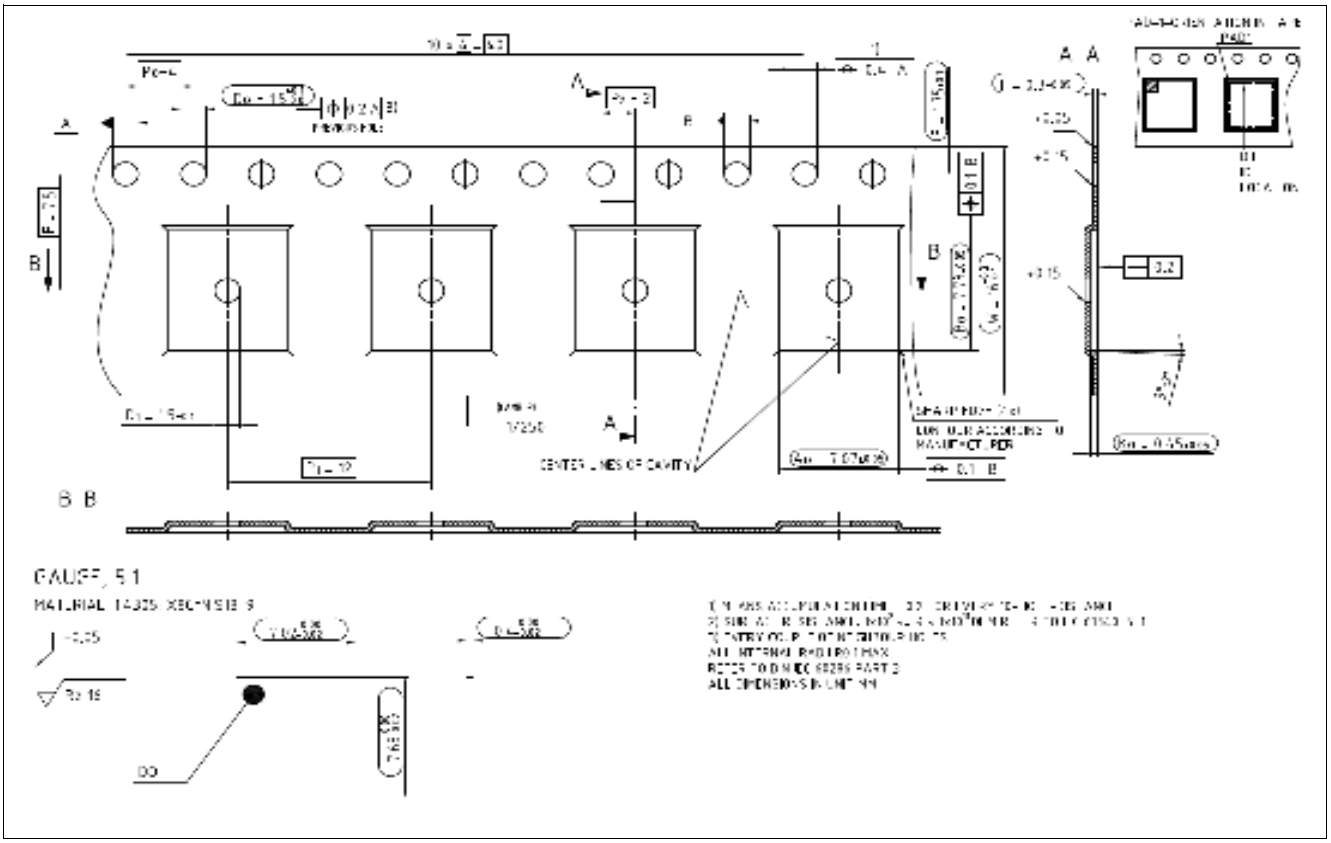


Figure 3-30 Carrier Tape Dimenions

Table 3-97 TC270 Chip Dimenions

Device	A	B	T
TC270	7,590 mm	6,930 mm	0,3 mm

3.35 Quality Declarations

Table 3-98 Quality Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Operation Lifetime	t_{OP}	-	-	24500	hour	
ESD susceptibility according to Human Body Model (HBM)	V_{HBM}	-	-	2000	V	Conforming to JESD22-A114-B
ESD susceptibility of the LVDS pins	V_{HBM1}	-	-	500	V	
ESD susceptibility according to Charged Device Model (CDM)	V_{CDM}	-	-	500	V	for all other balls/pins; conforming to JESD22-C101-C
		-	-	750	V	for corner balls/pins; conforming to JESD22-C101-C
Moisture Sensitivity Level	MSL	-	-	3		Conforming to Jedec J-STD--020C for 240C

4 History

Version 0.6 is the first version of this document.

4.1 Changes from version version 0.6 to 0.7

- Changes in table 'Overload Parameters' of Overload
  - Add max 1.7*10^{-3} to K_{OVDN}
  - Add max 2*10^{-2} to K_{OVDN}
  - Add max 1*10^{-2} to K_{OVDN}
  - Add max 1*10^{-4} to K_{OVDP}
  - Add max 1*10^{-2} to K_{OVAN}
  - Change note of K_{OVAN} from '-5mA < I_{IN} < -1mA' to 'Analog Inputs overlaid with class LP pads or pull down diagnostics; -5mA < I_{IN} < -1mA'
  - Change max value of K_{OVAN} from 3*10^{-3} to 1*10^{-2}
  - Change min value of I_{INANA} from -1 mA to -3 mA
  - Change note of K_{OVAN} from 'else' to 'else; -5mA < I_{IN} < 0mA'
  - Change note of K_{OVAP} from 'else' to '5mA < I_{IN} < 0mA'
  - Change max value of K_{OVAN} from 1*10^{-3} to 6*10^{-4}
  - Change note of K_{OVAN} from 'Analog Inputs overlaid with class LP pads or pull down diagnostics' to 'Analog Inputs overlaid with class LP pads or pull down diagnostics; -1mA < I_{IN} < 0mA'
  - Change note of K_{OVDP} from 'Overload injected on LVDS pad and affecting neighbor LVDS pad' to 'Overload injected on LVDS pad and affecting neighbor LVDS pads'
  - Change note of K_{OVDP} from 'Overload injected on GPIO non LVDS pad and affecting neighbor GPIO non LVDS pad' to 'Overload injected on GPIO non LVDS pad and affecting neighbor GPIO non LVDS pads'
  - Change max value of K_{OVDN} from 0.9 to 0.93
  - Change note of K_{OVDN} from 'Overload injected on GPIO non LVDS pad and affecting neighbor GPIO non LVDS pad' to 'Overload injected on GPIO non LVDS pad and affecting neighbor LP and A2 pads; -2mA < I_{IN} < 0mA'
  - Change max value of K_{OVDN} from 1.5*10^{-3} to 6*10^{-4}
  - Change note of K_{OVDN} from 'Overload injected on LVDS pad and affecting neighbor LVDS pad' to 'Overload injected on LVDS pad and affecting neighbor LVDS pads'
- VADC
  - Add min 0 pC to Q_{CONV}
  - Add min 8 pC to Q_{CONV}
  - Add max 10 pC to Q_{CONV}
  - Add max 2 µA to I_{OZ2}
  - Change min value of I_{OZ3} from -2.5 µA to -3.3 µA
  - Change note of I_{OZ3} from '-1 µA' to '-2 µA'
  - Change max value of I_{OZ2} from 2 µA to 3 µA
  - Add min -2.8 µA to I_{OZ3}
  - Add max 2.5 µA to I_{OZ3}
  - Add max 20 pC to Q_{CONV}
  - Add min -2 µA to I_{OZ2}

  - Add min V_{SSM} V to V_{AGND}
  - Add max 7 µA to I_{OZ2}
  - Add min -13 µA to I_{OZ3}
  - Add min -4 µA to I_{OZ2}
  - Add max 4 µA to I_{OZ2}
  - Add min -7 µA to I_{OZ3}
  - Add max 7 µA to I_{OZ3}
  - Add max 13 µA to I_{OZ3}
  - Add typ 0.5 LSB to EN_{RMS}
  - Add min -7 µA to I_{OZ2}
  - Change note of Q_{CONV} from 'V_{AIN} = 5V, charge consumed from reference pin, precharging disabled' to 'V_{AIN} = 5 V, charge consumed from reference pin, precharging disabled'
  - Change typ value of Q_{CONV} from 80 pC to 14 pC
  - Change predicate of t_{BWG} from typ to max
  - Change max value of t_{BWG} from 50 cycles to 120 cycles
  - Change predicate of t_{BWR} from typ to max
  - Change max value of t_{BWR} from 50 cycles to 60 cycles
  - Change note of I_{OZ1} from 'Analog Inputs overlaid with GPIO functions or pull down diagnosis or DSADC inputs' to 'Analog Inputs overlaid with class LP pads or pull down diagnostics'
  - Change note of Q_{CONV} from 'V_{AIN} = 5V, charge consumed from reference pin, precharging enabled' to 'V_{AIN} = 5 V, charge consumed from reference pin, precharging enabled'
  - Change typ value of Q_{CONV} from 20 pC to 3 pC
  - Change note of EN_{RMS} from 'target' to ''
  - Change max value of EN_{RMS} from 0.5 LSB to 0.75 LSB
  - Change note of R_{AIN} from 'valid for analoge inputs mapped to GPIOs' to 'valid for analog inputs mapped to GPIOs'
- VADC_33V
  - Add min 0 pC to Q_{CONV}
  - Add min 4 pC to Q_{CONV}
  - Add max 15 pC to Q_{CONV}
  - Add max 8 pC to Q_{CONV}
  - Add min -2 µA to I_{OZ2}
  - Add max 2.5 µA to I_{OZ2}
  - Add min -2.2 µA to I_{OZ3}
  - Add max 2 µA to I_{OZ3}
  - Add max 12 µA to I_{OZ3}
  - Add min -6 LSB to EA_{GAIN}
  - Add min -12 LSB to TUE
  - Add max 12 LSB to TUE
  - Add min -12 LSB to EA_{INL}
  - Add max 12 LSB to EA_{INL}
  - Add min -6 LSB to EA_{OFF}

  - Add max 6 LSB to EA_{OFF}
  - Add max 6 LSB to EA_{GAIN}
  - Add min -3.5 µA to I_{OZ2}
  - Add min -6 µA to I_{OZ2}
  - Add max 3.5 µA to I_{OZ2}
  - Add max 6 µA to I_{OZ2}
  - Add min -6.5 µA to I_{OZ3}
  - Add min -12 µA to I_{OZ3}
  - Add max 6.5 µA to I_{OZ3}
  - Add max 150 °C to T_J
  - Add min V_{SSM} V to V_{AGND}
  - Add min 150 °C to T_J
  - Add max 10 % to $dVCSD$
  - Add max 28 kOhm to R_{CSD}
  - Change note of TUE from '12-bit resolution' to '12-bit Resolution; T_J ≤ 150 °C'
  - Change note of EA_{DNL} from '' to '12-bit resolution'
  - Change note of EA_{INL} from '' to '12-bit Resolution; T_J ≤ 150 °C'
  - Change note of EA_{OFF} from '' to '12-bit Resolution; T_J ≤ 150 °C'
  - Change note of EA_{GAIN} from '' to '12-bit Resolution; T_J ≤ 150 °C'
  - Change note of I_{OZ1} from 'Analog Inputs overlaid with GPIO functions or pull down diagnosis or DSADC inputs' to 'Analog Inputs overlaid with class LP pads or pull down diagnostics'
  - Change note of Q_{CONV} from 'V_{AIN} = 3.3V, charge consumed from reference pin, precharging disabled' to 'V_{AIN} = 3.3 V, charge consumed from reference pin, precharging disabled'
  - Change typ value of Q_{CONV} from 60 pC to 7 pC
  - Change note of Q_{CONV} from 'V_{AIN} = 3.3V, charge consumed from reference pin, precharging enabled' to 'V_{AIN} = 3.3 V, charge consumed from reference pin, precharging enabled'
  - Change typ value of Q_{CONV} from 15 pC to 3 pC
  - Change max value of t_{BWG} from 50 cycles to 120 cycles
  - Change predicate of t_{BWG} from typ to max
  - Change max value of t_{BWR} from 50 cycles to 60 cycles
  - Change predicate of t_{BWR} from typ to max
  - Change description of I_{OZ2} from 'Positive reference pin leakage' to 'Positive reference V_{AREFx} pin leakage'
  - Change description of I_{OZ3} from 'Negative reference pin leakage' to 'Negative reference V_{AGNDx} pin leakage'
  - Add footnote 'This parameter is valid for soldered devices and requires careful analog board design.' to $ENRMS$
  - Change max value of R_{AIN} from 1.5 kOhm to 1.6 kOhm
- EVR/LDO/1.3V
  - Add max 6.3 µF to C_{OUT}
  - Add min 3 µF to C_{OUT}
  - Change note of $dVout/dIout$ from 'dI=-150mA; $Tsettle$=20μs; pass device=off chip' to 'dI=-150mA; $Tsettle$=20μs; pass device=off chip'
- EVR/Back-up Clock
  - Add footnote 'All V_{EXT} pins shall be connected together externally on the PCB.' to V_{EXT}

- Changes in table 'EVR13 SMPS External components' of EVR/DCDC
  - Change name of C_{OUTDC} from CDC to COUTDC
- Changes in table 'EVR13 SMPS' of EVR/DCDC
  - Change note of $dVout/dIout$ from '$dI < 200mA$; f_{DCDC}=1MHz; t_r=0.1us; t_f=0.1us; V_{DDDC}=1.3V' to '$dI < 200mA$; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V'
  - Change note of $dVout/dIout$ from '$dI < 700mA$; f_{DCDC}=1MHz; t_r=0.1us; t_f=0.1us; V_{DDDC}=1.3V' to '$dI < 700mA$; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V'
  - Change note of $dVout/dIout$ from '$dI < 400mA$; f_{DCDC}=1MHz; t_r=0.1us; t_f=0.1us; V_{DDDC}=1.3V' to '$dI < 400mA$; f_{DCDC}=1MHz; t_r=0.1µs; t_f=0.1µs; V_{DDDC}=1.3V'
  - Add footnote 'Incase of SMPS mode, It shall be ensured that the VDD Output pin shall be connected on PCB level to all other V_{DD} Input pins.' to V_{DDDC}
  - Add footnote 'Capacitor min-max range represent typical ±35% tolerance including DC bias effect. The trace resistance from the capacitor to the supply or ground rail should be limited to 25 mOhm.' to C_{OUTDC}
  - Add footnote 'Incase of TC29x running with fSRI = 300 MHz, it shall be ensured that the VDD operating range is limited to 1.235V upto 1.430V. The DCDC may be configured in this case with a nominal voltage of 1.33V±7.5%. The static accuracy and regulation parameter ranges remain also valid for this case.' to V_{DD_DC}
- FLASH
  - Add max 2.2 s to t_{PRPB3_1MB}
  - Change note of t_{ERD} from '' to 'cycle count < 125000'
  - Change max value of t_{ERD} from 1 s to 0.928 + 0.15/(f_{FSI} [MHz]) s
  - Change max value of t_{PRD} from 75 µs to 50 + 2500/(f_{FSI} [MHz]) µs
  - Change note of t_{MERP} from 'For consecutive logical sectors in a physical sector' to 'For consecutive logical sectors in a physical sector, cycle count < 1000'
  - Change max value of t_{PRP5} from 80 µs to 50 + 3000/(f_{FSI} [MHz]) µs
  - Change max value of t_{PRPB5} from 220 µs to 125 + 9500/(f_{FSI} [MHz]) µs
  - Change max value of t_{PRPB3} from 530 µs to 410 + 12000/(f_{FSI} [MHz]) µs
  - Change note of t_{PRPB5_1MB} from 'Derived value for documentation purpose' to 'Derived value for documentation purpose, valid for f_{FSI} = 100MHz'
  - Change note of t_{PRPB5_PF} from 'Derived value for documentation purpose' to 'Derived value for documentation purpose, valid for f_{FSI} = 100MHz'
  - Change max value of t_{ADD} from 20 µs to 15 + 500/(f_{FSI} [MHz]) µs
  - Change max value of t_{SPNDP} from 120 µs to 12000/(f_{FSI} [MHz]) µs
  - Change note of t_{MERD} from 'For consecutive logical sectors' to 'For consecutive logical sector range of size S, cycle count < 125000'
  - Change max value of t_{MERD} from 1 s to 0.928 + 0.019 * (S [KByte]) / (f_{FSI} [MHz]) s
  - Change note of t_{ER_Dev} from 'Derived value for documentation purpose (excl. UCBs and HSMs)' to 'Derived value for documentation purpose (excl. UCBs and HSMs); valid for f_{FSI} = 100MHz'
  - Change max value of t_{PRDB} from 140 µs to 96 + 4400/(f_{FSI} [MHz]) µs
  - Change max value of t_{SPNDD} from 120 µs to 12000/(f_{FSI} [MHz]) µs
  - Change max value of t_{PRP3} from 115 µs to 81 + 3400/(f_{FSI} [MHz]) µs
  - Add typ 0.12 + 0.08/(f_{FSI} [MHz]) s to t_{ERD}
  - Add typ 0.207 + 0.003 * (S [KByte]) / (f_{FSI} [MHz]) s to t_{MERP}
  - Add typ 0.12 + 0.01 * (S [KByte]) / (f_{FSI} [MHz]) s to t_{MERD}

  - Add typ 0.207 + 0.003 * (S [KByte]) / (f_{FSI} [MHz]) s to t_{ERP}
  - Add typ 0.57 + 0.15/(f_{FSI} [MHz]) s to t_{ERD}
  - Add typ 0.57 + 0.019 * (S [KByte]) / (f_{FSI} [MHz]) s to t_{MERD}
- DSADC
  - Change note of SNR from 'f_{PB} = 30kHz' to 'f_{PB} = 30 kHz; V_{DDM} = ±5%'
  - Change min value of SNR from 76 dB to 80 dB
  - Change note of SNR from 'f_{PB} = 50kHz' to 'f_{PB} = 50 kHz; V_{DDM} = ±5%'
  - Change min value of SNR from 74 dB to 78 dB
  - Add footnote 'Single-ended mode reduces the SNR by 6 dB if the unused input is grounded, by 3 dB if the unused input connects to V_{CM} (GAIN = 2).' to SNR
  - Remove footnote 'Single-ended mode reduces the SNR by 6 dB if the unused input is grounded, by 3 dB if the unused input connects to V_{CM} (GAIN = 2).' from SNR
  - Add min 60 dB to SFDR
  - Add typ 100 kHz to f_{PB}
  - Add min 74 dB to SNR
  - Change min value of SNR from 70 dB to 74 dB
  - Add min 70 dB to SNR
  - Change min value of SNR from 65 dB to 70 dB
  - Add min 76 dB to SNR
  - Change min value of SNR from 72 dB to 76 dB
  - Add typ 30 kHz to f_{PB}
  - Change min value of ED_{GAIN} from -5 % to -3.5 %
  - Change min value of ED_{GAIN} from -0.1 % to -0.2 %
  - Change max value of ED_{GAIN} from 0.1 % to 0.2 %
  - Add footnote 'Recalibration needed in case of a temperature change > 20ºC' to ED_{GAIN}
  - Change max value of ED_{GAIN} from 5 % to 3.5 %
  - Change min value of ED_{OFF} from -350 mV to -100 mV
  - Add max 100 mV to ED_{OFF}
  - Change typ value of ED_{OFF} from -150 mV to mV
  - Change note of R_{DAIN} from 'Exact value (+-1%) available in UCB' to 'Exact value (±1%) available in UCB'
  - Add footnote 'The variation of the impedance between different channels is < 1.5%.' to R_{DAIN}
  - Change note of SNR from 'f_{PB} = 100kHz' to 'f_{PB} = 100 kHz; V_{DDM} = ±5%'
  - Change min value of SNR from 69 dB to 74 dB
  - Remove footnote '10 kHz only with 10MHz Modulator clock frequency reachable' from f_{PB}
  - Add footnote '10 kHz only reachable with 10 MHz modulator clock frequency.' to f_{PB}
  - Change note of SBA from '1,5 ... 2 f_D' to '1.5 ... 2 f_D'
  - Remove footnote 'Derating factors:-2 dB in standard-performance mode.-3 dB for CMV = 10_B, i.e. V_{CM} = (V_{AREF}±2%) / 2.0.' from SBA
  - Add footnote 'CIC3, FIR0, FIR1 filters enabled.' to SBA
  - Change note of SBA from '2,5 ... OSR/2 f_D' to '2.5 ... OSR/2 f_D'
  - Change note of SBA from '0,5 ... 1 f_D' to '0.5 ... 1 f_D'
  - Change note of SFDR from 'VCM = 2.2V, DC coupled' to 'V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±10%'

  - Add footnote 'SFDR = 20 * log(INL / 2^N)' to $SFDR$
  - Change description of $dVCM$ from 'Common Mode Voltage Accuracy' to 'Common mode voltage accuracy'
  - Change description of $dVCMH$ from 'Commom mode hold voltage deviation' to 'Common mode hold voltage deviation'
  - Change description of I_{OZ5} from 'Positive reference pin leakage' to 'Positive reference V_{AREF1} pin leakage'
  - Change description of I_{OZ6} from 'Negative reference pin leakage' to 'Negative reference V_{AGND1} pin leakage'
- DSADC_33V
  - Change note of SNR from 'f_{PB} = 30kHz' to 'f_{PB} = 30kHz; V_{DDM} = ±5%'
  - Change note of SNR from 'f_{PB} = 50kHz' to 'f_{PB} = 50kHz; V_{DDM} = ±5%'
  - Add min 45 dB to SNR
  - Add min 60 dB to SNR
  - Add min 55 dB to SNR
  - Add typ 63 dB to SNR
  - Add typ 66 dB to SNR
  - Add typ 68 dB to SNR
  - Add min 52 dB to SFDR
  - Change max value of ED_{GAIN} from 0.1 % to 0.2 %
  - Add footnote 'Recalibration needed in case of a temperature change > 20ºC.' to ED_{GAIN}
  - Change note of SBA from '1,5 ... 2 f_D' to '1.5 ... 2 f_D'
  - Change note of SBA from '0,5 ... 1 f_D' to '0.5 ... 1 f_D'
  - Change note of SBA from '2,5 ... OSR/2 f_D' to '2.5 ... OSR/2 f_D'
  - Change note of SFDR from 'VCM = 2.2V, DC coupled' to 'V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±5%'
  - Change note of SNR from 'f_{PB} = 100kHz' to 'f_{PB} = 100kHz; V_{DDM} = ±5%'
- Changes in table 'Class LP 5V' of Standard_Pads
  - Change max value of V_{ILHLP} from 2.85 V to 3.0 V
  - Change min value of $HYSLP$ from 0.1 * $V_{EXT/FLEX}$ V to 0.09 * $V_{EXT/FLEX}$ V
  - Change min value of $HYSLP$ from 0.08 * $V_{EXT/FLEX}$ V to 0.075 * $V_{EXT/FLEX}$ V
- Changes in table 'Class MPR 5V' of Standard_Pads
  - Change min value of $HYSMPR$ from 0.1 * $V_{EXT/FLEX}$ V to 0.09 * $V_{EXT/FLEX}$ V
  - Change min value of $HYSMPR$ from 0.08 * $V_{EXT/FLEX}$ V to 0.075* $V_{EXT/FLEX}$ V
- Changes in table 'Class I 3.3V' of Standard_Pads
  - Change min value of $HYSI$ from 0.047 * $V_{EXT/FLEX}$ V to 0.045 * $V_{EXT/FLEX}$ V
- Changes in table 'Class I 5V' of Standard_Pads
  - Change min value of $HYSI$ from 0.073 * $V_{EXT/FLEX}$ V to 0.07 * $V_{EXT/FLEX}$ V
  - Change min value of $HYSI$ from 0.1 * $V_{EXT/FLEX}$ V to 0.09 * $V_{EXT/FLEX}$ V
  - Change min value of $HYSI$ from 0.08 * $V_{EXT/FLEX}$ V to 0.075 * $V_{EXT/FLEX}$ V
  - Change max value of V_{ILHI} from 2.85 V to 3.0 V
- Changes in table 'Class S' of Standard_Pads
  - Change note of I_{OZS} from 'Analog Inputs overlaid with GPIO functions or pull down diagnosis or DSADC inputs' to 'Analog Inputs with pull down diagnostics'
- Changes in table 'Class MP 5V' of Standard_Pads
  - Change min value of $HYSMP$ from 0.1 * $V_{EXT/FLEX}$ V to 0.09 * $V_{EXT/FLEX}$ V

  - Change min value of $HYSMP$ from 0.08 * $V_{EXT/FLEX}$ V to 0.075 * $V_{EXT/FLEX}$ V
  - Change max value of V_{ILHMP} from 2.85 V to 3.0 V
- Changes in table 'Class MP+ 5V' of Standard_Pads
  - Change min value of $HYSMPP$ from 0.08 * $V_{EXT/FLEX}$ V to 0.075 * $V_{EXT/FLEX}$ V
  - Change min value of $HYSMPP$ from 0.1 * $V_{EXT/FLEX}$ V to 0.09 * $V_{EXT/FLEX}$ V
  - Change max value of V_{ILHMPP} from 2.85 V to 3.0 V
- Changes in table 'Class F' of Standard_Pads
  - Add footnote 'For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.' to $R_{DSONMPRW}$
  - Add footnote 'For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.' to $R_{DSONMPRM}$
  - Add footnote 'For currents smaller than the $I_{OL/OH}$ from the test condition the defined Max. value stays unchanged.' to $R_{DSONMPRS}$
  - Add footnote 'Rise / fall times are defined 10% - 90% of $V_{EXT/FLEX}$.' to t_{MPR}
- Changes in table 'Master Mode Timing, LVDSM output pads for data and clock' of QSPI_ED/3.3V
  - Change min value of t_{52} from 37 ns to 20 ns
- Absolute Maximum Ratings
  - Change note of T_{ST} from 'upto 65h @ T_J = 150°C' to 'upto 65h @ T_J = 150°C; upto 15h @ T_J = 170°C'
  - Change max value of T_{ST} from 150 °C to 170 °C
- Operating Conditions
  - Change description of V_{DDP3} from 'Digital supply voltage for LVDSH and A2 apds' to 'Digital supply voltage for LVDSH and A2 pads'
  - Add footnote 'All V_{DDP3} pins shall be connected together externally on the PCB.' to V_{DDP3}
  - Change min value of V_{DDPPA} from 0.7 V to 0.72 V
- Changes in table 'Master Mode Timing, LVDSM output pads for data and clock' of QSPI/3.3V
  - Change min value of t_{52} from 37 ns to 20 ns
- Changes in table 'Master Mode Weak output pads' of QSPI/5V
  - Add footnote 'Documented value is valid for master transmit or slave receive only. For full duplex the external SPI counterpart timing has to be taken into account.' to t_{50}
- Changes in table 'Receive Parameters' of ERAY
  - Change description of $t_{dCCTxAsymAccept15}$ from 'Acceptance of asymmetriy at receiving part' to 'Acceptance of asymmetry at receiving part'
  - Change description of $t_{dCCTxAsymAccept25}$ from 'Acceptance of asymmetriy at receiving part' to 'Acceptance of asymmetry at receiving part'
- Power Supply
  - Update footnote of $Power\ Supply$ to ' A single converter instance of VADC unit consumes 2 mA.'
  - Change description of $I_{DDx3RAIL}$ from '∑ Sum of 3.3 V supply currents' to '∑ Sum of 3.3 V supply currents without pad activity'
  - Change note of $I_{EXT/FLEX}$ from 'real power pattern with port activity absent; PORST output inactive.' to 'real power pattern; PORST output inactive.'
  - Change description of I_{DDIO} from 'Sum of I_{EXT} and I_{FLEX} supply current' to 'Sum of I_{EXT} and I_{FLEX} supply current without pad activity'
  - Change description of I_{DDP3} from 'I_{DDP3} supply current with no pad activity' to 'I_{DDP3} supply current without pad activity'

  - Change max value of I_{DDM} from 26 mA to 30 mA
  - Change max value of I_{DDM} from 18 mA to 14 mA
  - Change max value of I_{DDM} from 52 mA to 59 mA
  - Change max value of I_{DDM} from 24 mA to 17 mA
- Changes in table 'LVDSH - IEEE standard LVDS general purpose link (GPL)' of LVDSH
  - Change description of t_{fall20} from 'Fall time (20% - 80%)' to 'Fall time'
  - Change description of t_{rise20} from 'Rise time (20% - 80%)' to 'Rise time'
- Changes in table 'LVDSH - IEEE standard LVDS reduced link (REDL)' of LVDSH
  - Change description of t_{rise10} from 'Vod Rise time (10% - 90%)' to 'V_{OD} Rise time'
  - Change description of t_{fall10} from 'Vod Fall time (10% - 90%)' to 'V_{OD} Fall time'
- Changes in table 'LVDSH - Reduced TX and RX (RED)' of LVDSH
  - Change description of t_{rise} from 'Rise time (10% - 90%)' to 'Rise time'
  - Change description of t_{fall} from 'Fall time (10% - 90%)' to 'Fall time'
  - Add footnote 'Rise / fall times are defined for 10% - 90% of V_{OD}' to t_{fall}
  - Add footnote 'Rise / fall times are defined for 20% - 80% of V_{OD}' to t_{rise20}
  - Add footnote 'Rise / fall times are defined for 10% - 90% of V_{OD}' to t_{rise}
  - Add footnote 'Rise / fall times are defined for 20% - 80% of V_{OD}' to t_{fall20}
  - Add footnote 'Rise / fall times are defined for 10% - 90% of V_{OD}' to t_{rise10}
  - Add footnote 'Rise / fall times are defined for 10% - 90% of V_{OD}' to t_{fall10}

4.2 Changes from version version 0.7 to 1.0

- Package Chapter
  - update information for VADC functions ‘with pull down diagnostics’ and ‘MD’, no change in pinning
  - correct for P20.2 PU1 to PU
  - add additional pin VSSM at position 100 to TC270 Bare Die pin list, shift following pins accordingly
  - add additional pin VDDM at position 104 to TC270 Bare Die pin list, shift following pins accordingly
  - remove ‘P33.8: Emergency Stop can be overruled if this pin is used as safety output pin (SMUFSP)’
  - add ‘Supply (the Exposed Pad is also considered as VSS and shall be connected to ground)’ to Vx type definition
- Absolute Maximum Ratings
  - Add footnote 'Voltages below V_{INmin} have no Impact to the device reliabiltiy as Long as the times and currents defined in section Pin Reliability in Overload for the affected pad(s) are not violated.' to V_{INA}
  - Add footnote 'Voltages below V_{INmin} have no Impact to the device reliabiltiy as Long as the times and currents defined in section Pin Reliability in Overload for the affected pad(s) are not violated.' to V_{INB}
- Changes in table 'Overload Parameters' of Overload
  - Remove I_{INSA}
- Class S
  - Change footnote from 'VILSD is implemented to ensure J2716 specification. It can't be guaranteed that it suppresses switching due to external system noise if pads configured with Speed grade 1 setting (PDx.1=0 and PDx.0=0) is not configured for all of the two physically neighbors left and right of the used SENT input

pin.' to 'VILSD is implemented to ensure J2716 specification. For details of dedicated pins please see AP32286 for details.'

- Changes in table 'Class A2' of Standard_Pads
  - Change note of V_{IHA2} from 'TTL;else' to 'TTL;valid for all A2 pads except TMS/DAP1, TRST, and TCK/DAP0'
  - Change note of V_{ILA2} from 'TTL;else' to 'TTL;valid for all A2 pads except TMS/DAP1, TRST, and TCK/DAP0'
- VADC
  - Change max value of Q_{CONV} from 20 pC to 75 pC
  - Change max value of Q_{CONV} from 10 pC to 22 pC
  - Change typ value of Q_{CONV} from 14 pC to 50 pC
  - Change note of Q_{CONV} from '3 pC' to '10 pC'
  - Change note of I_{OZ3} from '-2 µA' to '-2.85 µA'
  - Change max value of EN_{RMS} from 0.75 LSB to 0.8 LSB
  - Change max value of R_{AIN} from 1.6 kOhmto 1.5 kOhm
  - Remove C_{AREFT}
- VADC_33V
  - Change max value of Q_{CONV} from 15 pC to 50 pC
  - Change note of Q_{CONV} from '8 pC' to '17 pC'
  - Change typ value of Q_{CONV} from 7 pC to 35 pC
  - Change type of $QCONV$ from SR to CC
  - Change typ value of Q_{CONV} from 3 pC to 8 pC
  - Change note of EN_{RMS} from '1.5 LSB' to '1.7 LSB'
  - Change note of EN_{RMS} from "target" to ""
  - Remove C_{AREFT}
- DSADC
  - Change note of SNR from 'f_{PB} = 30 kHz; V_{DDM} = ±5%' to 'f_{PB} = 30 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 50 kHz; V_{DDM} = ±5%' to 'f_{PB} = 50 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change max value of I_{REF} from 5.5 µA to 6.3 µA
  - Change note of ED_{GAIN} from 'Target, calibrated' to 'calibrated; GAIN = 1; MODCFG.INCFGx=01'
  - Change note of SNR from 'f_{PB} = 100 kHz; V_{DDM} = ±5%' to 'f_{PB} = 100 kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 50 kHz; V_{DDM} = ±10%' to 'f_{PB} = 50 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 100 kHz; V_{DDM} = ±10%' to 'f_{PB} = 100 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 30 kHz; V_{DDM} = ±10%' to 'f_{PB} = 30 kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Remove max parameter $SFDR$ from 'V_{CM} = 2.2 V, DC coupled; V_{DDM} = ±5%'
  - Add footnote 'The total DC error for the uncalibrated case can be calculated by the geometric addition of ED_{GAIN} and ED_{OFF}' to ED_{OFF}
  - Remove footnote 'Systematic offset shift' from ED_{OFF}
  - Remove old footnote 9)

  - Add footnote 'The defined limits are only valid if the following condition is not applicable: T_J > 150°C and V_{VAREF} > V_{DDM}.' to SNR
  - Change footnote from ‘SFDR = 20 * log(INL / 2<Superscript>N</Superscript>)’ to ‘SFDR = 20 * log(INL / 2<Superscript>N</Superscript>); N = amount of bits’
- DSADC_33V
  - Change note of SNR from 'f_{PB} = 30kHz; V_{DDM} = ±5%' to 'f_{PB} = 30kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 50kHz; V_{DDM} = ±5%' to 'f_{PB} = 50kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of I_{REF} from '5.5 µA' to '5.8 µA'
  - Change min value of ED_{OFF} from -350 mV to -100 mV
  - Add max 100 mV to ED_{OFF}
  - Change note of ED_{GAIN} from 'Target, calibrated' to 'calibrated; GAIN = 1; MODCFG.INCFGx=01'
  - Change note of SNR from 'f_{PB} = 30kHz; V_{DDM} = ±10%' to 'f_{PB} = 30kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 30kHz; V_{DDM} = ±5%' to 'f_{PB} = 30kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 50kHz; V_{DDM} = ±5%' to 'f_{PB} = 50kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 50kHz; V_{DDM} = ±10%' to 'f_{PB} = 50kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 100kHz; V_{DDM} = ±5%' to 'f_{PB} = 100kHz; V_{DDM} = ±5%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of SNR from 'f_{PB} = 100kHz; V_{DDM} = ±10%' to 'f_{PB} = 100kHz; V_{DDM} = ±10%; f_{MOD} = 20 MHz; GAIN = 1'
  - Change note of I_{OZ5} from 'all ADCs disabled' to ''
  - Change note of I_{OZ6} from 'all ADCs disabled' to ''
  - Add footnote 'The total DC error for the uncalibrated case can be calculated by the geometric addition of ED_{GAIN} and ED_{OFF}' to ED_{OFF}
  - Remove footnote 'Systematic offset shift' from ED_{OFF}
  - Remove old footnote 9)
  - Add footnote 'The defined limits are only valid if the following condition is not applicable: T_J > 150°C and V_{VAREF} > V_{DDM}.' to SNR
  - Change footnote from ‘SFDR = 20 * log(INL / 2<Superscript>N</Superscript>)’ to ‘SFDR = 20 * log(INL / 2<Superscript>N</Superscript>); N = amount of bits’
- MHz Oscillator
  - Change support OSC_XTAL frequency from 8 MHz to 24 MHz to 8 MHz to 40 MHz
- Power Supply
  - Change note of I_{DDM} from 'real pattern; current for VADC only;' to 'real pattern; current for VADC only'
- EVR13 SMPS
  - Update wording of footenote 2)
  - Add footenote ‘If frequency spreading (SDFREQSPRD = 1) is activated, an additional ripple of 1% need to be considered.’
- Reset Timings
  - Change note of t_{BP} from '1.1 ms' to '1.11 ms'
  - Remove footenote 2) from t_{BP} max limit 2.5ms
  - Update wording of footenote 4)
- Changes in table 'I2C Standard Mode Timing' of I2C

  - Change predicate of t_7 from max to min
- Changes in Package outline
  - Add information about epad size
  - Add section TC270 Carrier Tape

4.3 Changes from version version 1.0 to 1.1

- VADC
  - Add parameter t_{WU}
  - Add parameter R_{MDU}
  - Add parameter R_{MDD}

4.4 Changes from version version 1.1 to 1.2

- Add Package Version LF-BGA-292-10

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